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Clean Track LITHIUS ProZ

Intel Finger Print Document

ProZ System & ProZ Immersion System & ProZ EUV System & ProZ KrF System

All Tools except PBR tools, and

Software version : 500.1.17.200

Sub Operation Panel version : 5.32.23

PBR

Software version : 500.1.16.200

Sub Operation Panel version : 5.32.22

Teaching Version : 1.46.0

Temperature Version : 1.50.0

Revision 2.07

For the P1274 / P1276 / P1278 Tool

Created by TEA I-PRO

08/14/2023

~ INDEX ~

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1. Overview (Configuration)

1.1 BARC Tool Configuration [TBF]

Impossible to exchange wafers simultaneously

Possible to exchange wafers simultaneously

OVEN_C = OVEN w/ CWH

FEX			HCSB		PRB												
					16-36	TRS-F	16-21	CADH	16-22	CADH	16-23		16-24	CGCH	16-25	CGCH	16-26 CGCH
					16-35	TRS-F	16-11	CADH	16-12	CADH_C	16-13	CWH	16-14	THS	16-15	CGCH	16-16 CGCH
					16-34	TRS-B	16-0	PRA									
					16-33	TRS-B											
			1-20	HCRA	16-32	SCPL											
			Front		16-31	SCPL			16-1	BCT	16-2		BCT		16-3	BCT	
					15-36	TRS-F	15-21	CADH	15-22	CADH	15-23		15-24	CGCH	15-25	CGCH	15-26 CGCH
		1-4			15-35	TRS-F	15-11	CADH	15-12	CADH_C	15-13	CWH	15-14	THS	15-15	CGCH	15-16 CGCH
		FOUP			15-34	TRS-B	15-0	PRA									
					15-33	TRS-B											
					15-32	SCPL											
					15-31	SCPL			15-1	BCT	15-2		BCT		15-3	BCT	
1-54	1-34				14-36	TRS-F	14-21	CADH	14-22	CADH	14-23		14-24	CGCH	14-25	CGCH	14-26 CGCH
XLD	XSTK		1-29	SBU	14-35	TRS-F	14-11	CADH	14-12	CADH_C	14-13	CWH	14-14	THS	14-15	CGCH	14-16 CGCH
1-53	1-33		1-28	SBU	14-34	TRS-B	14-0	PRA									
XLD	XSTK	1-3	1-27	TRS	14-33	TRS-B											
1-52	1-32	FOUP	1-26	THS	14-32	SCPL											
XULD	XSTK		1-25	WEX	14-31	SCPL			14-1	BCT	14-2		BCT		14-3	BCT	
1-51	1-31		1-9	THS	13-36	TRS-F	13-21	CADH	13-22	CADH	13-23		13-24	CGCH	13-25	CGCH	13-26 CGCH
XULD	XSTK		1-8	WEX	13-35	TRS-F	13-11	CADH	13-12	CADH_C	13-13	CWH	13-14	THS	13-15	CGCH	13-16 CGCH
1-49	1-24		1-7	SBU	13-34	TRS-B	13-0	PRA									
XSTK	XSTK		1-6	TRS	13-33	TRS-B											
1-48	1-23		1-5	SBU	13-32	SCPL											
XSTK	XSTK	1-2	1-0	HCRA	13-31	SCPL			13-1	BCT	13-2		BCT		13-3	BCT	
1-47	1-22	FOUP	Back		12-36		12-21		12-22		12-23		12-24		12-25		12-26
XSTK	XSTK				12-35		12-11		12-12		12-13		12-14		12-15		12-16
1-46	1-21				12-34		12-0										
XSTK	XSTK				12-33												
1-44					12-32												
XSTK					12-31		12-1			12-2			12-3			12-4	
1-43					11-36		11-21		11-22		11-23		11-24		11-25		11-26
XULD	1-10	1-1			11-35		11-11		11-12		11-13		11-14		11-15		11-16
1-42	FTRA	FOUP			11-34		11-0										
XLD					11-33												
1-41					11-32												
XSTK					11-31		11-1			11-2			11-3			11-4	

1.2 BARC Tool Configuration [TBFna/TBFlt/TBFcn]

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Impossible to exchange wafers simultaneously

Possible to exchange wafers simultaneously

FEX			HCSB		PRB													
					16-36	TRS-F	16-21	FUTURE	16-22	FUTURE	16-23		16-24	CGCH	16-25	CGCH	16-26	CGCH
					16-35	TRS-F	16-11	FUTURE	16-12	CWH	16-13	CWH	16-14	THS	16-15	CGCH	16-16	CGCH
					16-34	TRS-B	16-0	PRA										
					16-33	TRS-B												
			1-20	HCRA	16-32	SCPL												
			Front		16-31	SCPL			16-1	BCT	16-2		BCT		16-3	BCT		
					15-36	TRS-F	15-21	FUTURE	15-22	FUTURE	15-23		15-24	CGCH	15-25	CGCH	15-26	CGCH
		1-4			15-35	TRS-F	15-11	FUTURE	15-12	CWH	15-13	CWH	15-14	THS	15-15	CGCH	15-16	CGCH
		FOUP			15-34	TRS-B	15-0	PRA										
					15-33	TRS-B												
					15-32	SCPL												
					15-31	SCPL			15-1	BCT	15-2		BCT		15-3	BCT		
1-54	1-34				14-36	TRS-F	14-21	FUTURE	14-22	FUTURE	14-23		14-24	CGCH	14-25	CGCH	14-26	CGCH
XLD	XSTK		1-29	SBU	14-35	TRS-F	14-11	FUTURE	14-12	CWH	14-13	CWH	14-14	THS	14-15	CGCH	14-16	CGCH
1-53	1-33		1-28	SBU	14-34	TRS-B	14-0	PRA										
XLD	XSTK	1-3	1-27	TRS	14-33	TRS-B												
1-52	1-32	FOUP	1-26	THS	14-32	SCPL												
XULD	XSTK		1-25	WEX	14-31	SCPL			14-1	BCT	14-2		BCT		14-3	BCT		
1-51	1-31		1-9	THS	13-36	TRS-F	13-21	FUTURE	13-22	FUTURE	13-23		13-24	CGCH	13-25	CGCH	13-26	CGCH
XULD	XSTK		1-8	WEX	13-35	TRS-F	13-11	FUTURE	13-12	CWH	13-13	CWH	13-14	THS	13-15	CGCH	13-16	CGCH
1-49	1-24		1-7	SBU	13-34	TRS-B	13-0	PRA										
XSTK	XSTK		1-6	TRS	13-33	TRS-B												
1-48	1-23		1-5	SBU	13-32	SCPL												
XSTK	XSTK	1-2	1-0	HCRA	13-31	SCPL			13-1	BCT	13-2		BCT		13-3	BCT		
1-47	1-22	FOUP	Back		12-36		12-21		12-22		12-23		12-24		12-25		12-26	
XSTK	XSTK				12-35		12-11		12-12		12-13		12-14		12-15		12-16	
1-46	1-21				12-34		12-0											
XSTK	XSTK				12-33													
1-44					12-32													
XSTK					12-31		12-1			12-2			12-3			12-4		
1-43					11-36		11-21		11-22		11-23		11-24		11-25		11-26	
XULD	1-10	1-1			11-35		11-11		11-12		11-13		11-14		11-15		11-16	
1-42	FTRA	FOUP			11-34		11-0											
XLD					11-33													
1-41					11-32													
XSTK					11-31		11-1			11-2			11-3			11-4		

1.3 Immersion Tool Configuration [TAP/TNP(Except TNP510)/TAF/TAA]

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Impossible to exchange wafers simultaneously

Possible to exchange wafers simultaneously

FEX		HCSB	PRB																						IFB		
			16-36	TRS-F	16-21		16-22		16-23		16-24	CPHP	16-25	CPHP	16-26	CPHP	16-45	THS	30-51	THS	
			16-35	TRS-F	16-11		16-12		16-13		16-14	CPHP	16-15	CPHP	16-16	CPHP	16-44	TRS	30-20	IRAM	
1-54			16-34	TRS-F	16-0	PRA											16-43	TRS	Front		
XLD			16-33	TRS-F													16-42	TRS	30-24	PIR	
1-53		1-20 HCRA	16-32	SCPL													16-41	TRS	30-23	PIR	
XLD		Front	16-31	SCPL		16-1	ADEV	16-2	ADEV	16-3	ADEV	16-4	ANTD	16-5	ANTD				30-22	PIR	
1-52			15-36	TRS-F	15-21		15-22		15-23		15-24	CPHP	15-25	CPHP	15-26	CPHP	15-45	THS	30-21	PIR	
XULD	1-4		15-35	TRS-F	15-11		15-12		15-13		15-14	CPHP	15-15	CPHP	15-16	CPHP	15-44	TRS	Front Side		
1-51	FOUP		15-34	TRS-F	15-0	PRA											15-43	TRS			
XULD			15-33	TRS-F													15-42	TRS			
1-49			15-32	SCPL													15-41	TRS			
XSTK			15-31	SCPL		15-1	ADEV	15-2	ADEV	15-3	ADEV	15-4	ANTD	15-5	ANTD						
1-48			14-36	TRS-F	14-21		14-22		14-23		14-24	CPHP	14-25	CPHP	14-26	CPHP	14-45	THS	30-4	RSM	
XSTK		1-29 SBU	14-35	TRS-F	14-11		14-12		14-13		14-14	CPHP	14-15	CPHP	14-16	CPHP	14-44	TRS	30-3	TRS	
1-47		1-28 SBU	14-34	TRS-F	14-0	PRA											14-43	TRS	30-2	TRS	
XSTK	1-3	1-27 TRS	14-33	TRS-F													14-42	TRS	30-0	IRAI	
1-46	FOUP	1-26 THS	14-32	SCPL													14-41	TRS			30-1
XSTK		1-25 WEX	14-31	SCPL		14-1	ADEV	14-2	ADEV	14-3	ADEV	14-4	ANTD	14-5	ANTD				30-8	ICPL	
1-44		1-9 THS	13-36	TRS-B	13-21	CADH	13-22	CADH	13-23	CPHP	13-24		13-25		13-26	CPHP	13-45	TRS	30-7	ICPL	
XSTK		1-8 WEX	13-35	TRS-B	13-11	CADH	13-12	CADH	13-13	CPHP	13-14	CPHP	13-15	CPHP	13-16	CPHP	13-44	TRS	30-6	ICPL	
1-43		1-7 SBU	13-34	SCPL	13-0	PRA											13-43	THS	30-5	RSMC	
XULD		1-6 TRS	13-33	SCPL													13-42	CWH			
1-42		1-5 SBU	13-32	SCPL													13-41	CWH	Back Side		
XLD	1-2	1-0 HCRA	13-31	SCPL	13-1	COT		13-2	COT		13-3	ITC		13-4	ITC				30-16	BST	
1-41	FOUP	Back	12-36	TRS-B	12-21	CADH	12-22	CADH	12-23	CPHP	12-24		12-25		12-26	CPHP	12-45	TRS	30-15	BST	
XSTK			12-35	TRS-B	12-11	CADH	12-12	CADH	12-13	CPHP	12-14	CPHP	12-15	CPHP	12-16	CPHP	12-44	TRS	30-14	SRS	
1-24			12-34	SCPL	12-0	PRA											12-43	THS	30-13	SRS	
XSTK			12-33	SCPL													12-42	CWH	30-12	SRS	
1-23			12-32	SCPL													12-41	CWH	30-11	SRS	
XSTK			12-31	SCPL	12-1	COT		12-2	COT		12-3	ITC		12-4	ITC				30-10	IRAM	
1-22			11-36	TRS-B	11-21	CADH	11-22	CADH	11-23	CPHP	11-24		11-25		11-26	CPHP	11-45	TRS	Back		
XSTK	1-1		11-35	TRS-B	11-11	CADH	11-12	CADH	11-13	CPHP	11-14	CPHP	11-15	CPHP	11-16	CPHP	11-44	TRS	30-62	SBU	
1-21	FOUP		11-34	SCPL	11-0	PRA											11-43	THS	30-52	SBU	
XSTK			11-33	SCPL													11-42	CWH	30-42	SBU	
1-10			11-32	SCPL													11-41	CWH	30-32	SBU	
FTRA			11-31	SCPL	11-1	COT		11-2	COT		11-3	ITC		11-4	ITC				30-31	THS	

1.4 Immersion Tool Configuration [TNP510]

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Impossible to exchange wafers simultaneously

Possible to exchange wafers simultaneously

FEX		HCSB	PRB																						IFB		
			16-36	TRS-F	16-21		16-22		16-23		16-24	CPHP	16-25	CPHP	16-26	CPHP	16-45	THS	30-51	THS	
			16-35	TRS-F	16-11		16-12		16-13		16-14	CPHP	16-15	CPHP	16-16	CPHP	16-44	TRS	30-20	IRAM	
1-54			16-34	TRS-F	16-0	PRA											16-43	TRS	Front		
XLD			16-33	TRS-F													16-42	TRS	30-24	PIR	
1-53		1-20 HCRA	16-32	SCPL													16-41	TRS	30-23	PIR	
XLD		Front	16-31	SCPL		16-1	ADEV	16-2	ADEV	16-3	ADEV	16-4	ANTD	16-5	ANTD				30-22	PIR	
1-52			15-36	TRS-F	15-21		15-22		15-23		15-24	CPHP	15-25	CPHP	15-26	CPHP	15-45	THS	30-21	PIR	
XULD	1-4		15-35	TRS-F	15-11		15-12		15-13		15-14	CPHP	15-15	CPHP	15-16	CPHP	15-44	TRS	Front Side		
1-51	FOUP		15-34	TRS-F	15-0	PRA											15-43	TRS			
XULD			15-33	TRS-F													15-42	TRS			
1-49			15-32	SCPL													15-41	TRS			
XSTK			15-31	SCPL		15-1	ADEV	15-2	ADEV	15-3	ADEV	15-4	ANTD	15-5	ANTD						
1-48			14-36	TRS-F	14-21		14-22		14-23		14-24	CPHP	14-25	CPHP	14-26	CPHP	14-45	THS	30-4	RSM	
XSTK		1-29 SBU	14-35	TRS-F	14-11		14-12		14-13		14-14	CPHP	14-15	CPHP	14-16	CPHP	14-44	TRS	30-3	TRS	
1-47		1-28 SBU	14-34	TRS-F	14-0	PRA											14-43	TRS	30-2	TRS	
XSTK	1-3	1-27 TRS	14-33	TRS-F													14-42	TRS	30-0	IRAI	
1-46	FOUP	1-26 THS	14-32	SCPL													14-41	TRS			30-1
XSTK		1-25 WEX	14-31	SCPL		14-1	ADEV	14-2	ADEV	14-3	ADEV	14-4	ANTD	14-5	ANTD				30-8	ICPL	
1-44		1-9 THS	13-36	TRS-B	13-21	CADH	13-22	CADH	13-23	CPHP	13-24		13-25		13-26	CPHP	13-45	TRS	30-7	ICPL	
XSTK		1-8 WEX	13-35	TRS-B	13-11	CADH	13-12	CADH	13-13	CPHP	13-14	CPHP	13-15	CPHP	13-16	CPHP	13-44	TRS	30-6	ICPL	
1-43		1-7 SBU	13-34	SCPL	13-0	PRA											13-43	THS	30-5	RSMC	
XULD		1-6 TRS	13-33	SCPL													13-42	CWH			
1-42		1-5 SBU	13-32	SCPL													13-41	CWH	Back Side		
XLD	1-2	1-0 HCRA	13-31	SCPL	13-1	COT		13-2	COT		13-3	ITC		13-4	ITC				30-16		
1-41	FOUP	Back	12-36	TRS-B	12-21	CADH	12-22	CADH	12-23	CPHP	12-24		12-25		12-26	CPHP	12-45	TRS	30-15	SRS	
XSTK			12-35	TRS-B	12-11	CADH	12-12	CADH	12-13	CPHP	12-14	CPHP	12-15	CPHP	12-16	CPHP	12-44	TRS	30-14	SRS	
1-24			12-34	SCPL	12-0	PRA											12-43	THS	30-13	SRS	
XSTK			12-33	SCPL													12-42	CWH	30-12	SRS	
1-23			12-32	SCPL													12-41	CWH	30-11	SRS	
XSTK			12-31	SCPL	12-1	COT		12-2	COT		12-3	ITC		12-4	ITC				30-10	IRAM	
1-22			11-36	TRS-B	11-21	CADH	11-22	CADH	11-23	CPHP	11-24		11-25		11-26	CPHP	11-45	TRS	Back		
XSTK	1-1		11-35	TRS-B	11-11	CADH	11-12	CADH	11-13	CPHP	11-14	CPHP	11-15	CPHP	11-16	CPHP	11-44	TRS	30-62	SBU	
1-21	FOUP		11-34	SCPL	11-0	PRA											11-43	THS	30-52	SBU	
XSTK			11-33	SCPL													11-42	CWH	30-42	SBU	
1-10			11-32	SCPL													11-41	CWH	30-32	SBU	
FTRA			11-31	SCPL	11-1	COT		11-2	COT		11-3	ITC		11-4	ITC				30-31	THS	

1.5 EUV Tool Configuration [TAW]

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Impossible to exchange wafers simultaneously

Possible to exchange wafers simultaneously

				16-36	TRS-F	16-21		16-22		16-23		16-24	CPHP	16-25	CPHP	16-26	CPHP	16-45	THS	30-51	THS		
				16-35	TRS-F	16-11		16-12		16-13		16-14	CPHP	16-15	CPHP	16-16	CPHP	16-44	TRS	30-20	IRAM		
1-54				16-34	TRS-F	16-0	PRA											16-43	TRS	Front			
XLD				16-33	TRS-F													16-42	TRS	30-24	PIR		
1-53		1-20	HCRA	16-32	SCPL													16-41	TRS	30-23	PIR		
XLD		Front		16-31	SCPL		16-1	ADEV	16-2	ADEV	16-3	FUTURE	16-4	ANTD	16-5	ANTD				30-22	PIR		
1-52				15-36	TRS-F	15-21		15-22		15-23		15-24	CPHP	15-25	CPHP	15-26	CPHP	15-45	THS	30-21	PIR		
XULD	1-4			15-35	TRS-F	15-11		15-12		15-13		15-14	CPHP	15-15	CPHP	15-16	CPHP	15-44	TRS	Front Side			
1-51	FOUP			15-34	TRS-F	15-0	PRA											15-43	TRS				
XULD				15-33	TRS-F													15-42	TRS				
1-49				15-32	SCPL													15-41	TRS				
XSTK				15-31	SCPL		15-1	ADEV	15-2	ADEV	15-3	FUTURE	15-4	ANTD	15-5	ANTD							
1-48				14-36	TRS-F	14-21		14-22		14-23		14-24	CPHP	14-25	CPHP	14-26	CPHP	14-45	THS	30-4	RSM		
XSTK		1-29	SBU	14-35	TRS-F	14-11		14-12		14-13		14-14	CPHP	14-15	CPHP	14-16	CPHP	14-44	TRS	30-3	TRS		
1-47		1-28	SBU	14-34	TRS-F	14-0	PRA											14-43	TRS	30-2	TRS		
XSTK	1-3	1-27	TRS	14-33	TRS-F													14-42	TRS	30-0	IRAI		
1-46	FOUP	1-26	THS	14-32	SCPL													14-41	TRS			30-1	
XSTK		1-25	WEX	14-31	SCPL		14-1	ADEV	14-2	ADEV	14-3	FUTURE	14-4	ANTD	14-5	ANTD				30-8	ICPL		
1-44		1-9	THS	13-36	TRS-B	13-21	CADH	13-22	CADH	13-23	CPHP	13-24	CPHP	13-25	CPHP	13-26	CPHP	13-45	TRS	30-7	ICPL		
XSTK		1-8	WEX	13-35	TRS-B	13-11	CADH	13-12	CADH	13-13	CPHP	13-14	CPHP	13-15	CPHP	13-16	CPHP	13-44	TRS	30-6	ICPL		
1-43		1-7	SBU	13-34	SCPL	13-0	PRA											13-43	THS	30-5	RSMC		
XULD		1-6	TRS	13-33	SCPL													13-42	CWH				
1-42		1-5	SBU	13-32	SCPL													13-41	CWH	Back Side			
XLD	1-2	1-0	HCRA	13-31	SCPL	13-1	COT		13-2	COT		13-3	ITC		13-4	ITC				30-16			
1-41	FOUP	Back		12-36	TRS-B	12-21	CADH	12-22	CADH	12-23	CPHP	12-24	CPHP	12-25	CPHP	12-26	CPHP	12-45	TRS	30-15	BST+		
XSTK				12-35	TRS-B	12-11	CADH	12-12	CADH	12-13	CPHP	12-14	CPHP	12-15	CPHP	12-16	CPHP	12-44	TRS	30-14	BST+		
1-24				12-34	SCPL	12-0	PRA											12-43	THS	30-13	BST+		
XSTK				12-33	SCPL													12-42	CWH	30-12	BST+		
1-23				12-32	SCPL													12-41	CWH	30-11	BST+		
XSTK				12-31	SCPL	12-1	COT		12-2	COT		12-3	ITC		12-4	ITC				30-10	IRAM		
1-22				11-36	FUTURE	11-21	FUTURE	11-22	FUTURE	11-23	FUTURE	11-24		11-25		11-26	FUTURE	11-45	FUTURE	Back			
XSTK	1-1			11-35	FUTURE	11-11	FUTURE	11-12	FUTURE	11-13	FUTURE	11-14	FUTURE	11-15	FUTURE	11-16	FUTURE	11-44	FUTURE	30-62	SBU		
1-21	FOUP			11-34	FUTURE	11-0	PRA											11-43	FUTURE	30-52	SBU		
XSTK				11-33	FUTURE													11-42	FUTURE	30-42	SBU		
1-10				11-32	FUTURE													11-41	FUTURE	30-32	SBU		
FTRA				11-31	FUTURE	11-1	FUTURE		11-2	FUTURE		11-3	FUTURE		11-4	FUTURE				30-31	THS		
FEX		***HCSB***								***PRB***										***IFB***			

1.6 EUV Tool Configuration [TAJ]

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Impossible to exchange wafers simultaneously

Possible to exchange wafers simultaneously

FEX		HCSB		PRB																IFB	
				16-36 TRS-F	16-21	16-22	16-23	16-24 CPHP	16-25 CPHP	16-26 CPHP						16-45 THS	30-51 THS	
				16-35 TRS-F	16-11	16-12	16-13	16-14 CPHP	16-15 CPHP	16-16 CPHP						16-44 TRS	30-20 IRAM	
1-54				16-34 TRS-F	16-0 PRA											16-43 TRS	Front	
XLD				16-33 TRS-F												16-42 TRS	30-24 PIR	
1-53		1-20 HCRA		16-32 SCPL												16-41 TRS	30-23 PIR	
XLD		Front		16-31 SCPL		16-1 ADEV	16-2 ADEV	16-3 FUTURE	16-4 ANTD	16-5 ANTD							30-22 PIR	
1-52				15-36 TRS-F	15-21	15-22	15-23	15-24 CPHP	15-25 CPHP	15-26 CPHP						15-45 THS	30-21 PIR	
XULD	1-4			15-35 TRS-F	15-11	15-12	15-13	15-14 CPHP	15-15 CPHP	15-16 CPHP						15-44 TRS	Front Side	
1-51	FOUP			15-34 TRS-F	15-0 PRA											15-43 TRS		
XULD				15-33 TRS-F												15-42 TRS		
1-49				15-32 SCPL												15-41 TRS		
XSTK				15-31 SCPL		15-1 ADEV	15-2 ADEV	15-3 FUTURE	15-4 ANTD	15-5 ANTD								
1-48				14-36 TRS-F	14-21	14-22	14-23	14-24 CPHP	14-25 CPHP	14-26 CPHP						14-45 THS	30-4 RSM	
XSTK		1-29 SBU		14-35 TRS-F	14-11	14-12	14-13	14-14 CPHP	14-15 CPHP	14-16 CPHP						14-44 TRS	30-3 TRS	
1-47		1-28 SBU		14-34 TRS-F	14-0 PRA											14-43 TRS	30-2 TRS	
XSTK	1-3	1-27 TRS		14-33 TRS-F												14-42 TRS	30-0 IRAI	
1-46	FOUP	1-26 THS		14-32 SCPL												14-41 TRS		30-1
XSTK		1-25 WEX		14-31 SCPL		14-1 ADEV	14-2 ADEV	14-3 FUTURE	14-4 ANTD	14-5 ANTD							30-8 ICPL	
1-44		1-9 THS		13-36 TRS-B	13-21 CADH	13-22 CADH	13-23 CPHP	13-24 CPHP	13-25 CPHP	13-26 CPHP						13-45 TRS	30-7 ICPL	
XSTK		1-8 WEX		13-35 TRS-B	13-11 CADH	13-12 CADH	13-13 CPHP	13-14 CPHP	13-15 CPHP	13-16 CPHP						13-44 TRS	30-6 ICPL	
1-43		1-7 SBU		13-34 SCPL	13-0 PRA											13-43 THS	30-5 RSMC	
XULD		1-6 TRS		13-33 SCPL												13-42 CWH		
1-42		1-5 SBU		13-32 SCPL												13-41 CWH	Back Side	
XLD	1-2	1-0 HCRA		13-31 SCPL	13-1 COT		13-2 COT	13-3 ITC		13-4 ITC							30-16	
1-41	FOUP	Back		12-36 TRS-B	12-21 CADH	12-22 CADH	12-23 CPHP	12-24 CPHP	12-25 CPHP	12-26 CPHP						12-45 TRS	30-15 SRS	
XSTK				12-35 TRS-B	12-11 CADH	12-12 CADH	12-13 CPHP	12-14 CPHP	12-15 CPHP	12-16 CPHP						12-44 TRS	30-14 SRS	
1-24				12-34 SCPL	12-0 PRA											12-43 THS	30-13 SRS	
XSTK				12-33 SCPL												12-42 CWH	30-12 SRS	
1-23				12-32 SCPL												12-41 CWH	30-11 SRS	
XSTK				12-31 SCPL	12-1 COT		12-2 COT	12-3 ITC		12-4 ITC							30-10 IRAM	
1-22				11-36 FUTURE	11-21 FUTURE	11-22 FUTURE	11-23 FUTURE	11-24	11-25	11-26 FUTURE						11-45 FUTURE	Back	
XSTK	1-1			11-35 FUTURE	11-11 FUTURE	11-12 FUTURE	11-13 FUTURE	11-14 FUTURE	11-15 FUTURE	11-16 FUTURE						11-44 FUTURE	30-62 SBU	
1-21	FOUP			11-34 FUTURE	11-0 PRA											11-43 FUTURE	30-52 SBU	
XSTK				11-33 FUTURE												11-42 FUTURE	30-42 SBU	
1-10				11-32 FUTURE												11-41 FUTURE	30-32 SBU	
FTRA				11-31 FUTURE	11-1 FUTURE		11-2 FUTURE	11-3 FUTURE		11-4 FUTURE							30-31 THS	

1.7 Oven S/A Tool Configuration [PBR]

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Impossible to exchange wafers simultaneously

Possible to exchange wafers simultaneously

FEX			HCSB		PRB													
					16-36	TRS-F	16-21		16-22		16-23		16-24		16-25		16-26	
					16-35	TRS-F	16-11	CVIP	16-12	CVIP	16-13	CVIP	16-14	CVIP	16-15	CVIP	16-16	THS
					16-34	TRS-B	16-0	PRA										
					16-33	TRS-B												
			1-20	HCRA	16-32	SCPL												
			Front		16-31	SCPL	16-1				16-2		16-3				16-4	
					15-36	TRS-F	15-21		15-22		15-23		15-24		15-25		15-26	
		1-4			15-35	TRS-F	15-11	CVIP	15-12	CVIP	15-13	CVIP	15-14	CVIP	15-15	CVIP	15-16	THS
		FOUP			15-34	TRS-B	15-0	PRA										
					15-33	TRS-B												
					15-32	SCPL												
					15-31	SCPL	15-1				15-2		15-3				15-4	
1-54	1-34				14-36	TRS-F	14-21		14-22		14-23		14-24		14-25		14-26	
XLD	XSTK		1-29	SBU	14-35	TRS-F	14-11	CVIP	14-12	CVIP	14-13	CVIP	14-14	CVIP	14-15	CVIP	14-16	THS
1-53	1-33		1-28	SBU	14-34	TRS-B	14-0	PRA										
XLD	XSTK	1-3	1-27	TRS	14-33	TRS-B												
1-52	1-32	FOUP	1-26	THS	14-32	SCPL												
XULD	XSTK		1-25	WEX	14-31	SCPL	14-1				14-2		14-3				14-4	
1-51	1-31		1-9	THS	13-36	TRS-F	13-21		13-22		13-23		13-24		13-25		13-26	
XULD	XSTK		1-8	WEX	13-35	TRS-F	13-11	CVIP	13-12	CVIP	13-13	CVIP	13-14	CVIP	13-15	CVIP	13-16	THS
1-49	1-24		1-7	SBU	13-34	TRS-B	13-0	PRA										
XSTK	XSTK		1-6	TRS	13-33	TRS-B												
1-48	1-23		1-5	SBU	13-32	SCPL												
XSTK	XSTK	1-2	1-0	HCRA	13-31	SCPL	13-1				13-2		13-3				13-4	
1-47	1-22	FOUP	Back		12-36	TRS-F	12-21		12-22		12-23		12-24		12-25		12-26	
XSTK	XSTK				12-35	TRS-F	12-11	CVIP	12-12	CVIP	12-13	CVIP	12-14	CVIP	12-15	CVIP	12-16	THS
1-46	1-21				12-34	TRS-B	12-0	PRA										
XSTK	XSTK				12-33	TRS-B												
1-44					12-32	SCPL												
XSTK					12-31	SCPL	12-1				12-2		12-3				12-4	
1-43					11-36	TRS-F	11-21		11-22		11-23		11-24		11-25		11-26	
XULD	1-10	1-1			11-35	TRS-F	11-11	CVIP	11-12	CVIP	11-13	CVIP	11-14	CVIP	11-15	CVIP	11-16	THS
1-42	FTRA	FOUP			11-34	TRS-B	11-0	PRA										
XLD					11-33	TRS-B												
1-41					11-32	SCPL												
XSTK					11-31	SCPL	11-1				11-2		11-3				11-4	

*PBR402 16-11, 16-12, 16-13, 16-14, 16-15 = CXHN

1.8 KrF Tool Configuration [TBZ]

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∗ TBZ458 only does not have BST +

Impossible to exchange wafers simultaneously

Possible to exchange wafers simultaneously

FEX		HCSB	PRB																IFB		
			16-36 TRS-F	16-21		16-22		16-23		16-24		16-25 CPHP		16-26 CPHP		16-45 THS		30-51 THS		
			16-35 TRS-F	16-11		16-12		16-13		16-14 FUTURE		16-15 CPHP		16-16 CPHP		16-44 TRS		30-20 IRAM		
1-54			16-34 FUTURE	16-0 PRA												16-43 TRS		Front		
XLD			16-33 FUTURE													16-42 TRS		30-24		
1-53		1-20 HCRA	16-32 SCPL													16-41 TRS		30-23		
XLD		Front	16-31 SCPL		16-1 ADEV		16-2 ADEV		16-3 FUTURE		16-4 ADEV		16-5 ADEV					30-22		
1-52			15-36 TRS-F	15-21		15-22		15-23		15-24		15-25 CPHP		15-26 CPHP		15-45 THS		30-21		
XULD	1-4		15-35 TRS-F	15-11		15-12		15-13		15-14 FUTURE		15-15 CPHP		15-16 CPHP		15-44 TRS		Front Side		
1-51	FOUP		15-34 FUTURE	15-0 PRA												15-43 TRS				
XULD			15-33 FUTURE													15-42 TRS				
1-49			15-32 SCPL													15-41 TRS				
XSTK			15-31 SCPL		15-1 ADEV		15-2 ADEV		15-3 FUTURE		15-4 ADEV		15-5 ADEV							
1-48			14-36 TRS-B	14-21 CADH		14-22 CADH		14-23 CPHP*		14-24 CPHP		14-25 CPHP		14-26		14-45 THS		30-4 RSM		
XSTK		1-29 SBU	14-35 TRS-B	14-11 CADH		14-12 CADH		14-13 CPHP*		14-14 CPHP*		14-15 CPHP		14-16 CPHP		14-44 TRS		30-3 TRS		
1-47		1-28 SBU	14-34 TRS-B	14-0 PRA												14-43 TRS		30-2 TRS		
XSTK	1-3	1-27 TRS	14-33 TRS-B													14-42 TRS		30-0 IRAI		
1-46	FOUP	1-26 THS	14-32 SCPL													14-41 TRS				30-1
XSTK		1-25 WEX	14-31 SCPL	14-1 COT			14-2 COT			14-3 COT			14-4 COT					30-8 ICPL		
1-44		1-9 THS	13-36 TRS-B	13-21 CADH		13-22 CADH		13-23 CPHP*		13-24 CPHP		13-25 CPHP		13-26		13-45 TRS		30-7 ICPL		
XSTK		1-8 WEX	13-35 TRS-B	13-11 CADH		13-12 CADH		13-13 CPHP*		13-14 CPHP*		13-15 CPHP		13-16 CPHP		13-44 TRS		30-6 ICPL		
1-43		1-7 SBU	13-34 TRS-B	13-0 PRA												13-43 THS		30-5 RSMC		
XULD		1-6 TRS	13-33 TRS-B													13-42 CWH				
1-42		1-5 SBU	13-32 SCPL													13-41 CWH		Back Side		
XLD	1-2	1-0 HCRA	13-31 SCPL	13-1 COT			13-2 COT			13-3 COT			13-4 COT					30-16 BST+		
1-41	FOUP	Back	12-36 FUTURE	12-21 FUTURE		12-22 FUTURE		12-23 FUTURE		12-24 FUTURE		12-25 FUTURE		12-26		12-45 FUTURE		30-15 BST+		
XSTK			12-35 FUTURE	12-11 FUTURE		12-12 FUTURE		12-13 FUTURE		12-14 FUTURE		12-15 FUTURE		12-16		12-44 FUTURE		30-14 BST+		
1-24			12-34 FUTURE	12-0 FUTURE												12-43 FUTURE		30-13 BST+		
XSTK			12-33 FUTURE													12-42 FUTURE		30-12 BST+		
1-23			12-32 FUTURE													12-41 FUTURE		30-11 BST+		
XSTK			12-31 FUTURE	12-1 FUTURE			12-2 FUTURE			12-3 FUTURE			12-4 FUTURE					30-10 IRAM		
1-22			11-36	11-21		11-22		11-23		11-24		11-25		11-26		11-45		Back		
XSTK	1-1		11-35	11-11		11-12		11-13		11-14		11-15		11-16		11-44		30-62 SBU		
1-21	FOUP		11-34	11-0												11-43		30-52 SBU		
XSTK			11-33													11-42		30-42 SBU		
1-10			11-32													11-41		30-32 SBU		
FTRA			11-31	11-1			11-2			11-3			11-4					30-31 THS		

* N2 purge using for CPHP

1.9 KrF Tool Configuration [TBN]

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Impossible to exchange wafers simultaneously

Possible to exchange wafers simultaneously

FEX		HCSB		PRB																IFB		
				16-36 TRS-F	16-21		16-22		16-23		16-24		16-25 CPHP		16-26 CPHP		16-45 THS		30-51 THS		
				16-35 TRS-F	16-11		16-12		16-13		16-14 CPHP		16-15 CPHP		16-16 CPHP		16-44 TRS		30-20 IRAM		
1-54				16-34 SCPL	16-0 PRA												16-43 TRS		Front		
XLD				16-33 SCPL													16-42 TRS		30-24		
1-53		1-20 HCRA		16-32 SCPL													16-41 TRS		30-23		
XLD		Front		16-31 SCPL		16-1 ADEV		16-2 ADEV		16-3 ADEV		16-4 ADEV		16-5 ADEV					30-22		
1-52				15-36 TRS-F	15-21		15-22		15-23		15-24		15-25 CPHP		15-26 CPHP		15-45 THS		30-21		
XULD	1-4			15-35 TRS-F	15-11		15-12		15-13		15-14 CPHP		15-15 CPHP		15-16 CPHP		15-44 TRS		Front Side		
1-51	FOUP			15-34 SCPL	15-0 PRA												15-43 TRS				
XULD				15-33 SCPL													15-42 TRS				
1-49				15-32 SCPL													15-41 TRS				
XSTK				15-31 SCPL		15-1 ADEV		15-2 ADEV		15-3 ADEV		15-4 ADEV		15-5 ADEV							
1-48				14-36 TRS-B	14-21 CADH		14-22 CPHP*		14-23 CPHP*		14-24 CPHP		14-25 CPHP		14-26		14-45 THS		30-4 RSM		
XSTK		1-29 SBU		14-35 TRS-B	14-11 CADH		14-12 CADH		14-13 CPHP*		14-14 CPHP		14-15 CPHP		14-16		14-44 TRS		30-3 TRS		
1-47		1-28 SBU		14-34 TRS-B	14-0 PRA												14-43 TRS		30-2 TRS		
XSTK	1-3	1-27 TRS		14-33 TRS-B													14-42 TRS		30-0 IRAI		
1-46	FOUP	1-26 THS		14-32 SCPL													14-41 TRS				30-1
XSTK		1-25 WEX		14-31 SCPL	14-1 COT			14-2 COT			14-3 COT			14-4 COT					30-8 ICPL		
1-44		1-9 THS		13-36 TRS-B	13-21 CADH		13-22 CPHP*		13-23 CPHP*		13-24 CPHP		13-25 CPHP		13-26		13-45 TRS		30-7 ICPL		
XSTK		1-8 WEX		13-35 TRS-B	13-11 CADH		13-12 CADH		13-13 CPHP*		13-14 CPHP		13-15 CPHP		13-16		13-44 TRS		30-6 ICPL		
1-43		1-7 SBU		13-34 TRS-B	13-0 PRA												13-43 THS		30-5 RSMC		
XULD		1-6 TRS		13-33 TRS-B													13-42 CWH				
1-42		1-5 SBU		13-32 SCPL													13-41 CWH		Back Side		
XLD	1-2	1-0 HCRA		13-31 SCPL	13-1 COT			13-2 COT			13-3 COT			13-4 COT					30-16 BST+		
1-41	FOUP	Back		12-36 TRS-B	12-21 CADH		12-22 CPHP*		12-23 CPHP*		12-24 CPHP		12-25 CPHP		12-26		12-45 TRS		30-15 BST+		
XSTK				12-35 TRS-B	12-11 CADH		12-12 CADH		12-13 CPHP*		12-14 CPHP		12-15 CPHP		12-16		12-44 TRS		30-14 BST+		
1-24				12-34 TRS-B	12-0 PRA												12-43 THS		30-13 BST+		
XSTK				12-33 TRS-B													12-42 CWH		30-12 BST+		
1-23				12-32 SCPL													12-41 CWH		30-11 BST+		
XSTK				12-31 SCPL	12-1 COT			12-2 COT			12-3 COT			12-4 COT					30-10 IRAM		
1-22				11-36	11-21		11-22		11-23		11-24		11-25		11-26		11-45		Back		
XSTK	1-1			11-35	11-11		11-12		11-13		11-14		11-15		11-16		11-44		30-62 SBU		
1-21	FOUP			11-34	11-0												11-43		30-52 SBU		
XSTK				11-33													11-42		30-42 SBU		
1-10				11-32													11-41		30-32 SBU		
FTRA				11-31	11-1			11-2			11-3			11-4					30-31 THS		

* N2 purge using for CPHP

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2. SYSTEM (FAB)

FEX

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
FEX	FTRA	FTRA Level	0.00	degree	-0.2 ~ 0.2	0.0±0.2	Level is checked with the X-axis base.
FEX	XLD,XSTK,XULD	XLD,XSTK,XULD Level	Tool Specific	degree	±0.1 in contrast to FTRA level	±0.1 in contrast to FTRA level	Level adjustment is performed while a wafer is placed on the KC pin.
FEX	SYSTEM	FEX Chemical EXH.(E15C,E15D)	25.0	Pa	25 ~ 280	100 or More	TARGFET CFM 14.1 *KrF E15D Only
FEX	SYSTEM	FEX Chemical EXH. (U/L Setting) (E15C,E15D)	0.0	Pa	---	0.0	
		FEX Chemical EXH. (L/L Setting) (E15C,E15D)	10.0	Pa	---	10.0	

CSB/HCSB

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
HCSB	SYSTEM	Installation height of HCSB	200.0	mm	200 ~ 203	200+3/-0	The height from the floor to the frame lower surface.
HCSB	SYSTEM	Positive pressure	0.3(ASML) 0.4(NIKON)	Pa	0.3 ~ 0.4	0.3+0.1/-0.0	HCSB≦PRB≦SPIN *Refer to ASML value for BARC tool
HCSB	SYSTEM	HCSB Chemical EXH.(E15A & E15B)	100.0	Pa	25 ~ 280	100 or More	TARGET CFM E15A is 29.0 E15B is 18.4
HCSB	SYSTEM	HCSB Chemical EXH. (U/L Setting) (E15A & E15B)	0.0	Pa	---	0.0	
		HCSB Chemical EXH. (L/L Setting) (E15A & E15B)	10.0	Pa	---	10.0	
HCSB	SYSTEM	STAGE VAC. (Regulator Setting)	-55.0	KPa	-53 ~ -57	-55.0	Static Pressure
HCSB	SYSTEM	Resist Bottle Press	30.0	KPa	25.0 to 35.0	50±5	Dynamic Pressure
HCSB	HCRA	HCRA Front area ULPA wind pressure	170.0	Pa	165 ~ 175	170±5	The wind volume is adjusted based on the measurement value in the front side, and the volume on the back is subject to the front side.
HCSB	HCRA	HCRA Back area ULPA wind pressure	170.0	Pa	150 ~ 190	Front pressure±15	
HCSB	HCRA	HCSB transfer area FAN UNIT wind pressure	270	Pa	250 ~ 300	Tool Specific	Adjustment based on the positive pressure of the block alone
HCSB	HCRA	HCSB transfer area FAN UNIT wind pressure (L/L Setting)	SV-90	Pa	---	Tool Specific	
HCSB	HCRA	HCRA Level	0.00	degree	-0.2 ~ 0.2	0.0±0.2	Differential of HCRA/FOUP in the HCRA access direction should be within 0.2º.
HCSB	HCRA	HCRA Fork VAC.	-75.0	KPa	-80 ~ -75	-75+0/-5	Static Pressure
HCSB	HCRA	HCRA Fork VAC. (U/L Setting)	-10.0	KPa	---	-10.0	
		HCRA Fork VAC. (L/L Setting)	-55.0	KPa	---	-55.0	
HCSB	SYSTEM	Amine concentration(HCRA)	<1.0	ppb	---	<1.0	
HCSB	CADH*	HMDS Chemical EXH.(E13A)	150.0	Pa	20 ~ 250	100 or More	TARGET CFM 29.3
HCSB	CADH*	HMDS Chemical EXH. (U/L Setting) (E13A)	0.0	Pa	---	0.0	
		HMDS Chemical EXH. (L/L Setting) (E13A)	15.0	Pa	---	10.0	
HCSB	CADH*	HMDS Buffer Tank Temperature	22.0	℃	21.5 ~ 22.5	---	Control by STHC except PBR
HCSB	SCPL	SCPL Plate VAC.	-75.0	KPa	-80 ~ -75	-75+0/-5	Static Pressure
HCSB	SCPL	Plate Temperature for pre BCT/COT/ITC modules	22.2	℃	22.0 ~ 22.4	SV±0.15	
HCSB	SCPL	Plate Temperature for pre DEV/NTD modules	23.0	℃	22.8 ~ 23.2	SV±0.15	Only IMM/EUV tools 14-31,14-32,15-31,15-32,16-31,16-32
HCSB	SBU	SBU Level	0.00	degree	-0.2 ~ 0.2	0.0±0.2	Level adjustment is performed with the center aluminum frame on HCRA.
HCSB	Rotation Loader	LOADER Level	0.00	degree	-0.2 ~ 0.2	0.0±0.2	Differential of HCRA/FOUP in the HCRA access direction should be within 0.2º. Measure the level at the center of the mark on the loader.
HCSB	Rotation Loader	Foup VAC.	-55.0	KPa	-52 ~ -58	-55.0	Static Pressure
HCSB	Rotation Loader	Foup VAC. (U/L Setting)	-30.0	KPa	---	-30.0	
HCSB	Rotation Loader	Foup VAC. (L/L Setting)	-100.0	KPa	---	-100.0	
HCSB	Rotation Loader	Load Port Door CLAMP Speed	0.2	sec	0.1 ~ 0.3	0.2±0.1	Set by Sub-Op display (Without FOUP)
HCSB	Rotation Loader	Load Port Door UNCLAMP Speed	0.8	sec	0.5 ~ 1.1	0.8±0.3	Set by Sub-Op display (Without FOUP)
HCSB	Rotation Loader	Load Port Door DOCK Speed	1.8	sec	1.5 ~ 2.1	1.8±0.3	Set by Sub-Op display (Without FOUP)
HCSB	Rotation Loader	Load Port Door UNDOCK Speed	1.8	sec	1.5 ~ 2.1	1.8±0.3	Set by Sub-Op display (Without FOUP)
HCSB	Rotation Loader	Load Port Door LATCH Speed	0.8	sec	0.5 ~ 1.1	0.8±0.3	Set by Sub-Op display (Without FOUP)
HCSB	Rotation Loader	Load Port Door UNLATCH Speed	0.8	sec	0.5 ~ 1.1	0.8±0.3	Set by Sub-Op display (Without FOUP)
HCSB	Rotation Loader	Load Port Door OPEN Speed	2.3	sec	2.0 ~ 2.6	2.3±0.3	Set by Sub-Op display (Without FOUP)
HCSB	Rotation Loader	Load Port Door CLOSED Speed	2.3	sec	2.0 ~ 2.6	2.3±0.3	Set by Sub-Op display (Without FOUP)
HCSB	Rotation Loader	Load Port Door TURN-IN Speed	6.0	sec	5.5 ~ 6.5	6.0±0.5	Set by Sub-Op display (Without FOUP) Under normal system operations WITH FOUP , the speed of the FIMS lifting axis reuires readjustment when exceeds ±1.0sec.
HCSB	Rotation Loader	Load Port Door TURN-OUT Speed	4.8	sec	4.5 ~ 5.1	4.8±0.3	Set by Sub-Op display (Without FOUP) Under normal system operations WITH FOUP , the speed of the FIMS lifting axis reuires readjustment when exceeds ±1.0sec.

* N/A for No CADH tool TBFna/TBFlt/TBFcn

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2.SYSTEM (FAB)

PRB

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	SYSTEM	Positive pressure	0.3(ASML) 0.4(NIKON)	Pa	0.3 ~ 0.4	0.3+0.1/-0.0	HCSB≦PRB≦SPIN *Refer to ASML value for BARC tool
PRB	SYSTEM	PRB installation height	200.0	mm	198 ~ 203	200+3/-2	
PRB	SYSTEM	Clearance between HCSB-PRB	5.0	mm	3 ~ 7	5±2	No clearance at the sealing section.
PRB	SYSTEM	SPIN Chemical(L)(R) EXH.(E1A,E1B)	150	Pa	100 ~ 270	150 or More	TARGET CFM 28.3 ※BARC tool setting
PRB	SYSTEM	SPIN Chemical(L)(R) EXH. (U/L Setting) (E1A,E1B)	0.0	Pa	---	0.0	
PRB	SYSTEM	SPIN Chemical(L)(R) EXH. (L/L Setting) (E1A,E1B)	10.0	Pa	---	10.0	
PRB	SYSTEM	SPIN Chemical(L)(R) EXH.(E1A,E1B)	90	Pa	40 ~ 210	90 or More	TARGET CFM 14.1 ※KrF tool setting
PRB	SYSTEM	SPIN Chemical(L)(R) EXH. (U/L Setting) (E1A,E1B)	0.0	Pa	---	0.0	
PRB	SYSTEM	SPIN Chemical(L)(R) EXH. (L/L Setting) (E1A,E1B)	10.0	Pa	---	10.0	
PRB	SYSTEM	Module Drive(A1A)	0.35	MPa	0.32 ~ 0.38	0.35±0.03	Static Pressure
PRB	SYSTEM	Air Pressure Switch (A1A) Digital Gage	0.35	MPa	0.32 ~ 0.38	0.35±0.03	
PRB	SYSTEM	Air Pressure Switch (A1A) Digital Gage--UL	0.38	MPa	---	0.38	
PRB	SYSTEM	Air Pressure Switch (A1A) Digital Gage--LL	0.32	MPa	---	0.32	
PRB	SYSTEM	HP Cooling Air Source(A3A,A3B,A3C,A3D)	0.35	MPa	0.34 ~ 0.36	0.35±0.01	Static Pressure
PRB	SYSTEM	SPIN Chuck VAC. and SPIN Chemical(L) VAC.	-75.0	KPa	-80 ~ -75	-75+0/-5	Static Pressure
PRB	SYSTEM	SPIN Chemical(R) VAC.	-75.0	KPa	-80 ~ -75	-75+0/-5	Static Pressure
PRB	SYSTEM	Resist Tank Pressure	0.05	MPa	0.05 ~ 0.2	0.05 ~ 0.2	Static Pressure
PRB	SYSTEM	Resist Bottle Press (12-3,4 SPIN Chemical)	30.0	KPa	25.0 to 35.0	50±5	Dynamic Pressure
PRB	SYSTEM	PRA(L) area FAN UNIT wind pressure	650	Pa	500 ~800	Tool Specific	Adjustment based on the positive pressure of the block alone. PRA-L and PRA-R FFU to be within 20 Pa
PRB	SYSTEM	PRA(L) area FAN UNIT wind pressure (L/L Setting)	SV-90	Pa	---	Tool Specific	
PRB	SYSTEM	PRA(R) area FAN UNIT wind pressure	650	Pa	500 ~800	Tool Specific	Adjustment based on the positive pressure of the block alone PRA-L and PRA-R FFU to be within 20 Pa
PRB	SYSTEM	PRA(R) area FAN UNIT wind pressure (L/L Setting)	SV-90	Pa	---	Tool Specific	
PRB	SYSTEM*	Flow rate of cooling water from factory(C5A,C6A) (COOL ARM: PCW)	TBF : 11.0 TAP/TAF/TNP/TAA/TBN: 20.0 TAW/TAJ : 17.0 TBZ: 16.0	L/min	TAP/TAF/TNP/TAA/TBN : 19.0 ~21.0 TAW/TAJ : 16.0~18.0 TBZ : 14.0~16.0	SV±1.0	0.6L/min×(Number of Cool Arms + Number of pressure reducing parts) + 0.6L/min×Number of OVENs equipped with a water-cooled plate.
PRB	SYSTEM*	Flow rate of cooling water from factory(C5A,C6A) (COOL ARM: PCW) (L/L Setting)	TBF : 9.0 TAP/TAF/TNP/TAA/TBN: 17.0 TAW/TAJ : 15.0 TBZ : 13.0	L/min	---	Tool Specific	
PRB	SYSTEM	P.C.Water(3) In (C5A)	Tool specific	MPA	<0.5	Tool Specific	Adjust regulator to achieve tool specific flow rate setting "Flow rate of cooling water from factory(C5A,C6A)"
PRB	SYSTEM	THC SPIN(L) wind Pressure	200	Pa	125 to 275	Tool Specific	BARC tool: Left or Right, per deck See Wind Pressure Sheet when setting values.
PRB	SYSTEM	THC SPIN(R) wind Pressure	200	Pa	125 to 275	Tool Specific	BARC tool: Left or Right, per deck See Wind Pressure Sheet when setting values.
PRB	SYSTEM*	Amine concentration(CADH)	<1.0	ppb	---	<1.0	
PRB	SYSTEM*	Amine concentration(SPIN)	<1.0	ppb	---	<1.0	
PRB	PRA	PRA Level	0.00	degree	-0.2 ~ 0.2	0.0±0.2	
PRB	PRA	PRA Fork VAC.	-75.0	KPa	-80 ~ -75	-75+0/-5	Static Pressure
PRB	PRA	PRA Fork VAC. (U/L Setting)	-10.0	KPa	---	-10.0	
		PRA Fork VAC. (L/L Setting)	-55.0	KPa	---	-55.0	
PRB	BCT	SPIN CUP EXH. (E3A,E4A,E5A,E6A)	360	Pa	340 ~ 380	360±50	EPC damper must be held Open and use EXH BKM. Target CFM 169.5 *for Barc tool 310±50Pa when system recipe transferd.
PRB	BCT	SPIN CUP EXH. (E3B,E4B,E5B,E6B)	200	Pa	180 ~ 220	200±25	EPC damper must be held Open and use EXH BKM. Target CFM 98.9 *for Barc tool 160±25Pa when system recipe transferd.
PRB	COT	SPIN CUP EXH. (E1A,E2A,E3A)	360	Pa	340 ~ 380	360±50	EPC damper must be held Open and use EXH BKM. Target CFM 155.5 *for Imm tool 310±50Pa when system recipe transferd.
PRB	ITC	SPIN CUP EXH. (E1B,E2B,E3B)	360	Pa	340 ~ 380	360±50	EPC damper must be held Open and use EXH BKM. Target CFM 155.5 *for Imm tool 310±50Pa when system recipe transferd.
PRB	COT (L)	SPIN CUP EXH. (E2A,E3A,E4A)	360	Pa	340 ~ 380	360±50	EPC damper must be held Open and use EXH BKM. Target CFM 155.5 *for KrF tool 310±50Pa when system recipe transferd.
PRB	COT (R)	SPIN CUP EXH. (E2B,E3B,E4B)	360	Pa	340 ~ 380	360±50	EPC damper must be held Open and use EXH BKM. Target CFM 155.5 *for KrF tool 310±50Pa when system recipe transferd.
PRB	COT/BCT/ITC	SPIN CUP EXH. (L/L Setting) (E3A,E3B,E4A,E4B,E5A,E5B,E6A,E6B)	20	Pa	---	20.0	
PRB	COT/BCT/ITC	RRC (Dispense Rate)	70	ml/min	63 ~ 77	75	
PRB	COT/BCT/ITC	EBR (Dispense Rate) (Dispense Rate)	20	ml/min	18 ~ 22	20	
PRB	COT/BCT/ITC	Back Rinse (Dispense Rate)	100	ml/min	90 ~110	100	
PRB	COT/BCT/ITC	EXH. Duct Clean (Dispense Rate)	200	ml/min	180 ~220	200	

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PRB

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	BCT	TBF Deck13 Drain Case Cleaning + Resist individual Drain Manifold Clean (Dispense Rate)	350	ml/min	325 ~ 375	350	TBF Deck13(BCT) Drain Case Clean is branched to Resist individual drain manifold
PRB	COT	TAP/TNP/TAF/TAA Deck11 Drain Case Cleaning + Resist individual Drain Manifold Clean (Dispense Rate)	300	ml/min	275 ~ 325	350	TAP/TNP/TAF/TAA Deck11(COT) Drain Case Clean is branched to Resist individual drain manifold
PRB	ITC	TAP/TNP/TAF/TAA Deck11 Drain Case Cleaning + Resist individual Drain Manifold Clean (Dispense Rate)	275	ml/min	250 ~ 300	350	TAP/TNP/TAF/TAA Deck11(ITC) Drain Case Clean is branched to Resist individual drain manifold
PRB	COT	TAW/TAJ Deck12 Drain Case Cleaning + Resist individual Drain Manifold Clean (Dispense Rate)	300	ml/min	275 ~ 325	350	TAW/TAJ Deck12(COT) Drain Case Clean is branched to Resist individual drain manifold
PRB	ITC	TAW/TAJ Deck12 Drain Case Cleaning + Resist individual Drain Manifold Clean (Dispense Rate)	275	ml/min	250 ~ 300	350	TAW/TAJ Deck12(ITC) Drain Case Clean is branched to Resist individual drain manifold
PRB	COT	TBN Deck12 Drain Case Cleaning + Resist individual Drain Manifold Clean (Dispense Rate)	275	ml/min	250 ~ 300	350	TBN Deck12(COT) Drain Case Clean is branched to Resist individual drain manifold
PRB	COT	TBZ/TBN Deck13 Drain Case Cleaning + Resist individual Drain Manifold Clean (Dispense Rate)	275	ml/min	250 ~ 300	350	KrF Deck13(COT) Drain Case Clean is branched to Resist individual drain manifold
PRB	COT	TBZ/TBN Deck14 Drain Case Cleaning + Resist individual Drain Manifold Clean (Dispense Rate)	275	ml/min	250 ~ 300	350	KrF Deck14(COT) Drain Case Clean is branched to Resist individual drain manifold
PRB	COT/BCT/ITC	Other Deck Drain Case Cleaning (Dispense Rate)	250	ml/min	225 ~ 275	250	
PRB	COT/BCT/ITC	Nozzle/Bath CLN R# (Dispense Rate)	100	ml/min	90 ~110	100	
PRB	COT/BCT/ITC	Nozzle/Bath CLN CMN (Dispense Rate)	300	ml/min	270 ~ 330	300	
PRB	COT/BCT/ITC	Bevel Rinse (Dispense Rate)	50	ml/min	45 ~ 55	50	*KrF not use
PRB	COT/BCT/ITC	Bevel Rinse Speed Controller	15	Turns	---	---	*KrF not use
PRB	COT/BCT/ITC	Resist temperature	22.2	℃	22.0 ~ 22.4	SV±0.15	
PRB	COT/BCT/ITC	SPIN cup temperature	22.2	℃	22.0 ~ 22.4	SV±0.1	After the installation of temperature and humidity sensor, close the door and wait for 15 min. for stabilization.=> Then record the display value for 1min. Adjust the offset to the average if five data for 5 minutes is within the standard value (SPEC).
PRB	COT/BCT/ITC	SPIN cup humidity	40.7	%	40.2 ~ 41.2	SV±0.5	After the installation of temperature and humidity sensor, close the door and wait for 15 min. for stabilization.=> Then record the display value for 1min. Adjust the offset to the average if five data for 5 minutes is within the standard value (SPEC).
PRB	COT/BCT/ITC	Motor Flange temperature	22.2	℃	22.0 ~ 22.4	SV±0.15	
PRB	COT/BCT/ITC	SPIN wind speed	0.22	m/sec	0.14 ~ 0.30	---	will verify to put fix value
PRB	COT/BCT/ITC	Positive pressure	PRB≦SPIN≦PRB+0.1	Pa	PRB≦SPIN≦PRB+0.1	PRB≦SPIN≦PRB+0.1	HCSB≦PRB≦SPIN
PRB	COT/BCT/ITC	AMC N2 Purge	15.0	KPa	14 ~ 16	15.0±1.0	Static Pressure
PRB	COT/BCT/ITC	AMC N2 Purge (U/L Setting)	20.0	KPa	---	20.0	
PRB	COT/BCT/ITC	AMC N2 Purge (L/L Setting)	5.0	KPa	---	5.0	
PRB	COT/BCT/ITC	Resist Pump Purge	15.0	KPa	14 ~ 16	15±1	Static Pressure
PRB	COT/BCT/ITC	Resist Pump Purge (U/L Setting)	20.0	KPa	---	20.0	
PRB	COT/BCT/ITC	Resist Pump Purge (L/L Setting)	5.0	KPa	---	5.0	
PRB	COT/BCT/ITC	Resist Pump VAC.	-50.0	KPa	-55 ~ -45	-50±5	Static Pressure
PRB	CADH*	Vaporize CADH	0.1	MPa	0.1 ~ 0.12	0.1±0.00	Static Pressure
PRB	CADH*	Chamber Purge CADH	0.1	MPa	0.1 ~ 0.12	0.04±0.00	Static Pressure
PRB	CADH*	Ejector Chamber EXH. Source(A2B)	0.35	MPa	0.34 ~ 0.36	0.35±0.01	Dynamic Pressure
PRB	CADH*	Ejector Chamber EXH. Setting	4.7	KPa	4.6 ~ 4.8	4.7±0.1	Chamber should be down
PRB	CADH*	Ejector Chamber EXH. Setting (U/L Setting)	5.5	KPa	---	5.5	
		Ejector Chamber EXH. Setting (L/L Setting)	3.9	KPa	---	3.9	
PRB	CADH* (BARC)	CADH Ring Purge Pressure	D13/14: 0.35 D15/16: 0.35	MPa	0.15 ~ 0.45	---	Depend on flow rate
PRB	CADH* (BARC)	CADH Ring Purge Flow Rate	D13/14: 88.0 D15/16: 88.0	L/min	D13/14: 87~89 D15/16: 87~89	SV±1	Dynamic 11*Module Amount
PRB	CADH* (BARC)	CADH Ring Purge (U/L Setting)	D13/14: 100.0 D15/16: 100.0	L/min	---	SV+2*Module Amount	
PRB	CADH* (BARC)	CADH Ring Purge (L/L Setting)	D13/14: 72.0 D15/16: 72.0	L/min	---	SV+2*Module Amount	
PRB	CADH (TBZ)	CADH Ring Purge Pressure	D13/14: 0.35	MPa	0.15 ~ 0.45	---	Depend on flow rate
PRB	CADH (TBZ)	CADH Ring Purge Flow Rate	D13/14: 88.0	L/min	D13/14: 87~89	SV±1	Dynamic 11*Module Amount
PRB	CADH (TBZ)	CADH Ring Purge (U/L Setting)	D13/14: 100.0	L/min	---	SV+2*Module Amount	
PRB	CADH (TBZ)	CADH Ring Purge (L/L Setting)	D13/14: 72.0	L/min	---	SV+2*Module Amount	
PRB	CADH (TBN)	CADH Ring Purge Pressure	D13/14: 0.30 D12: 0.15	MPa	0.15 ~ 0.45	---	Depend on flow rate
PRB	CADH (TBN)	CADH Ring Purge Flow Rate	D13/14: 66.0 D12: 33.0	L/min	D13/14: 87~89 D12: 32~34	SV±1	Dynamic 11*Module Amount
PRB	CADH (TBN)	CADH Ring Purge (U/L Setting)	D13/14: 78.0 D12: 39.0	L/min	---	SV+2*Module Amount	
PRB	CADH (TBN)	CADH Ring Purge (L/L Setting)	D13/14: 54.0 D12: 27.0	L/min	---	SV+2*Module Amount	

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PRB

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	CADH (Imm)	CADH Ring Purge Pressure	D12/13: 0.35 D11: 0.20	MPa	0.15 ~ 0.45	---	Depend on flow rate
PRB	CADH (Imm)	CADH Ring Purge Flow Rate	D12/13: 88.0 D11: 44.0	L/min	D12/13: 87~89 D11: 43~45	SV±1	Dynamic 11*Module Amount
PRB	CADH (Imm)	CADH Ring Purge (U/L Setting)	D12/13: 100.0 D11: 52.0	L/min	---	SV+2*Module Amount	
PRB	CADH (Imm)	CADH Ring Purge (L/L Setting)	D12/13: 72.0 D11: 38.0	L/min	---	SV+2*Module Amount	
PRB	CADH (EUV)	CADH Ring Purge Pressure	D13: 0.20 D12: 0.20	MPa	0.15 ~ 0.45	---	Depend on flow rate
PRB	CADH (EUV)	CADH Ring Purge Flow Rate	D13: 44.0 D12: 44.0	L/min	D13: 43~45 D12: 43~45	SV±1	Dynamic 11*Module Amount
PRB	CADH (EUV)	CADH Ring Purge (U/L Setting)	D13: 52.0 D12: 52.0	L/min	---	SV+2*Module Amount	
PRB	CADH (EUV)	CADH Ring Purge (L/L Setting)	D13: 38.0 D12: 38.0	L/min	---	SV+2*Module Amount	
PRB	ADEV	MGP Main (Dispense Rate)	Imm/EUV=300 KrF=320	ml/min	270 ~ 330 290~350	300	Dynamic Setting
PRB	ADEV	MGP Sub DEV (Dispense Rate)	250.0	ml/min	225 ~ 275	250	Dynamic Setting
PRB	ADEV	GP DEV (Dispense Rate)	600.0	ml/min	540 ~ 660	600	Dynamic Setting
PRB	ADEV	MGP Sub DIW (Dispense Rate)	250.0	ml/min	225 ~ 275	400	Dynamic Setting
PRB	ADEV	RINSE (Dispense Rate)	Imm/EUV=1000 KrF=1050	ml/min	900 ~ 1100 950~1150	1000	Dynamic Setting
PRB	ADEV	ADR (Dspense Rate)	350.0	ml/min	315 ~ 385	350	Dynamic Setting
PRB	ADEV	Back Rinse (Dispense Rate)	200.0	ml/min	180 ~ 220	200	Dynamic Setting
PRB	ANTD	NTD (Dispense Rate)	300.0	ml/min	270 ~ 330	300	Dynamic Setting
PRB	ANTD	Rinse with NTD (Dispense Rate)	120.0	ml/min	108 ~ 132	120	Dynamic Setting
PRB	ANTD	Back Rinse with NTD (Dispense Rate)	200.0	ml/min	180 ~ 220	200	Dynamic Setting
PRB	ADEV	MGP Bath Exhaust Flow	10.0	L/min	7.5 ~ 12.5	10±2.5	Static Setting
PRB	ADEV	ADR N2 Source Pressure	50.0	KPa	40 ~ 60	50±10	Dynamic Setting
PRB	ADEV	ADR N2 Flow Setting	5.0	L/min	4.5 ~ 5.5	4.4±0.4	
PRB	ADEV	ADR N2 Pressure Setting	15.0	KPa	5 ~ 25	---	Based on 5L/min setting
PRB	ADEV	ADR N2 Pressure Sensor U/L	Module Specifie	KPa	---	Module Specifie	U/L is based on flow setting of 6L/min
PRB	ADEV	ADR N2 Pressure Sensor U/L	Module Specifie	KPa	---	Module Specifie	U/L is based on flow setting of 3L/min
PRB	ANTD	NTD N2 Pressure Setting	4.0	KPa	2.0 ~ 6.0	---	Based on 5L/min setting
PRB	ANTD	NTD N2 Pressure Sensor U/L	Module Specifie	KPa	---	Module Specifie	U/L is based on flow setting of 6L/min
PRB	ANTD	NTD N2 Pressure Sensor U/L	Module Specifie	KPa	---	Module Specifie	U/L is based on flow setting of 3L/min
PRB	ADEV/ANTD	Developer Solution Temperature	23.0	℃	22.8 ~ 23.2	23±0.15	
PRB	ADEV/ANTD	SPIN cup temperature	22.2	℃	22.0 ~ 22.4	SV±0.1	After the installation of temperature and humidity sensor, close the door and wait for 15 min. for stabilization.=> Then record the display value for 1min. Adjust the offset to the average if five data for 5 minutes is within the standard value (SPEC).
PRB	ADEV/ANTD	SPIN cup humidity	40.7	%	40.2 ~ 41.2	SV±0.5	After the installation of temperature and humidity sensor, close the door and wait for 15 min. for stabilization.=> Then record the display value for 1min. Adjust the offset to the average if five data for 5 minutes is within the standard value (SPEC).
PRB	ADEV/ANTD	Motor Flange Temperature	23.0	℃	22.8 ~ 23.2	23±0.15	Same temp as Developer Solution check point
PRB	ADEV/ANTD	SPIN wind speed	0.22	m/sec	0.14 ~ 0.30	---	will verify to put fix value
PRB	ADEV/ANTD	Positive pressure	PRB≦SPIN≦PRB+0.1	Pa	PRB≦SPIN≦PRB+0.1	PRB≦SPIN≦PRB+0.1	HCSB≦PRB≦SPIN
PRB	ADEV	SPIN CUP EXH. (E4A,E5A,E6A)	---	Pa	---	---	No monitor on the tool Imm/EUV/KrF Target CFM 243.7
PRB	ANTD	SPIN CUP EXH. (E4B,E5B,E6B)	425	Pa	350 ～ 500	425±75	Following the EXH BKM. Target CFM 159.0
PRB	ANTD	SPIN CUP EXH. (L/L Setting) (E4B,E5B,E6B)	20	Pa	---	20.0	
PRB	ADEV	SPIN CUP EXH. (E5B,E6B)	---	Pa	---	---	No monitor on the tool KrF Target CFM 159.0

* N/A for no CADH tool TBFna/TBFlt/TBFcn

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2.SYSTEM (FAB)

PRB (PBR Tools)

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	CVIP	Regulator O2 Purge	0.0	MPa	±0.03		PBR404+ : OFF
PRB	CVIP	Regulator N2 Purge	0.0	MPa	±0.03		PBR404+ : OFF
PRB	CVIP	Regulator Air Purge	0.4	MPa	±0.03		
PRB	CVIP	Box EXH	150.0	Pa		> 150	
PRB	CVIP	Box EXH Lower Limit	110.0	Pa	-	110.0	
PRB	CVIP	Flowmeter N2/Air Purge (D15-D16)	60 (Air)	L/min	Total 60±2.0		PBR404+ : N2 or O2 are not used. Switched to air supply.
PRB	CVIP	Flowmeter O2 Purge (D15-D16)	0.0	L/min			
PRB	CVIP	Flowmeter N2/Air Purge (D13-D14)	60 (Air)	L/min	Total 60±2.0		PBR404+ : N2 or O2 are not used. Switched to air supply.
PRB	CVIP	Flowmeter O2 Purge (D13-D14)	0.0	L/min			
PRB	CVIP	Flowmeter N2/Air Purge (D11-D12)	60 (Air)	L/min	Total 60±2.0		PBR404+ : N2 or O2 are not used. Switched to air supply.
PRB	CVIP	Flowmeter O2 Purge (D11-D12)	0.0	L/min			

PRB (PBR402 Only)

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	CVIP	Regulator O2 Purge (D15)	0.0	MPa	±0.03		PBR402 : OFF
PRB	CVIP	Regulator O2 Purge (D11-D14)	0.0	MPa	±0.03		PBR402 : OFF
PRB	CVIP	Regulator N2 Purge (D15)	0.0	MPa	±0.03		PBR402 : OFF
PRB	CVIP	Regulator N2 Purge (D11-D14)	0.0	MPa	±0.03		PBR402 : OFF
PRB	CVIP	Regulator Air Purge (D15)	0.4	MPa	±0.03		
PRB	CVIP	Box EXH	150.0	Pa		> 150	
PRB	CVIP	Box EXH Lower Limit	110.0	Pa	-	110.0	
PRB	CVIP	Flowmeter N2/Air Purge (D15)	30 (Air)	L/min	Total 30±1.0		N2 or O2 are not used. Switched to air supply. (Ref.) N2 purge 47.6 L/min and O2 purge 13.4 L/min when N2 and O2 are used instead of Air and the O2 conc.20.9%. See the O2 conc. Table. 6 ± 0.2 liters per module
PRB	CVIP	Flowmeter O2 Purge (D15)	0.0	L/min			
PRB	CVIP	Flowmeter N2/Air Purge (D13-D14)	60 (Air)	L/min	Total 60±2.0		
PRB	CVIP	Flowmeter O2 Purge (D13-D14)	0.0	L/min			
PRB	CVIP	Flowmeter N2/Air Purge (D11-D12)	60 (Air)	L/min	Total 60±2.0		
PRB	CVIP	Flowmeter O2 Purge (D11-D12)	0.0	L/min			

O2 Conc. Table (PBR402)

Number of CVIP		15th Layer		11th-12th Layer		13th-14th Layer	
		5		10		10	
Inside chamber O2 Conc. [%]	Supply O2 Conc. [%]	Flow rate[L/min] --> **O2+N2= 30L/min**		Flow rate[L/min] --> **O2+N2= 60L/min**		Flow rate[L/min] --> **O2+N2= 60L/min**	
		O2	N2	O2	N2	O2	N2
10 %	**9.5 %**	**2.9**	**27.1**	**6.1**	**54.9**	**5.8**	**53.4**
11 %	10.5 %	3.3	26.8	6.8	54.2	6.4	52.9
12 %	11.6 %	3.6	26.4	7.5	53.5	7.0	52.4
13 %	12.6 %	3.9	26.1	8.1	52.9	7.6	52.0
14 %	13.7 %	4.3	25.8	8.8	52.2	8.2	51.5
15 %	14.7 %	4.6	25.4	9.5	51.5	8.8	51.1
16 %	15.8 %	4.9	25.1	10.1	50.9	9.4	50.6
17 %	16.8 %	5.2	24.8	10.8	50.2	10.0	50.2
18 %	**17.9 %**	**5.6**	**24.5**	**11.5**	**49.5**	**10.5**	**49.7**
19 %	18.9 %	5.9	24.1	12.1	48.9	11.1	49.2
20 %	20.0 %	6.2	23.8	12.8	48.2	11.7	48.8
20.9 %	20.9 %	6.5	23.5	13.4	47.6	12.3	48.4
21 %	21.0 %	6.6	23.5	13.5	47.5	12.3	48.3
22 %	22.1 %	6.9	23.2	14.1	46.9	12.9	47.9
23 %	23.1 %	7.2	22.8	14.8	46.2	13.5	47.4
24 %	24.2 %	7.5	22.5	15.5	45.5	14.1	46.9
25 %	**25.2 %**	**7.9**	**22.2**	**16.2**	**44.8**	**14.7**	**46.5**

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IFB**

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
IFB	SYSTEM	Positive pressure	0.3(ASML) 0.4(NIKON)	Pa	0.3 ~ 0.4	0.3+0.1/-0.0	HCSB≦PRB≧IFB
IFB	SYSTEM	IFB installation height	150.0	mm	148 ~ 153	150+3/-2	
IFB	SYSTEM	Clearance between PRB-IFB(IMM)	7.0	mm	5.5 ~ 7.0	7+0/-1.5	No clearance at the sealing section.
IFB	SYSTEM	Clearance between IFB(IMM)-EXP	30.0	mm	20 ~ 40	30±10	
IFB	SYSTEM	IFB Front EXH.(E12A)	360.0	Pa	360～460	410±50	Target CFM 197.8
IFB	SYSTEM	IFB Back EXH.(E12B)	260.0	Pa	260～360	310±50	Target CFM 247.3
IFB	SYSTEM	KrF Back EXH.(E12B)	280.0	Pa	280～380	330±50	Target CFM 296.6
IFB	SYSTEM	Module Drive(A4A)	0.35	MPa	0.32 ~ 0.38	0.35±0.03	Static Pressure
IFB	SYSTEM	Air Pressure Switch (A4A) Digital Gage	0.35	MPa	0.32 ~ 0.38	0.35±0.03	
IFB	SYSTEM	Air Pressure Switch (A4A) Digital Gage--UL	0.38	MPa	---	0.38	
IFB	SYSTEM	Air Pressure Switch (A4A) Digital Gage--LL	0.32	MPa	---	0.32	
IFB	SYSTEM	SPIN Chuck VAC.	-75.0	KPa	-80 ~ -75	-75+0/-5	Static Pressure
IFB	SYSTEM	IFB Seal	-50.0	KPa	-55 ~ -50	-50+0/-5	Static Pressure
IFB	SYSTEM	Air knife pressure regulator	0.20	MPa	0.19 ~ 0.21	0.20±0.01	
IFB	SYSTEM	Air nozzle pressure regulator	0.40	MPa	0.39 ~ 0.41	0.40±0.01	
IFB	IRA	IRA Front area ULPA wind pressure	200.0	Pa	195 ~ 205	200±5	
IFB	IRA	IRA Back area ULPA wind pressure	200.0	Pa	195 ~ 205	200±5	
IFB	IRA	IRA Front area FAN UNIT wind pressure	Tool Specific	Pa	---	Tool Specific	Adjustment based on the positive pressure of the block alone
IFB	IRA	IRA Front area FAN UNIT wind pressure (L/L Setting)	SV-90	Pa	---	Tool Specific	
IFB	IRA	IRA Back area FAN UNIT wind pressure	Tool Specific	Pa	---	Tool Specific	Adjustment based on the positive pressure of the block alone
IFB	IRA	IRA Back area FAN UNIT wind pressure (L/L Setting)	SV-90	Pa	---	Tool Specific	
IFB	IRA	IRA Level	0.00	degree	-0.2 ~ 0.2	0.0±0.2	
IFB	IRA	IRA Fork VAC.	-75.0	KPa	-80 ~ -75	-75+0/-5	Static Pressure
IFB	IRA	IRA Fork VAC. (U/L Setting)	-10.0	KPa	---	-10.0	
		IRA Fork VAC. (L/L Setting)	-55.0	KPa	---	-55.0	
IFB	IRAI	IRAI Level	0.00	degree	-0.2 ~ 0.2	0.0±0.2	
IFB	IRAI	IRAI Fork VAC.	-75.0	KPa	-80 ~ -75	-75+0/-5	Static Pressure
IFB	IRAI	IRAI Fork VAC. (U/L Setting)	-10.0	KPa	---	-10.0	
		IRAI Fork VAC. (L/L Setting)	-55.0	KPa	---	-55.0	
IFB	SYSTEM	Amin concentration(PIR)	＜1.0	ppb	---	＜1.0	
IFB	SYSTEM	Amine concentration(IRA)	＜1.0	ppb	---	＜1.0	
IFB	PIR/SRS	Back Rinse (Dispense Rate)	200.0	ml/min	180 ~ 220	200	Dynamic Setting
IFB	PIR/SRS	IDR (Dispense Rate)	150.0	ml/min	135 ~ 165	200	Dynamic Setting
IFB	SRS	IE (Dispense Rate)	200.0	ml/min	180 ~ 220	200	Dynamic Setting
IFB	PIR/SRS	Positive pressure	0.3(ASML) 0.4(NIKON)	Pa	0.3 ~ 0.4	0.3+0.1/-0.0	
IFB	BST/BST+	Positive pressure	0.1	Pa	0.1 ~ 0.2	0.1+0.1/-0.0	
IFB	PIR	Wind pressure PIR	45.0	Pa	25.0 ~ 65.0	Tool Specific	Adjustment based on the positive pressure
IFB	SRS	Wind pressure SRS	45.0	Pa	25.0 ~ 65.0	Tool Specific	Adjustment based on the positive pressure
IFB	BST/BST+	Wind pressure BST/BST+	45.0	Pa	25.0 ~ 65.0	Tool Specific	Adjustment based on the positive pressure
IFB	BST/BST+	IDR (Dispense Rate)	200.0	ml/min	190 ~ 210	200±10	Dynamic Setting
IFB	BST/BST+	Brush rinse flow rate	400.0	ml/min	380 ~ 420	400±20	Dynamic Setting
IFB	BST/BST+	Brush Rinse [Slow Leak Drop Dispense Time Interval]	0.5 ~ 2.0	sec	---	0.5 ~ 2.0	Dynamic Setting
IFB	BST/BST+	Brush sub rinse flow rate	400.0	ml/min	380 ~ 420	400±20	Dynamic Setting
IFB	BST/BST+	Brush sub Rinse [Slow Leak Drop Dispense Time Interval]	0.5 ~ 2.0	sec	---	0.5 ~ 2.0	Dynamic Setting
IFB	BST/BST+	IE Nozzle (Dispense Rate)	200.0	ml/min	180 ~ 220	200±20	Dynamic Setting
IFB	BST/BST+	IE Nozzle [Slow Leak Drop Dispense Time Interval]	0.5 ~ 2.0	sec	---	0.5 ~ 2.0	Dynamic Setting
IFB	BST/BST+	Brush Bath Rinse (Dispense Rate)	150.0	ml/min	140 ~ 160	150±10	Dynamic Setting

**=for Immersion and EUV tools

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AC Power Box

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	AC Power Box	AC Power Box Installation Height	100.0	mm	95 ~ 105	100±5	
External	AC Power Box	Primary Supply Power Voltage	3Phases AC	V	200 ~ 220	±10%	

COT Cabinet1

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	COT Cabinet	COT CAB Installation Height	80	mm	80 ~ 85	80+5/-0	
External	COT Cabinet	Module Drive Source(AA1)	0.35	MPa	0.35 ~ 0.4	0.35+.0.05/-0	Static Pressure
External	COT Cabinet	N2 Source Primary(NA1) Label name "HPN2"	0.55	MPa	0.55 or More	0.55+.0.05/-0	Static Pressure, located back side cab
External	COT Cabinet	N2 Source Secondary(NA1) Label name "HPN2(N-1)"	0.5	MPa	0.5 ~ 0.55	0.50+.0.05/-0	Static Pressure, BARC only
External	COT Cabinet	N2 Source Secondary(NA1) Label name "HPN2"	0.5	MPa	0.5 ~ 0.55	0.50+.0.05/-0	Static Pressure, Imm/EUV / KrF only.
External	COT Cabinet	N2 Source Secondary(NA1) Label name "HPN2(N-8)"	0.4	MPa	0.4 or More	0.40+.0.05/-0	Static Pressure, BARC only
External	COT Cabinet	N2 Source Primary(NA8) Label name "UN2"	0.5	MPa	0.5 ~ 0.55	0.50+.0.05/-0	Static Pressure
External	COT Cabinet	Solvent PCS(1,2,3,4) Drive	0.25	MPa	0.20 ~ 0.30	0.1 ~ 0.3	Static Pressure *Imm no PCS(4) / EUV no PCS(3) and PCS(4) / KrF no PCS(1) and PCS(4) *EBR/Bevel and Back Rinse/Exh. Duct clean/Drain Case clean line CPV should bypass.
External	COT Cabinet	Solvent PCS(1,2,3,4) Ejector Drive	0.1 ~ 0.35	MPa	0.1 ~ 0.35	0.1 ~ 0.35	Static Pressure *Imm no PCS(4) / EUV no PCS(3) and PCS(4) / KrF no PCS(1) and PCS(4)
External	COT Cabinet	Solvent PCS(1,2,3,4) Fill Pressure	0.1	MPa	0.1 ~ 0.12	0.1+0.02/-0	Dynamic Pressure *Imm no PCS(4) / EUV no PCS(3) and PCS(4) / KrF no PCS(1) and PCS(4)
External	COT Cabinet	PCS(1,2,3,4) VAC. Setting Sol.(1,2)	-45.0	KPa	-50 ~ -40	-35+0/-5	Dynamic Pressure *Imm no PCS(4) / EUV no PCS(3) and PCS(4) / KrF no PCS(1) and PCS(4)
External	COT Cabinet	PCS(1,2,3,4) VAC. U/L Setting Sol.(1,2)	-29.0	KPa	---	-29	
External	COT Cabinet	PCS(1,2,3,4) VAC. L/L Setting Sol.(1,2)	-99.0	KPa	---	-99	
External	COT Cabinet	HMDS Canister Pressurization	0.08	MPa	0.075 ~ 0.085	Tool Specific	P(setting pressure: MPa)=0.03(MPa)+0.008(coefficient)×H(lifting height: m) *Lifting height = Difference in height between the CAB and the floor where the main body is installed. Dynamic Pressure
External	COT Cabinet	HMDS Empty Weight	Variable	Kg	---	---	Zero with empty weight scale
External	COT Cabinet	HMDS Vent Valve Setting	2T	---	---	Full Open	2T=Full open then closed by 2 Turns. This allows for some adjustment if needed.
External	COT Cabinet	FILTER VENT	60.0	ml/min	54 ~ 66	60.0	Filter Air Vent(IFF-S Filter Air Vent)
External	COT Cabinet	FILTER PURGE	75.0	ml/min	68 ~ 82	75.0	Filter Out Drain(IFF-S Filter Drain)
External	COT Cabinet	IFFS SOL. PCS(1,2,3,4) VAC. Setting Sol.(1,2)	-80.0	KPa	-83 ~ -77	-80.0±3.0	Dynamic Pressure *Imm no PCS(4) / EUV no PCS(3) and PCS(4) / KrF no PCS(1) and PCS(4)
External	COT Cabinet	IFFS SOL. PCS(1,2,3,4) VAC. U/L Setting Sol.(1,2)	-75.0	KPa	---	-75.0	*Imm no PCS(4) / EUV no PCS(3) and PCS(4) / KrF no PCS(1) and PCS(4)
External	COT Cabinet	IFFS SOL. PCS(1,2,3,4) VAC. L/L Setting Sol.(1,2)	-85.0	KPa	---	-80.0	*Imm no PCS(4) / EUV no PCS(3) and PCS(4) / KrF no PCS(1) and PCS(4)
External	COT Cabinet	Solvent Supply System IFF-S Control box P_1 setting	0.13	MPa	0.10 ~ 0.16	Tool Specific	Pressure necessary to achieve 100 ml/min with filter vent valve full open and filter blank installed
External	COT Cabinet	Solvent Supply System IFF-S Control box P_2 setting	0.16	MPa	0.13 ~ 0.19	Tool Specific	P_2 setting is 0.03 higher than P_1
External	COT Cabinet	Solvent Supply System IFF-S Control box P_3 setting	0.21	MPa	0.18 ~ 0.24	Tool Specific	P_3 is 0.05 less than PCS drive pressure. *EBR/Bevel and Back Rinse/Exh. Duct clean/Drain Case clean line CPV should bypass.
External	COT Cabinet	Solvent Supply System IFF-S Control box P_4 setting	0.3	MPa	---	0.3	PCS HW Limitation
External	COT Cabinet	Solvent Supply System CRF Return Line Flow Rate	60.0	ml/min	54 ~ 66	60.0	
External	COT Cabinet	Solvent Supply System CRF Drain Line Flow Rate	60.0	ml/min	54 ~ 66	60.0	
External	COT Cabinet	Solvent Supply System Line Valve Drive	0.2	MPa	0.15 ~ 0.25	SV +0/-0.05	Dynamic Pressure SV = PCS drive pressure - 0.05 (MPa) *EBR/Bevel and Back Rinse/Exh. Duct clean/Drain Case clean line CPV should bypass. *Apply for Nozzle/Bath clean line only.

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3. SYSTEM (Sub-FAB)

COT Cabinet2 Only Imm / EUV

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	COT Cabinet2	COT CAB Installation Height	80	mm	80 ~ 85	80+5/-0	
External	COT Cabinet2	Module Drive Source(AB1)	0.35	MPa	0.35 ~ 0.4	0.35+.0.05/-0	Static Pressure
External	COT Cabinet2	NTD PCS(1,2) Drive	0.25	MPa	0.20 ~ 0.30	0.1 ~ 0.3	Static Pressure, 0 MPa on no-LND/LNR tracks
External	COT Cabinet2	NTD PCS(1,2) Ejector Drive	0.1 ~ 0.35	MPa	0.1 ~ 0.35	0.1 ~ 0.35	Static Pressure, 0 MPa on no-LND/LNR tracks
External	COT Cabinet2	NTD PCS(1,2) Fill Pressure	0.1	MPa	0.1 ~ 0.12	0.1+0.02/-0	Dynamic Pressure, 0 MPa on no-LND/LNR tracks
External	COT Cabinet2	NTD PCS(1,2) VAC. Setting	-45.0	KPa	-50 ~ -40	-35+0/-5	Dynamic Pressure, N/A on no-LND/LNR tracks
External	COT Cabinet2	NTD PCS(1,2) VAC. U/L Setting	-29.0	KPa	---	-29	Dynamic Pressure, N/A on no-LND/LNR tracks
External	COT Cabinet2	NTD PCS(1,2) VAC. L/L Setting	-99.0	KPa	---	-99	Dynamic Pressure, N/A on no-LND/LNR tracks
External	COT Cabinet2	NTD Rinse PCS Drive	0.25	MPa	0.20 ~ 0.30	0.1 ~ 0.3	Static Pressure, 0 MPa on no-LND/LNR tracks
External	COT Cabinet2	NTD Rinse PCS Ejector Drive	0.1 ~ 0.35	MPa	0.1 ~ 0.35	0.1 ~ 0.35	Static Pressure, 0 MPa on no-LND/LNR tracks
External	COT Cabinet2	NTD Rinse PCS Fill Pressure	0.1	MPa	0.1 ~ 0.12	0.1+0.02/-0	Dynamic Pressure, 0 MPa on no-LND/LNR tracks
External	COT Cabinet2	NTD Rinse PCS VAC. Setting	-65.0	KPa	-60.0 ~ -70.0	-35+0/-5	Dynamic Pressure, N/A on no-LND/LNR tracks
External	COT Cabinet2	NTD Rinse PCS VAC. U/L Setting	-49.0	KPa	---	-29	Dynamic Pressure, N/A on no-LND/LNR tracks
External	COT Cabinet2	NTD Rinse PCS VAC. L/L Setting	-99.0	KPa	---	-99	Dynamic Pressure, N/A on no-LND/LNR tracks
External	COT Cabinet2	FILTER VENT	60.0	ml/min	54 ~ 66	60.0	Filter Air Vent(IFF-S Filter Air Vent)
External	COT Cabinet2	FILTER PURGE	75.0	ml/min	68 ~ 82	75.0	Filter Out Drain(IFF-S Filter Drain)
External	COT Cabinet2	IFFS NTD PCS(1,2) VAC. Setting Sol.(1,2)	-80.0	KPa	-83 ~ -77	-80.0±3.0	Dynamic Pressure
External	COT Cabinet2	IFFS NTD PCS(1,2) VAC. U/L Setting Sol.(1,2)	-75.0	KPa	---	-75.0	
External	COT Cabinet2	IFFS NTD PCS(1,2) VAC. L/L Setting Sol.(1,2)	-85.0	KPa	---	-80.0	
External	COT Cabinet2	Solvent Supply System IFF-S Control box P_1 setting	0.13	MPa	0.10 ~ 0.16	Tool Specific	IFFS ENABLED TOOL CONFIGURATIONS Pressure necessary to achieve 100 ml/min with filter vent valve full open and filter blank installed
External	COT Cabinet2	Solvent Supply System IFF-S Control box P_2 setting	0.16	MPa	0.13 ~ 0.19	Tool Specific	IFFS ENABLED TOOL CONFIGURATIONS P_2 setting is 0.03 higher than P_1
External	COT Cabinet2	Solvent Supply System IFF-S Control box P_3 setting	0.21	MPa	0.18 ~ 0.24	Tool Specific	IFFS ENABLED TOOL CONFIGURATIONS P_3 is 0.05 less than PCS drive pressure. *Back Rinse line CPV should bypass.
External	COT Cabinet2	Solvent Supply System IFF-S Control box P_4 setting	0.3	MPa	---	0.3	IFFS ENABLED TOOL CONFIGURATIONS PCS HW Limitation
External	COT Cabinet2	Solvent Supply System CRF Return Line Flow Rate	60.0	ml/min	54 ~ 66	60.0	IFFS ENABLED TOOL CONFIGURATIONS
External	COT Cabinet2	Solvent Supply System CRF Drain Line Flow Rate	60.0	ml/min	54 ~ 66	60.0	IFFS ENABLED TOOL CONFIGURATIONS
External	COT Cabinet2	N.T.Dev.Solution(1) PCS1 Line Valve Drive	0.2	MPa	0.15 ~ 0.25	SV+0/-0.05	Dynamic Pressure SV=PCS drive pressure - 0.05 (MPa) 0 MPa on no-LND/LNR tracks

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3. SYSTEM (Sub-FAB)

DEV Cabinet Only Imm / EUV / KrF

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	DEV Cabinet	DEV CAB Installation Height (V5)	80	mm	80 ~ 85	80+5/-0	
External	DEV Cabinet	Module Drive (AC1)	0.35	MPa	0.32 ~ 0.38	0.35 (+0.05/-0)	Static Pressure Setting
External	DEV Cabinet	DEV Solution (1,2) PCS (1,2) Drive	0.25	MPa	0.20 ~ 0.30	0.10 ~ 0.30	Static Pressure Setting
External	DEV Cabinet	DEV Solution (1,2) PCS (1,2) Ejector Drive 1,2,3	0.1 ~ 0.35	MPa	---	0.1 ~ 0.35	Static Pressure Setting
External	DEV Cabinet	DEV Solution PCS (1,2) Fill Pressure	0.15	MPa	0.15 to 0.17	0.1 (+0.02/-0)	Due to Pre-PCS filter add from INTEL
External	DEV Cabinet	PCS (1,2) VAC Setting Dev Sol. (1,2)	-65.0	kPa	-60.0 to 65.0	-55 (+0/-5)	Static Pressure Setting
External	DEV Cabinet	PCS (1,2) VAC U/L Setting DEV (1,2) PCS (1,2) VAC L/L Setting DEV (1,2)	-49.0 -99.9	kPa	---	-49.0 -99.0	Static Pressure Setting
External	DEV Cabinet	DEV Rinse Nozzle(ADR) / MGP1 SUB DIW	0.30	MPa	0.30 ~ 0.32	0.1 ~ 0.30	Supply Regulator
External	DEV Cabinet	DEV Back Rinse Nozzle	0.30	MPa	0.30 ~ 0.32	0.1 ~ 0.30	Supply Regulator
External	DEV Cabinet	DIW Line Drive	0.25	MPa	0.23 ~ 0.27	SV+0/-0.05	For DEV RINSE and BACK RINSE and MGP1 SUB DIW
External	DEV Cabinet	SRS Rinse / Back Rinse	0.25	MPa	0.25 ~ 0.27	0.1 ~ 0.30	Supply Regulator
External	DEV Cabinet	SRS Line Drive	0.20	MPa	0.18 ~ 0.22	0.15	
External	DEV Cabinet	PIR Rinse / Back Rinse	0.25	MPa	0.25 ~ 0.27	0.1 ~ 0.30	Supply Regulator
External	DEV Cabinet	PIR Line Drive	0.20	MPa	0.18 ~ 0.22	0.15	
External	DEV Cabinet	BST Rinse	0.27	MPa	0.27 ~ 0.29	0.1 ~ 0.30	Supply Regulator for both BST / BST+
External	DEV Cabinet	BST Brush Rinse	0.27	MPa	0.27 ~ 0.29	0.1 ~ 0.30	Supply Regulator for both BST / BST+
External	DEV Cabinet	BST Line Drive	0.22	MPa	0.20 ~ 0.24	0.15	for both BST / BST+

Chemical Cabinet Exhaust Setting for all Configurations

Tool Config	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
TBF/TBFna /TBFlt/TBFcn	COT Cabinet	Exhaust Solvent (EA1)	50.0	Pa	10 ~ 325	50+10/-0	TARGET CFM 21.2
	COT Cabinet	Exhaust Solvent (EA1) U/L Setting (EA1)	350.0	Pa	---	0	
	COT Cabinet	Exhaust Solvent (EA1) L/L Setting (EA1)	10.0	Pa	---	25	
	COT Cabinet	Exhaust HMDS (EA5)*	25.0	Pa	5 ~ 325	30+10/-0	TARGET CFM 14.1
	COT Cabinet	Exhaust HMDS (EA5) U/L Setting (EA5)*	350.0	Pa	---	0	
	COT Cabinet	Exhaust HMDS (EA5) L/L Setting (EA5)*	5.0	Pa	---	5	
TAP/TAF/TNP /TAA/TAW/TAJ	COT Cabinet1	Exhaust Solvent (EA1)	50.0	Pa	10 ~ 325	50+10/-0	TARGET CFM 21.2
	COT Cabinet1	Exhaust Solvent (EA1) U/L Setting (EA1)	350.0	Pa	---	0	
	COT Cabinet1	Exhaust Solvent (EA1) L/L Setting (EA1)	10.0	Pa	---	25	
	COT Cabinet1	Exhaust HMDS (EA5)	25.0	Pa	5 ~ 325	30+10/-0	TARGET CFM 14.1
	COT Cabinet1	Exhaust HMDS (EA5) U/L Setting (EA5)	350.0	Pa	---	0	
	COT Cabinet1	Exhaust HMDS (EA5) L/L Setting (EA5)	5.0	Pa	---	5	
	COT Cabinet2	Exhaust Solvent (EB1)	40.0	Pa	10 ~ 325	40+10/-0	TARGET CFM 17.7
	COT Cabinet2	Exhaust Solvent (EB1) U/L Setting (EB1)	350.0	Pa	---	0	
	COT Cabinet2	Exhaust Solvent (EB1) L/L Setting (EB1)	10.0	Pa	---	15	
	DEV Cabinet	DEV CAB Exhaust(EC1)	50.0	Pa	10 ~ 325	50+10/-0	TARGET CFM 21.2
	DEV Cabinet	DEV CAB Exhaust (EC1) U/L Setting (EC1)	350.0	Pa	---	0	
	DEV Cabinet	DEV CAB Exhaust (EC1) L/L Setting (EC1)	10.0	Pa	---	25	
	DEV Cabinet	DEV CAB Exhaust (EC2)	40.0	Pa	10 ~ 325	40+10/-0	TARGET CFM 14.1
	DEV Cabinet	DEV CAB Exhaust (EC2) U/L Setting (EC2)	350.0	Pa	---	0	
	DEV Cabinet	DEV CAB Exhaust (EC2) L/L Setting (EC2)	10.0	Pa	---	15	
TBZ/TBN	COT Cabinet1	Exhaust Solvent (EA1)	50.0	Pa	10 ~ 325	50+10/-0	TARGET CFM 21.2
	COT Cabinet1	Exhaust Solvent (EA1) U/L Setting (EA1)	350.0	Pa	---	0	
	COT Cabinet1	Exhaust Solvent (EA1) L/L Setting (EA1)	10.0	Pa	---	25	
	COT Cabinet1	Exhaust HMDS (EA5)	25.0	Pa	5 ~ 325	30+10/-0	TARGET CFM 14.1
	COT Cabinet1	Exhaust HMDS (EA5) U/L Setting (EA5)	350.0	Pa	---	0	
	COT Cabinet1	Exhaust HMDS (EA5) L/L Setting (EA5)	5.0	Pa	---	5	
	DEV Cabinet	DEV CAB Exhaust(EC1)	50.0	Pa	10 ~ 325	50+10/-0	TARGET CFM 21.2
	DEV Cabinet	DEV CAB Exhaust (EC1) U/L Setting (EC1)	350.0	Pa	---	0	
	DEV Cabinet	DEV CAB Exhaust (EC1) L/L Setting (EC1)	10.0	Pa	---	25	
	DEV Cabinet	DEV CAB Exhaust (EC2)	40.0	Pa	10 ~ 325	40+10/-0	TARGET CFM 14.1
	DEV Cabinet	DEV CAB Exhaust (EC2) U/L Setting (EC2)	350.0	Pa	---	0	
	DEV Cabinet	DEV CAB Exhaust (EC2) L/L Setting (EC2)	10.0	Pa	---	15	

* N/A for no CADH tool TBFna/TBFlt/TBFcn

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Ultrasonic flowmeter setting for "Liquid Kind"

CHEMICAL NAME	Flow meter Chemical TYPE
Solvent(POS,PGMEA,EL)	Solvent/Cyclohexane
DI Water	DIW
Developer Solution	Developer Solution/Developer Solution
LNR	Solvent/Other
LND	Solvent/Other

3. SYSTEM (Sub-FAB)

System THC

Location	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
External	THC&Chiller	SYSTEM THC Installation Height	110	mm	105 ~ 115	110±5	
External	THC&Chiller	Primary Supply Power Voltage	3Phases AC	V	200 ~ 220	±10%	
External	THC	STHC blower inverter frequency	Tool Specific	Hz	30 ~ 60	30 ~ 60	
External	THC	Condensation pressure	2.25	MPa	2.23 ~ 0.27	2.25±0.02	
External	THC	Evaporation pressure	0.60	MPa	0.60 ~ 0.80	0.60 ~	
External	THC	Air Volume warning value	ADJ Value ±10%	m3/min	---	ADJ Value	
External	THC	Cup Temperature Offset Value	22.2	℃	22.1 ~ 22.3	SV±0.1	
External	THC	Cup Humidity Offset Value	40.7	%	40.2 ~ 41.2	SV±0.5	
External	THC	Cup Temperature across all Cups	0.2	℃	---		
External	THC	Cup Humidity across all Cups	1.0	%	---		
External	THC	D.I.WATER.P (THC)	0.1	MPa	0.08 ~ 0.12	0.1±0.02	
External	THC	P.C.WATER.P (THC)	0.35	MPa	0.3 ~ 0.4	0.35±0.05	
External	THC	AIR Digital Pressure Gauge	0.35	MPa	0.30 ~ 0.40	0.35 ~ 0.50	Manually actuate drain pump to ensure pressure is not lower than low limit.
External	Chiller	P.C.WATER.P (CHR)	0.35	MPa	0.3 ~ 0.4	0.35±0.05	
External	Chiller	CHILLER pump inverter frequency	Tool Specific	Hz	30 ~ 60	30 ~ 60	
External	Chiller	Condensation pressure	1.5	MPa	2.23 ~ 0.27	1.50±0.02	
External	Chiller	Evaporation pressure	0.42	MPa	0.39 ~ 0.45	0.42±0.03	

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STHC CHILLER FLOW RATE SETTING CHART

TBF/TBFna/TBFlt/TBFcn

							Line Setting of STHC Pump menu						
				Flow Rate Setting						Stop		Warning	
Location	Module	Ch	Description of Setting	Tool Setting	Tolerance	TEL Std.	Line	Using	Range	Recov.	Detect	Recov.	Detect
External	Chiller	Ch0*	HMDS	2.0 L/min	1.8 ~ 2.2 L/min	2.0±0.2 L/min	Line0	Valid	4.00	1.60	1.50	1.70	1.60
External	Chiller	Ch1	BCT1+M/F	2.0 L/min	1.8 ~ 2.2 L/min	2.0±0.2 L/min	Line1	Valid	4.00	1.60	1.50	1.70	1.60
External	Chiller	Ch2	BCT2+M/F	2.0 L/min	1.8 ~ 2.2 L/min	2.0±0.2 L/min	Line2	Valid	4.00	1.60	1.50	1.70	1.60
External	Chiller	Ch3	Bypass	4.0 L/min	3.3 ~ 4.7 L/min	4.0±0.7 L/min	Line3	Valid	20.00	3.10	3.00	3.30	3.20
External	Chiller	Ch4-1	CPL(BCT)	25.0 L/min	24.5 ~ 25.5 L/min	25.0±0.5 L/min	Line4	Valid	50.00	24.00	23.00	24.50	24.00
External	Chiller	Ch4-2	Cool Arm	8.0 L/min	7.3 ~8.7 L/min	8.0±0.7 L/min	Line5	Valid	20.00	7.10	7.00	7.30	7.20
External	Chiller	Ch4-2**	Cool Arm	9.6 L/min	8.9 ~10.3 L/min	9.6±0.7 L/min	Line5	Valid	20.00	8.70	8.60	8.90	8.80
External	Chiller	Ch4-3	Bypass	4.0 L/min	3.3 ~ 4.7 L/min	4.0±0.7 L/min	Line6	Valid	20.00	3.10	3.00	3.30	3.20
External	Chiller	Ch4-4	NA	-	-	-	Line7	Invalid	0.00	0.00	0.00	0.00	0.00
External	Chiller	Ch5-1	Bypass	49.0 L/min	46.0 ~ 52.0 L/min	49.0±3.0 L/min	Line8	Valid	50.00	45.00	44.00	46.00	45.00
External	Chiller	Ch5-2	Bypass	13.0 L/min	12.3 ~ 13.7 L/min	13.0±0.7 L/min	Line9	Valid	20.00	12.10	12.00	12.30	12.20
External	Chiller	Ch5-3	NA	-	-	-	Line10	Invalid	0.00	0.00	0.00	0.00	0.00
External	Chiller	Ch5-4	NA	-	-	-	Line11	Invalid	0.00	0.00	0.00	0.00	0.00
External	Chiller	Ch5-5	NA	-	-	-	Line12	Invalid	0.00	0.00	0.00	0.00	0.00

*No CADH tool TBFna/TBFlt/TBFcn is no HMDS

**for dead corner counter installed

For TAP/TAF/TNP/TAA/TAW/TAJ

							Line Setting of STHC Pump menu						
				Flow Rate Setting						Stop		Warning	
Location	Module	Ch	Description of Setting	Tool Setting	Tolerance	TEL Std.	Line	Using	Range	Recov.	Detect	Recov.	Detect
External	Chiller	Ch0	HMDS	2.0 L/min	1.8 ~ 2.2 L/min	2.0±0.2 L/min	Line0	Valid	4.00	1.60	1.50	1.70	1.60
External	Chiller	Ch1	COT+M/F	2.0 L/min	1.8 ~ 2.2 L/min	2.0±0.2 L/min	Line1	Valid	4.00	1.60	1.50	1.70	1.60
External	Chiller	Ch2	ITC+M/F	2.0 L/min	1.8 ~ 2.2 L/min	2.0±0.2 L/min	Line2	Valid	4.00	1.60	1.50	1.70	1.60
External	Chiller	Ch3	ICPL	6.2 L/min	5.9 ~ 6.5 L/min	6.2±0.3 L/min	Line3	Valid	20.00	5.30	5.20	5.90	5.80
External	Chiller	Ch4-1	CPL(COT)	37.0 L/min	36.5 ~37.5 L/min	37.0±0.5 L/min	Line4	Valid	50.00	36.00	35.00	36.50	36.00
External	Chiller	Ch4-2	Cool Arm	7.2 L/min	6.5 ~ 7.9 L/min	7.2±0.7 L/min	Line5	Valid	20.00	6.30	6.20	6.50	6.40
External	Chiller	Ch4-2*	Cool Arm	8.4 L/min	7.7 ~9.1 L/min	8.4±0.7 L/min	Line5	Valid	20.00	7.10	7.00	7.30	7.20
External	Chiller	Ch4-3	Imm=PIR/SRS,EUV=PIR	2.0 L/min	1.8 ~ 2.2 L/min	2.0±0.2 L/min	Line6	Valid	4.00	1.60	1.50	1.70	1.60
External	Chiller	Ch4-4	Bypass	2.0 L/min	1.8 ~ 2.2 L/min	2.0±0.2 L/min	Line7	Valid	4.00	1.60	1.50	1.70	1.60
External	Chiller	Ch5-1	CPL(DEV)	19.0 L/min	18.3 ~ 19.7 L/min	19.0±0.7 L/min	Line8	Valid	20.00	18.10	18.00	18.30	18.20
External	Chiller	Ch5-2	DEV	9.0 L/min	8.3 ~ 9.7 L/min	9.0±0.7 L/min	Line9	Valid	20.00	8.10	8.00	8.30	8.20
External	Chiller	Ch5-3	NTD	6.0 L/min	5.3 ~ 6.7 L/min	6.0±0.7 L/min	Line10	Valid	20.00	5.10	5.00	5.30	5.20
External	Chiller	Ch5-4	M/F(DEV)	6.0 L/min	5.3 ~ 6.7 L/min	6.0±0.7 L/min	Line11	Valid	20.00	5.10	5.00	5.30	5.20
External	Chiller	Ch5-5	Bypass	6.0 L/min	5.3 ~ 6.7 L/min	6.0±0.7 L/min	Line12	Valid	20.00	5.10	5.00	5.30	5.20

*for dead corner counter installed

For PBR

							Line Setting of STHC Pump menu						
				Flow Rate Setting						Stop		Warning	
Location	Module	Ch	Description of Setting	Tool Setting	Tolerance	TEL Std.	Line	Using	Range	Recov.	Detect	Recov.	Detect
External	Chiller	Ch0	NA	-	-	-	Line0	Invalid	0.00	0.00	0.00	0.00	0.00
External	Chiller	Ch1	Bypass	2.0 L/min	1.8 ~ 2.2 L/min	2.0±0.2 L/min	Line1	Valid	4.00	1.60	1.50	1.70	1.60
External	Chiller	Ch2	Bypass	2.0 L/min	1.8 ~ 2.2 L/min	2.0±0.2 L/min	Line2	Valid	4.00	1.60	1.50	1.70	1.60
External	Chiller	Ch3	Bypass	2.0 L/min	1.8 ~ 2.2 L/min	2.0±0.2 L/min	Line3	Valid	4.00	1.60	1.50	1.70	1.60
External	Chiller	Ch4-1	SCPL	37.0 L/min	36.5 ~ 37.5 L/min	37.0±0.5 L/min	Line4	Valid	50.00	36.00	35.00	36.50	36.00
External	Chiller	Ch4-2	NA	-	-	-	Line5	Invalid	0.00	0.00	0.00	0.00	0.00
External	Chiller	Ch4-3	NA	-	-	-	Line6	Invalid	0.00	0.00	0.00	0.00	0.00
External	Chiller	Ch4-4	NA	-	-	-	Line7	Invalid	0.00	0.00	0.00	0.00	0.00
External	Chiller	Ch5-1	Bypass	37.5 L/min	37.0 ~ 38.0 L/min	37.5±0.5 L/min	Line8	Valid	50.00	36.50	35.50	37.00	36.50
External	Chiller	Ch5-2	Bypass	7.5 L/min	6.8 ~ 8.2 L/min	7.5±0.7 L/min	Line9	Valid	20.00	6.60	6.50	6.80	6.70
External	Chiller	Ch5-3	NA	-	-	-	Line10	Invalid	0.00	0.00	0.00	0.00	0.00
External	Chiller	Ch5-4	NA	-	-	-	Line11	Invalid	0.00	0.00	0.00	0.00	0.00
External	Chiller	Ch5-5	NA	-	-	-	Line12	Invalid	0.00	0.00	0.00	0.00	0.00

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STHC CHILLER FLOW RATE SETTING CHART

For TBZ

							Line Setting of STHC Pump menu						
				Flow Rate Setting						Stop		Warning	
Location	Module	Ch	Description of Setting	Tool Setting	Tolerance	TEL Std.	Line	Using	Range	Recov.	Detect	Recov.	Detect
External	Chiller	Ch0	HMDS	2.0 L/min	1.8 ~ 2.2 L/min	2.0±0.2 L/min	Line0	Valid	4.00	1.60	1.50	1.70	1.60
External	Chiller	Ch1	COT+M/F	2.0 L/min	1.8 ~ 2.2 L/min	2.0±0.2 L/min	Line1	Valid	4.00	1.60	1.50	1.70	1.60
External	Chiller	Ch2	COT2+M/F	2.0 L/min	1.8 ~ 2.2 L/min	2.0±0.2 L/min	Line2	Valid	4.00	1.60	1.50	1.70	1.60
External	Chiller	Ch3	ICPL	6.2 L/min	5.9 ~ 6.5 L/min	6.2±0.3 L/min	Line3	Valid	20.00	5.30	5.20	5.90	5.80
External	Chiller	Ch4-1	CPL(COT)	19.0 L/min	18.3 ~ 19.7 L/min	19.0±0.7 L/min	Line4	Valid	20.00	18.10	18.00	18.30	18.20
External	Chiller	*Ch4-2	BYPASS	13.2 L/min	12.5 ~ 13.9 L/min	13.2±0.7 L/min	Line5	Valid	20.00	12.30	12.20	12.50	12.40
External	Chiller	*Ch4-3	Cool Arm	4.0 L/min	3.3 ~ 4.7 L/min	4.0±0.7 L/min	Line6	Valid	20.00	3.10	3.00	3.30	3.20
External	Chiller	Ch4-4	NA	-	-	-	Line7	Invalid	0.00	0.00	0.00	0.00	0.00
External	Chiller	Ch5-1	CPL(DEV)	25.0 L/min	24.3 ~ 25.7 L/min	25.0±0.7 L/min	Line8	Valid	50.00	24.00	23.00	24.50	24.00
External	Chiller	Ch5-2	BYPASS	15.0 L/min	14.3 ~ 15.7 L/min	15.0±0.7 L/min	Line9	Valid	20.00	14.10	14.00	14.30	14.20
External	Chiller	Ch5-3	DEV	10.0 L/min	9.3 ~ 10.7 L/min	10.0±0.7 L/min	Line10	Valid	20.00	9.10	9.00	9.30	9.20
External	Chiller	Ch5-4	M/F(DEV)	4.0 L/min	3.3 ~ 4.7 L/min	4.0±0.7 L/min	Line11	Valid	20.00	3.10	3.00	3.30	3.20
External	Chiller	Ch5-5	NA	-	-	-	Line12	Invalid	0.00	0.00	0.00	0.00	0.00

*for dead corner counter installed

For TBN

							Line Setting of STHC Pump menu						
				Flow Rate Setting						Stop		Warning	
Location	Module	Ch	Description of Setting	Tool Setting	Tolerance	TEL Std.	Line	Using	Range	Recov.	Detect	Recov.	Detect
External	Chiller	Ch0	HMDS	2.0 L/min	1.8 ~ 2.2 L/min	2.0±0.2 L/min	Line0	Valid	4.00	1.60	1.50	1.70	1.60
External	Chiller	Ch1	COT+M/F	2.0 L/min	1.8 ~ 2.2 L/min	2.0±0.2 L/min	Line1	Valid	4.00	1.60	1.50	1.70	1.60
External	Chiller	Ch2	COT2+M/F	2.0 L/min	1.8 ~ 2.2 L/min	2.0±0.2 L/min	Line2	Valid	4.00	1.60	1.50	1.70	1.60
External	Chiller	Ch3	ICPL	6.2 L/min	5.9 ~ 6.5 L/min	6.2±0.3 L/min	Line3	Valid	20.00	5.30	5.20	5.90	5.80
External	Chiller	Ch4-1	CPL(COT)	19.0 L/min	18.3 ~ 19.7 L/min	19.0±0.7 L/min	Line4	Valid	20.00	18.10	18.00	18.30	18.20
External	Chiller	*Ch4-2	BYPASS	13.2 L/min	12.5 ~ 13.9 L/min	13.2±0.7 L/min	Line5	Valid	20.00	12.30	12.20	12.50	12.40
External	Chiller	*Ch4-3	Cool Arm	4.8 L/min	4.1 ~ 5.5 L/min	4.8±0.7 L/min	Line6	Valid	20.00	3.10	3.00	3.30	3.20
External	Chiller	Ch4-4	NA	-	-	-	Line7	Invalid	0.00	0.00	0.00	0.00	0.00
External	Chiller	Ch5-1	CPL(DEV)	25.0 L/min	24.3 ~ 25.7 L/min	25.0±0.7 L/min	Line8	Valid	50.00	24.00	23.00	24.50	24.00
External	Chiller	Ch5-2	BYPASS	23.0 L/min	22.3 ~ 23.7 L/min	23.0±0.7 L/min	Line9	Valid	20.00	14.10	14.00	14.30	14.20
External	Chiller	Ch5-3	DEV	10.0 L/min	9.3 ~ 10.7 L/min	10±0.7 L/min	Line10	Valid	20.00	9.10	9.00	9.30	9.20
External	Chiller	Ch5-4	M/F(DEV)	4.0 L/min	3.3 ~ 4.7 L/min	4.0±0.7 L/min	Line11	Valid	20.00	3.10	3.00	3.30	3.20
External	Chiller	Ch5-5	NA	-	-	-	Line12	Invalid	0.00	0.00	0.00	0.00	0.00

*for dead corner counter installed

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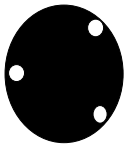
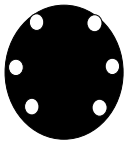
Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	COT/BCT/ITC	Spin Chuck VAC.	-75.0	KPa	-71.0 ~ -79.0	-75±4.0	
PRB	COT/BCT/ITC	Spin Chuck VAC. U/L Setting	-45.0	KPa	---	-45.0	
PRB	COT/BCT/ITC	Spin Chuck VAC. L/L Setting	-99.0	KPa	---	-99.0	
PRB	COT/BCT/ITC	3-Pin Level	0.0	degree	-0.06 ~ 0.06	0.0±0.06	
PRB	COT/BCT/ITC	Chuck Level	0.0	degree	-0.06 ~ 0.06	0.0±0.06	
PRB	COT/BCT/ITC	3-Pin Reference Position	-0.5	mm	Over -0.5	Over -0.5	From Chuck Top Suraface
PRB	COT/BCT/ITC	3-Pin Up Speed	N/A*	sec	---	1.5	*MOTOR driving(NO ADJ)
PRB	COT/BCT/ITC	3-Pin Down Speed	N/A*	sec	---	1.5	*MOTOR driving(NO ADJ)
PRB	COT/BCT/ITC	Overflow Sensor Height	77.0	mm	76.0 ~ 78.0	77.0±1.0	Cup Exhaust Overflow sensor
PRB	COT/ITC	Middle Cup Height	3.1	mm	2.6 ~ 3.6	2.8±0.5	PZ CUP
PRB	COT/ITC	Knife Edge Height	-1.5	mm	-1.0 ~ -2.0	---	PZ CUP The setting is reference only, cup is set up by Middle Cup height.
PRB	BCT	Knife Edge Height	-2.5	mm	-2.3 ~ -2.7	-2.5±0.5	TCT CUP
PRB	COT/BCT/ITC	Cup Height Range Value	0.2	mm	---	---	Applies to the 3 adjustments pts. on the base cup. 
PRB	COT/BCT/ITC	Cup Height Range Value	0.5	mm	---	---	Applies to the 6 adjustments pts. on the base cup. 
PRB	COT/BCT/ITC	Bevel Rinse Nozzle Height	Cup height±0.0	mm	Cup height+0/-0.5	Cup height±0.5	If Cup Height=-2.5, Nozzle Height=-2.5 ~ -3.0
PRB	COT/BCT/ITC	Screw tightening torque for INNER CUP	50.0	cN·m	4.0 ~ 5.0	50.0	
PRB	COT/BCT/ITC	Wafer ~ Resist/RRC Nozzle Height	5.0	mm	4.5 ~ 5.5	4.5±0.5	
PRB	COT/BCT/ITC	Resist Arm X-axis Centering Position	0.0	mm	Wafer Center±0.27	Wafer Center±0.27	from chuck center
PRB	COT/BCT/ITC	Resist Nozzle Height Home Position	4.5	mm	4.0 ~ 5.0	4.5±0.2	
PRB	COT/BCT/ITC	Wafer ~ E.B.R. Nozzle Height	1.0	mm	0.8 ~ 1.2	1.0±0.2	
PRB	COT/BCT/ITC	Back Rinse Dispense Position	80	mm	78 ~ 82	φ160.0±5.0	
PRB	COT/BCT/ITC	Shutter Open Speed	0.9	sec	0.8 ~ 1.0	0.9±0.1	
PRB	COT/BCT/ITC	Shutter Close Speed	0.9	sec	0.8 ~ 1.0	0.9±0.1	
PRB	COT/BCT/ITC	E.B.R Up Speed	0.9	sec	0.8 ~ 1.0	1.0±0.1	
PRB	COT/BCT/ITC	E.B.R Down Speed	0.9	sec	0.8 ~ 1.0	0.8±0.1	
PRB	COT/BCT/ITC	Individual Auto Damper Open Speed	0.4	sec	0.3 ~ 0.5	0.6±0.2	
PRB	COT/BCT/ITC	Individual Auto Damper Close Speed	0.4	sec	0.3 ~ 0.5	0.6±0.2	
PRB	COT/BCT/ITC	Shared Auto Damper Open Speed	0.4	sec	0.3 ~ 0.5	Less than 0.2	
PRB	COT/BCT/ITC	Shared Auto Damper Close Speed	0.3	sec	0.2 ~ 0.3	Less than 0.2	
PRB	COT/BCT/ITC	CUP Changer Up Speed	3.0	sec	2.8 ~ 3.2	3.0±0.2	With CUP installed
PRB	COT/BCT/ITC	CUP Changer Down Speed	3.0	sec	2.8 ~ 3.2	3.0±0.2	With CUP installed
PRB	COT/BCT/ITC	Resist Nozzle Centering Position	0.0	mm	-0.2 ~ 0.2	Wafer Center±0.2	
PRB	COT/BCT/ITC	RRC Nozzle Centering Position	0.0	mm	-0.2 ~ 0.2	Wafer Center±0.2	
PRB	COT/BCT/ITC	E.B.R. Cut Width	Cut Value	mm	Cut Value±0.1	Cut Value±0.1	
PRB	COT/BCT/ITC	E.B.R. Nozzle Angle	30.0	degree	---	30.0	Set by HW (NO ADJ)
PRB	BCT	Cup Exhaust Open	23.0	Pa	22.0 ~ 24.0	23.0±1.0	prevents D.I. water splash (R20)
PRB	BCT	Cup Exhaust Close	65.0	Pa	60.0 ~ 70.0	65.0±5.0	prevents D.I. water splash (R20)
PRB	BCT	Cup EXH U/L Setting	85.0	Pa	---	105.0	
PRB	BCT	Cup EXH L/L Setting	20.0	Pa	---	20.0	
PRB	COT/ITC	Cup Exhaust Open	23.0	Pa	22.0 ~ 24.0	23.0±1.0	PZ CUP
PRB	COT/ITC	Cup Exhaust Close	65.0	Pa	60.0 ~ 70.0	65.0±5.0	PZ CUP
PRB	COT/ITC	Cup EXH U/L Setting	85.0	Pa	---	105.0	
PRB	COT/ITC	Cup EXH L/L Setting	20.0	Pa	---	20.0	
PRB	COT*	Cup Exhaust Open	13.0	Pa	12.0 ~ 14.0	23.0±1.0	PZ CUP
PRB	COT*	Cup Exhaust Close	65.0	Pa	60.0 ~ 70.0	65.0±5.0	PZ CUP
PRB	COT*	Cup EXH U/L Setting	85.0	Pa	---	105.0	
PRB	COT*	Cup EXH L/L Setting	8.0	Pa	---	8.0	
PRB	COT/BCT/ITC	PSB- Process Suckback Position	2.0	mm	2 ~ 3	2 ~ 3	

* for KrF tools

5. ADEV / ANTD

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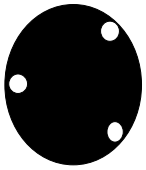
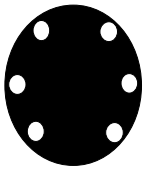
Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	ADEV/ANTD	Spin Chuck VAC.	-75.0	KPa	-71.0 ~ -79.0	-75±4.0	
PRB	ADEV/ANTD	Spin Chuck VAC. U/L Setting	-45.0	KPa	---	-45.0	
PRB	ADEV/ANTD	Spin Chuck VAC. L/L Setting	-99.0	KPa	---	-99.0	
PRB	ADEV/ANTD	3-Pin Level	0.0	degree	-0.06 ~ 0.06	0.0±0.06	
PRB	ADEV/ANTD	Chuck Level	0.0	degree	-0.06 ~ 0.06	0.0±0.06	
PRB	ADEV/ANTD	3-Pin Height- Up	42	mm	---	42	From the chuck to the top surface of the 3-Pin
PRB	ADEV/ANTD	3-Pin Height- Down	-10	mm	---	-10	From the chuck to the top surface of the 3-Pin
PRB	ADEV/ANTD	3-Pin Up Speed	N/A*	sec	---	1.5	*MOTOR driving(NO ADJ)
PRB	ADEV/ANTD	3-Pin Down Speed	N/A*	sec	---	1.5	*MOTOR driving(NO ADJ)
PRB	ADEV/ANTD	Shutter Open Speed	0.9	sec	0.8 ~ 1.0	0.9±0.1	
PRB	ADEV/ANTD	Shutter Close Speed	0.9	sec	0.8 ~ 1.0	0.9±0.1	
PRB	ADEV/ANTD	Auto Damper Open Speed	0.4	sec	0.4 ~ 0.6	0.6±0.2	
PRB	ADEV/ANTD	Auto Damper Close Speed	0.4	sec	0.4 ~ 0.6	0.6±0.2	
PRB	ADEV/ANTD	Cup Exhaust Open	10.0	Pa	5.0 ~ 15.0	10.0±5.0	
PRB	ADEV/ANTD	Cup Exhaust Close	40.0	Pa	35.0 ~ 45.0	40.0±5.0	
PRB	ADEV/ANTD	Cup EXH U/L Setting	80.0	Pa	---	80.0	
PRB	ADEV/ANTD	Cup EXH L/L Setting	1.0	Pa	---	1.0	
PRB	ADEV/ANTD	Knife Edge Height	-2.5	mm	-2.0 ~ -3.0	-2.5±0.5	
PRB	ADEV/ANTD	Upper CUP Height	17	mm	16.0 ~ 18.0		As reference
PRB	ADEV/ANTD	Cup Height Range Value	0.2	mm	---	---	Applies to the 3 adjustments pts. on the base cup. 
PRB	ADEV/ANTD	Cup Height Range Value	0.5	mm	---	---	Applies to the 6 adjustments pts. on the base cup. 
PRB	ADEV	MGP main Nozzle Height	12.6	mm	12.1 ~ 13.1	12.6±0.5	
PRB	ADEV	MGP Sub(DIW,DEV) Nozzle Height	20.0	mm	19.5 ~ 20.5	22.0±0.5	Nozzle replace from TEL STD
PRB	ADEV	MGP main Nozzle Home Height	Nozzle specific	mm	Nozzle specific	Nozzle specific	Home Position Adjusted by fixture.
PRB	ANTD	NTD Nozzle Height	16.0	mm	15.5 ~ 16.5	16.0±0.5	
PRB	ANTD	NTD Nozzle Home Height	Nozzle specific	mm	Nozzle specific	Nozzle specific	Home Position Adjusted by fixture.
PRB	ANTD	NTD Rinse Nozzle Height	16.0	mm	15.5 ~ 16.5	16.0±0.5	As reference
PRB	ANTD	NTD Rinse Home Nozzle Height	Nozzle specific	mm	Nozzle specific	Nozzle specific	Home Position Adjusted by fixture.
PRB	ANTD	NTD N2 Nozzle Height	16.0	mm	15.5 ~ 16.5	16.0±0.5	As reference
PRB	ADEV	ADR N2 Nozzle Height	25.0	mm	24.5 ~ 25.5	25.0±0.5	
PRB	ADEV	ADR Rinse Nozzle Height	12.0	mm	11.5 ~ 12.5	12.0±0.5	
PRB	ADEV	ADR Rinse Nozzle Home Height	Nozzle specific	mm	Nozzle specific	Nozzle specific	Home Position Adjusted by fixture.
PRB	ADEV	MGP main Nozzle Center Position	Center = Chuck Center	mm	---	Center = Chuck Center	Set by using ProZ set up tool
PRB	ADEV	ADR Rinse Nozzle Center Position	Center = Chuck Center	mm	---	Center = Chuck Center	Set by using ProZ set up tool

6. PIR* / SRS** / BST** / BST+***

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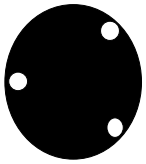
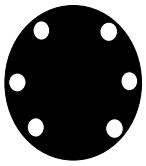
Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
IFB	PIR/SRS	Spin Chuck VAC.	-75.0	KPa	-71.0 ~ -79.0	-75±4.0	
IFB	PIR/SRS	Spin Chuck VAC. U/L Setting	-45.0	KPa	---	-45.0	
IFB	PIR/SRS	Spin Chuck VAC. L/L Setting	-99.0	KPa	---	-99.0	
IFB	PIR/SRS	3-Pin Level	0.0	degree	-0.06 ~ 0.06	0.0±0.06	
IFB	PIR/SRS	Chuck Level	0.0	degree	-0.06 ~ 0.06	0.0±0.06	
IFB	PIR/SRS	3-Pin Up Height	45	mm	---	45	
IFB	PIR/SRS	3-Pin Down Height	-10	mm	---	-10	
IFB	PIR/SRS	3-Pin Up Speed	N/A*	sec	---	1.5	*MOTOR driving(NO ADJ)
IFB	PIR/SRS	3-Pin Down Speed	N/A*	sec	---	1.5	*MOTOR driving(NO ADJ)
IFB	PIR/SRS	Knife Edge Height	-2.5	mm	-2.3 ~ -2.7	-2.5±0.5	
IFB	PIR/SRS	Cup Height Range Value	0.2	mm	---	---	Applies to the 3 adjustments pts. on the base cup. 
IFB	PIR/SRS	Cup Height Range Value	0.5	mm	---	---	Applies to the 6 adjustments pts. on the base cup. 
IFB	PIR/SRS	IDR Nozzle Height	4.0	mm	3.5 ~ 4.5	4±0.5	
IFB	PIR/SRS	Module Arm Up Speed	0.9	sec	0.8 ~ 1.0	0.9±0.1	
IFB	PIR/SRS	Module Arm Down Speed	0.9	sec	0.8 ~ 1.0	0.9±0.1	
IFB	PIR/SRS	IDR Nozzle Center Position	Center = Dispense at Chuck Center	mm	---	Center = Dispense at Chuck Center	Dispense onglass wafer and check if liquid covers center of wafer.
IFB	PIR/SRS	Back Rinse Dispense Position	80	mm	78 ~ 82	φ160.0±5.0	
IFB	SRS	Cup Exhaust Open	20.0	Pa	18.0 ~ 22.0	20.0±2.0	
IFB	SRS	Cup EXH U/L Setting	35.0	Pa	---	30.0	
IFB	SRS	Cup EXH L/L Setting	12.0	Pa	---	15.0	
IFB	PIR	Cup Exhaust Open	15.0	Pa	10.0 ~ 20.0	20.0±2.0	
IFB	PIR	Cup EXH U/L Setting	30.0	Pa	---	30.0	
IFB	PIR	Cup EXH L/L Setting	7.0	Pa	---	15.0	
IFB	SRS	IE Nozzle Dispense position	4.5	mm		4.5±1	From edge of wafer

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Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
IFB	BST/BST+	3-Pin Level	0.0	degree	-0.1 ~ 0.1	0.0±0.1	3-Pin up
IFB	BST/BST+	Chuck Level	0.0	degree	-0.1 ~ 0.1	0.0±0.1	
IFB	BST/BST+	PAD Level	0.0	degree	-0.15 ~ 0.15	0.0±0.15	Home and cleaning positions with PAD up.
IFB	BST/BST+	Brush base levelness	0.0	degree	-0.15 ~ 0.15	Average value: 0.0±0.15	Turn 90º pitch and take the average of measured 4 points.
IFB	BST/BST+	Brush base levelness -pad levelness	0.0	degree	X: -0.15 ~ 0.00 Y: -0.05 ~ +0.05	X: -0.15 ~ 0.00 Y: 0.00±0.05	Home and cleaning positions with PAD up. Direction of installing the level CSB Side is +X, SPIN Door Side is +Y.
IFB	BST/BST+	Brush bath levelness	0.0	degree	-0.15 ~ 0.15	0.0±0.10	
IFB	BST/BST+	3-Pin Up Height	41.5	mm	---	41.5±1.0	
IFB	BST/BST+	3-Pin Down Height	-6.5	mm	---	-6.5±1.0	
IFB	BST/BST+	Main base - SPIN chuck top surface	247.0	mm	246.7 ~ 247.3	247±0.3	Basing the flat surface of main base
IFB	BST/BST+	IDR nozzle tip bottom surface- wafer top surface	4.5	mm	4.0 ~ 5.0	4.5±0.5	IDR arm down
IFB	BST/BST+	Brush arm base top surface - SPIN chuck top surface	39.5	mm	39.0 ~ 40.0	39.5±0.5	Brush arm Z-axis at the home position
IFB	BST/BST+	Brush arm height for periphery cleaning	0 (HOME height +30.0)	mm	-0.3 ~ 0.0	0+1.0/-0.3	Clearance between fixtures when the fixtures are set
IFB	BST/BST+	Brush arm height for center cleaning	0 (HOME height +31.5)	mm	-0.3 ~ 0.0	0+1.0/-0.3	Clearance between fixtures when the fixtures are set
IFB	BST/BST+	Brush arm height for bath cleaning	0 (HOME height +33.0)	mm	-0.3 ~ 0.0	0+1.0/-0.3	Clearance between fixtures when the fixtures are set
IFB	BST/BST+	Brush arm height for brush replacement	Bath cleaning height +1.5	mm	Bath cleaning height +1.5/-0.0	Bath cleaning height +1.5	
IFB	BST/BST+	Brush arm height for brush moisture	Periphery cleaning height -5.0	mm	Periphery cleaning height +0.0/-5.0	Periphery cleaning height +0.0/-5.0	
IFB	BST/BST+	SPIN chuck top surface - air knife top surface	1.0	mm	0.7 ~ 1.3	1±0.3	
IFB	BST/BST+	SPIN chuck top surface - PAD top surface	1.5	mm	1.0 ~ 2.0	1.5±0.5	PAD up
IFB	BST/BST+	SPIN shaft ball plunger protruding length	13.7	mm	13.55 ~ 13.85	13.7±0.15	
IFB	BST/BST+	Shutter plate - transfer opening panel	4.0	mm	3.0 ~ 5.0	4.0±1.0	
IFB	BST/BST+	Brush rinse dispense position	X: 27.0, Y: -44.5	mm	X: 27.0, Y: -44.5 ±ø7 circle	X: 27.0, Y: -44.5 ±ø7 circle	Center of SPIN chuck as (0, 0)
IFB	BST/BST+	Brush sub rinse dispense position	X: -65.0, Y: -62.0	mm	X: -65.0, Y: -62.0 ±ø7 circle	X: -65.0, Y: -62.0 ±ø7 circle	Center of SPIN chuck as (0, 0)
IFB	BST/BST+	IE nozzle dispense position	5.0	mm	4.0 ~ 6.0	5.0±1.0	Distance from wafer periphery
IFB	BST/BST+	IDR nozzle dispense position	0.5	mm	0.5 ~ 1.0	0.5±0.5	Bevel cleaning position (edge B). Distance from wafer periphery. Dispense STREAM should be 0.5mm from the edge.
IFB	BST/BST+	PAD arm Y-axis home position	X axis for PAD center and SPIN chuck center align.	mm	SPIN chuck center±0.5	SPIN chuck center±0.5	
IFB	BST/BST+	Brush arm cleaning position at the center	Brush center and Y-axis center line align.	mm	± 0.5 to swinging direction	± 0.5 to swinging direction	
IFB	BST/BST+	Brush arm bath position	Brush center and brush bath center align.	mm	± 1.0 to swinging direction	± 1.0 to swinging direction	
IFB	BST/BST+	PAD arm up	1.0	sec	0.9 ~ 1.1	1.0±0.1	Prioritize the balance between the main and sub upper/lower speeds for adjustment.
IFB	BST/BST+	PAD arm down	1.0	sec	0.9 ~ 1.1	1.0±0.1	Prioritize the balance between the main and sub upper/lower speeds for adjustment.
IFB	BST/BST+	PAD arm sub up	1.0	sec	0.9 ~ 1.1	1.0±0.1	Prioritize the balance between the main and sub upper/lower speeds for adjustment.
IFB	BST/BST+	PAD arm sub down	1.0	sec	0.9 ~ 1.1	1.0±0.1	Prioritize the balance between the main and sub upper/lower speeds for adjustment.
IFB	BST/BST+	IDR arm up	1.0	sec	0.8 ~ 1.2	1.0±0.2	
IFB	BST/BST+	IDR arm down	1.0	sec	0.8 ~ 1.2	1.0±0.2	
IFB	BST/BST+	Shutter up	1.0	sec	0.8 ~ 1.2	1.0±0.2	
IFB	BST/BST+	Shutter down	1.0	sec	0.8 ~ 1.2	1.0±0.2	
IFB	BST/BST+	3-Pin Up Speed	N/A*	sec	---	1.5	*MOTOR driving(NO ADJ)
IFB	BST/BST+	3-Pin Down Speed	N/A*	sec	---	1.5	*MOTOR driving(NO ADJ)

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Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
IFB	BST/BST+	EV Drive	0.25	MPa	0.22 ~ 0.28	0.25±0.03	
IFB	BST/BST+	Brush pressure set to 1 N	1.0	N	0.9 ~ 1.1	1.0±0.1	Re-measured value after calibration: ± 0.1 N
IFB	BST/BST+	Brush pressed (no load)	0.0	N	0.0	0.0	Sensor under no load with the brush pressed: 0
IFB	BST/BST+	Spin Chuck VAC.	-75.0	KPa	-71.0 ~ -79.0	-75±4.0	
IFB	BST/BST+	Spin Chuck VAC. U/L Setting	-45.0	KPa	---	-45.0	
IFB	BST/BST+	Spin Chuck VAC. L/L Setting	-99.0	KPa	---	-99.9	
IFB	BST/BST+	Pad Vacuum Ejector Drive	0.50	MPa	0.47 ~ 0.53	0.50±0.03	
IFB	BST/BST+	Pad Vacuum Pressure	-75.0	KPa	-75 or more	-75 or more	
IFB	BST/BST+	Pad VAC. U/L Setting	-51.0	KPa	---	-51.0	
IFB	BST/BST+	Pad VAC. L/L Setting	-99.8	KPa	---	-99.8	
IFB	BST/BST+	Local Exhaust	> -12.0	Pa	-12 or more	-12 or more	
IFB	BST/BST+	Local Exhaust U/L Setting	-12.0	KPa	---	-12.0	
IFB	BST/BST+	Local Exhaust L/L Setting	-99.9	KPa	---	-99.9	
IFB	BST/BST+	CUP Exhaust pressure	40.0	Pa	35.0 ~ 45.0	40.0±5.0	
IFB	BST/BST+	CUP Exhaust U/L Setting	50.0	Pa	---	50.0	
IFB	BST/BST+	CUP Exhaust L/L Setting	35.0	Pa	---	35.0	
IFB	BST/BST+	Air knife dispense pressure	45.0	KPa	41.0 ~ 49.0	45.0±4.0	
IFB	BST/BST+	Air knife dispense pressure U/L Setting	99.9	KPa	---	99.9	
IFB	BST/BST+	Air knife dispense pressure L/L Setting	30.0	KPa	---	30.0	
IFB	BST+	Backside air nozzle Flow Setting	80.0	L/min	79.0 ~ 81.0	80.0±1.0	Air Flow Rate Measurement fixture required
IFB	BST+	Backside air nozzle Pressure Setting	30.0 ~ 60.0	KPa	30.0 ~ 60.0	---	Based on 80L/min setting
IFB	BST+	Backside air nozzle Pressure Setting U/L Setting	35.0 ~ 65.0	KPa	35.0 ~ 65.0	Module Specific	U/L is based on flow setting of 90L/min
IFB	BST+	Backside air nozzle Pressure Setting L/L Setting	18.0 ~ 38.0	KPa	18.0 ~ 38.0	Module Specific	L/L is based on flow setting of 65L/min
IFB	BST+	Wafer edge air nozzle Flow Setting	12.0	L/min	11.8 ~ 12.2	12.0±0.2	Air Flow Rate Measurement fixture required
IFB	BST+	Wafer edge air nozzle Pressure Setting	35.0 ~ 45.0	KPa	35.0 ~ 45.0	---	Based on 12L/min setting
IFB	BST+	Wafer edge air nozzle Pressure U/L Setting	40.0 ~ 50.0	KPa	40.0 ~ 50.0	Module Specific	U/L is based on flow setting of 13L/min
IFB	BST+	Wafer edge air nozzle Pressure L/L Setting	20.0 ~ 30.0	KPa	20.0 ~ 30.0	Module Specific	L/L is based on flow setting of 9L/min
IFB	BST+	Wafer edge air nozzle height	3.5	mm	3.0 ~ 4.0	3.5±0.5	Measure with the special fixture and adjust the height with the special shim.
IFB	BST+	Wafer edge air nozzle position	151.5	mm	151.5 ~ 151.6	151.5+0.1/-0.0	Adjust the position with the special fixture. Distance from the center of the chuck
IFB	BST+	Wafer edge air nozzle angle	12.5	degree	---	12.5	Adjust the angle with the special fixture. Angle formed by the backside air nozzle

* = for Immersion and EUV tool ONLY

** = for Immersion tool ONLY

*** = for EUV and KrF tool ONLY (TBZ458 does not have BST +)

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CGCH

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	CGCH	OVEN Module(R) EXH.(E10B)	170	Pa	165 ~ 175	170±5	
PRB	CGCH	OVEN Module(R) EXH. U/L Setting (E10B)	180	Pa	---	180	
PRB	CGCH	OVEN Module(R) EXH. L/L Setting (E10B)	150	Pa	---	150	
PRB	CGCH	CGCH Cover EXH. For Deck13(E8B)	330	Pa	300 ~ 360	195±2	Set by pressure and setting for Individual Chamber exhausts. DO NOT EXCEED TARGET CHAMBER EXH SETTING
PRB	CGCH	CGCH Cover EXH. For Deck13 U/L Setting (E8B)	370	Pa	---	225	
PRB	CGCH	CGCH Cover EXH. For Deck13 L/L Setting (E8B)	290	Pa	---	165	
PRB	CGCH	CGCH Cover EXH. For Deck14	350	Pa	320 ~ 380	230±2	
PRB	CGCH	CGCH Cover EXH. For Deck14 U/L Setting (E8B)	390	Pa	---	260	
PRB	CGCH	CGCH Cover EXH. For Deck14 L/L Setting (E8B)	310	Pa	---	200	
PRB	CGCH	CGCH Cover EXH. For Deck15	130	Pa	100 ~ 160	280±2	
PRB	CGCH	CGCH Cover EXH. For Deck15 U/L Setting (E8B)	170	Pa	---	310	
PRB	CGCH	CGCH Cover EXH. For Deck15 L/L Setting (E8B)	90	Pa	---	250	
PRB	CGCH	CGCH Cover EXH. For Deck16	140	Pa	110 ~ 170	300±2	
PRB	CGCH	CGCH Cover EXH. For Deck16 U/L Setting (E8B)	180	Pa	---	330	
PRB	CGCH	CGCH Cover EXH. For Deck16 L/L Setting (E8B)	100	Pa	---	270	
PRB	CGCH	Individual Chamber Exhaust Pressure	16.0 (80L/min)	Pa	13.0 ~ 19.0 (71.1 ~ 86.1L/min)	12.6±1.0 (70L/min)	
PRB	CGCH	Individual Chamber Exhaust Pressure U/L Setting	19.0 (86.1L/min)	Pa	---	17.1	
PRB	CGCH	Individual Chamber Exhaust Pressure L/L Setting	13.0 (71.1L/min)	Pa	---	8.7	
PRB	CGCH	HP Level	0.0	degree	-0.1 ~ 0.1	0.0±0.10	
PRB	CGCH	3-Pin Level	0.0	degree	-0.05 ~ 0.05	0.0±0.05	Against HP Level
PRB	CGCH	Cool Arm Guide Pin Upper Surface ~ The End of 3-Pin/ Undersurface of Wafer	3.0	mm	1.5 or More	1.5 or More	Cool Arm is In and 3-Pin is Up.
PRB	CGCH	HP Surface ~ The End of 3-Pin(Up)	16.0	mm	16.0 ~ 17.0	16.0+1/-0	3-Pin is Up, For All Pins of 3-Pin.
PRB	CGCH	HP Surface ~ The End of 3-Pin(Down)	1.0	mm	0.5 or More	0.5 or More	3-Pin is Down, For All Pins of 3-Pin.
PRB	CGCH	Module Base Upper Surface ~ Cool Arm Upper Surface	78	mm	78.20 ~ 77.55	78.0+0.20/-0.45	Cool Arm is Out.
PRB	CGCH	HP Upper Surface ~ Cover Heater Undersurface	25.0	mm	24.5 ~ 25.5	25±0.5	
PRB	CGCH	HP Gap Pin	0.1	mm	0.085 ~ 0.115	0.1±0.015	
PRB	CGCH	Cool Arm Gap Pin	0.33	mm	0.315 ~ 0.345	0.33±0.015	
PRB	CGCH	Ring Shutter(L/R) Up Speed	0.7	sec	0.6 ~ 0.8		L/R must match within 0.1s
PRB	CGCH	Ring Shutter(L/R) Down Speed	0.7	sec	0.6 ~ 0.8		L/R must match within 0.1s
PRB	CGCH	Ring Shutter Surface ~ Cover Heater Undersurface	3.0	mm	2.8 ~ 3.2	3.0±0.2	Ring Shutter is Up.
PRB	CGCH	Hot Plate 3-Pin Hole ~ 3-Pin(Up)	2.0	mm	0.95 or More (No contact with a tool)	0.95 or More (No contact with a tool)	3-pin is Up. (No Temp. Rising)
PRB	CGCH	Hot Plate 3-Pin Hole ~ 3-Pin(Down)	2.0	mm	0.95 or More (No contact with a tool)	0.95 or More (No contact with a tool)	3-pin is Down. (No Temp. Rising)
PRB	CGCH	Cool Arm 3-Pin Slit ~ 3-Pin	2.0	mm	1.0 or More (No contact with a tool)	1.0 or More (No contact with a tool)	Cool Arm is In and 3-Pin is Up.
PRB	CGCH	Cool Arm Center ~ HP Plate Center: Centering	0.0	mm	-0.33 ~ 0.33	0.0±0.33	Make Sure that HP Center and Cool Arm Center are Aligned when Cool Arm is In while the Motor is Activated and the Sensors are Enabled.

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CADH

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	CADH*	Chamber Open Speed L/R	0.7	sec	0.6 ~ 0.8	0.7±0.1	L/R must match within 0.1s
PRB	CADH*	Chamber Close Speed L/R	0.7	sec	0.6 ~ 0.8	0.7±0.1	L/R must match within 0.1s
PRB	CADH*	HMDS Vapor Flow Rate	2.5	L/min	2.3 ~ 2.7	2.5±0.2	Chamber is Down.
PRB	CADH*	N2 Purge Flow Rate	5.0	L/min	4.8 ~ 5.2	5.0±0.2	Chamber is Down.
PRB	CADH*	HP Level	0.0	degree	-0.1 ~ 0.1	0.0±0.10	
PRB	CADH*	3-Pin Level	0.0	degree	-0.05 ~ 0.05	0.0±0.05	Against HP Level
PRB	CADH*	Cool Arm Undersurface ~ HP Wafer Guide	3.0	mm	1.5 or More	1.5 or More	Cool Arm is In.
PRB	CADH*	HP Surface ~ The End of 3-Pin(Up)	16.0	mm	16.0 ~ 17.0	16.0+1/-0	3-Pin is Up, For All Pins of 3-Pin.
PRB	CADH*	HP Surface ~ The End of 3-Pin(Down)	>1.0	mm	0.5 or More	0.5 or More	3-Pin is Down, For All Pins of 3-Pin.
PRB	CADH*	Module Base Upper Surface ~ Cool Arm Upper Surface	78	mm	78.20 ~ 77.55	78.0+0.20/-0.45	Cool Arm is Out.
PRB	CADH*	Support Ring Upper Surface ~ Chamber Undersurface	15.0	mm	15 or More	15 or More	Chamber is Up.
PRB	CADH*	Support Ring Upper Surface ~ Chamber Undersurface	0.5	mm	0.3 ~ 0.7	0.5±0.20	Chamber is Down.
PRB	CADH*	HP Gap Pin	0.1	mm	0.085 ~ 0.115	0.1±0.015	
PRB	CADH*	Cool Arm Gap Pin	0.33	mm	0.315 ~ 0.345	0.33±0.015	
PRB	CADH*	OVEN Module(L) EXH.(E10A)	170	Pa	165 ~ 175	170±5	
PRB	CADH*	OVEN Module(L) EXH. U/L Setting (E10A)	180	Pa	---	180	
PRB	CADH*	OVEN Module(L) EXH. L/L Setting (E10A)	150	Pa	---	150	
PRB	CADH*	Local EXH. For Deck13 (E11A)	350	Pa	300 ~ 400	350±50	For BARC tool config -E11A = 8CADH units -E11C = 8CADH units
PRB	CADH*	Local EXH. For Deck13 U/L Setting (E11A)	400	Pa	---	400.0	
PRB	CADH*	Local EXH. For Deck13 L/L Setting (E11A)	300	Pa	---	300.0	
PRB	CADH*	Local EXH. For Deck14 (E11A)	380	Pa	330 ~ 430	380±50	
PRB	CADH*	Local EXH. For Deck14 U/L Setting (E11A)	430	Pa	---	430.0	
PRB	CADH*	Local EXH. For Deck14 L/L Setting (E11A)	330	Pa	---	330.0	
PRB	CADH*	Local EXH. For Deck15 (E11C)	410	Pa	360 ~ 460	410±50	
PRB	CADH*	Local EXH. For Deck15 U/L Setting (E11C)	460	Pa	---	460.0	
PRB	CADH*	Local EXH. For Deck15 L/L Setting (E11C)	360	Pa	---	360.0	
PRB	CADH*	Local EXH. For Deck16 (E11C)	440	Pa	390 ~ 490	440±50	
PRB	CADH*	Local EXH. For Deck16 U/L Setting (E11C)	490	Pa	---	490.0	
PRB	CADH*	Local EXH. For Deck16 L/L Setting (E11C)	390	Pa	---	390.0	
PRB	CADH*	Local EXH. For Deck11/12 (E11A)	220	Pa	190 ~ 250	220±30	For IMM tool config -E11A = 8CADH units (11/12deck) -E11A = 4CADH units(13deck)
PRB	CADH*	Local EXH. For Deck11/12 U/L Setting (E11A)	250	Pa	---	250.0	
PRB	CADH*	Local EXH. For Deck11/12 L/L Setting (E11A)	190	Pa	---	190.0	
PRB	CADH*	Local EXH. For Deck13 (E11A)	140	Pa	120 ~ 160	140±20	
PRB	CADH*	Local EXH. For Deck13 U/L Setting (E11A)	160	Pa	---	160.0	
PRB	CADH*	Local EXH. For Deck13 L/L Setting (E11A)	120	Pa	---	140.0	
PRB	CADH*	Local EXH. For Deck12 (E11A)	140	Pa	120 ~ 160	140±20	For EUV tool config -E11A = 4CADH units (12deck) -E11A = 4CADH units(13deck)
PRB	CADH*	Local EXH. For Deck12 U/L Setting (E11A)	160	Pa	---	160.0	
PRB	CADH*	Local EXH. For Deck12 L/L Setting (E11A)	120	Pa	---	140.0	
PRB	CADH*	Local EXH. For Deck13 (E11A)	140	Pa	120 ~ 160	140±20	
PRB	CADH*	Local EXH. For Deck13 U/L Setting (E11A)	160	Pa	---	160.0	
PRB	CADH*	Local EXH. For Deck13 L/L Setting (E11A)	120	Pa	---	140.0	
PRB	CADH*	Local EXH. For Deck12 (E11A)	140	Pa	120 ~ 160	140±20	For KrF tool config -E11A = 3CADH units (12 deck) --TBN only -E11A = 6CADH or 8 CADH units (13/14 deck)
PRB	CADH*	Local EXH. For Deck12 U/L Setting (E11A)	160	Pa	---	160.0	
PRB	CADH*	Local EXH. For Deck12 L/L Setting (E11A)	120	Pa	---	140.0	
PRB	CADH*	Local EXH. For Deck13/14 (E11A)	230	Pa	200 ~ 260	230±30	
PRB	CADH*	Local EXH. For Deck13/14 U/L Setting (E11A)	260	Pa	---	260.0	
PRB	CADH*	Local EXH. For Deck13/14 L/L Setting (E11A)	200	Pa	---	200.0	
PRB	CADH*	Individual Chamber Exhaust Pressure	4.7 (11L/min)	KPa	4.6 ~ 4.8	4.7±0.1	Chamber is Down.
PRB	CADH*	Individual Chamber Exhaust Pressure U/L Setting	5.5	KPa	---	5.5	
PRB	CADH*	Individual Chamber Exhaust Pressure U/L Setting	3.9	KPa	---	3.9	
PRB	CADH*	Cool Arm Guide Pin Upper Surface ~ The End of 3-Pin/ Undersurface of Wafer	3.0	mm	1.5 or More	1.5 or More	Cool Arm is In and 3-Pin is Up.
PRB	CADH*	Hot Plate 3-Pin Hole ~ 3-Pin(Up)	2.0	mm	0.95 or More (No contact with a tool)	0.95 or More (No contact with a tool)	3-pin is Up. (No Temp. Rising)
PRB	CADH*	Hot Plate 3-Pin Hole ~ 3-Pin(Down)	2.0	mm	0.95 or More (No contact with a tool)	0.95 or More (No contact with a tool)	3-pin is Down. (No Temp. Rising)
PRB	CADH*	Cool Arm 3-Pin Slit ~ 3-Pin	2.0	mm	1.0 or More (No contact with a tool)	1.0 or More (No contact with a tool)	Cool Arm is In and 3-Pin is Up.
PRB	CADH*	Cool Arm Center ~ HP Plate Center: Centering	0.0	mm	-0.33 ~ 0.33	0.0±0.33	Make Sure that HP Center and Cool Arm Center are Aligned when Cool Arm is In while the Motor is Activated and the Sensors are Enabled.

* N/A for no CADH tool TBFna/TBFlt/TBFcn

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SCPL

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	SCPL	Plate Vac.(w/ Wafer)	1.5	KPa	1.4 ~ 1.6	1.5±0.2/-0.1	Setting is positive value representing differential pressure on the plate. Set by using touch wafers on all SCPL in the deck at the same time
PRB	SCPL	Plate Vac. U/L Setting	5.0	KPa	---	5.0	
PRB	SCPL	Plate Vac. L/L Setting	0.5	KPa	---	0.5	
PRB	SCPL	Plate Gap Pin	0.05	mm	0.045 ~ 0.05	0.05+0/-0.005	
PRB	SCPL	Plate Pull/Push Pin	0.5	mm	0.4 ~ 0.7	0.5+0.2/-0.1	

CPHP

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	CPHP	OVEN Module(R) EXH.(E10B)	170	Pa	165 ~ 175	170±5	
PRB	CPHP	OVEN Module(R) EXH. U/L Setting (E10B)	180	Pa	---	180	
PRB	CPHP	OVEN Module(R) EXH. L/L Setting (E10B)	150	Pa	---	150	
PRB	CPHP	CPHP Chamber (R) EXH. (E9B)	120	Pa	100 ~ 140	---	Set by pressure and setting for Individual Chamber exhausts. DO NOT EXCEED TARGET CHAMBER EXH SETTING
PRB	CPHP	CPHP Chamber (R) EXH U/L Setting (E9B)	155	Pa	---	---	
PRB	CPHP	CPHP Chamber (R) EXH L/L Setting (E9B)	85	Pa	---	---	
PRB	CPHP	CPHP Chamber (L) EXH. (E9A)	120	Pa	100 ~ 140	---	
PRB	CPHP	CPHP Chamber (L) EXH U/L Setting (E9A)	155	Pa	---	---	
PRB	CPHP	CPHP Chamber (L) EXH L/L Setting (E9A)	85	Pa	---	---	
PRB	CPHP	Individual Chamber Exhaust flowrate	9.4 (4.0L/min)	Pa	7.4 ~ 11.3 (3.5 ~ 4.5L/min)	9.4±1.0 (4.0L/min)	
PRB	CPHP	Individual Chamber Exhaust flowrate U/L Setting	11.3 (4.5L/min)	Pa	---	11.3	
PRB	CPHP	Individual Chamber Exhaust flowrate L/L Setting	7.4 (3.5L/min)	Pa	---	7.4	
PRB	CPHP	HP Level	0.0	degree	-0.1 ~ 0.1	0.0±0.10	
PRB	CPHP	3-Pin Level	0.0	degree	-0.05 ~ 0.05	0.0±0.05	Against HP Level
PRB	CPHP	Cool Arm Guide Pin Upper Surface ~ The End of 3-Pin/ Undersurface of Wafer	3.0	mm	1.5 or More	1.5 or More	Cool Arm is In and 3-Pin is Up.
PRB	CPHP	HP Surface ~ The End of 3-Pin(Up)	16.0	mm	16.0 ~ 17.0	16.0+1/-0	3-Pin is Up, For All Pins of 3-Pin.
PRB	CPHP	HP Surface ~ The End of 3-Pin(Down)	1.0	mm	0.5 or More	0.5 or More	3-Pin is Down, For All Pins of 3-Pin.
PRB	CPHP	Module Base Upper Surface ~ Cool Arm Upper Surface	78	mm	78.20 ~ 77.55	78.0+0.20/-0.45	Cool Arm is Out.
PRB	CPHP	HP Gap Pin	0.1	mm	0.092 ~ 0.108	0.1±0.008	
PRB	CPHP	Cool Arm Gap Pin	0.25	mm	0.245 ~ 0.275	-0.005/0.025	
PRB	CPHP	Chamber (L/R) Purge flowrate	4.0	L/min	3.8 ~ 4.2	4.0±0.2	
PRB	CPHP	Chamber (L/R) Purge flowrate U/L Setting	4.5	L/min	---	4.5	
PRB	CPHP	Chamber (L/R) Purge flowrate L/L Setting	3.5	L/min	---	3.5	
PRB	CPHP	Chamber-L/R OPEN / CLOSED	0.7	sec	0.6 ~ 0.8	0.7±0.1	L/R must match within 0.1s

ICPL/RSMC

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
IFB	ICPL/RSMC	Plate Vac.(w/ Wafer)	1.5	KPa	1.4 ~ 1.6	1.5±0.1	Setting is positive value representing differential pressure on the plate. Set by using touch wafers on all ICPL/RSMC at the same time
IFB	ICPL/ RSMC	Plate Vac. U/L Setting	5.0	KPa	---	5.0	
IFB	ICPL/ RSMC	Plate Vac. L/L Setting	0.5	KPa	---	0.5	
IFB	ICPL/ RSMC	Plate Gap Pin	0.05	mm	0.045 ~ 0.05	0.05+0/-0.005	
IFB	ICPL/ RSMC	Plate Pull/Push Pin	0.50	mm	0.4 ~ 0.7	0.5+0.2/-0.1	
IFB	ICPL/ RSMC	CP Surface ~ The End of 3-Pin(Up)	19.0	mm	18.5 ~ 19.5	19.0±0.5	3-Pin is Up, For All Pins of 3-Pin.
IFB	ICPL/ RSMC	CP Surface ~ The End of 3-Pin(Down)	1.0	mm	0.5 ~ 1.5	1.0±0.5	3-Pin is Down, For All Pins of 3-Pin.
IFB	ICPL/ RSMC	Plate Level	0.0	degree	-0.05 ~ 0.05	0.0±0.05	
IFB	ICPL/ RSMC	3-Pin Level	0.0	degree	-0.05 ~ 0.05	0.0±0.05	

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CXHN (pg 1 of 2)

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	CXHN	Gate shutter X-axis OPEN	0.2	sec	±0.1 (st=5mm)	←	* Cylinder air tube φ2 specification equipment: Wait for 7 seconds after one stroke before performing the next operation. (Do not make adjustment during the continuous motion of moving up/down the cylinder.)
PRB	CXHN	Gate shutter X-axis CLOSE	0.4	sec	±0.1 (st=5mm)	←	
PRB	CXHN	Gate shutter Z-axis OPEN	1.4	sec	±0.1 (st=68mm)	←	
PRB	CXHN	Gate shutter Z-axis CLOSE	1.4	sec	±0.1 (st=68mm)	←	
PRB	CXHN	N2 purge pressure gauge setting (primary)	0.5	MPa	+0.05/0	←	
PRB	CXHN	N2 purge pressure gauge setting (inside the electrical device)	0.3	MPa	+0.05/0	←	
PRB	CXHN	HP Level	0.0	degree	±0.10	←	Measure the level with a digital level.
PRB	CXHN	Level when the 3-pin is UP	0.0	degree	±0.05 (against HP level)	←	Use a digital level that does not bend 3-pin due to the weight of the digital level.
PRB	CXHN	HT plate surface <=> The end of 3-pin (When 3-pin is UP)	16.0	mm	-0/+1	←	
PRB	CXHN	HT plate surface <=> The end of 3-pin (When 3-pin is DOWN)	1.0	mm	(0.5≦)	←	3-pin does not protrude through the surface of HP plate.
PRB	CXHN	Hot plate 3-pin hole <=> 3-pin (When 3-pin is UP)	2	mm	0.95≤ No contact with a tool	←	3-pin hole dia. φ7
PRB	CXHN	Hot plate 3-pin hole <=> 3-pin (When 3-pin is DOWN)	2	mm		←	3-pin hole dia. φ7
PRB	CXHN	3-pin	355 to 406 (Minimum value)	Hz	Max - Min ≤ 114 Hz	←	Check that the tension range of the four points measured using the method described in the left column is: Span: 60 mm, width: 4 mm, mass: 1.3 g/m
PRB	CXHN	Gate shutter Z-axis	12.2 or less	N		←	
PRB	CXHN	Chamber N2 purge flowrate	30	L/min	±0.3	30±0.3	
PRB	CXHN	Chamber N2 purge flowrate U/L Setting	32	L/min	-	←	
PRB	CXHN	Chamber N2 purge flowrate L/L Setting	28	L/min	-	←	
PRB	CXHN	Cool plate N2 purge flowrate	90	L/min	±1	90±1	
PRB	CXHN	Cool plate N2 purge flowrate U/L Setting	96	L/min	-	←	
PRB	CXHN	Cool plate N2 purge flowrate L/L Setting	84	L/min	-	←	
PRB	CXHN	Module exhaust at room temperature (at oxygen concentration measurement)	42.3	Pa	±5	-	
PRB	CXHN	Module exhaust when temperature rising	49	Pa	±5	49±5	
PRB	CXHN	Module exhaust when temperature rising U/L Setting	63.5	Pa	-	←	
PRB	CXHN	Module exhaust when temperature rising L/L Setting	37.5	Pa	-	←	
PRB	CXHN	Chamber exhaust at room temperature (at oxygen concentration measurement)	3.6	Pa	±1	-	
PRB	CXHN	Chamber exhaust when temperature rising (when temperature is fixed)	450 to 475 degrees C: 9.0 475.1 to 525 degrees C: 9.5 525.1 to 575 degrees C: 10.5 575.1 to 600 degrees C: 11.5	Pa	±1	450 to 475 degrees C: 9.0 475.1 to 525 degrees C: 9.5 525.1 to 575 degrees C: 10.5 575.1 to 600 degrees C: 11.5	450 to 475 degrees C: Hi 12.0 / Lo 6.0 475.1 to 525 degrees C: Hi 13.0 / Lo 6.5 525.1 to 575 degrees C: Hi 14.5 / Lo 7.0 575.1 to 600 degrees C: Hi 16.0 / Lo 8.0
PRB	CXHN	Chamber exhaust when temperature rising (when temperature is fixed) U/L Setting	450 to 475 degrees C: 12.0 475.1 to 525 degrees C: 13.0 525.1 to 575 degrees C: 14.5 575.1 to 600 degrees C: 16.0	Pa	-	450 to 475 degrees C: 12.0 475.1 to 525 degrees C: 13.0 525.1 to 575 degrees C: 14.5 575.1 to 600 degrees C: 16.0	
PRB	CXHN	Chamber exhaust when temperature rising (when temperature is fixed) L/L Setting	450 to 475 degrees C: 6.0 475.1 to 525 degrees C: 6.5 525.1 to 575 degrees C: 7.0 575.1 to 600 degrees C: 8.0	Pa	-	450 to 475 degrees C: 6.0 475.1 to 525 degrees C: 6.5 525.1 to 575 degrees C: 7.0 575.1 to 600 degrees C: 8.0	

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CXHN (pg 2 of 2)

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	CXHN	Chamber exhaust when temperature rising (when temperature is not fixed)	450 to 600 degrees C: 10.0	Pa	±1	10±1	This value is not used because temperature change was unexpected for mass-production.
PRB	CXHN	Chamber exhaust when temperature rising (when temperature is not fixed) U/L Setting	450 to 600 degrees C: 12	Pa	-	←	
PRB	CXHN	Chamber exhaust when temperature rising (when temperature is not fixed) L/L Setting	450 to 600 degrees C: 8	Pa	-	←	
PRB	CXHN	Chamber EXH (E27B : D6)	25.0	Pa	-	←	Keep Fully Open. Adjust to match CXHN Chamber Exh Fixed (10Pa). Set by pressure and setting for individual chamber exhaust.
PRB	CXHN	Chamber EXH U/L Setting(E27B : D6)	40.0	Pa	-	←	
PRB	CXHN	Chamber EXH L/L Setting(E27B : D6)	10.0	Pa	-	←	
PRB	CXHN	Chamber EXH (E27A : D6)	25.0	Pa	-	←	
PRB	CXHN	Chamber EXH U/L Setting(E27A : D6)	40.0	Pa	-	←	
PRB	CXHN	Chamber EXH L/L Setting(E27A : D6)	10.0	Pa	-	←	
PRB	CXHN	Plate VAC adjustment at room temperature (at oxygen concentration measurement)	-0.75	KPa	±0.05	-0.75±0.05	(Procedure) (1) Check the conditions described in the left. (2) Set the target module to maintenance mode. Turn on the plate vacuum using the sub-operating panel. (3) Vacuum without a wafer to perform rough adjustment.
PRB	CXHN	Plate VAC adjustment when temperature rising	-2.9	KPa	±0.1	-2.9±0.1	
PRB	CXHN	Plate VAC adjustment when temperature rising U/L Setting	-1.7	KPa	-	←	
PRB	CXHN	Plate VAC adjustment when temperature rising L/L Setting	-3.9	KPa	-	←	
PRB	CXHN	Cool plate cooling water	0.6L/min per 1 Cool Plate	L/min	0.6L/min per 1 Cool Plate	0.6L/min per 1 Cool Plate	Refer to System Adjustment Standard (document No.: 5095-D00259)
PRB	CXHN	Middle plate cooling water	0.6L/min per 1 Middle Plate	L/min	0.6L/min per 1 Middle Plate	0.6L/min per 1 Middle Plate	Refer to System Adjustment Standard (document No.: 5095-D00259)
PRB	CXHN	Sub arm fork undersurface <=> HP W.guide	3.7	mm	2.2 or more	←	
PRB	CXHN	Sub arm block undersurface <=> CP W.guide	3.0	mm	1.5 or more	←	
PRB	CXHN	Sub arm guide pin upper surface <=> The end of HP 3-pin/ undersurface of wafer	5.0	mm	3.5 or more	←	
PRB	CXHN	Sub arm guide pin upper surface <=> The end of CP 3-pin/ undersurface of wafer	3.0	mm	1.5 or more	←	
PRB	CXHN	Hot plate surface <=> Support ring flange	0.5	mm	0.3 or more	←	
PRB	CXHN	Cool plate surface <=> The end of 3-pin (When 3-pin is UP)	17.0	mm	-0/+1	←	
PRB	CXHN	Cool plate 3-pin hole <=> 3-pin (When CP 3-pin is UP)	2	mm	0.95≤ No contact with a tool	←	3-pin hole dia. φ7
PRB	CXHN	Cool plate 3-pin hole <=> 3-pin (When CP 3-pin is DOWN)	2	mm		←	3-pin hole dia. φ7
PRB	CXHN	Cool plate center <=> HP plate center: Centering	0.0	mm	±0.33	←	The stroke between HP center and cool arm center: 370mm
PRB	CXHN	Module base upper surface <=> HP upper surface	198.5	mm	±0.35	←	With reference to the upper surface of module base, make a measurement.
PRB	CXHN	HP plate gap pin	0.1	mm	Refer to Remarks	←	±0.008 (in consideration of measurement difference: 5um)
PRB	CXHN	Cool plate gap pin	0.5	mm	Refer to Remarks	←	±0.015 (in consideration of measurement difference: 5um)
PRB	CXHN	Sub arm	69.1	Hz	67.5 to 70.7	←	
PRB	CXHN	Oxygen concentration on HP side at the end of pre-standby (105 sec.)	100	ppm	≤100	←	

7. Oven

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CVIP (pg 1 of 2)

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	CVIP	CHAMBER(L) UP	0.7	sec	±0.1	←	* Cylinder air tube φ2 specification equipment: Wait for 7 seconds after one stroke before performing the next operation. (Do not make adjustment during the continuous motion of moving up/down the cylinder.)
PRB	CVIP	CHAMBER(R) UP	0.7	sec	±0.1	←	
PRB	CVIP	CHAMBER(L) DOWN	0.7	sec	±0.1	←	
PRB	CVIP	CHAMBER(R) DOWN	0.7	sec	±0.1	←	
PRB	CVIP	Chamber purge	6.0	L/min	±0.2	←	
PRB	CVIP	Chamber purge U/L	6.5	L/min	-	←	
PRB	CVIP	Chamber purge L/L	5.5	L/min	-	←	
PRB	CVIP	Chamber exhaust (Center) ON Chamber temperature: 300 to 350 degrees C	26	Pa	±2	26±2	Set by pressure and setting for individual chamber exhaust. (22±4L/min)
PRB	CVIP	Chamber exhaust (Center) ON U/L Setting Chamber temperature: 300 to 350 degrees C	32	Pa	-	←	
PRB	CVIP	Chamber exhaust (Center) ON L/L Setting Chamber temperature: 300 to 350 degrees C	20	Pa	-	←	
PRB	CVIP	Chamber exhaust (Center) OFF Chamber temperature: 300 to 350 degrees C	0	Pa	±2	0±2	
PRB	CVIP	Chamber exhaust (Periphery) Chamber temperature: 300 to 350 degrees C	26	Pa	±2	26±2	Set by pressure and setting for individual chamber exhaust. （15±3L/min）
PRB	CVIP	Chamber exhaust (Periphery) U/L Setting Chamber temperature: 300 to 350 degrees C	34	Pa	-	←	
PRB	CVIP	Chamber exhaust (Periphery) L/L Setting Chamber temperature: 300 to 350 degrees C	18	Pa	-	←	
PRB	CVIP	Local exhaust (E27B : D11)	10.0	Pa	±1	←	
PRB	CVIP	Local exhaust U/L Setting (E27B : D11)	15.0	Pa	-	←	
PRB	CVIP	Local exhaust L/L Setting (E27B : D11)	5.0	Pa	-	←	
PRB	CVIP	Local exhaust (E27B : D12)	11.0	Pa	±1	←	
PRB	CVIP	Local exhaust U/L Setting (E27B : D12)	16.0	Pa	-	←	
PRB	CVIP	Local exhaust L/L Setting (E27B : D12)	6.0	Pa	-	←	
PRB	CVIP	Local exhaust (E27B : D13)	12.0	Pa	±1	←	
PRB	CVIP	Local exhaust U/L Setting (E27B : D13)	17.0	Pa	-	←	
PRB	CVIP	Local exhaust L/L Setting (E27B : D13)	7.0	Pa	-	←	
PRB	CVIP	Local exhaust (E27B : D14)	13.0	Pa	±1	←	
PRB	CVIP	Local exhaust U/L Setting (E27B : D14)	18.0	Pa	-	←	
PRB	CVIP	Local exhaust L/L Setting (E27B : D14)	8.0	Pa	-	←	
PRB	CVIP	Local exhaust (E27B : D15)	14.0	Pa	±1	←	
PRB	CVIP	Local exhaust U/L Setting (E27B : D15)	19.0	Pa	-	←	
PRB	CVIP	Local exhaust L/L Setting (E27B : D15)	9.0	Pa	-	←	
PRB	CVIP	Local exhaust (E27B : D16)	15.0	Pa	±1	←	PBR402 not applicable
PRB	CVIP	Local exhaust U/L Setting (E27B : D16)	20.0	Pa	-	←	PBR402 not applicable
PRB	CVIP	Local exhaust L/L Setting (E27B : D16)	10.0	Pa	-	←	PBR402 not applicable
PRB	CVIP	Oven Module EXH (E10B)	170	Pa	±5	170±5	
PRB	CVIP	Oven Module EXH U/L Setting (E10B)	180	Pa	-	←	
PRB	CVIP	Oven Module EXH L/L Setting (E10B)	150	Pa	-	←	
PRB	CVIP	Chamber EXH (E28B)	50	Pa	-	←	*Dependent on CVIP/CXHN Chamber Exh
PRB	CVIP	Chamber EXH U/L Setting (E28B)	65	Pa	-	←	
PRB	CVIP	Chamber EXH L/L Setting (E28B)	35	Pa	-	←	
PRB	CVIP	Local exhaust (E27A : D11)	10.0	Pa	±1	←	
PRB	CVIP	Local exhaust U/L Setting (E27A : D11)	15.0	Pa	-	←	
PRB	CVIP	Local exhaust L/L Setting (E27A : D11)	5.0	Pa	-	←	
PRB	CVIP	Local exhaust (E27A : D12)	11.0	Pa	±1	←	
PRB	CVIP	Local exhaust U/L Setting (E27A : D12)	16.0	Pa	-	←	
PRB	CVIP	Local exhaust L/L Setting (E27A : D12)	6.0	Pa	-	←	
PRB	CVIP	Local exhaust (E27A : D13)	12.0	Pa	±1	←	
PRB	CVIP	Local exhaust U/L Setting (E27A : D13)	17.0	Pa	-	←	
PRB	CVIP	Local exhaust L/L Setting (E27A : D13)	7.0	Pa	-	←	
PRB	CVIP	Local exhaust (E27A : D14)	13.0	Pa	±1	←	
PRB	CVIP	Local exhaust U/L Setting (E27A : D14)	18.0	Pa	-	←	
PRB	CVIP	Local exhaust L/L Setting (E27A : D14)	8.0	Pa	-	←	
PRB	CVIP	Local exhaust (E27A : D15)	14.0	Pa	±1	←	
PRB	CVIP	Local exhaust U/L Setting (E27A : D15)	19.0	Pa	-	←	
PRB	CVIP	Local exhaust L/L Setting (E27A : D15)	9.0	Pa	-	←	
PRB	CVIP	Local exhaust (E27A : D16)	15.0	Pa	±1	←	PBR402 not applicable
PRB	CVIP	Local exhaust U/L Setting (E27A : D16)	20.0	Pa	-	←	PBR402 not applicable
PRB	CVIP	Local exhaust L/L Setting (E27A : D16)	10.0	Pa	-	←	PBR402 not applicable

7. Oven

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CVIP (pg 2 of 2)

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	CVIP	Oven Module EXH (E10A)	170	Pa	±5	170±5	
PRB	CVIP	Oven Module EXH U/L Setting (E10A)	180	Pa	-	←	
PRB	CVIP	Oven Module EXH L/L Setting (E10A)	150	Pa	-	←	
PRB	CVIP	Chamber EXH (E28A)	50	Pa	-	←	*Dependent on CVIP/CXHN Chamber Exh
PRB	CVIP	Chamber EXH U/L Setting (E28A)	65	Pa	-	←	
PRB	CVIP	Chamber EXH L/L Setting (E28A)	35	Pa	-	←	
PRB	CVIP	Cool arm cooling water	0.6L/min per 1 Cool arm	L/min	0.6L/min per 1 Cool arm	0.6L/min per 1 Cool arm	Refer to System Adjustment Standard (document No.: 5095-D00259)
PRB	CVIP	HP Level	0.0	degree	±0.10		Measure the level with a digital level.
PRB	CVIP	Level when the 3-pin is UP	0.0	degree	±0.05 (against HP level)		Use a digital level that does not bend 3-pin due to the weight of the digital level.
PRB	CVIP	Cool arm undersurface <=> HP W.guide	3.0	mm	1.5≥		Measure the clearance with a thickness gauge.
PRB	CVIP	Hot plate surface <=> The end of 3-pin (When 3-pin is UP)	18.0	mm	-0/+1		
PRB	CVIP	Hot plate surface <=> The end of 3-pin (When 3-pin is MIDDLE)	4.0	mm	-0/+1		
PRB	CVIP	Hot plate surface <=> The end of 3-pin (When 3-pin is DOWN)	1.0	mm	Refer to Remarks		3-pin does not protrude through the surface of HP plate. (0.5 ≤)
PRB	CVIP	Cool arm guide pin upper surface <=> The end of 3-pin/ undersurface of wafer	3.0	mm	1.5≤		
PRB	CVIP	Module base upper surface <=> Cool arm upper surface	217.5	mm	±0.45		With reference to the upper surface of hot plate, cool arm height is measured at 5 points with a height gauge when cool arm is IN and OUT.
PRB	CVIP	Hot plate periphery <=> Clearance between ring (2) and support	1.3	mm	±0.1		Whole circumference consistency is 0.1 or less.
PRB	CVIP	Support ring periphery upper surface <=> Chamber undersurface (When chamber is UP)	18	mm	15≤		
PRB	CVIP	Support ring periphery upper surface <=> Chamber undersurface (When chamber is DOWN)	0.5	mm	±0.2		Measure the clearance with a thickness gauge.
PRB	CVIP	Hot plate 3-pin hole <=> 3-pin (When 3-pin is UP)	2	mm	0.95≤ No contact with a tool		3-pin hole dia. φ7: KCR hot plate (SiC)
PRB	CVIP	Hot plate 3-pin hole <=> 3-pin (When 3-pin is DOWN)	2	mm			3-pin hole dia. φ7: KCR hot plate (SiC)
PRB	CVIP	Cool arm 3-pin slit <=> 3-pin	2.0	mm	1.0≤ No contact with a tool		Like LITHIUS, use a tool to check a clearance.
PRB	CVIP	Cool arm center <=> Hot plate center: Centering	0.0	mm	±0.33		The stroke between HP center and cool arm center: 370mm
PRB	CVIP	Module base level	0.0	degree	±0.10		
PRB	CVIP	Module base upper surface <=> HP upper surface	205.5	mm	±0.25		With reference to the upper surface of module base, make a measurement.
PRB	CVIP	Motor bracket <=> Pulley	1.0	mm	1.0 to 1.1		Insert a 1mm-thickness gauge into the space between bracket and the end of pulley, and secure the pulley. Make sure that a 1.1mm-thickness gauge cannot enter the clearance.
PRB	CVIP	Cooling water pipe IN <=> Cooling water pipe OUT	1.0	mm	1.0 or more		Measure against cooling water pipe crack
PRB	CVIP	Hot plate gap pin	0.1	mm	±0.008 (in consider		Manufacturer specification: 0.1±0.003 mm
PRB	CVIP	Cool arm gap pin	0.5	mm	±0.015 (in consider		
PRB	CVIP	Cool arm	69.1	Hz	67.5 to 70.7		
PRB	CVIP	3-pin	355 to 406 (Minimum value)	Hz	Max - Min ≤ 114 Hz		Check that the tension range of the four points measured using the method described in the left column is:
PRB	CVIP	Cool arm	0.0	mm	±1.00		Measure the cool arm distortion.
PRB	CVIP	Back side of cool arm <=> Top surface of alignment pin for automatic position adjustment	2.0	mm	0.5≤		Measure the cool arm distortion.

8. Arm

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HCRA-F

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
HCSB	HCRA-F	Fork Vac.	-75	KPa	-80 ~ -75	-75+0/-5	Static Pressure
HCSB	HCRA-F	Fork VAC. (U/L Setting)	-10	KPa	---	-10	
HCSB	HCRA-F	Fork VAC. (L/L Setting)	-55	KPa	---	-55	
HCSB	HCRA-F	LIS Aluminum Fork Edge	85000	Pixel	85000 or More	85000 or More	
HCSB	HCRA-F	LIS Ceramic Fork Edge	100000	Pixel	100000 or More	100000 or More	
HCSB	HCRA-F	LIS Standard Wafer Edge	47000	Pixel	37000 ~ 57000	47000±10000	

HCRA-B

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
HCSB	HCRA-B	Fork Vac.	-75	KPa	-80 ~ -75	-75+0/-5	Static Pressure
HCSB	HCRA-B	Fork VAC. (U/L Setting)	-10	KPa	---	-10	
HCSB	HCRA-B	Fork VAC. (L/L Setting)	-55	KPa	---	-55	
HCSB	HCRA-B	LIS Aluminum Fork Edge	85000	Pixel	85000 or More	85000 or More	
HCSB	HCRA-B	LIS Ceramic Fork Edge	100000	Pixel	100000 or More	100000 or More	
HCSB	HCRA-B	LIS Standard Wafer Edge	47000	Pixel	37000 ~ 57000	47000±10000	

PRA

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
PRB	PRA	Fork Vac.	-75	KPa	-80 ~ -75	-75+0/-5	Static Pressure
PRB	PRA	Fork VAC. (U/L Setting)	-10	KPa	---	-10	
PRB	PRA	Fork VAC. (L/L Setting)	-55	KPa	---	-55	
PRB	PRA	LIS Aluminum Fork Edge	85000	Pixel	85000 or More	85000 or More	
PRB	PRA	LIS Standard Wafer Edge	47000	Pixel	37000 ~ 57000	47000±10000	

IRAM-F

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
IFB	IFAM-F	Fork Vac.	-75	KPa	-80 ~ -75	-75+0/-5	Static Pressure
IFB	IFAM-F	Fork VAC. (U/L Setting)	-10	KPa	---	-10	
IFB	IFAM-F	Fork VAC. (L/L Setting)	-55	KPa	---	-55	
IFB	IFAM-F	LIS Ceramic Fork Edge	100000	Pixel	100000 or More	100000 or More	
IFB	IFAM-F	LIS Standard Wafer Edge	47000	Pixel	37000 ~ 57000	47000±10000	

IRAM-B

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
Tools except PBR t	IFAM-B	Fork Vac.	-75	KPa	-80 ~ -75	-75+0/-5	Static Pressure
IFB	IFAM-B	Fork VAC. (U/L Setting)	-10	KPa	---	-10	
IFB	IFAM-B	Fork VAC. (L/L Setting)	-55	KPa	---	-55	
IFB	IFAM-B	LIS Ceramic Fork Edge	100000	Pixel	100000 or More	100000 or More	
IFB	IFAM-B	LIS Standard Wafer Edge	47000	Pixel	37000 ~ 57000	47000±10000	

IRAI

Block	Module	Description of Setting	Tool Setting	Unit	Tolerance	TEL Std.	Remarks
IFB	IRAI	Fork Vac.	-75	KPa	-80 ~ -75	-75+0/-5	Static Pressure
IFB	IRAI	Fork VAC. (U/L Setting)	-10	KPa	---	-10	
IFB	IRAI	Fork VAC. (L/L Setting)	-55	KPa	---	-55	
IFB	IRAI	LIS Ceramic Fork Edge	100000	Pixel	100000 or More	100000 or More	
IFB	IRAI	LIS Standard Wafer Edge	47000	Pixel	37000 ~ 57000	47000±10000	

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9. Sensor Setting

DP100 Sensor

Block	Module	Object	Out1	Out2	I/O	N.oN.c	SPED	CLOR	Unit	0-Adj.	Lo-1	Hi-1	Key Lock
PRB	SYSTEM	Module Drive(Source)	W.CMP	OFF	A.out	N.o	5000	R-ON	MPa	Required	LL	UL	Required
IFB	SYSTEM	Module Drive(Source)	W.CMP	OFF	A.out	N.o	5000	R-ON	MPa	Required	-	-	Required
PRB	COT	COT Chuck Vac.	W.CMP	OFF	A.out	N.o	2.5	R-ON	KPa	Required	LL	UL	Required
PRB	BCT	BCT Chuck Vac.	W.CMP	OFF	A.out	N.o	2.5	R-ON	KPa	Required	LL	UL	Required
PRB	DEV	DEV Chuck Vac.	W.CMP	OFF	A.out	N.o	2.5	R-ON	KPa	Required	LL	UL	Required
PRB	NTD	NTD Chuck Vac.	W.CMP	OFF	A.out	N.o	2.5	R-ON	KPa	Required	LL	UL	Required
PRB	SRS	SRS Chuck Vac.	W.CMP	OFF	A.out	N.o	2.5	R-ON	KPa	Required	LL	UL	Required
PRB	PIR	PIR Chuck Vac.	W.CMP	OFF	A.out	N.o	2.5	R-ON	KPa	Required	LL	UL	Required
PRB	ACRD	Resist Pump Purge	W.CMP	OFF	A.out	N.o	5000	R-ON	KPa	Required	LL	UL	Required
PRB	AMC	AMC Purge	W.CMP	OFF	A.out	N.o	5000	R-ON	KPa	Required	LL	UL	Required
PRB	DEV	ADR N2	W.CMP	OFF	A.out	N.o	2.5	R-ON	KPa	Required	LL	UL	Required
Eternal	COT/DEV Cabinet	PCS Pump Vac.	W.CMP	OFF	A.out	N.o	2.5	R-ON	KPa	Required	LL	UL	Required
All Block	All Arm	Fork Vac.	HYS	OFF	A.out	N.o	2.5	G-ON	KPa	Required	LL	UL	Required
All Block	All Arm(Source)	Fork Vac.	Easy	OFF	A.out	N.c	2.5	R-ON	KPa	Required	LL	-	Required
HCSB	Rotation Loader	Stage Vac.	W.CMP	OFF	-	N.o	2.5	R-ON	KPa	Required	LL	UL	Required
IFB	BST	BST Chuck Vac.	W.CMP	OFF	A.out	N.o	2.5	R-ON	KPa	Required	LL	UL	Required
IFB	BST	Local Exh.	W.CMP	OFF	A.out	N.o	2.5	R-ON	KPa	Required	LL	UL	Required
IFB	BST	Air Knife	W.CMP	OFF	A.out	N.o	2.5	R-ON	KPa	Required	LL	UL	Required
Eternal	COT/DEV Cabinet	IFF-S PCS Pump Vac.	W.CMP	OFF	A.out	N.o	2.5	R-ON	KPa	Required	-99.0	-74.0	Required

GC30 Sensor

Block	Module	Object	0-Adj.	CnP	Uni	d-P	D-L	D-H	Fil	A-L	A-H
			A-1	b-1	on1	off1	A-2	b-2	on2	off2	LoP
FEX	SYSTEM	FEX EXT Chemical Exh.	Required	Hys	Pa	-	-	-	F-3	0	100
			LL	0	0	0	0	0	0	0	0
HCSB	SYSTEM	HCSB FEX EXT Chemical Exh.	Required	Hys	Pa	-	-	-	F-3	0	100
			LL	0	0	0	0	0	0	0	0
HCSB	SYSTEM	HCSB Loader Chemical Exh.	Required	Hys	Pa	-	-	-	F-3	0	100
			LL	0	0	0	0	0	0	0	0
HCSB	SYSTEM	HMDS Chemical Exh.	Required	Hys	Pa	-	-	-	F-3	0	100
			LL	0	0	0	0	0	0	0	0
HCSB	SYSTEM	FFU Wind Pressure	Required	Hys	Etc	0	0	1000	F-5	0	100
			LL	0	0	0	0	0	0	0	0
HCSB	SCPL	Plate Vac.	Required	Win	KPa	0	0	0	F-2	0	100
			LL	UL	0	0	0	0	0	0	0
Tools except PBR t	SYSTEM	SPIN Chemical Exh.	Required	Hys	Pa	-	-	-	F-3	0	100
			LL	0	0	0	0	0	0	0	0
PRB	SYSTEM	SPIN Cup Exh.(COT)	Required	Hys	Pa	-	-	-	F-2	0	100
			UL	-1	0	0	LL	0	0	0	0
PRB	SYSTEM	SPIN Cup Exh.(BCT)	Required	Hys	Pa	-	-	-	F-2	0	100
			UL	-1	0	0	LL	0	0	0	0
PRB	SYSTEM	SPIN Cup Exh.(DEV)	Required	Hys	Pa	-	-	-	F-2	0	100
			UL	-1	0	0	LL	0	0	0	0
PRB	SYSTEM	SPIN Cup Exh.(NTD)	Required	Hys	Pa	-	-	-	F-2	0	100
			UL	-1	0	0	LL	0	0	0	0
PRB	SYSTEM	FFU Wind Pressure	Required	Hys	Etc	0	0	1000	F-5	0	100
			LL	0	0	0	0	0	0	0	0
PRB	CGCH	Chamber Source Exh.	Required	Win	Pa	-	-	-	F-3	0	100
			LL	UL	0	0	0	0	0	0	0
PRB	CADH	Chamber Source Exh.	Required	Win	Pa	-	-	-	F-3	0	100
			LL	UL	0	0	0	0	0	0	0
PRB	CGCH	CGCH Individual Exh (Ring shutter)	Required	Win	Pa	-	-	-	F-3	0	100
			LL	UL	0	0	0	0	0	0	0
PRB	CADH	CADH Indibidual Exh. (Chamber)	Required	Win	Pa	-	-	-	F-2	0	100
			LL	UL	0	0	0	0	0	0	0
PRB	OVEN	Oven Module Source Exh.	Required	Win	Pa	-	-	-	F-3	0	100
			LL	UL	0	0	0	0	0	0	0
PRB	CPHP	CPHP Indibidual Exh. (Chamber)	Required	Win	Pa	-	-	-	F-3	0	100
			LL	UL	0	0	0	0	0	0	0
IFB	ICPL	Plate Vac.	Required	Win	KPa	0	0	0	F-2	0	100
			LL	UL	0	0	0	0	0	0	0
IFB	BST	SPIN Cup Exh.(BST)	Required	Hys	Pa	-	-	-	F-3	0	100
			UL	-1	0	0	LL	0	0	0	0
IFB	SYSTEM	SPIN Cup Exh.(SRS)	Required	Hys	Pa	-	-	-	F-3	0	100
			UL	-1	0	0	LL	0	0	0	0
IFB	SYSTEM	SPIN Cup Exh.(PIR)	Required	Hys	Pa	-	-	-	F-3	0	100
			UL	-1	0	0	LL	0	0	0	0
IFB	SYSTEM	FFU Wind Pressure	Required	Hys	Etc	0	0	1000	F-5	0	100
			LL	0	0	0	0	0	0	0	0

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9. Sensor Setting

GC30 Sensor

External	COT Cabnet	HMDS Chemical Source Exh.	Required	Hys	Pa	-	-	-	F-2	0	100
			LL	0	0	0	0	0	0	0	0
External	COT Cabnet	Solvent Source Exh.	Required	Hys	Pa	-	-	-	F-3	0	0
			LL	0	0	0	0	0	0	0	0
External	DEV Cabnet	Solvent Source Exh.	Required	Hys	Pa	-	-	-	F-3	0	0
			LL	0	0	0	0	0	0	0	0

Photo Sensor

Block	Module	Object	SENS	MODE
FEX	SYSTEM	Bottle RS Sensor	HIGH	D-ON
HCSB	SYSTEM	Bottle RS Sensor	HIGH	D-ON
PRB	SYSTEM	Bottle RS Sensor	HIGH	D-ON

E3X-MD36T-T Sensor

Block	Module	Object	Power tune	Key Lock	tEch	0-oP	1-Fn	2-tF	3-ot	4-md	PL	5-dP	6-ru
PRB	SYSTEM	RSV Tank(L,LL)	Required	Required	-	D-ON	Stnd	on-d	2out	PrUn	2000	Income Light Amount/Threshold Value=1600	Unspecified
PRB	SYSTEM	RSV Tank(H)	Required	Required	-	L-ON	Stnd	oFFd	2out	PrUn	2000	Income Light Amount/Threshold Value=1700	Unspecified

FSM2-NVF10* Sensor

Block	Module	Object	Unit / 0-Adj. / Key Lock	CH1 Output Mode / CH2 Output Mode	CH1 High	CH1 Low	CH2 High	CH2 Low	Flow rate direction setting	Auto-reference function	Response time setting	Indication speed setting	Sub-screen setting	Indication color setting function	Hysteresis setting	Flow rate unit setting	Eco mode setting	Reset setting
PRB	CADH	HMDS Vapor Flow Rate	L/min	┐┌└	4.0	4.0			→	out	SP-4	250	FLO	grEn	|	Anr	OFF	OFF
			Required															
			Required	- - - -	-	-												
PRB	CADH	HMDS N2 Purge Flow Rate	L/min	- - - -	-	-			→	out	SP-4	250	FLO	grEn	|	Anr	OFF	OFF
			Required															
			Required	- - - -	-	-												
PRB	CADH	Ringe Purge Flow Rate	L/min	- - - -	UL	LL			→	out	SP-4	250	FLO	grEn	|	Anr	OFF	OFF
			Required															
			Required	- - - -	-	-												
PRB	CPHP	Chamber Purge Flow rate	L/min	_┌└_	UL	LL			→	out	SP-4	250	FLO	grEn	|	Anr	OFF	OFF
			Required															
			Required	- - - -	-	-												

AM-125A Sensor

Block	Module	Object	Comparator Data								
			S-Hi	S-Lo	H-Hi	H-Lo	L-Hi	L-Go	L-Lo	AL 1	AL2
PRB	System	HCSB Positive Pressure	10.00	0.10	0.00	0.00	N.O	N.O	N.C	Hi	Lo
			Condition Data								
			P.L	AYG	MAY	S.ud	bLnk	dL.t	b.UP	LCnE	trt	Pon
			PL0	200	32	1	oFF	cUt	oFF	cLr	0	oFF

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9. Sensor Setting

PSE310-M Sensor

Block	Module	Object	Indication color	Indication color output	Pressure range	OUT1 Operation mode	OUT1 output form	OUT2 Operation mode/Output form	Response time [ms]	P_1	P_2	H_1	P_3	P_4	H_2
IFB	BST	PAD Vac.	Sor	C1	in0	1 ᵁ_n	lno	-	1	LL	UL	0.1	-	-	-

PC-3 Sensor

Block	Module	Object	P_1	Col	rES	oPE	H	oUT
External	STHC	AIR Digital Pressure Gauge	0.3	Sog	2.0	HyS	0.05	no

PF3W30C-MT Sensor

Block	Module	Object	F0	F1					F3	F22	
			Range	oU1	1ot	P1	H 1	COL	rES	ANA	FrE
PRB	SYSTEM	PCW Flow Meter 40L/min	40	HYS	1_P	Setting Value	0	SoG	1	FLOW	OFF

WFK2 Sensor - BARC

Block	Module	Object	Output1: Analog_Flow			Ouput2: Switch_Flow1				
			Range	OR L/L	OR U/L	Mode	NO/NC	L/L	U/L	Hys.
External	STHC	TCW Flow Rate Line0 / Ch0 / HMDS	1-5V	0.00	4.00	Hys.	NO	---	0.40	0.00
External	STHC	TCW Flow Rate Line1 / Ch1 / BCT1+MF	1-5V	0.00	4.00	Hys.	NO	---	0.40	0.00
External	STHC	TCW Flow Rate Line2 / Ch2 / BCT2+MF	1-5V	0.00	4.00	Hys.	NO	---	0.40	0.00
External	STHC	TCW Flow Rate Line3 / Ch3 / Bypass	1-5V	0.0	20.0	Hys.	NO	---	1.6	0.0
External	STHC	TCW Flow Rate Line4 / Ch4-1 / CPL(BCT)	1-5V	0.0	50.0	Hys.	NO	---	4.0	0.0
External	STHC	TCW Flow Rate Line5 / Ch4-2 / Cool Arm	1-5V	0.0	20.0	Hys.	NO	---	1.6	0.0
External	STHC	TCW Flow Rate Line6 / Ch4-3 / Bypass	1-5V	0.0	20.0	Hys.	NO	---	1.6	0.0
External	STHC	TCW Flow Rate Line8 / Ch5-1 / Bypass	1-5V	0.0	50.0	Hys.	NO	---	4.0	0.0
External	STHC	TCW Flow Rate Line9 Ch5-2 / Bypass	1-5V	0.0	20.0	Hys.	NO	---	1.6	0.0

WFK2 Sensor - Imm/EUV

Block	Module	Object	Output1: Analog_Flow			Ouput2: Switch_Flow1				
			Range	OR L/L	OR U/L	Mode	NO/NC	L/L	U/L	Hys.
External	STHC	TCW Flow Rate Line0 / Ch0 / HMDS	1-5V	0.00	4.00	Hys.	NO	---	0.40	0.00
External	STHC	TCW Flow Rate Line1 / Ch1 / COT+MF	1-5V	0.00	4.00	Hys.	NO	---	0.40	0.00
External	STHC	TCW Flow Rate Line2 / Ch2 / ITC+MF	1-5V	0.00	4.00	Hys.	NO	---	0.40	0.00
External	STHC	TCW Flow Rate Line3 / Ch3 / ICPL	1-5V	0.0	20.0	Hys.	NO	---	1.6	0.0
External	STHC	TCW Flow Rate Line4 / Ch4-1 / CPL(COT)	1-5V	0.0	50.0	Hys.	NO	---	4.0	0.0
External	STHC	TCW Flow Rate Line5 / Ch4-2 / Cool Arm	1-5V	0.0	20.0	Hys.	NO	---	1.6	0.0
External	STHC	TCW Flow Rate Line6 / Ch4-3 / Imm=PIR/SRS,EUV=PIR	1-5V	0.00	4.00	Hys.	NO	---	0.40	0.00
External	STHC	TCW Flow Rate Line7 / Ch4-4 / Bypass	1-5V	0.00	4.00	Hys.	NO	---	0.40	0.00
External	STHC	TCW Flow Rate Line8 / Ch5-1 / CPL(DEV)	1-5V	0.0	20.0	Hys.	NO	---	1.6	0.0
External	STHC	TCW Flow Rate Line9 / Ch5-2 / DEV	1-5V	0.0	20.0	Hys.	NO	---	1.6	0.0
External	STHC	TCW Flow Rate Line10 / Ch5-3 / NTD	1-5V	0.0	20.0	Hys.	NO	---	1.6	0.0
External	STHC	TCW Flow Rate Line11 / Ch5-4 / MF(DEV)	1-5V	0.0	20.0	Hys.	NO	---	1.6	0.0
External	STHC	TCW Flow Rate Line12 / Ch5-5 / Bypass	1-5V	0.0	20.0	Hys.	NO	---	1.6	0.0

WFK2 Sensor - PBR

Block	Module	Object	Output1: Analog_Flow			Ouput2: Switch_Flow1				
			Range	OR L/L	OR U/L	Mode	NO/NC	L/L	U/L	Hys.
External	STHC	TCW Flow Rate Line1 / Ch1 / Bypass	1-5V	0.00	4.00	Hys.	NO	---	0.40	0.00
External	STHC	TCW Flow Rate Line2 / Ch2 / Bypass	1-5V	0.00	4.00	Hys.	NO	---	0.40	0.00
External	STHC	TCW Flow Rate Line3 / Ch3 / Bypass	1-5V	0.00	4.00	Hys.	NO	---	0.40	0.00
External	STHC	TCW Flow Rate Line4 / Ch4-1 / SCPL	1-5V	0.0	50.0	Hys.	NO	---	4.0	0.0
External	STHC	TCW Flow Rate Line8 / Ch5-1 / Bypass	1-5V	0.0	50.0	Hys.	NO	---	4.0	0.0
External	STHC	TCW Flow Rate Line9 / Ch5-2 / Bypass	1-5V	0.0	20.0	Hys.	NO	---	1.6	0.0

PFMB7201 Flowmeter (CXHN N2)

F0			F1							F3	F10	F13	F20	F22	F30	F31		F80	F81	F90	F98	F99
	rEF	Uni	oU1	1ot	P1L	P1H	H1		CoL	rES	FLo	rEv	inP	FrE	Sav	PoS	PrS	dSP	Pin	ALL	tES	ini
	Anr	-	Win	1_P	84	96	0		Grn	0.5	inS	oFF	---	oFF	oFF	Hor	Lo	on	oFF	oFF	n	oFF

*All F2 settings = "-".

PF2M721 Flowmeter (CXHN N2)

F0			F1							F3	F4	F10	F11	F13	F14	F22		F30	F80	F81	F90	F98	F99
FLU	rEF	Unit	oUt1	1ot	P1L	P1H	H1	dt1	CoL	FiL	PrS	FLo	drE	rEv	CUt	AoUt	FrEE	SAvE	diSP	Pin	ALL	tESt	ini
Air	Std	L	Wind	1_P	84	96	0	0	1SoG	0.5	---	inS	---	oFF	1.0	1-5	oFF	oFF	on	oFF	oFF	n	oFF

*All F2 settings = "-".

10. High Altitude Setting Fab/Sub-Fab

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Block	Module	Description of Setting	F32	Unit	Tolerance F32 MIN ~ MAX		TEL Std.	Remarks
PRB	CPHP	OVEN Module(R) EXH.(E10B)	164	Pa	159	169	170±5	
PRB	CPHP	OVEN Module(R) EXH. U/L Setting (E10B)	174	Pa	---	---	180	
PRB	CPHP	OVEN Module(R) EXH. L/L Setting (E10B)	145	Pa	---	---	150	
PRB	CPHP	CPHP Chamber (R) EXH. (E9B)	116	Pa	96	136	---	Set by pressure and setting for Individual Chamber exhausts. DO NOT EXCEED TARGET CHAMBER EXH SETTING
PRB	CPHP	CPHP Chamber (R) EXH U/L Setting (E9B)	150	Pa	---	---	---	
PRB	CPHP	CPHP Chamber (R) EXH L/L Setting (E9B)	82	Pa	---	---	---	
PRB	CPHP	CPHP Chamber (L) EXH. (E9A)	116	Pa	96	136	---	
PRB	CPHP	CPHP Chamber (L) EXH U/L Setting (E9A)	150	Pa	---	---	---	
PRB	CPHP	CPHP Chamber (L) EXH L/L Setting (E9A)	82	Pa	---	---	---	
PRB	CPHP	Individual Chamber Exhaust flowrate	9.1 (4.0L/min)	Pa	7.1	10.9	9.4±1.0 (4.0L/min)	
PRB	CPHP	Individual Chamber Exhaust flowrate U/L Setting	10.9 (4.5L/min)	Pa	---	---	11.3	
PRB	CPHP	Individual Chamber Exhaust flowrate L/L Setting	7.1 (3.5L/min)	Pa	---	---	7.4	
PRB	CGCH	OVEN Module(R) EXH.(E10B)	164	Pa	159	169	170±5	
PRB	CGCH	OVEN Module(R) EXH. U/L Setting (E10B)	174	Pa	---	---	180	
PRB	CGCH	OVEN Module(R) EXH. L/L Setting (E10B)	145	Pa	---	---	150	
PRB	CGCH	CGCH Cover EXH. For Deck13(E8B)	251	Pa	221	281	195±2	Set by pressure and setting for Individual Chamber exhausts. DO NOT EXCEED TARGET CHAMBER EXH SETTING
PRB	CGCH	CGCH Cover EXH. For Deck13 U/L Setting (E8B)	289	Pa	---	---	225	
PRB	CGCH	CGCH Cover EXH. For Deck13 L/L Setting (E8B)	212	Pa	---	---	165	
PRB	CGCH	CGCH Cover EXH. For Deck14	298	Pa	268	328	230±2	
PRB	CGCH	CGCH Cover EXH. For Deck14 U/L Setting (E8B)	337	Pa	---	---	260	
PRB	CGCH	CGCH Cover EXH. For Deck14 L/L Setting (E8B)	259	Pa	---	---	200	
PRB	CGCH	CGCH Cover EXH. For Deck15	122	Pa	92	152	280±2	
PRB	CGCH	CGCH Cover EXH. For Deck15 U/L Setting (E8B)	160	Pa	---	---	310	
PRB	CGCH	CGCH Cover EXH. For Deck15 L/L Setting (E8B)	83	Pa	---	---	250	
PRB	CGCH	CGCH Cover EXH. For Deck16	124	Pa	94	154	300±2	
PRB	CGCH	CGCH Cover EXH. For Deck16 U/L Setting (E8B)	163	Pa	---	---	330	
PRB	CGCH	CGCH Cover EXH. For Deck16 L/L Setting (E8B)	86	Pa	---	---	270	
PRB	CGCH	Individual Chamber Exhaust Pressure	15.5 (80L/min)	Pa	12.6	18.4	12.6±1.0 (70L/min)	
PRB	CGCH	Individual Chamber Exhaust Pressure U/L Setting	18.4 (86.1L/min)	Pa	---	---	17.1	
PRB	CGCH	Individual Chamber Exhaust Pressure L/L Setting	12.6 (71.1L/min)	Pa	---	---	8.7	
PRB	CADH*	OVEN Module(L) EXH.(E10A)	164	Pa	159	169	170±5	
PRB	CADH*	OVEN Module(L) EXH. U/L Setting (E10A)	174	Pa	---	---	180	
PRB	CADH*	OVEN Module(L) EXH. L/L Setting (E10A)	145	Pa	---	---	150	
Tools except PBR t	CADH*	Local EXH. For Deck13 (E11A)	338	Pa	288	388	350±50	For BARC tool config -E11A = 8CADH units -E11C = 8CADH units
PRB	CADH*	Local EXH. For Deck13 U/L Setting (E11A)	386	Pa	---	---	400.0	
PRB	CADH*	Local EXH. For Deck13 L/L Setting (E11A)	290	Pa	---	---	300.0	
PRB	CADH*	Local EXH. For Deck14 (E11A)	367	Pa	317	417	380±50	
PRB	CADH*	Local EXH. For Deck14 U/L Setting (E11A)	415	Pa	---	---	430.0	
PRB	CADH*	Local EXH. For Deck14 L/L Setting (E11A)	319	Pa	---	---	330.0	
PRB	CADH*	Local EXH. For Deck15 (E11C)	396	Pa	346	446	410±50	
PRB	CADH*	Local EXH. For Deck15 U/L Setting (E11C)	444	Pa	---	---	460.0	
PRB	CADH*	Local EXH. For Deck15 L/L Setting (E11C)	348	Pa	---	---	360.0	
PRB	CADH*	Local EXH. For Deck16 (E11C)	425	Pa	375	475	440±50	
PRB	CADH*	Local EXH. For Deck16 U/L Setting (E11C)	473	Pa	---	---	490.0	
PRB	CADH*	Local EXH. For Deck16 L/L Setting (E11C)	377	Pa	---	---	390.0	
PRB	CADH*	Local EXH. For Deck11/12 (E11A)	212	Pa	182	242	220±30	For IMM tool config -E11A = 8CADH units (11/12deck) -E11A = 4CADH units(13deck)
PRB	CADH*	Local EXH. For Deck11/12 U/L Setting (E11A)	241	Pa	---	---	250.0	
PRB	CADH*	Local EXH. For Deck11/12 L/L Setting (E11A)	184	Pa	---	---	190.0	
PRB	CADH*	Local EXH. For Deck13 (E11A)	135	Pa	115	155	140±20	
PRB	CADH*	Local EXH. For Deck13 U/L Setting (E11A)	155	Pa	---	---	160.0	
PRB	CADH*	Local EXH. For Deck13 L/L Setting (E11A)	116	Pa	---	---	140.0	
PRB	CADH*	Local EXH. For Deck12 (E11A)	135	Pa	115	155	220±30	For EUV tool config -E11A = 4CADH units (12deck) -E11A = 4CADH units(13deck)
PRB	CADH*	Local EXH. For Deck12 U/L Setting (E11A)	155	Pa	---	---	250.0	
PRB	CADH*	Local EXH. For Deck12 L/L Setting (E11A)	116	Pa	---	---	190.0	
PRB	CADH*	Local EXH. For Deck13 (E11A)	135	Pa	115	155	140±20	
PRB	CADH*	Local EXH. For Deck13 U/L Setting (E11A)	155	Pa	---	---	160.0	
PRB	CADH*	Local EXH. For Deck13 L/L Setting (E11A)	116	Pa	---	---	140.0	
PRB	CADH*	Local EXH. For Deck13/14 (E11A)	135	Pa	115	155	230±30	For KrF tool config -E11A = 8CADH units
PRB	CADH*	Local EXH. For Deck13/14 U/L Setting (E11A)	155	Pa	---	---	260.0	
PRB	CADH*	Local EXH. For Deck13/14 L/L Setting (E11A)	116	Pa	---	---	200.0	
PRB	CADH*	Individual Chamber Exhaust Pressure	4.5 (11L/min)	KPa	3.8	5.3	4.7±0.1	Chamber is Down.
PRB	CADH*	Individual Chamber Exhaust Pressure U/L Setting	5.3	KPa	---	---	5.5	
PRB	CADH*	Individual Chamber Exhaust Pressure U/L Setting	3.8	KPa	---	---	3.9	
PRB	CVVP	Chamber exhaust (Center) ON Chamber temperature: 300 to 350 degrees C	25.1	Pa	±2		26±2	Set by pressure and setting for individual chamber exhaust. (22±4L/min)
PRB	CVVP	Chamber exhaust (Center) ON U/L Setting Chamber temperature: 300 to 350 degrees C	30.9	Pa	-		←	
PRB	CVVP	Chamber exhaust (Center) ON L/L Setting Chamber temperature: 300 to 350 degrees C	19.3	Pa	-		←	
PRB	CVVP	Chamber exhaust (Periphery) Chamber temperature: 300 to 350 degrees C	25.1	Pa	±2		26±2	Set by pressure and setting for individual chamber exhaust. (15±3L/min)
PRB	CVVP	Chamber exhaust (Periphery) U/L Setting Chamber temperature: 300 to 350 degrees C	32.8	Pa	-		←	
PRB	CVVP	Chamber exhaust (Periphery) L/L Setting Chamber temperature: 300 to 350 degrees C	17.4	Pa	-		←	
PRB	COT/BCT/ITC	SPIN wind speed	0.21	m/sec	0.13	0.29	---	will verify to put fix value
PRB	ADEV/ANTD	SPIN wind speed	0.21	m/sec	0.13	0.29	---	will verify to put fix value

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Block	Module	Description of Setting	F32	Unit	Tolerance F32 MIN ~ MAX		TEL Std.	Remarks
HCSB	HCRA	HCRA Front area ULPA wind pressure	164	Pa	159	169	170±5	The wind volume is adjusted based on the measurement value in the front side, and the volume on the back is subject to the front side.
HCSB	HCRA	HCRA Back area ULPA wind pressure	164	Pa	144	184	Front pressure±15	
HCSB	HCRA	HCSB transfer area FAN UNIT wind pressure	261	Pa	241	291	Tool Specific	Adjustment based on the positive pressure of the block alone
HCSB	HCRA	HCSB transfer area FAN UNIT wind pressure (L/L Setting)	SV-90	Pa	---	---	Tool Specific	
PRB	SYSTEM	PRA(L) area FAN UNIT wind pressure	628	Pa	478	778	Tool Specific	Adjustment based on the positive pressure of the block alone. PRA-L and PRA-R FFU to be within 20 Pa
PRB	SYSTEM	PRA(L) area FAN UNIT wind pressure (L/L Setting)	SV-90	Pa	---	---	Tool Specific	
PRB	SYSTEM	PRA(R) area FAN UNIT wind pressure	628	Pa	478	778	Tool Specific	Adjustment based on the positive pressure of the block alone PRA-L and PRA-R FFU to be within 20 Pa
PRB	SYSTEM	PRA(R) area FAN UNIT wind pressure (L/L Setting)	SV-90	Pa	---	---	Tool Specific	
PRB	SYSTEM	THC SPIN(L) wind Pressure	193	Pa	118	268	Tool Specific	BARC tool: Left or Right, per deck See Wind Pressure Sheet when setting values.
PRB	SYSTEM	THC SPIN(R) wind Pressure	193	Pa	118	268	Tool Specific	BARC tool: Left or Right, per deck See Wind Pressure Sheet when setting values.
IFB	IRA	IRA Front area ULPA wind pressure	193	Pa	188	198	200±5	
IFB	IRA	IRA Back area ULPA wind pressure	193	Pa	188	198	200±5	
IFB	IRA	IRA Front area FAN UNIT wind pressure	Tool Specific	Pa	---	---	Tool Specific	Adjustment based on the positive pressure of the block alone
IFB	IRA	IRA Front area FAN UNIT wind pressure (L/L Setting)	SV-90	Pa	---	---	Tool Specific	
IFB	IRA	IRA Back area FAN UNIT wind pressure	Tool Specific	Pa	---	---	Tool Specific	Adjustment based on the positive pressure of the block alone
IFB	IRA	IRA Back area FAN UNIT wind pressure (L/L Setting)	SV-90	Pa	---	---	Tool Specific	
HCSB	SYSTEM	Positive pressure	Tool Specific	Pa	Tool Specific		0.3+0.1/-0.0	HCSB≦PRB≦SPIN
PRB	SYSTEM	Positive pressure	Tool Specific	Pa	Tool Specific		0.3+0.1/-0.0	HCSB≦PRB≦SPIN
PRB	COT/BCT/ITC	Positive pressure	Tool Specific	Pa	Tool Specific		PRB≦SPIN≦PRB+0.1	HCSB≦PRB≦SPIN
PRB	ADEV/ANTD	Positive pressure	Tool Specific	Pa	Tool Specific		PRB≦SPIN≦PRB+0.1	HCSB≦PRB≦SPIN
IFB	SYSTEM	Positive pressure	Tool Specific	Pa	Tool Specific		0.3+0.1/-0.0	HCSB≦PRB≧IFB
IFB	PIR/SRS	Positive pressure	Tool Specific	Pa	Tool Specific		0.3+0.1/-0.0	
IFB	BST/BST+	Positive pressure	Tool Specific	Pa	Tool Specific		0.1+0.1/-0.0	
FEX	SYSTEM	FEX Chemical EXH.(E15C,E15D)	24	Pa	10	279	100 or More	TARGFET CFM 14.1
FEX	SYSTEM	FEX Chemical EXH. (U/L Setting) (E15C,E15D)	0	Pa	---	---	0.0	
		FEX Chemical EXH. (L/L Setting) (E15C,E15D)	10	Pa	---	---	10.0	
HCSB	SYSTEM	HCSB Chemical EXH.(E15A & E15B)	97	Pa	10	352	100 or More	TARGET CFM E15A is 29.0 E15B is 18.4
HCSB	SYSTEM	HCSB Chemical EXH. (U/L Setting) (E15A & E15B)	0	Pa	---	---	0.0	
		HCSB Chemical EXH. (L/L Setting) (E15A & E15B)	10	Pa	---	---	10.0	
HCSB	CADH	HMDS Chemical EXH.(E13A)	145	Pa	14	245	100 or More	TARGET CFM 29.3
HCSB	CADH	HMDS Chemical EXH. (U/L Setting) (E13A)	0	Pa	---	---	0.0	
		HMDS Chemical EXH. (L/L Setting) (E13A)	14	Pa	---	---	10.0	
PRB	SYSTEM	SPIN Chemical(L)(R) EXH.(E1A,E1B)	145	Pa	95	265	150 or More	TARGET CFM 28.3 ※BARC tool setting
PRB	SYSTEM	SPIN Chemical(L)(R) EXH. (U/L Setting) (E1A,E1B)	0	Pa	---	---	0.0	
PRB	SYSTEM	SPIN Chemical(L)(R) EXH. (L/L Setting) (E1A,E1B)	10	Pa	---	---	10.0	
TBF/TBFna /TBFlt/TBFcn	COT Cabinet	Exhaust Solvent (EA1)	48	Pa	3	98	50+10/-0	TARGET CFM 21.2
	COT Cabinet	Exhaust Solvent (EA1) U/L Setting (EA1)	338	Pa	---	---	0	
	COT Cabinet	Exhaust Solvent (EA1) L/L Setting (EA1)	10	Pa	---	---	25	

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Block	Module	Description of Setting	F32	Unit	Tolerance F32 MIN ~ MAX		TEL Std.	Remarks
TBF	COT Cabinet	Exhaust HMDS (EA5)	338	Pa	318	413	30+10/-0	TARGET CFM 14.1
	COT Cabinet	Exhaust HMDS (EA5) U/L Setting (EA5)	10	Pa	---	---	0	
	COT Cabinet	Exhaust HMDS (EA5) L/L Setting (EA5)	39	Pa	---	---	5	
TAP/TAF/TNP /TAW/TAJ	COT Cabinet1	Exhaust Solvent (EA1)	338	Pa	293	388	50+10/-0	TARGET CFM
	COT Cabinet1	Exhaust Solvent (EA1) U/L Setting (EA1)	10	Pa	---	---	0	
	COT Cabinet1	Exhaust Solvent (EA1) L/L Setting (EA1)	0	Pa	---	---	25	
	COT Cabinet1	Exhaust HMDS (EA5)	0	Pa	-20	75	30+10/-0	TARGET CFM
	COT Cabinet1	Exhaust HMDS (EA5) U/L Setting (EA5)	0	Pa	---	---	0	
	COT Cabinet1	Exhaust HMDS (EA5) L/L Setting (EA5)	0	Pa	---	---	5	
	COT Cabinet2	Exhaust Solvent (EB1)	0	Pa	-35	60	40+10/-0	TARGET CFM
	COT Cabinet2	Exhaust Solvent (EB1) U/L Setting (EB1)	0	Pa	---	---	0	
	COT Cabinet2	Exhaust Solvent (EB1) L/L Setting (EB1)	0	Pa	---	---	15	
	DEV Cabinet	DEV CAB Exhaust(EC1)	0	Pa	-45	50	50+10/-0	TARGET CFM
	DEV Cabinet	DEV CAB Exhaust (EC1) U/L Setting (EC1)	#REF!	Pa	---	---	0	
	DEV Cabinet	DEV CAB Exhaust (EC1) L/L Setting (EC1)	0	Pa	---	---	25	
	DEV Cabinet	DEV CAB Exhaust (EC2)	0	Pa	-35	60	40+10/-0	TARGET CFM
	DEV Cabinet	DEV CAB Exhaust (EC2) U/L Setting (EC2)	0	Pa	---	---	0	
	DEV Cabinet	DEV CAB Exhaust (EC2) L/L Setting (EC2)	0	Pa	---	---	15	
PRB	BCT	SPIN CUP EXH. (E3A,E4A,E5A,E6A)	348	Pa	328	368	360±50	EPC damper must be held Open and use EXH BKM. Target CFM 169.5 *for Barc tool 310±50Pa when system recipe transferd.
PRB	BCT	SPIN CUP EXH. (E3B,E4B,E5B,E6B)	193	Pa	173	213	200±25	EPC damper must be held Open and use EXH BKM. Target CFM 98.9 *for Barc tool 160±25Pa when system recipe transferd.
PRB	COT	SPIN CUP EXH. (E1A,E2A,E3A)	348	Pa	328	368	360±50	EPC damper must be held Open and use EXH BKM. Target CFM 155.5 *for Imm tool 310±50Pa when system recipe transferd.
PRB	ITC	SPIN CUP EXH. (E1B,E2B,E3B)	348	Pa	328	368	360±50	EPC damper must be held Open and use EXH BKM. Target CFM 155.5 *for Imm tool 310±50Pa when system recipe transferd.
PRB	COT/BCT/ITC	SPIN CUP EXH. (L/L Setting) (E3A,E3B,E4A,E4B,E5A,E5B,E6A,E6B)	19	Pa	---	---	20.0	
PRB	BCT	Cup Exhaust Open	22	Pa	21	23	23.0±1.0	prevents D.I. water splash (R20)
PRB	BCT	Cup Exhaust Close	63	Pa	62	64	65.0±5.0	prevents D.I. water splash (R20)
PRB	BCT	Cup EXH U/L Setting	82	Pa	---	---	105.0	
PRB	BCT	Cup EXH L/L Setting	19	Pa	---	---	20.0	
PRB	COT/ITC	Cup Exhaust Open	22	Pa	21	23	23.0±1.0	PZ CUP
PRB	COT/ITC	Cup Exhaust Close	63	Pa	62	64	65.0±5.0	PZ CUP
PRB	COT/ITC	Cup EXH U/L Setting	82	Pa	---	---	105.0	
PRB	COT/ITC	Cup EXH L/L Setting	19	Pa	---	---	20.0	
PRB	ADEV	SPIN CUP EXH. (E4A,E5A,E6A)	---	Pa	---	---	---	No monitor on the tool Target CFM 243.7
PRB	ADEV	SPIN CUP EXH. (L/L Setting) (E4A,E5A,E6A)	---	Pa	---	---	---	
PRB	ANTD	SPIN CUP EXH. (E4B,E5B,E6B)	410	Pa	335	485	425±75	Following the EXH BKM. Target CFM 159.0
PRB	ANTD	SPIN CUP EXH. (L/L Setting) (E4B,E5B,E6B)	19	Pa	---	---	20.0	
PRB	ADEV/ANTD	Cup Exhaust Open	10	Pa	5	15	10.0±5.0	
PRB	ADEV/ANTD	Cup Exhaust Close	39	Pa	34	44	40.0±5.0	
PRB	ADEV/ANTD	Cup EXH U/L Setting	77	Pa	---	---	80.0	
PRB	ADEV/ANTD	Cup EXH L/L Setting	1	Pa	---	---	1.0	
IFB	SYSTEM	IFB Front EXH.(E12A)	348	Pa	348	448	410±50	Target CFM 197.8
IFB	SYSTEM	IFB Back EXH.(E12B)	251	Pa	251	351	310±50	Target CFM 247.3
IFB	SRS	Cup Exhaust Open	19	Pa	17	21	20.0±2.0	
IFB	SRS	Cup EXH U/L Setting	34	Pa	---	---	30.0	
IFB	SRS	Cup EXH L/L Setting	12	Pa	---	---	15.0	
IFB	PIR	Cup Exhaust Open	14	Pa	9	19	20.0±2.0	
IFB	PIR	Cup EXH U/L Setting	29	Pa	---	---	30.0	
IFB	PIR	Cup EXH L/L Setting	7	Pa	---	---	15.0	
IFB	BST/BST+	Local Exhaust	-11.6	Pa	-11.6	---	-12 or more	
IFB	BST/BST+	Local Exhaust U/L Setting	-11.6	KPa	---	---	-12.0	
IFB	BST/BST+	Local Exhaust L/L Setting	-96.5	KPa	---	---	-99.9	
IFB	BST/BST+	CUP Exhaust pressure	39	Pa	34	44	40.0±5.0	
IFB	BST/BST+	CUP Exhaust U/L Setting	48	Pa	---	---	50.0	
IFB	BST/BST+	CUP Exhaust L/L Setting	34	Pa	---	---	35.0	

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1. Overview (Configuration)

Parameter Layout

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Notes:

1. System Configuration Parameter contains Dispense Parameter, Monitoring Parameter, Transfer Arm Parameter and Spinner Parameter.

2. To avoid going over same parameter multiple times, only System configuration parameter is documented in this fingerprint.

3. In this Fingerprint, System configuration parameter is divided into Arm, Spinner, and Oven.

4. To audit values in Parameter Editor, log into User Service level with username CTADMIN4.
User/level display in Parameter Editor will show: CTADMIN (Service).

5. To audit values in the EC, use the “Temporary User Registration” function to log with username CTADMIN.
User/level display in EC will show: CTADMIN with red background.

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Default Language Setting	English
HOST Computer Interface	Valid
LINKED LITHO Interface	Valid*

*= Not present on BARC tools

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3. System Configuration Parameter, System

System

Monitoring Parameter

Chiller BYPASS1 / Chiller BYPASS2 / Chiller BYPASS3 / Chiller BYPASS4 /Chiller BYPASS5 *

Valid, Invalid	**Valid**
Measured Data ID	**Chiller BYPASS1,2,3,4,5***
Recipe Setting Method	**Local**
Temperature Control Method	**Tmp ctl ON**
Recipe Verification Range Lower Limit	**0.00**
Recipe Verification Range Upper Limit	**35.00**

* BYPASS5 for PBR only

Controller TM206-CHILLER

Controller ID	**TM206-CHILLER**
Channel No.	**See Table**
Line No.	**See Table**
Set Value	**See Table**
Warning Range Lower Limit	**100.00**
Warning Range Upper Limit	**100.00**
Stop Range Lower Limit	**100.00**
Stop Range Upper Limit	**100.00**
Offset	**0.00**

Table for Chanel No. / Line No. / Set Value

[TBF]

	Channel No.	Line No.	Set Value
BYPASS-1	3	3	4.00
BYPASS-2	4	6	4.00
BYPASS-3	5	8	49.00
BYPASS-4	5	9	13.00

[TAP/TNP/TAF/TAW/TAJ]

	Channel No.	Line No.	Set Value
BYPASS-1	4	7	2.00
BYPASS-2	5	12	6.00

[PBR]

	Channel No.	Line No.	Set Value
BYPASS-1	1	1	2.00
BYPASS-2	2	2	2.00
BYPASS-3	3	3	2.00
BYPASS-4	4	8	37.50
BYPASS-5	5	9	7.50

[TBZ]

	Channel No.	Line No.	Set Value
BYPASS-1	4-2	5	13.20
BYPASS-2	5-2	9	15.00

[TBN]

	Channel No.	Line No.	Set Value
BYPASS-1	4-2	5	13.20
BYPASS-2	5-2	9	23.00

N2 Ring Purge flow1 / N2 Ring Purge flow2

Valid, Invalid	**Valid**
Measured Data ID	**N2 Ring Purge flow**
Recipe Setting Method	**Local**
Temperature Control Method	**Tmp ctl OFF**
Recipe Verification Range Lower Limit	**0.00**
Recipe Verification Range Upper Limit	**0.00**

Controller Analogue Sensor

Controller ID	**Analogue sensor**
Band Monitoring Valid, Invalid	**Valid**
Band Monitoring Refernce Value	**11L/min×Number of CADH modules**
	See Table
Warning Range Lower Limit	**See Table**
Warning Range Upper Limit	**See Table**
Stop Range Lower Limit	**100.00**
Stop Range Upper Limit	**100.00**
Offset	**0.00**

Table for Band Monitoring Refernce Value / Warning Range Lower Limit / Warning Range Upper Limit

	N2 Ring purge flow1		N2 Ring purge flow2	
	Band Monitoring Refernce Value	Warning Range Lower&Upper Limit	Band Monitoring Refernce Value	Warning Range Lower&Upper Limit
BARC	88L/min	16L/min	88L/min	16L/min
IMM	88L/min	16L/min	44L/min	8L/min
EUV	44L/min	8L/min	44L/min	8L/min
TBZ*	88L/min	16L/min	-	-
TBN*	22L/min	4L/min	44L/min	8L/min

*KrF

Main1,2 L1-L2/L2-L3/L3-L1 Voltage

Valid, Invalid	**Valid**
Measured Data ID	**Main1,2 L#-L# Voltage**
Recipe Setting Method	**Local**
Temperature Control Method	**Tmp ctl OFF**
Recipe Verification Range Lower Limit	**0.00**
Recipe Verification Range Upper Limit	**0.00**

Controller Analogue Sensor

Controller ID	**Analogue sensor**
Band Monitoring Valid, Invalid	**Valid**
Band Monitoring Refernce Value	**200.00**
Warning Range Lower Limit	**30.00**
Warning Range Upper Limit	**42.00**
Stop Range Lower Limit	**100.00**
Stop Range Upper Limit	**100.00**
Offset	**0.00**

Barometric Pressure

Valid, Invalid	**Valid**
Measured Data ID	**Barometric Pressure**
Recipe Setting Method	**Local**
Temperature Control Method	**Tmp ctl OFF**
Recipe Verification Range Lower Limit	**0.00**
Recipe Verification Range Upper Limit	**0.00**

Controller Analogue Sensor

Controller ID	**Analogue sensor**
Set Value	**FAB Specific***
Warning Range Lower Limit	**100.00**
Warning Range Upper Limit	**100.00**
Stop Range Lower Limit	**100.00**
Stop Range Upper Limit	**100.00**
Offset	**Tool Specific**

- *** Portland / Ireland : 1010.00hPa**
- *** Phoenix: 970.00hPa**
- *** Albuquerque: 840.00hPa**
- *** Israel: 1000.00hPa**
- *** PBR: NA**

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4. System Configuration Parameter, Arm

Block 1 CS Block

1-0 / 1-20 HCSB Arm

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**1-2**
Wafer Store Count	**2**
Start Slot	**0**

Position Data

Item / Module	1-0 HCRA	1-20 HCRA	Unit
X1-axis Access Reference Point	**-30**	**-30**	pulse
X1-axis Wafer Check Position	**-30**	**-30**	pulse
X2-axis Access Reference Point	**-30**	**-30**	pulse
X2-axis Wafer Check Position	**-30**	**-30**	pulse
Z-axis Maintenance Position	**328749**	**322086**	pulse
Theta-axis Maintenance Position	**0**	**0**	pulse
X1-axis Pulse Rate	**0.006592282**	**0.006592282**	mm/pulse
X2-axis Pulse Rate	**0.006592282**	**0.006592282**	mm/pulse
Z-axis Pulse Rate	**0.006138115**	**0.006138115**	mm/pulse
Theta-axis Pulse Rate	**0.000343323**	**0.000343323**	deg/pulse
Auto Flow Adjustment X-axis Offset*	**0**	**0**	pulse
Auto Flow Adjustment Z-axis Offset*	**19143**	**19143**	pulse
Auto Flow Adjustment Th-axis Offset*	**0**	**0**	pulse

*It is not a used parameter in Intel operation.

Up Side Maintenance Position

Item / Module	1-0 HCRA	1-20 HCRA
Default Maintenance Position	**1**	**1**
Z-axis Maintenance Position	**277935**	**273211**
Theta-axis Maintenance Position	**0**	**0**

Bottom Side Maintenance Position

Item / Module	1-0 HCRA	1-20 HCRA
Default Maintenance Position	**1**	**1**
Z-axis Maintenance Position	**0**	**0**
Theta-axis Maintenance Position	**0**	**0**

Transfer Arm Control Parameter

Item / Axis	X1	X2	Z	Theta
Movement between Modules Speed	**100%**	**100%**	**100%**	**100%**
Wafer OUT Speed	**100%**	**100%**	**N/A**	**100%**
Wafer IN Speed	**100%**	**100%**	**N/A**	**100%**
Maintenance Speed	**50%**	**50%**	**50%**	**50%**
Inching Speed	**50%**	**50%**	**50%**	**50%**
Auto Flow Adjustment Move Module Speed*	**100%**	**100%**	**100%**	**100%**
Auto Flow Adjustment Wafer In/Out Speed*	**100%**	**100%**	**100%**	**100%**
Multiple Axes Synchronous Control of Movement between modules	**Invalid**	**Invalid**	**Valid**	**Valid**
IP Zone at Wafer OUT	**NA**	**NA**	**0**	**NA**
IP Zone at Wafer IN	**NA**	**NA**	**0**	**NA**

*It is not a used parameter in Intel operation.

Fork1 / Fork2

Item	FOUP		TTS		THS		All Others	
	Fork1	Fork2	Fork1	Fork2	Fork1	Fork2	Fork1	Fork2
Z-axis Receive Stroke	**990**	**990**	**2310**	**2310**	**1955**	**1500**	**1955**	**1500**
Z-axis Receive Stroke Movement Speed	**70%**	**60%**	**30%**	**30%**	**30%**	**30%**	**75%**	**70%**
X-axis Receive Stroke Movement Speed	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**
Z-axis Send Stroke	**990**	**990**	**2310**	**2310**	**1955**	**1500**	**1955**	**1500**
Z-axis Send Stroke Movement Speed	**70%**	**60%**	**30%**	**30%**	**30%**	**30%**	**75%**	**70%**
X-axis Send Stroke Movement Speed	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**

Z-axis Multistep Movement

Item	FOUP	SBU	TRS	WEX	TTS	THS
Valid, Invalid	**Invalid**	**Invalid**	**Invalid**	**Valid**	**Invalid**	**Invalid**
Slow Speed Start Position Offset	**0**	**0**	**0**	**90**	**0**	**0**
Slow Speed End Position Offset	**0**	**0**	**0**	**410**	**0**	**0**
Slow Speed	**0%**	**0%**	**0%**	**30%**	**0%**	**0%**
High Speed	**0%**	**0%**	**0%**	**100%**	**0%**	**0%**

Z-axis Multistep Movement (Receive)

Item	FOUP	SBU	TRS	WEX	TTS	THS
Valid, Invalid	**Invalid**	**Invalid**	**Invalid**	**Invalid**	**Invalid**	**Invalid**
Slow Speed Start Position Offset	**0**	**0**	**0**	**0**	**0**	**0**
Slow Speed End Position Offset	**0**	**0**	**0**	**0**	**0**	**0**
Slow Speed	**0%**	**0%**	**0%**	**0%**	**0%**	**0%**
High Speed	**0%**	**0%**	**0%**	**0%**	**0%**	**0%**

Z-axis Multistep Movement (Send)

Item	FOUP	SBU	TRS	WEX	TTS	THS
Valid, Invalid	**Invalid**	**Invalid**	**Invalid**	**Invalid**	**Invalid**	**Invalid**
Slow Speed Start Position Offset	**0**	**0**	**0**	**0**	**0**	**0**
Slow Speed End Position Offset	**0**	**0**	**0**	**0**	**0**	**0**
Slow Speed	**0%**	**0%**	**0%**	**0%**	**0%**	**0%**
High Speed	**0%**	**0%**	**0%**	**0%**	**0%**	**0%**

Z-axis Multistep Movement (Long Receive)

Item	FOUP	SBU	TRS	WEX	TTS	THS
Valid, Invalid	**Invalid**	**Invalid**	**Invalid**	**Valid**	**Invalid**	**Invalid**
Slow Speed Start Position Offset	**0**	**0**	**0**	**380**	**0**	**0**
Slow Speed End Position Offset	**0**	**0**	**0**	**700**	**0**	**0**
Slow Speed	**0%**	**0%**	**0%**	**80%**	**0%**	**0%**
High Speed	**0%**	**0%**	**0%**	**100%**	**0%**	**0%**

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4. System Configuration Parameter, Arm

X axis Position & Offset

Arm	Module	X Send Position	X Receive Position	Offset (X Receive - X Send)
1-0 / 1-20 HCRA X1	FOUP	Tool Specific*	Tool Specific*	0 pulse
	All Others	Tool Specific*	Tool Specific*	0 pulse
1-0 / 1-20 HCRA X2	FOUP	Tool Specific*	Tool Specific*	228 pulse
	All Others	Tool Specific*	Tool Specific*	0 pulse

***Auto adjustment**

Z and Theta axis Offset

Arm	Module	Offset (Z Send - Z Receive)	Offset (Th Receive - Th Send)
1-0 / 1-20 HCRA X1	FOUP	Tool Specific*	0 pulse
	TTS	Tool Specific**	0 pulse
	All Others	1955 pulse***	0 pulse
1-0 / 1-20 HCRA X2	FOUP	990 pulse	0 pulse
	TTS	Tool Specific**	0 pulse
	All Others	1500 pulse	0 pulse

* X1 is AL fork. X1 does not access to FOUP. It can not be position adjusted.

** TTS is used for X-axis and Th-axis position teaching of SBU and TRS modules. It can not be position adjusted.

*** Except TRS and SBU. X1 is AL fork. X1 dose not access to TRS and SBU. Because next access module is FOUP. It can not be position adjusted.

Wafer Edge Detector

Item	Set Value	Unit
Send Wafer Position Adjust	**Valid**	
Bright Adjust Target	**125**	
Bright Down Warning	**70**	
Bright Down Error	**60**	
Continuous Pixel Lack Pass Width	**10**	pixel
Total Pixel Lack Pass Width	**3**	pixel
Slewing Radius	**100000**	um
Notch Judgment Threshold	**30**	um

Linear Image Sensor

Item	Set Value	Unit
Installation Angle	**30**	deg
LED Intensity	**Tool Specific**	
Fork Edge Pixel	**85000**	pixel
Fork1 Rate	**12500**	nm/pixel
Fork2 Rate	**13477**	nm/pixel
Fork1 Standard Wafer Edge Pixel	**Tool Specific**	pixel
Fork1 Edge Detect Threshold	**1000**	
Fork1 Edge Continuous Detect Pass Width	**10**	pixel
Fork2 Standard Wafer Edge Pixel	**Tool Specific**	pixel
Fork2 Edge Detect Threshold	**1000**	
Fork1 Edge Continuous Detect Pass Width	**10**	pixel

EDR Function

Item	Set value	Unit
EDR Function	**Valid**	

Wafer Shift Detect Function

Item	Set value	Unit
Warning Valid, Invalid	**Invalid**	
Warning Threshold	**500**	um

1-X FOUP UST

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**Invalid**
Wafer Store Count	**25**
Start Slot	**1**

Wafer Information

Wafer Thickness	**800 um**
Thickness (+) Range	**60%**
Thickness (-) Range	**50%**

Mapping Data

Pitch between Slots	**480**
Mapping Type	**Carrier Mapping**
Mapping Start Position	**6240**
Mapping End Position	**18456**
Slot Recognition Position	**Tool Specific**
Standby Position	**-100**

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4. System Configuration Parameter, Arm

1-10 FT Arm

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**Invalid**
Wafer Store Count	**1**
Start Slot	**0**

Position Data

Item	Set Value	Unit
X1-axis Access Reference Point	**1200**	pulse
Y-axis Safe Position	**0**	pulse
Z-axis Safe Position	**0**	pulse
Y-axis Maintenance Position	**0**	pulse
Z-axis Maintenance Position	**272384**	pulse
X1-axis Pulse Rate	**0.001085069**	mm/pulse
Y-axis Pulse Rate	**0.007324219**	mm/pulse
Z-axis Pulse Rate	**0.003906250**	mm/pulse

Transfer Arm Control Parameter

Item / Axis	X1	Y	Z
Normal Speed (No Carrier)	**100***	**100**	**100**
Normal Speed (Carrier Present)	**100**	**100**	**100**
Maintenance Speed	**50**	**100**	**100**
Inching Speed	**50**	**50**	**50**
Multiple Axes Synchronous Control of Movement between modules	**Invalid**	**Valid**	**Valid**
IP Zone at Wafer OUT	**N/A**	**N/A**	**0**
IP Zone at Wafer IN	**N/A**	**N/A**	**0**

*Normal speed(No Carrier) setting value x1.8 in internal parameter.(actually working 180%).

Fork1

Item	Set Value
Y-axis Slide Stroke at Receiving	**19200**
Z-axis Down Stroke at Receiving	**6700**
Z-axis Up Stroke at Receiving	**6700**
Y-axis Slide Stroke at Sending	**19200**
Z-axis Down Stroke at Sending	**6700**
Z-axis Up Stroke at Sending	**6700**
Y-axis Slide Movement Speed	**20%**
Z-axis Stroke Movement Speed (No Carrier)	**40%**
Z-axis Stroke Movement Speed (Carrier Present)	**10%**

X axis Position & Offset

Arm	Module	X Send Position	X Receive Position	Offset (X Receive - X Send)
1-10 FTRA	All	Tool Specific*	Tool Specific*	0 pulse

***Auto adjustment**

Y and Z axis Offset

Arm	Module	Offset (Y Slide Start Position at Sending - Y Slide Start Position at Receiving)	Offset (Z Start Position at Sending - Z Start Position at Receiving)
1-10 FTRA	All	19200 pulse	0 pulse

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4. System Configuration Parameter, Arm

Block 11, 12, 13, 14, 15, 16 PR Block

11-0 / 12-0 / 13-0 / 14-0 /15-0 / 16-0 PRB Arm

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**1-2**
Wafer Store Count	**2**
Start Slot	**0**

Position Data

Item	Set Value	Unit
X1-axis Access Reference Point	**-30**	pulse
X1-axis Wafer Check Position	**-30**	pulse
X2-axis Access Reference Point	**-30**	pulse
X2-axis Wafer Check Position	**-30**	pulse
Y-axis Maintenance Position	**338000**	pulse
Z-axis Maintenance Position	**0**	pulse
Theta-axis Maintenance Position	**262144**	pulse
X1-axis Pulse Rate	**0.006592282**	mm/pulse
X2-axis Pulse Rate	**0.006592282**	mm/pulse
Y-axis Pulse Rate	**0.005858954**	mm/pulse
Z-axis Pulse Rate	**0.003580311**	mm/pulse
Theta-axis Pulse Rate	**0.000343323**	deg/pulse

CSB Side Maintenance Position Data

Item	Set Value	Unit
Default Maintenance Position	**1**	
Y-axis Maintenance Position	**0**	pulse
Z-axis Maintenance Position	**0**	pulse
Theta-axis Maintenance Position	**786432**	pulse

IFB Side Maintenance Position Data

Item	Set Value	Unit
Default Maintenance Position	**1**	
Y-axis Maintenance Position	**392562**	pulse
Z-axis Maintenance Position	**0**	pulse
Theta-axis Maintenance Position	**262144**	pulse

Transfer Arm Control Parameter

Item / Axis	X1	X2	Y	Theta	Z
Movement between Modules Speed	**100% / (50%*)**	**100% / (50%*)**	**80% / (50%*)**	**80% / (50%*)**	**80% / (50%*)**
Wafer OUT Speed	**90% / (50%*)**	**90% / (50%*)**	**100% / (50%*)**	**100% / (50%*)**	**N/A**
Wafer IN Speed	**90% / (50%*)**	**90% / (50%*)**	**100% / (50%*)**	**100% / (50%*)**	**N/A**
Maintenance Speed	**50%**	**50%**	**50%**	**50%**	**50%**
Auto Temperature Adjustment Speed	**50%**	**50%**	**50%**	**50%**	**50%**
Inching Speed	**50%**	**50%**	**50%**	**50%**	**50%**
Auto Flow Adjustment Move Module Speed	**100%**	**100%**	**100%**	**100%**	**100%**
Auto Flow Adjustment Wafer In/Out Speed	**100%**	**100%**	**100%**	**100%**	**100%**
Multiple Axes Synchronous Control of Movement between modules	**Invalid**	**Invalid**	**Valid**	**Valid**	**Valid**
IP Zone at Wafer OUT	**N/A**	**N/A**	**N/A**	**N/A**	**100**
IP Zone at Wafer IN	**N/A**	**N/A**	**N/A**	**N/A**	**100**

* PBR 50%

Fork1 / Fork2

Item	TRS	COT/BCT/ADEV/ANTD	CADH/CGCH/CPHP/CVIP	SCPL	CWH	TTS	THS	CXHN
Z-axis Receive Stroke	**3350/3770***	**3350**	**6150**	**6150**	**3910**	**3400**	**3350/4750****	**3350**
Z-axis Receive Stroke Movement Speed	**100%**	**100%**	**100%**	**100%**	**30%**	**30%**	**30%**	**100%**
X-axis Receive Stroke Movement Speed	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**
Z-axis Send Stroke	**3350/3770***	**3350**	**6150**	**6150**	**3910**	**3400**	**3350/4750****	**3350**
Z-axis Send Stroke Movement Speed	**100%**	**100%**	**100%**	**100%**	**30%**	**30%**	**30%**	**100%**
X-axis Send Stroke Movement Speed	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**

*COT Deck or PBR = 3350, DEV Deck = 3770

**Link Tool = 4750, Standalone Tool = 3550

Z-axis Multistep Movement

Item	TRS	COT/BCT/ADEV/ANTD	CADH/CGCH/CPHP/CVIP	SCPL	CWH	TTS	THS	CXHN
Valid, Invalid	**Invalid**	**Valid**	**Valid**	**Valid**	**Invalid**	**Invalid**	**Invalid**	**Invalid**
Slow Speed Start Position Offset	**0**	**700**	**1955**	**1955**	**0**	**0**	**0**	**0**
Slow Speed End Position Offset	**0**	**1255**	**2515**	**2515**	**0**	**0**	**0**	**0**
Slow Speed	**0%**	**50%**	**40%**	**40%**	**0%**	**0%**	**0%**	**0%**
High Speed	**0%**	**90%**	**100%**	**100%**	**0%**	**0%**	**0%**	**0%**

Z-axis Multistep Movement (Receive)

Item	TRS	COT/BCT/ADEV/ANTD	CADH/CGCH/CPHP/CVIP	SCPL	CWH	TTS	THS	CXHN
Valid, Invalid	**Invalid**	**Invalid**	**Valid**	**Valid**	**Invalid**	**Invalid**	**Invalid**	**Invalid**
Slow Speed Start Position Offset	**0**	**0**	**2960**	**2960**	**0**	**0**	**0**	**0**
Slow Speed End Position Offset	**0**	**0**	**3520**	**3520**	**0**	**0**	**0**	**0**
Slow Speed	**0%**	**0%**	**50%**	**50%**	**0%**	**0%**	**0%**	**0%**
High Speed	**0%**	**0%**	**90%**	**90%**	**0%**	**0%**	**0%**	**0%**

Z-axis Multistep Movement (Send)

Item	TRS	COT/BCT/ADEV/ANTD	CADH/CGCH/CPHP/CVIP	SCPL	CWH	TTS	THS	CXHN
Valid, Invalid	**Invalid**	**Invalid**	**Valid**	**Valid**	**Invalid**	**Invalid**	**Invalid**	**Invalid**
Slow Speed Start Position Offset	**0**	**0**	**1955**	**1955**	**0**	**0**	**0**	**0**
Slow Speed End Position Offset	**0**	**0**	**2515**	**2515**	**0**	**0**	**0**	**0**
Slow Speed	**0%**	**0%**	**70%**	**70%**	**0%**	**0%**	**0%**	**0%**
High Speed	**0%**	**0%**	**90%**	**90%**	**0%**	**0%**	**0%**	**0%**

Z-axis Multistep Movement (Long Receive)

Item	TRS	COT/BCT/ADEV/ANTD	CADH/CGCH/CPHP/CVIP	SCPL	CWH	TTS	THS	CXHN
Valid, Invalid	**Invalid**	**Valid**	**Valid**	**Valid**	**Invalid**	**Invalid**	**Invalid**	**Invalid**
Slow Speed Start Position Offset	**0**	**1675**	**3350**	**3350**	**0**	**0**	**0**	**0**
Slow Speed End Position Offset	**0**	**2235**	**3910**	**3910**	**0**	**0**	**0**	**0**
Slow Speed	**0%**	**70%**	**70%**	**70%**	**0%**	**0%**	**0%**	**0%**
High Speed	**0%**	**90%**	**90%**	**90%**	**0%**	**0%**	**0%**	**0%**

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4. System Configuration Parameter, Arm

X axis Position & Offset

Arm	Module	X Send Position	X Receive Position	Offset (X Receive - X Send)
11, 12, 13, 14, 15, 16-0 PRA	All Modules	Tool Specific*	Tool Specific*	0 pulse

***Auto adjustment**

Y, Z and Theta Axis Offset

Arm	Module	Offset(Y Receive - Y Send)	Offset(Z Send - Z Receive)	Offset(Th Receive - Th Send)
11, 12, 13, 14, 15, 16-0 PRA	TRS	0 pulse	*	0 pulse
	COT/BCT/ADEV/ANTD/CXHN	0 pulse	3350	0 Pulse
	SCPL/CADH/CGCH/CPHP/CVIP	0 pulse	6150 pulse	0 pulse
	CWH	0 pulse	3910 pulse	0 pulse
	TTS	0 pulse	Tool Specific**	0 pulse
	THS	0 pulse	3350/4750 pulse***	0 pulse

***COT Deck or PBR = 3350, DEV Deck = 3770**

****TTS is used for X-axis and Th-axis position teaching of SCPL and TRS modules. It can not be position adjusted.**

*****Link Tool = 4750, Standalone Tool = 3550**

Wafer Edge Detector

Item	Set Value	Unit
Send Wafer Position Adjust	**Valid**	
Bright Adjust Target	**125**	
Bright Down Warning	**70**	
Bright Down Error	**60**	
Continuous Pixel Lack Pass Width	**10**	pixel
Total Pixel Lack Pass Width	**3**	pixel
Slewing Radius	**110000**	um
Notch Judgment Threshold	**30**	um

Linear Image Sensor

Item	Set Value	Unit
Installation Angle	**30**	deg
LED Intensity	**Tool Specific**	
Fork Edge Pixel	**85000**	pixel
Fork1 Rate	**12500**	nm/pixel
Fork2 Rate	**13333**	nm/pixel
Fork1 Standard Wafer Edge Pixel	**Tool Specific**	pixel
Fork1 Edge Detect Threshold	**1000**	
Fork1 Edge Continuous Detect Pass Width	**10**	pixel
Fork2 Standard Wafer Edge Pixel	**Tool Specific**	pixel
Fork2 Edge Detect Threshold	**1000**	
Fork1 Edge Continuous Detect Pass Width	**10**	pixel

EDR Function

Item	Set value	Unit
EDR Function	**Valid**	

Wafer Shift Detect Function

Item	Set value	Unit
Warning Valid, Invalid	**Invalid**	
Warning Threshold	**500**	um

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4. System Configuration Parameter, Arm

Block 30 IFB Block

30-0 IFBSI Arm 30-10/30-20 IFBM Arm

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**1-2**
Wafer Store Count	**2**
Start Slot	**0**

Position Data

Item / Module	30-0 IFBSI	30-10 IFBM	30-20 IFBM	Unit
X1-axis Access Reference Point	**-30**	**-30**	**-30**	pulse
X1-axis Wafer Check Position	**-30**	**-30**	**-30**	pulse
X2-axis Access Reference Point	**-30**	**-30**	**-30**	pulse
X2-axis Wafer Check Position	**-30**	**-30**	**-30**	pulse
Y-axis Maintenance Position	**0**	**N/A**	**N/A**	pulse
Z-axis Maintenance Position	**116382**	**255689**	**255689**	pulse
Theta-axis Maintenance Position	**262144**	**0**	**0**	pulse
X1-axis Pulse Rate	**0.006592282**	**0.006592282**	**0.006592282**	mm/pulse
X2-axis Pulse Rate	**0.006592282**	**0.006592282**	**0.006592282**	mm/pulse
Y-axis Pulse Rate	**0.003526451**	**N/A**	**N/A**	mm/pulse
Z-axis Pulse Rate	**0.004231742**	**0.008719585**	**0.008719585**	mm/pulse
Theta-axis Pulse Rate	**0.000343323**	**0.000343323**	**0.000343323**	deg/pulse

Up Side Maintenance Position

Item / Module	30-0IFBSI	30-10/30-20IFBM
Default Maintenance Position	**1**	**1**
Y-axis Maintenance Position	**0**	**N/A**
Z-axis Maintenance Position	**116382**	**255689**
Theta-axis Maintenance Position	**262144**	**0**

Bottom Side Maintenance Position

Item / Module	30-0IFBSI	30-10/30-20IFBM
Default Maintenance Position	**1**	**1**
Y-axis Maintenance Position	**235364**	**N/A**
Z-axis Maintenance Position	**116382**	**0**
Theta-axis Maintenance Position	**262144**	**0**

Transfer Arm Control Parameter

Item / Axis	X1	X2	Y	Z	Theta
Movement between Modules Speed	**100**	**100**	**100**	**100**	**100**
Wafer OUT Speed	**100**	**100**	**100**	**N/A**	**100**
Wafer IN Speed	**100**	**100**	**100**	**N/A**	**100**
Maintenance Speed	**50**	**50**	**50**	**50**	**50**
Auto Temperature Adjustment Speed - IRAM	**N/A**	**N/A**	**N/A**	**N/A**	**N/A**
Auto Temperature Adjustment Speed - IRAI	**50**	**50**	**50**	**50**	**50**
Inching Speed	**50**	**50**	**50**	**50**	**50**
Auto Flow Adjustment Move Module Speed	**100**	**100**	**100**	**100**	**100**
Auto Flow Adjustment Wafer In/Out Speed	**100**	**100**	**100**	**N/A**	**100**
Multiple Axes Synchronous Control of Movement between modules	**Invalid**	**Invalid**	**Valid**	**Valid**	**Valid**
IP Zone at Wafer OUT	**N/A**	**N/A**	**N/A**	**100**	**N/A**
IP Zone at Wafer IN	**N/A**	**N/A**	**N/A**	**100**	**N/A**

Fork1 / Fork2 30-0 IFBSI Arm

Item	EXP		RSM		All Others	
	Fork1	Fork2	Fork1	Fork2	Fork1	Fork2
Z-axis Receive Stroke	**1700**	**1700**	**2170**	**2170**	**2170**	**2170**
Z-axis Receive Stroke Movement Speed	**90%**	**90%**	**30%**	**30%**	**90%**	**90%**
X-axis Receive Stroke Movement Speed	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**
Z-axis Send Stroke	**1700**	**1700**	**2170**	**2170**	**2170**	**2170**
Z-axis Send Stroke Movement Speed	**90%**	**70%**	**30%**	**30%**	**90%**	**90%**
X-axis Send Stroke Movement Speed	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**

Fork1 / Fork2 30-10 IFBM Arm

Item	TRS(PRB)		ICPL/SRS/BST		THS/TTS		SBU	
	Fork1	Fork2	Fork1	Fork2	Fork1	Fork2	Fork1	Fork2
Z-axis Receive Stroke	**1055**	**1055**	**1055**	**1055**	**1630**	**1630**	**1110**	**1110**
Z-axis Receive Stroke Movement Speed	**100%**	**100%**	**90%**	**90%**	**30%**	**30%**	**100%**	**100%**
X-axis Receive Stroke Movement Speed	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**
Z-axis Send Stroke	**1055**	**1055**	**1055**	**1055**	**1630**	**1630**	**1110**	**1110**
Z-axis Send Stroke Movement Speed	**100%**	**100%**	**90%**	**90%**	**30%**	**30%**	**100%**	**100%**
X-axis Send Stroke Movement Speed	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**

Fork1 / Fork2 30-20 IFBM Arm

Item	TRS(PRB)		PIR/TRS(IFB)		THS/TTS		SBU	
	Fork1	Fork2	Fork1	Fork2	Fork1	Fork2	Fork1	Fork2
Z-axis Receive Stroke	**1230**	**1230**	**1055**	**1055**	**1630**	**1630**	**1110**	**1110**
Z-axis Receive Stroke Movement Speed	**100%**	**100%**	**90%**	**90%**	**30%**	**30%**	**100%**	**100%**
X-axis Receive Stroke Movement Speed	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**
Z-axis Send Stroke	**1230**	**1230**	**1055**	**1055**	**1630**	**1630**	**1110**	**1110**
Z-axis Send Stroke Movement Speed	**100%**	**100%**	**90%**	**90%**	**30%**	**30%**	**100%**	**100%**
X-axis Send Stroke Movement Speed	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**	**100%**

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4. System Configuration Parameter, Arm

Z-axis Multistep Movement

Item	PIR	SRS	BST	All others
Valid, Invalid	**Valid**	**Valid**	**Valid**	**Invalid**
Slow Speed Start Position Offset	**230**	**230**	**230**	**0**
Slow Speed End Position Offset	**460**	**460**	**460**	**0**
Slow Speed	**60%**	**60%**	**60%**	**0%**
High Speed	**80%**	**80%**	**80%**	**0%**

Z-axis Multistep Movement (Receive)

Item	PIR	SRS	BST	All others
Valid, Invalid	**Invalid**	**Invalid**	**Invalid**	**Invalid**
Slow Speed Start Position Offset	**0**	**0**	**0**	**0**
Slow Speed End Position Offset	**0**	**0**	**0**	**0**
Slow Speed	**0%**	**0%**	**0%**	**0%**
High Speed	**0%**	**0%**	**0%**	**0%**

Z-axis Multistep Movement (Send)

Item	PIR	SRS	BST	All others
Valid, Invalid	**Invalid**	**Invalid**	**Invalid**	**Invalid**
Slow Speed Start Position Offset	**0**	**0**	**0**	**0**
Slow Speed End Position Offset	**0**	**0**	**0**	**0**
Slow Speed	**0%**	**0%**	**0%**	**0%**
High Speed	**0%**	**0%**	**0%**	**0%**

Z-axis Multistep Movement (Long Receive)

Item	PIR	SRS	BST	All others
Valid, Invalid	**Valid**	**Valid**	**Valid**	**Invalid**
Slow Speed Start Position Offset	**320**	**320**	**320**	**0**
Slow Speed End Position Offset	**550**	**550**	**550**	**0**
Slow Speed	**90%**	**90%**	**90%**	**0%**
High Speed	**90%**	**90%**	**90%**	**0%**

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4. System Configuration Parameter, Arm

X axis Position & Offset

Arm	Module	X Send Position	X Receive Position	Offset (X Receive - X Send)
30-0,30-10, 30-20 IFB Arm	All Modules	Tool Specific*	Tool Specific*	0 pulse

*Auto adjustment

Z and Theta axis Offset

Arm	Module	Offset (Z Send - Z Receive)	Offset (Th Receive - Th Send)
30-0 IFBSI Arm	EXP	1700 pulse	0 pulse
	All Others	2170 pulse	0 pulse
30-10 IFBM Arm	TRS(PRB)	1055 pulse	0 pulse
30-20 IFBM Arm	TRS(PRB)	1230 pulse	0 pulse
30-10/20 IFBM Arm	ICPL/SRS/BST/PIR/TRS(IFB)	1055 pulse	0 pulse
	THS/TTS	1630 pulse	0 pulse
	SBU	1110 pulse	0 pulse

EDR Function

Item	Set value	Unit
EDR Function	**Valid**	

Wafer Edge Detector

Item	Set Value	Unit
Send Wafer Position Adjust	**Valid**	
Bright Adjust Target	**125**	
Bright Down Warning	**70**	
Bright Down Error	**60**	
Continuous Pixel Lack Pass Width	**10**	pixel
Total Pixel Lack Pass Width	**3**	pixel
Slewing Radius	**100000/90000***	um
Notch Judgment Threshold	**30**	um

* 30-20IFBM Arm

Linear Image Sensor

Item	Set Value	Unit
Installation Angle	**30**	deg
LED Intensity	**Tool Specific**	
Fork Edge Pixel	**100000**	pixel
Fork1 Rate	**12626**	nm/pixel
Fork2 Rate	**13477**	nm/pixel
Fork1 Standard Wafer Edge Pixel	**Tool Specific**	pixel
Fork1 Edge Detect Threshold	**1000**	
Fork1 Edge Continuous Detect Pass Width	**10**	pixel
Fork2 Standard Wafer Edge Pixel	**Tool Specific**	pixel
Fork2 Edge Detect Threshold	**1000**	
Fork1 Edge Continuous Detect Pass Width	**10**	pixel

Wafer Shift Detect Function

Item	Set value	Unit
Warning Valid, Invalid	**Invalid**	
Warning Threshold	**500**	um

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5.1. System Config Parameter, Spinners (ADEV)

Block 14,15,16 PR Block, Developers [14-1/2/3] - [16-1/2/3] for 9x9 PTD
Block 15,16 PR Block, Developers [15-1/2/4/5] - [16-1/2/4/5] for 8×0 KrF Tool

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**1-2**
Wafer Store Count	**1**
Start Slot	**0**

Dispense Parameter
Local Nozzle

DEV3(Local Arm) = MGP Nozzle

Process Recipe Attribute	**Valid**
Dummy Dispense Attribute	**Valid**
Nozzle Pattern No	**Tool Specific**

Dispense Mechanism Connection [1]

Valid, Invalid	**Valid**

Dispense Monitoring Mechanism Connection

Valid, Invalid	**Valid**

UltrasonicType flow meter

Dispense Monitoring Type	UltrasonicType flow meter
Sensor Channel No.	Line Specific
Chemical Name	DEVE SOLUTION/DEVE SOLUTION
FRType	TYPE2(3000ml/min)

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid

Supply System

Valid, Invalid	**Valid**

DEV.SOLU.1 Supply System - [Tool Specific]

Refill Monitoring Time	**180**
Pre-Refill Decompress Time	**20.0**
Post-Refill Vent Time	**1.0**
Post-Refill Pressurize Time	**15.0**
Post-Refill Depressurize Time	**60.0**
Post-Refill Delay Time	**1**
Supply Valve Close Delay Time	**0.10**
N2 Dissolution Monitoring Time	**0**
Monitoring Time for Chemical Replacement	**0**
Vent Time at Chemical Replacement	**150**
Tank Switch during Dispensing	**Valid**

CSS Refill System

Valid, Invalid	**Valid**

FailsafeValve

Failsafe Valve Close Delay Time	**0.0 sec**

Dispense Monitoring Control Data

Pulse Rate	**0.05**
Delay Time	**0.6**
Set Flow Rate	**600**
Flow Rate Sensor Check Timing	**Dispense end**
Calibration 1	**1.00**
Offset	**0**
Upper Limit Error Level	**30.00%**
Upper Limit Warning Level	**20.00%**
Lower Limit Error Level	**30.00%**
Lower Limit Warning Level	**20.00%**
Dummy Dispense Flow Rate Monitoring Valid/Invalid	**Valid**
Reporting Dispense Amount to Dispense State Monitor	**Valid**
Monitoring Flow Rate Upper Limit for Short Time Dispense	**Execute**
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	**1.0**

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5.1. System Config Parameter, Spinners (ADEV)

Local Nozzle

DEV6(Local Arm)

Process Recipe Attribute	**Valid**
Dummy Dispense Attribute	**Valid**
Nozzle Pattern No	**Tool Specific**

Dispense Mechanism Connection [1]

Valid, Invalid	**Valid**

Dispense Monitoring Mechanism Connection

Valid, Invalid	**Valid**

UltrasonicType flow meter

Dispense Monitoring Type	UltrasonicType flow meter
Sensor Channel No.	Line Specific
Chemical Name	DEVE SOLUTION/DEVE SOLUTION
FRType	TYPE2(3000ml/min)

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid

Supply System

Valid, Invalid	**Valid**

DEV.SOLU.1 Supply System - [Tool Specific]

Refill Monitoring Time	**180**
Pre-Refill Decompress Time	**20.0**
Post-Refill Vent Time	**1.0**
Post-Refill Pressurize Time	**15.0**
Post-Refill Depressurize Time	**60.0**
Post-Refill Delay Time	**1**
Supply Valve Close Delay Time	**0.10**
N2 Dissolution Monitoring Time	**0**
Monitoring Time for Chemical Replacement	**0**
Vent Time at Chemical Replacement	**150**
Tank Switch during Dispensing	**Valid**

CSS Refill System

Valid, Invalid	**Valid**

FailsafeValve

Failsafe Valve Close Delay Time	**0.0 sec**

Dispense Monitoring Control Data

Pulse Rate	**0.05**	
Delay Time	**0.60**	
Set Flow Rate	**300, *320**	* KrF Setting
Flow Rate Sensor Check Timing	**Dispense End**	
Calibration 1	**1.00**	
Offset	**0**	
Upper Limit Error Level	**20.00%**	
Upper Limit Warning Level	**15.00%**	
Lower Limit Error Level	**20.00%**	
Lower Limit Warning Level	**15.00%**	
Dummy Dispense Flow Rate Monitoring Valid/Invalid	**Valid**	
Reporting Dispense Amount to Dispense State Monitor	**Valid**	
Monitoring Flow Rate Upper Limit for Short Time Dispense	**Execute**	
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	**1.0**	

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5.1. System Config Parameter, Spinners (ADEV)

Dispense Parameter
Local Nozzle
DEV6 Sub Local

Process Recipe Attribute	**Valid**
Dummy Dispense Attribute	**Valid**
Nozzle Pattern No	**Tool Specific**

Dispense Mechanism Connection [1]

Valid, Invalid	**Valid**

Dispense Monitoring Mechanism Connection

Valid, Invalid	**Valid**

UltrasonicType flow meter

Dispense Monitoring Type	UltrasonicType flow meter
Sensor Channel No.	Line Specific
Chemical Name	DEVE SOLUTION/DEVE SOLUTION
FRType	TYPE2(3000ml/min)

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid

Supply System

Valid, Invalid	**Valid**

DEV.SOLU.1 Supply System - [Tool Specific]

Refill Monitoring Time	**180**
Pre-Refill Decompress Time	**20.0**
Post-Refill Vent Time	**1.0**
Post-Refill Pressurize Time	**15.0**
Post-Refill Depressurize Time	**60.0**
Post-Refill Delay Time	**1**
Supply Valve Close Delay Time	**0.10**
N2 Dissolution Monitoring Time	**0**
Monitoring Time for Chemical Replacement	**0**
Vent Time at Chemical Replacement	**150**
Tank Switch during Dispensing	**Valid**

CSS Refill System

Valid, Invalid	**Valid**

FailsafeValve

Failsafe Valve Close Delay Time	**0.0 sec**

Dispense Monitoring Control Data

Pulse Rate	**0.05**
Delay Time	**0.6**
Set Flow Rate	**250**
Flow Rate Sensor Check Timing	**Dispense End**
Calibration 1	**1.00**
Offset	**0**
Upper Limit Error Level	**20.00%**
Upper Limit Warning Level	**15.00%**
Lower Limit Error Level	**20.00%**
Lower Limit Warning Level	**15.00%**
Dummy Dispense Flow Rate Monitoring Valid/Invalid	**Valid**
Reporting Dispense Amount to Dispense State Monitor	**Valid**
Monitoring Flow Rate Upper Limit for Short Time Dispense	**Execute**
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	**1.0**

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5.1. System Config Parameter, Spinners (ADEV)

Dispense Parameter
Local Nozzle
Back Rinse1

Process Recipe Attribute	**Valid**
Dummy Dispense Attribute	**Invalid**
Nozzle Pattern No	**Tool Specific**

Dispense Mechanism Connection [1]

Valid, Invalid	**Valid**

Dispense Monitoring Mechanism Connection

Valid, Invalid	**Valid**

UltrasonicType flow meter

Dispense Monitoring Type	UltrasonicType flow meter
Sensor Channel No.	Line Specific
Chemical Name	DI WATER
FRType	TYPE3(300ml/min)

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid

Dispense Monitoring Control Data

Pulse Rate	**0.005**
Delay Time	**0.60**
Set Flow Rate	**200**
Flow Rate Sensor Check Timing	**Dispense end**
Calibration 1	**1.00**
Offset	**0**
Upper Limit Error Level	**30.00%**
Upper Limit Warning Level	**20.00%**
Lower Limit Error Level	**30.00%**
Lower Limit Warning Level	**20.00%**
Dummy Dispense Flow Rate Monitoring Valid/Invalid	**Invalid**
Monitoring Flow Rate Upper Limit for Short Time Dispense	**Execute**
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	**1.0**

CUP EXH.

Process Recipe Attribute	**Valid**
Dummy Dispense Attribute	**Invalid**

Dispense Mechanism Connection [1]

Valid, Invalid	**Valid**

Spinner Exhaust Monitoring Control Data

High Pressure	**40.00/*39.00**
High Pressure (Error Lower Limit)	**22.00**
Low Pressure	**10.00**
Low Pressure (Error Upper Limit)	**22.00**
Cup EXH. Monitoring Start Delay Time	**3000**
Offset	**0.0**
Cup EXH. Monitoring Valid(1)/Invalid(0)	**1**

***High altitude setting**

ADR1 N2

Process Recipe Attribute	**Valid**
Dummy Dispense Attribute	**Valid**

Dispense Mechanism Connection [1]

Valid, Invalid	**Valid**

Unexpected Pressure Watch

Unexpected Pressure Watch Valid	**Valid**
Delay Time Before Unexpected Presure Watch	**3.0**

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5.1. System Config Parameter, Spinners (ADEV)

Dispense Parameter
Local Nozzle
ADR1 RINSE

Process Recipe Attribute	**Valid**
Dummy Dispense Attribute	**Valid**
Nozzle Pattern No	**Tool Specific**

Dispense Mechanism Connection

Valid, Invalid	**Valid**

Dispense Monitoring Mechanism Connection

Valid, Invalid	**Valid**

UltrasonicType flow meter

Dispense Monitoring Type	UltrasonicType flow meter
Sensor Channel No.	Line Specific
Chemical Name	DI WATER
FRType	TYPE2(3000ml/min)

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid

Dispense Monitoring Control Data

Pulse Rate	**0.05**
Delay time	**0.60**
Set Flow Rate	**350**
Flow Rate Sensor Check Timing	**Dispense end**
Calibration 1	**1.00**
Offset	**0**
Upper Limit Error Level	**30.00%**
Upper Limit Warning Level	**20.00%**
Lower Limit Error Level	**30.00%**
Lower Limit Warning Level	**20.00%**
Dummy Dispense Flow Rate Monitoring Valid/Invalid	**Valid**
Monitoring Flow Rate Upper Limit for Short Time Dispense	**Execute**
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	**1.0**

RINSE 1

Process Recipe Attribute	**Valid**
Dummy Dispense Attribute	**Valid**
Nozzle Pattern No	**Tool Specific**

Dispense Mechanism Connection [1]

Valid, Invalid	**Valid**

Dispense Monitoring Mechanism Connection

Valid, Invalid	**Valid**

UltrasonicType flow meter

Dispense Monitoring Type	UltrasonicType flow meter
Sensor Channel No.	Line Specific
Chemical Name	DI WATER
FRType	TYPE2(3000ml/min)

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid

Dispense Monitoring Control Data

Pulse Rate	**0.05**	
Delay Time	**0.6**	
Set Flow Rate	**1000, *1050**	*KrF setting
Flow Rate Sensor Check Timing	**Dispense end**	
Calibration 1	**1.00**	
Offset	**0**	
Upper Limit Error Level	**30.00%**	
Upper Limit Warning Level	**20.00%**	
Lower Limit Error Level	**30.00%**	
Lower Limit Warning Level	**20.00%**	
Dummy Dispense Flow Rate Monitoring Valid/Invalid	**Valid**	
Monitoring Flow Rate Upper Limit for Short Time Dispense	**Execute**	
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	**1.0**	

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5.1. System Config Parameter, Spinners (ADEV)

Dispense Parameter
Local Nozzle

BATH EXH

Process Recipe Attribute	**Invalid**
Dummy Dispense Attribute	**Valid**

Dispense Mechanism Connection [1]

Valid, Invalid	**Valid**

DIW6 Sub Local

Process Recipe Attribute	**Valid**
Dummy Dispense Attribute	**Valid**
Nozzle Pattern No	**Tool Specific**

Dispense Mechanism Connection [1]

Valid, Invalid	**Valid**

Dispense Monitoring Mechanism Connection

Valid, Invalid	**Valid**

UltrasonicType flow meter

Dispense Monitoring Type	UltrasonicType flow meter
Sensor Channel No.	Line Specific
Chemical Name	DI WATER
FRType	TYPE2(3000ml/min)

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid

Dispense Monitoring Control Data

Pulse Rate	**0.05**
Delay Time	**0.6**
Set Flow Rate	**250**
Flow Rate Sensor Check Timing	**Dispense End**
Calibration 1	**1.00**
Offset	**0**
Upper Limit Error Level	**30.00%**
Upper Limit Warning Level	**20.00%**
Lower Limit Error Level	**30.00%**
Lower Limit Warning Level	**20.00%**
Dummy Dispense Flow Rate Monitoring Valid/Invalid	**Valid**
Monitoring Flow Rate Upper Limit for Short Time Dispense	**Execute**
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	**1.0**

EXH DRAIN PUMP

Process Recipe Attribute	**Invalid**
Dummy Dispense Attribute	**Valid**

Dispense Mechanism Connection [1]

Valid, Invalid	**Valid**

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5.1. System Config Parameter, Spinners (ANTD)

Dispense Parameter
Local Nozzle
DEV6(Local Arm) / DEV6 Sub Local / RINSE1 / BACK RINSE

Process Recipe Attribute	**Valid**	
Dummy Dispense Attribute	**Valid ***	* Invalid for BACK RINSE1

Dispense Mechanism Connection [1]

Valid, Invalid	**Valid*** **	*** Invalid on no-LND/LNR tracks

Dispense Monitoring Mechanism Connection

Valid, Invalid	**Valid*** **	*** Invalid on no-LND/LNR tracks

UltrasonicType flow meter

Dispense Monitoring Type	UltrasonicType flow meter
Sensor Channel No.	Line Specific
Chemical Name	Solvent/Other
FRType	See Table

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid

Table for FRType

DEV6(Local Arm)	DEV6 Sub Local	RINSE1	BACK RINSE
TYEP2(3000ml/min)	TYEP2(3000ml/min)	TYEP3(300ml/min)	TYEP3(300ml/min)

CRF Setting**

Valid, Invalid	**Valid**	** DEV6(LocalArm)/RINSE/DEV6 Sub Local

Interval for Circulation**

Valid, Invalid	**Valid**	** DEV6(LocalArm)/RINSE/DEV6 Sub Local
Time for Circulation Recovery	**60**	
Time for Continuous Circulation	**60**	

Supply System

Valid, Invalid	**Valid*** **

*** Invalid on no-LND/LNR tracks

Flow Watch

Measurement Valid/Invalid	**Invalid**
Measurement Start Delay Time	**3.0**
Measurement Time	**5.0**
Monitoring Set Value for Warning	**45**

N.T.DEV SOLUTION1 Supply System

Item / Dispense	DEV6(Local Arm)	DEV6 Sub Local	RINSE1	BACK RINSE 1
Refill Monitoring Time	**180**	**180**	**180**	**180**
Pre-Refill Decompress Time	**20.0**	**20.0**	**20.0**	**20.0**
Post-Refill Vent Time	**1.0**	**1.0**	**1.0**	**1.0**
Post-Refill Pressurize Time	**15.0**	**15.0**	**15.0**	**15.0**
Post-Refill Depressurize Time	**60.0**	**60.0**	**60.0**	**60.0**
Post-Refill Delay Time	**1.0**	**1.0**	**1.0**	**1.0**
Supply Valve Close Delay Time	**0.10**	**0.10**	**0.10**	**0.10**
N2 Dissolution Monitoring Time	**0.0**	**0.0**	**0.0**	**0.0**
Vent Time at IFF-S	**150.0**	**150.0**	**150.0**	**150.0**
Monitoring Time for Chemical Replacement	**0.0**	**0.0**	**0.0**	**0.0**
Vent Time at Chemical Replacement	**150.0**	**150.0**	**150.0**	**150.0**
Tank Switch during Dispensing	**Valid**	**Valid**	**Valid**	**Valid**
Return Mode Setting	**Valid**	**Valid**	**Valid**	**Valid**

CRF Setting

Wait Time for Circulation Recovery	**240**
Guarantee Time of Continuous Circulation	**0**
Circulation Buffer Pressure Release Time	**1**
Circulation Liquid Vent Monitoring Time	**60**
Pressurization Time for Circulation Switching	**3**
Vent Time for Circulation Switching	**0**
Small-Pressurization Time for Circulation Switching	**1**

CSS Refill System

Valid, Invalid	**Valid**

FailsafeValve

Failsafe Valve Close Delay Time	**0**

Dispense Monitoring Control Data

Item / Dispense	DEV6(Local Arm)	DEV6 Sub Local	RINSE1	BACK RINSE 1
Pulse Rate	**0.05**	**0.05**	**0.00333**	**0.005**
Delay Time	**0.60**	**0.60**	**0.60**	**0.60**
Set Flow Rate	**300.00**	**120**	**120.00**	**200.00**
Flow Rate Sensor Check Timing	**Dispense end**	**Dispense end**	**Dispense end**	**Dispense end**
Calibration 1	**1.00**	**1.00**	**1.00**	**1.00**
Offset	**0.00**	**0**	**0.00**	**0.00**
Upper Limit Error Level	**30.00**	**30.00**	**30.00**	**30.00**
Upper Limit Warning Level	**20.00**	**20.00**	**20.00**	**20.00**
Lower Limit Error Level	**30.00**	**30.00**	**30.00**	**30.00**
Lower Limit Warning Level	**20.00**	**20.00**	**20.00**	**20.00**
Dummy Dispense Flow Rate Monitoring Valid/Invalid	**Valid**	**Valid**	**Valid**	**Invalid**
Reporting Dispense Amount to Dispense State Monitor	**Valid**	**Valid**	**Valid**	**Valid**
Monitoring Flow Rate Upper Limit for Short Time Dispense	**Execute**	**Execute**	**Execute**	**Execute**
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	**1.00**	**1**	**1.00**	**1.00**

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5.1. System Config Parameter, Spinners (ANTD)

Dispense Parameter
Local Nozzle
CUP EXH.

Process Recipe Attribute	**Valid**
Dummy Dispense Attribute	**Invalid**

Dispense Mechanism Connection [1]

Valid, Invalid	**Valid**

Spinner Exhaust Monitoring Control Data

High Pressure	**40.00/*39.00**
High Pressure (Error Lower Limit)	**22.00**
Low Pressure	**10.00**
Low Pressure (Error Upper Limit)	**22.00**
Cup EXH. Monitoring Start Delay Time	**3000**
Offset	**0.0**
Cup EXH. Monitoring Valid(1)/Invalid(0)	**1**

***High altitude setting**

NTD FILTDRAIN1* /3* /5*

* - IFF-S Specific

Process Recipe Attribute	**Invalid**
Dummy Dispense Attribute	**Invalid**
IFF-S Supported Nozzle	**Tool Specific**

Dispense Mechanism Connection

Valid, Invalid	**Valid****

** Invalid on no-LND/LNR tracks

Dispense Monitoring Mechanism Connection

Valid, Invalid	**Valid****

** Invalid on no-LND/LNR tracks

UltrasonicType flow meter

Dispense Monitoring Type	**UltrasonicType flow meter**
Sensor Channel No.	**Line Specific**
Chemical Name	**Solvent/Other**
FRType	**Type2(3000ml/min)**

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid

CRF Setting

Valid, Invalid	**Valid**

Interval for Circulation

Valid, Invalid	**Valid**
Time for Circulation Recovery	**60**
Time for Continuous Circulation	**60**

Supply System[1]

Valid, Invalid	**Valid****

** Invalid on no-LND/LNR tracks

SOLVENT-D Supply System

Supply System Type	**Solvent super clean supply sys**
Chemical Name	**SOLVENT-D**
Refill Monitoring Time	**180**
Pre-Refill Decompress Time	**30**
Post-Refill Vent Time	**3**
Post-Refill Pressurize Time	**15**
Post-Refill Depressurize Time	**60**
Post-Refill Delay Time	**1**
Vent Time at Chemical Drain	**150**
Filter Replacement Supply System No.	**Tool Specific**

Flow Watch

Measurement Valid/Invalid	**Invalid**
Measurement Start Delay Time	**3**
Measurement Time	**5**
Monitoring Set Value for Warning	**45**

NTD-RFILTDRAIN1* /2*/ 3*

* - IFF-S Specific

Process Recipe Attribute	**Invalid**
Dummy Dispense Attribute	**Invalid**
IFF-S Supported Nozzle	**Tool Specific**

Dispense Mechanism Connection

Valid, Invalid	**Valid****

** Invalid on no-LND/LNR tracks

Dispense Monitoring Mechanism Connection

Valid, Invalid	**Valid****

** Invalid on no-LND/LNR tracks

UltrasonicType flow meter

Dispense Monitoring Type	**UltrasonicType flow meter**
Sensor Channel No.	**Line Specific**
Chemical Name	**Solvent/Other**
FRType	**Type3(300ml/min)**

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid

CRF Setting

Valid, Invalid	**Valid**

Interval for Circulation

Valid, Invalid	**Valid**
Time for Circulation Recovery	**60**
Time for Continuous Circulation	**60**

Supply System[1]

Valid, Invalid	**Valid****

** Invalid on no-LND/LNR tracks

SOLVENT-E Supply System

Supply System Type	**Solvent super clean supply sys**
Chemical Name	**SOLVENT-E**
Refill Monitoring Time	**180**
Pre-Refill Decompress Time	**30**
Post-Refill Vent Time	**1**
Post-Refill Pressurize Time	**15**
Post-Refill Depressurize Time	**60**
Post-Refill Delay Time	**1**
Vent Time at Chemical Drain	**150**
Filter Replacement Supply System No.	**Tool Specific**

Flow Watch

Measurement Valid/Invalid	**Invalid**
Measurement Start Delay Time	**3.0**
Measurement Time	**5.0**
Monitoring Set Value for Warning	**45**

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5.1. System Config Parameter, Spinners (ANTD)

FILTDRAIN / RFILTDRAIN

		Filter Replacement Sequence(1)[1]	Filter Replacement Sequence(2)[2]	Filter Replacement Sequence(3)[3]	Filter Replacement Sequence(4)[4]	Filter Replacement Sequence(5)[5]	Filter Replacement Sequence(6)[6]	Filter Replacement Sequence(7)[7]	Filter Replacement Sequence(8)[8]	Filter Replacement Sequence(9)[9]
	Comment	IFF-1	IFF-2	IFF-3	IFF-4	IFF-5	IFF-6	IFF-7	IFF-8	IFF-9
STEP 1	Process Time	10	10	10	0	0	0	0	0	0
	Pressure Setting	LL	LL	LL	None	None	None	None	None	None
	Process Name	Hold	Hold	Hold	None	None	None	None	None	None
STEP 2	Process Time	200	200	200	0	0	0	0	0	0
	Pressure Setting	LL	LL	LL	None	None	None	None	None	None
	Process Name	Filter vent	Filter vent	Filter vent	None	None	None	None	None	None
STEP 3	Process Time	640	100	640	0	0	0	0	0	0
	Pressure Setting	L	L	L	None	None	None	None	None	None
	Process Name	Filter out	Filter out	Filter out	None	None	None	None	None	None
STEP 4	Process Time	600	1200	600	0	0	0	0	0	0
	Pressure Setting	None	L	None	None	None	None	None	None	None
	Process Name	Hold	Filter out	Hold	None	None	None	None	None	None
STEP 5	Process Time	3200	0	3200	0	0	0	0	0	0
	Pressure Setting	L	None	L	None	None	None	None	None	None
	Process Name	Filter out	None	Filter out	None	None	None	None	None	None
STEP 6	Process Time	0	0	10	0	0	0	0	0	0
	Pressure Setting	None	None	LL	None	None	None	None	None	None
	Process Name	None	None	Hold	None	None	None	None	None	None
STEP 7	Process Time	0	0	200	0	0	0	0	0	0
	Pressure Setting	None	None	LL	None	None	None	None	None	None
	Process Name	None	None	Filter vent	None	None	None	None	None	None
STEP 8	Process Time	0	0	640	0	0	0	0	0	0
	Pressure Setting	None	None	L	None	None	None	None	None	None
	Process Name	None	None	Filter out	None	None	None	None	None	None
STEP 9	Process Time	0	0	600	0	0	0	0	0	0
	Pressure Setting	None	None	None	None	None	None	None	None	None
	Process Name	None	None	Hold	None	None	None	None	None	None
STEP 10	Process Time	0	0	3200	0	0	0	0	0	0
	Pressure Setting	None	None	L	None	None	None	None	None	None
	Process Name	None	None	Filter out	None	None	None	None	None	None
STEP 11	Process Time	0	0	10	0	0	0	0	0	0
	Pressure Setting	None	None	LL	None	None	None	None	None	None
	Process Name	None	None	Hold	None	None	None	None	None	None
STEP 12	Process Time	0	0	200	0	0	0	0	0	0
	Pressure Setting	None	None	LL	None	None	None	None	None	None
	Process Name	None	None	Filter vent	None	None	None	None	None	None
STEP 13	Process Time	0	0	640	0	0	0	0	0	0
	Pressure Setting	None	None	L	None	None	None	None	None	None
	Process Name	None	None	Filter out	None	None	None	None	None	None
STEP 14	Process Time	0	0	600	0	0	0	0	0	0
	Pressure Setting	None	None	None	None	None	None	None	None	None
	Process Name	None	None	Hold	None	None	None	None	None	None
STEP 15	Process Time	0	0	3200	0	0	0	0	0	0
	Pressure Setting	None	None	L	None	None	None	None	None	None
	Process Name	None	None	Filter out	None	None	None	None	None	None
STEP 16	Process Time	0	0	10	0	0	0	0	0	0
	Pressure Setting	None	None	LL	None	None	None	None	None	None
	Process Name	None	None	Hold	None	None	None	None	None	None
STEP 17	Process Time	0	0	200	0	0	0	0	0	0
	Pressure Setting	None	None	LL	None	None	None	None	None	None
	Process Name	None	None	Filter vent	None	None	None	None	None	None
STEP 18	Process Time	0	0	640	0	0	0	0	0	0
	Pressure Setting	None	None	L	None	None	None	None	None	None
	Process Name	None	None	Filter out	None	None	None	None	None	None
STEP 19	Process Time	0	0	600	0	0	0	0	0	0
	Pressure Setting	None	None	None	None	None	None	None	None	None
	Process Name	None	None	Hold	None	None	None	None	None	None
STEP 20	Process Time	0	0	3200	0	0	0	0	0	0
	Pressure Setting	None	None	L	None	None	None	None	None	None
	Process Name	None	None	Filter out	None	None	None	None	None	None

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5.1. System Config Parameter, Spinners (ANTD)

NTD FILTDRAIN1* 2* 3* / NTD-RFILTDRAIN1* 2* 3*

Dispense Monitoring Control Data

Item / Dispense	NTD FILTDRAIN	NTD-RFILTDRAIN
Pulse Rate	**0.05**	**0.00333**
Delay Time	**0.60**	**0.60**
Set Flow Rate	**75**	**75**
Flow Rate Sensor Check Timing	**None**	**None**
Calibration 1	**1.00**	**1.00**
Offset	**0**	**0**
Upper Limit Error Level	**30.00**	**30.00**
Upper Limit Warning Level	**20.00**	**20.00**
Lower Limit Error Level	**30.00**	**30.00**
Lower Limit Warning Level	**20.00**	**20.00**
Dummy Dispense Flow Rate Monitoring Valid/Invalid	**Invalid**	**Invalid**
Reporting Dispense Amount to Dispense State Monitor	**Valid**	**Valid**
Monitoring Flow Rate Upper Limit for Short Time Dispense	**Not Execute**	**Not Execute**
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	**1.0**	**1.0**

NTD1 N2

Process Recipe Attribute	**Valid**
Dummy Dispense Attribute	**Valid**

Dispense Mechanism Connection [1]

Valid, Invalid	**Valid**

Unexpected Pressure Watch

Unexpected Pressure Watch Valid	**Valid**
Delay Time Before Unexpected Presure Watch	**3.0**

EXH DRAIN PUMP

Process Recipe Attribute	**Invalid**
Dummy Dispense Attribute	**Valid**

Dispense Mechanism Connection [1]

Valid, Invalid	**Valid**

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5.1. System Config Parameter, Spinners (ADEV, ANTD)

MONITORING PARAMETER [For ADEV and ANTD]

Developer 1 temp./ Motor flang temp./ DEV Temp. Control flow rate / NTD Temp. Control flow rate / M/F Temp. Control flow rate

Item	Dev 1 temp.	Motor flange	DEV Temp. Control flow rate	NTD Temp. Control flow rate	M/F Temp. Control flow rate
Valid, Invalid	Valid	Valid	Valid	Valid	Valid
Measured Data ID	Dev 1 temp.	Motor flange temp.	DEV Temp. Control flow rate	NTD Temp. Control flow rate	M/F Temp. Control flow rate
Recipe Setting Method	System recipe	System recipe	Local	Local	Local
Temperature Control Method	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl ON	Tmp ctl ON
Range Lower Limit	20.00	20.00	0.00	0.00	0.00
Range Upper Limit	25.00	25.00	35.00	35.00	35.00

Controller TM206-CHILLER

Item	Dev 1 temp.	Motor flange	DEV Temp. Control flow rate	NTD Temp. Control flow rate	M/F Temp. Control flow rate
Controller ID	TM206-CHILLER	TM206-CHILLER	TM206-CHILLER	TM206-CHILLER	TM206-CHILLER
Channel No.	5	5	5	5	5
Monitoring Type	Use point read	Use point read	N/A	N/A	N/A
Control Method	Standard	Standard	N/A	N/A	N/A
Usepoint reading method	AI reading	AI reading	N/A	N/A	N/A
Use Point Offset	0.00	0.00	N/A	N/A	N/A
Band Monitoring Method at Process Start	Normal	Normal	N/A	N/A	N/A
Band Monitoring Invalid Time at Process Start	0.0	0.0	N/A	N/A	N/A
Band Monitoring Determine Method during Processing	No monitor	No monitor	N/A	N/A	N/A
Band Monitoring Determine Time during Processing	0.0	0.0	N/A	N/A	N/A
Band Monitoring Value during Processing	0.00	0.00	N/A	N/A	N/A
Pump Frequency	30 ~ 60 Hz	30 ~ 60 Hz	N/A	N/A	N/A
Initial Data	23.00	23.00	N/A	N/A	N/A
Overtemperature	40.00	40.00	N/A	N/A	N/A
Setting Determination Time	5.0	5.0	N/A	N/A	N/A
Setting Time-out Time	3600.0	3600.0	N/A	N/A	N/A
Line No.	N/A	N/A	9	10	11
Set Value	N/A	N/A	9.00	6.00	6.00
Warning Range Lower Limit	N/A	N/A	100.00	100.00	100.00
Warning Range Upper Limit	N/A	N/A	100.00	100.00	100.00
Stop Range Lower Limit	N/A	N/A	100.00	100.00	100.00
Stop Range Upper Limit	N/A	N/A	100.00	100.00	100.00
Offset	N/A	N/A	0.00	0.00	0.00

Cup temp./ Cup humidity

Item	Cup temp.	Cup humidity
Valid, Invalid	Valid	Valid
Measured Data ID	Cup temp.	Cup humidity
Recipe Setting Method	System recipe	System recipe
Temperature Control Method	Tmp ctl OFF	Tmp ctl OFF
Recipe Verification Range Lower Limit	20.00	28.00
Recipe Verification Range Upper Limit	27.00	55.00

Controller TM206-THC

Item	Cup temp.	Cup humidity
Controller ID	TM206-THC	TM206-THC
Channel No.	1	2
Monitoring Type	Use point read	Use point read
Control Method	Standard	Standard
Use Point Offset	0.00	0.00
Band Monitoring Method at Process Start	Normal	Normal
Band Monitoring Invalid Time at Process Start	0.0	0.0
Band Monitoring Determination Method	No monitor	No monitor
Band Monitoring Determination Time	0.0	0.0
Band Monitoring Value during Processing	0.00	0.00
Air Blower Frequency	30 ~ 60 Hz	30 ~ 60 Hz
Initial Data	22.20	40.70
Overtemperature	40.00	0.00
Settling Determination Time	5.0	5.0
Setting Time-out Time	3600.0	3600.0

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5.1. System Config Parameter, Spinners (ADEV, ANTD)

Block Arm - Left/ Block Arm - Right/ Module Arm - Left

Spinner Arm Control Data	ADEV Modules	
Item	Module Arm - Left	Module Arm - Right
Rail No. ADEV14/15/16-1/2/3	Lower Rail	Lower Rail
Arm Presence	**Exist**	**Exist**
Nozzle Type	**Rinse Nozzle**	**Rinse Nozzle**
X-axis Drive Type	**Motor Drive**	**Motor Drive**
Z-axis Drive Type	**Motor Drive**	**Motor Drive**
X-axis Pulse Rate	**0.002751**	**0.002751**
Z-axis Pulse Rate	**0.003**	**0.003**
IN, OUT Speed	**120326**	**120326**
IN, OUT Acceleration	**558000**	**558000**
IN, OUT Deceleration	**558000**	**558000**
UP, DOWN Speed	**33333**	**33333**
UP, DOWN Acceleration	**100000**	**100000**
UP, DOWN Deceleration	**100000**	**100000**

Spinner Arm Control Data	ANTD Modules
Item	Module Arm - Left
Rail No. ANTD14/15/16-1/2	**Lower Rail**
Arm Presence	**Exist**
Nozzle Type	**Rinse Nozzle[NTD]**
X-axis Drive Type	**Motor Drive**
Z-axis Drive Type	**Motor Drive**
X-axis Pulse Rate	**0.002751**
Z-axis Pulse Rate	**0.003**
IN, OUT Speed	**120326**
IN, OUT Acceleration	**558000**
IN, OUT Deceleration	**558000**
UP, DOWN Speed	**33333**
UP, DOWN Acceleration	**100000**
UP, DOWN Deceleration	**100000**

Home Offset

	ADEV Module Arm - Left	ADEV Module Arm - Right	ANTD Module Arm - Left
X-Axis Home Position Offset	0	0	0
Z-Axis Home Position Offset	667	667	667

Arm Move Limitation

	ADEV Module Arm - Left	ADEV Module Arm - Right	ANTD Module Arm - Left
Allowable Radius for Arm Down to the Plus Area	59.00	25.50	44.00
Allowable Radius for Arm Down to the Minus Area	159.00	163.00	151.00

Home Position

	ADEV Module Arm - Left	ADEV Module Arm - Right	ANTD Module Arm - Left
X - Position	Nozzle Specific*	Nozzle Specific*	Nozzle Specific*
Z - Position	Nozzle Specific*	Nozzle Specific*	Nozzle Specific*

*Home Position determined from fixture setup

Reference Point

	ADEV Module Arm - Left	ADEV Module Arm - Right	ANTD Module Arm - Left
X - Position	Nozzle Specific	Nozzle Specific	Nozzle Specific
Z - Position	Nozzle Specific	Nozzle Specific	Nozzle Specific

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5.1. System Config Parameter, Spinners (ADEV, ANTD)

Recipe Position

BLOCK ARM - Recipe Position Name	MGP Nozzle	
	Module Arm - Left (mm)*	
	X Position	Z Position
Begin	**-140.00**	**12.60**
Center	**0.00**	**12.60**
End	**0.00**	**12.60**
Dispense 1	**-5.00**	**12.60**
Dispense 2	**-100.00**	**12.60**
Dispense 3	**6.00**	**12.60**
Dispense 4	**-6.00**	**12.60**
Dispense 5	**0.00**	**12.60**
Dispense 6	**50.00**	**12.60**
Dispense 7	**N/A**	**N/A**
Edge (B)	**-145.00**	**12.60**
Edge (E)	**-140.00**	**12.60**
MNT 1	**0.00**	**5.00**
MNT 2	**0.00**	**5.00**
MNT 3	**0.00**	**5.00**

***Values displayed in mm on Parameter Editor may differ from values in the table below by up to 0.02 mm since the actual position is based on an integer number of pulses.**

Recipe Position

MODULE ARM - Recipe Position Name	ADR - Rinse Arm		NTD - Rinse Arm	
	Module Arm - Right (mm)*		Module Arm - Left (mm)*	
	X Position	Z Position	X Position	Z Position
Begin	**0.00**	**12.00**	**-140.00**	**16.00**
Center	**0.00**	**12.00**	**0.00**	**16.00**
End	**0.00**	**12.00**	**0.00**	**16.00**
Dispense 1	**0.00**	**12.00**	**-10.00**	**16.00**
Dispense 2	**0.00**	**12.00**	**-100.00**	**16.00**
Dispense 3	**-15.00**	**12.00**	**0.00**	**16.00**
Dispense 4	**-40.00**	**12.00**	**0.00**	**16.00**
Dispense 5	**-145.00**	**12.00**	**0.00**	**16.00**
Dispense 6	**21.00**	**12.00**	**0.00**	**16.00**
Dispense 7	**0.00**	**12.00**	**0.00**	**16.00**
Edge (B)	**-100.00**	**12.00**	**0.00**	**16.00**
Edge (E)	**0.00**	**12.00**	**0.00**	**16.00**
MNT 1	**0.00**	**5.00**	**0.00**	**5.00**
MNT 2	**0.00**	**5.00**	**0.00**	**5.00**
MNT 3	**0.00**	**5.00**	**0.00**	**5.00**

*Values displayed in mm on Parameter Editor may differ from values in the table below by up to 0.02 mm since the actual position is based on an integer number of pulses.

Spin Motor

Spin Motor Control Data(ADEV/ANTD)

Rinse Arm Select	**L Arm**
Maximum Speed	**3000.00**
Maximum Acceleration	**3000.00**
Speed at Rinse	**1000.00**
Acceleration at Rinse	**3000.00**
Rinse Time	**15.00**
Spin Off Speed	**1000.00**
Spin Off Acceleration	**3000.00**
Spin Off Time	**15.00**

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5.2. System Config Parameter, Spinners (COT/BCT/ITC)

Block 13.14.15.16 PR Block for BARC tool

Block 11.12.13 PR Block for IMM tool / Blcok 12.13 PR Block for EUV tool / Blcok 13.14 PR Block for KrF tool

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**1-2**
Wafer Store Count	**1**
Start Slot	**0**

Dispense Parameter

Shared Nozzle

Possible Number of Simultaneous Resist Dispense Processes	**10**

RESIST NOZZLE#

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid
Dry Free Suck Back	Valid
Out-Filter Vent Attribute	Valid

Pump18

Viscosity Type	Standard
Pressure Monitoring Warning Range	20.0
Pressure Monitoring Stop Range	30.0
Pump Pressure Calibration	1.00
Pressure For Wait	20.0
Reload Preparation Pressure	35.0
Reload Initial Pressure	See Table
Pump Trap Vent Initial Pressure	2.0
Pump Return Vent Initial Pressure	See Table
Return Line Valid/Invalid for Pump Vent	Valid
Pior Pressurization Time for Pump Vent	2.0
Trap BDSensor Monitoring Valid/Invalid	Valid
Retry Count for Pump Vent	10
AMC Close Timing Adjust Valid/Invalid	Valid
Filter Vent Valid/Invalid	Valid
Cyclic Filter Vent Interval Time	0
Filter Vent Interval	600
Filter Vent Time	1.0
Prior Pressurization Time for Filter Vent	2.0
Delay Time Before Reload	3.0
Pump Out Valve Close Delay Time	0.1

AMC

AV Open Time	0
AV Close Time	0
Process S.B. Time	0

DFS

Process Setup Time	0	
Suckback Offset	0	
Setup1 Time	300	
Setup2 Time	300	
Setup3 Time	300	
Suckback1 Time	4000	
Suckback2 Time	2000	
Suckback3 Time	2000	**BARC**
Process Setup Position	13	48 ± 3
Setup1 Position	0	0
Setup2 Position	0	0
Process Suckback Position	0	0
Suckback1 Position	13 [+/-1]	22 ± 3
Suckback2 Position	15 [+/-1]	23 ± 3
Suckback3 Position	5 [+/-1]	5 ± 3

DispenseLine Data

Resist Flow Data Collection Valid/Invalid	Valid
Pump Pressure Data Collection Valid/Invalid	Valid

Resist Interval Return Setting

Excessive-Return Preventive Amount	999
Excessive-Return Preventive Purge Amount	3

IFF-R Setting

IFF-R Pressure	-45.0
IFF-R Time	10

Out-Filter Setting

Pump Out-Filter Vent Initial Pressure	2.0
Out-Filter Vent Press Mode For Wait	Enclosed Press

Dispense Mechanism Connection [1]

Valid, Invalid	Valid*

*Invalid if Resist is not plumbed.

Supply System [Tool Specific]

Valid, Invalid	Valid*

*Invalid if Resist is not plumbed.

Resist# Supply System [Tool Specific]

Air vent in process	Valid
The Number of Wafers to be Processed with Remaining Resist	See Table1 Below
Transfer control/Chemical Amount to be Continue After Bottle Empty	See Table1 Below
Liquid Sensor Watch Time	1
Bottle Empty Recover Mode	Refill Movement
Refill Monitoring Time	40
Press After Free Time	1.0
Automatic Refill Interval for Idle Time	0

Table 1

	Number of Wafers	Chemical Amount
EUV COT/ITC, KrF	100	0 ml
BARC, Immersion	0	50 ml

Refill System - [Tool Specific]

RefillSysNo	Nozzle Specific
RefillSystemValid	Valid

Multi tank refill system

Supply Method	Vaccum
Prior Pressurization Time	5.0

Bottle Empty Detectction Setting

Instant detect Refill Stop Sensor	Invalid
Refill Stop Sensor Detect Fix Time	1.0
Refill Stop Sensor Watch Invalid Time	6.0

Bottle [0]

Container No.	1

Bottle [1]*

Container No.	2

*Not exist on Resist9.

Dispense Monitoring Control Data

Delay Time	0.60
Flow Rate Sensor Check Timing	Dispense end
Calibration 2	1.0000
Upper Limit Error Level	20.00
Upper Limit Warning Level	10.00
Lower Limit Error Level	20.00
Lower Limit Warning Level	10.00
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid
Reporting Dispense Amount to Dispense State Monitor	Valid
Duration for Stabilizing Pressure to Validate Measurement Result	20.0
Dsp Amount Monitoring	Invalid
Specific Gravity	1.0000

5.2. System Config Parameter, Spinners (COT/BCT/ITC) *BARC

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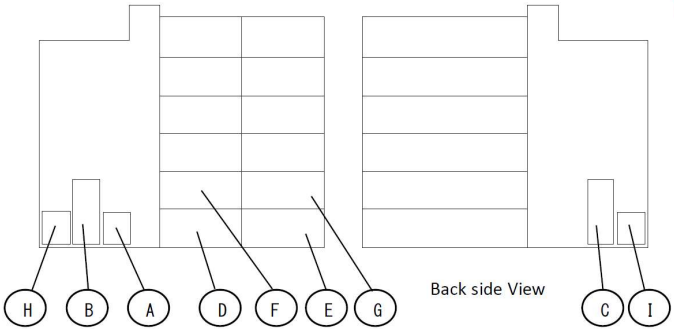
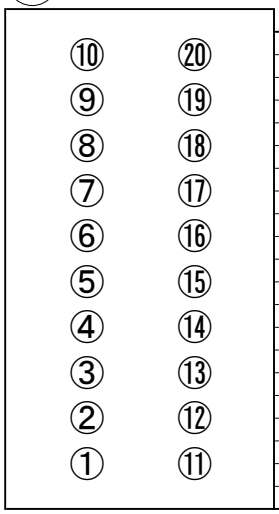


F

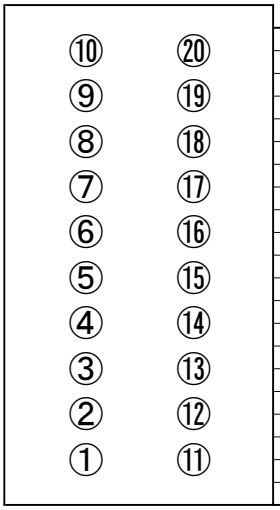
PRB Spin Chemical (12-1,2)



Front

F1 Tank Area (12-1)

No.	Tank		Point of Use	Setting
1	RSV Tank		13-1,2,3 RESIST1	4.0
2	RSV Tank		14-1,2,3 RESIST1	4.0
3	RSV Tank		13-1,2,3 RESIST2	4.0
4	RSV Tank		14-1,2,3 RESIST2	4.0
5	RSV Tank		13-1,2,3 RESIST3	4.0
6	RSV Tank		14-1,2,3 RESIST3	4.0
7	RSV Tank		13-1,2,3 RESIST4	4.0
8	RSV Tank		14-1,2,3 RESIST4	4.0
9	RSV Tank		13-1,2,3 RESIST9	4.0
10	UNUSED			
11	RSV Tank		13-1,2,3 RESIST5	4.0
12	RSV Tank		14-1,2,3 RESIST5	4.0
13	RSV Tank		13-1,2,3 RESIST6	4.0
14	RSV Tank		14-1,2,3 RESIST6	4.0
15	RSV Tank		13-1,2,3 RESIST7	4.0
16	RSV Tank		14-1,2,3 RESIST7	4.0
17	RSV Tank		13-1,2,3 RESIST8	4.0
18	RSV Tank		14-1,2,3 RESIST8	4.0
19	RSV Tank		14-1,2,3 RESIST9	4.0
20	UNUSED			



Front

F2 Tank Area (12-2)

No.	Tank	Point of Use	Setting
1	RSV Tank	15-1,2,3 RESIST1	4.0
2	RSV Tank	16-1,2,3 RESIST1	4.0
3	RSV Tank	15-1,2,3 RESIST2	4.0
4	RSV Tank	16-1,2,3 RESIST2	4.0
5	RSV Tank	15-1,2,3 RESIST3	4.0
6	RSV Tank	16-1,2,3 RESIST3	4.0
7	RSV Tank	15-1,2,3 RESIST4	4.0
8	RSV Tank	16-1,2,3 RESIST4	4.0
9	RSV Tank	15-1,2,3 RESIST9	4.0
10	UNUSED		
11	RSV Tank	15-1,2,3 RESIST5	4.0
12	RSV Tank	16-1,2,3 RESIST5	4.0
13	RSV Tank	15-1,2,3 RESIST6	4.0
14	RSV Tank	16-1,2,3 RESIST6	4.0
15	RSV Tank	15-1,2,3 RESIST7	4.0
16	RSV Tank	16-1,2,3 RESIST7	4.0
17	RSV Tank	15-1,2,3 RESIST8	4.0
18	RSV Tank	16-1,2,3 RESIST8	4.0
19	RSV Tank	16-1,2,3 RESIST9	4.0
20	UNUSED		

5.2. System Config Parameter, Spinners (COT/ITC) *Imm

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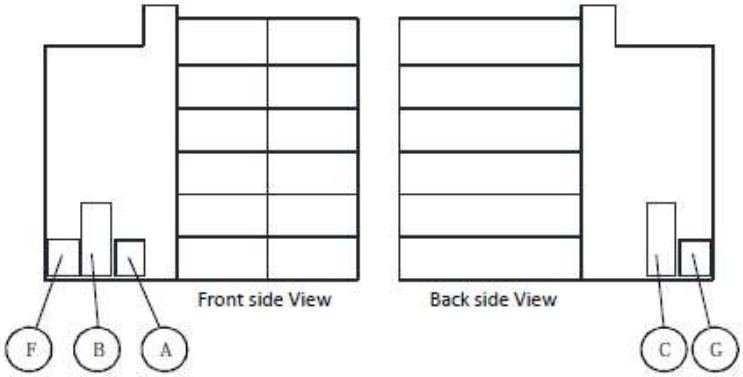

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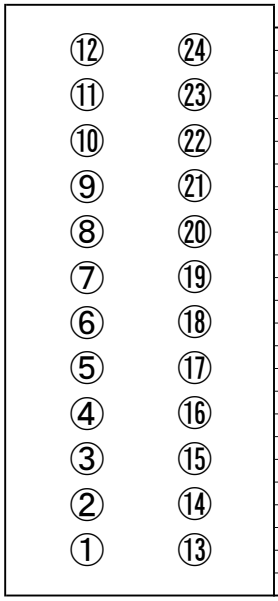


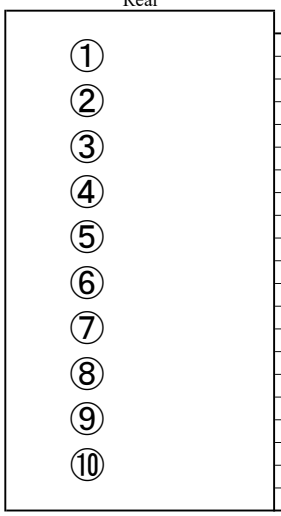
Front

B Tank Area (upper)

No.	Tank		Point of Use	Setting
1	RSV Tank		11-1,2 RESIST1	2.5
2	RSV Tank		12-1,2 RESIST1	1.5
3	RSV Tank		13-1,2 RESIST1	3.0
4	RSV Tank		11-1,2 RESIST2	2.5
5	RSV Tank		12-1,2 RESIST2	1.5
6	RSV Tank		13-1,2 RESIST2	3.0
7	RSV Tank		11-1,2 RESIST3	2.5
8	RSV Tank		12-1,2 RESIST3	1.5
9	RSV Tank		13-1,2 RESIST3	3.0
10	RSV Tank		11-1,2 RESIST4	2.5
11	RSV Tank		12-1,2 RESIST4	1.5
12	RSV Tank		13-1,2 RESIST4	3.0
13	RSV Tank		11-1,2 RESIST5	2.5
14	RSV Tank		12-1,2 RESIST5	1.5
15	RSV Tank		13-1,2 RESIST5	3.0
16	RSV Tank		11-1,2 RESIST6	2.5
17	RSV Tank		12-1,2 RESIST6	1.5
18	RSV Tank		13-1,2 RESIST6	3.0
19	RSV Tank		11-1,2 RESIST7	2.5
20	RSV Tank		12-1,2 RESIST7	1.5
21	RSV Tank		13-1,2 RESIST7	3.0
22	UNUSED			
23	UNUSED			
24	UNUSED			

C

Rear



C Bottle &Tank Area

No.	Tank	Point of Use	Setting
1	RSV Tank	11-3,4, RESIST1	2.0
2	RSV Tank	12-3,4, RESIST1	3.0
3	RSV Tank	13-3,4, RESIST1	3.5
4	RSV Tank	11-3,4, RESIST2	2.0
5	RSV Tank	12-3,4, RESIST2	3.0
6	RSV Tank	13-3,4, RESIST2	3.5
7	RSV Tank	11-3,4, RESIST3	2.0
8	RSV Tank	12-3,4, RESIST3	3.0
9	RSV Tank	13-3,4, RESIST3	3.5
10	UNUSED		

5.2. System Config Parameter, Spinners (COT/ITC) *EUV

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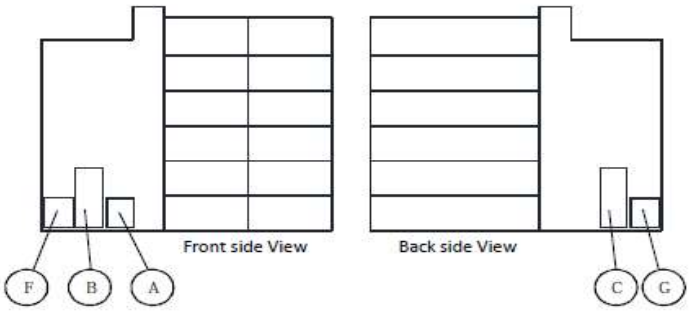

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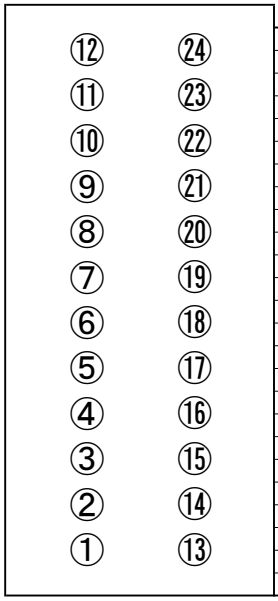


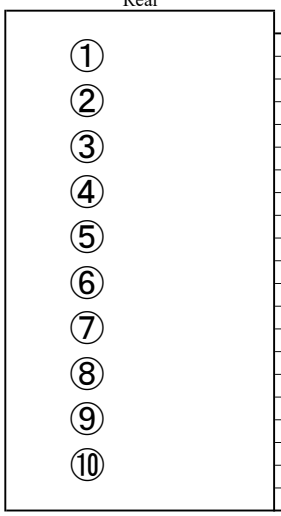
Front

B Tank Area (upper)

No.	Tank		Point of Use	Setting
1	RSV Tank		(Future Plan)	
2	RSV Tank		12-1,2 RESIST1	1.5
3	RSV Tank		13-1,2 RESIST1	3.0
4	RSV Tank		(Future Plan)	
5	RSV Tank		12-1,2 RESIST2	1.5
6	RSV Tank		13-1,2 RESIST2	3.0
7	RSV Tank		(Future Plan)	
8	RSV Tank		12-1,2 RESIST3	1.5
9	RSV Tank		13-1,2 RESIST3	3.0
10	RSV Tank		(Future Plan)	
11	RSV Tank		12-1,2 RESIST4	1.5
12	RSV Tank		13-1,2 RESIST4	3.0
13	RSV Tank		(Future Plan)	
14	RSV Tank		12-1,2 RESIST5	1.5
15	RSV Tank		13-1,2 RESIST5	3.0
16	RSV Tank		(Future Plan)	
17	RSV Tank		12-1,2 RESIST6	1.5
18	RSV Tank		13-1,2 RESIST6	3.0
19	RSV Tank		(Future Plan)	
20	RSV Tank		12-1,2 RESIST7	1.5
21	RSV Tank		13-1,2 RESIST7	3.0
22	UNUSED			
23	UNUSED			
24	UNUSED			

C

Rear



C Bottle &Tank Area

No.	Tank	Point of Use	Setting
1	RSV Tank	(Future Plan)	
2	RSV Tank	12-3,4, RESIST1	3.0
3	RSV Tank	13-3,4, RESIST1	3.5
4	RSV Tank	(Future Plan)	
5	RSV Tank	12-3,4, RESIST2	3.0
6	RSV Tank	13-3,4, RESIST2	3.5
7	RSV Tank	(Future Plan)	
8	RSV Tank	12-3,4, RESIST3	3.0
9	RSV Tank	13-3,4, RESIST3	3.5
10	UNUSED		

5.2. System Config Parameter, Spinners (COT) *TBZ

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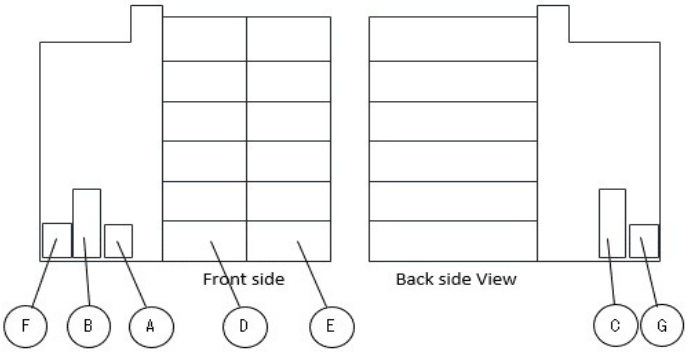

B

⑫
⑪
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①

Front

B Tank Area (upper)

No.	Tank		Point of Use	Setting
1	RSV Tank		(Future Plan)	
2	RSV Tank		13-3,4 RESIST1	1.5
3	RSV Tank		14-3,4 RESIST1	1.5
4	RSV Tank		(Future Plan)	
5	RSV Tank		13-3,4 RESIST2	1.5
6	RSV Tank		14-3,4 RESIST2	1.5
7	RSV Tank		(Future Plan)	
8	RSV Tank		13-3,4 RESIST3	1.5
9	RSV Tank		14-3,4 RESIST3	1.5
10	RSV Tank		(Future Plan)	
11	RSV Tank		13-3,4 RESIST4	1.5
12	RSV Tank		14-3,4 RESIST4	1.5

C

Rear

①
②
③
④
⑤
⑥
⑦
⑧
⑨
⑩
⑪
⑫

C Bottle & Tank Area

No.	Tank	Point of Use	Setting
1	RSV Tank	(Future Plan)	
2	RSV Tank	13-1,2 RESIST1	1.5
3	RSV Tank	14-1,2 RESIST1	1.5
4	RSV Tank	(Future Plan)	
5	RSV Tank	13-1,2 RESIST2	1.5
6	RSV Tank	14-1,2 RESIST2	1.5
7	RSV Tank	(Future Plan)	
8	RSV Tank	13-1,2 RESIST3	1.5
9	RSV Tank	14-1,2 RESIST3	1.5
10	RSV Tank	(Future Plan)	
11	RSV Tank	13-1,2 RESIST4	1.5
12	RSV Tank	14-1,2 RESIST4	1.5

5.2. System Config Parameter, Spinners (COT) *TBN

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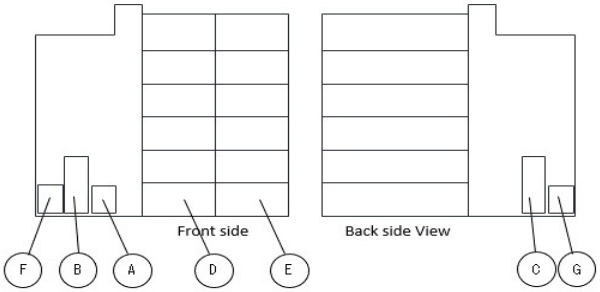
Reload Initial Pressure
and
Pump Return Vent Initial Pressure Settings



B

Front

⑫
⑪
⑩
⑨
⑧
⑦
⑥
⑤
④
③
②
①

B Tank Area (upper)

No.	Tank		Point of Use	Setting
1	RSV Tank		12-3,4 RESIST1	1.5
2	RSV Tank		13-3,4 RESIST1	1.5
3	RSV Tank		14-3,4 RESIST1	1.5
4	RSV Tank		12-3,4 RESIST2	1.5
5	RSV Tank		13-3,4 RESIST2	1.5
6	RSV Tank		14-3,4 RESIST2	1.5
7	RSV Tank		12-3,4 RESIST3	1.5
8	RSV Tank		13-3,4 RESIST3	1.5
9	RSV Tank		14-3,4 RESIST3	1.5
10	RSV Tank		12-3,4 RESIST4	1.5
11	RSV Tank		13-3,4 RESIST4	1.5
12	RSV Tank		14-3,4 RESIST4	1.5

C

Rear

①
②
③
④
⑤
⑥
⑦
⑧
⑨
⑩
⑪
⑫

C Bottle & Tank Area

No.	Tank	Point of Use	Setting
1	RSV Tank	12-1,2 RESIST1	1.5
2	RSV Tank	13-1,2 RESIST1	1.5
3	RSV Tank	14-1,2 RESIST1	1.5
4	RSV Tank	12-1,2 RESIST2	1.5
5	RSV Tank	13-1,2 RESIST2	1.5
6	RSV Tank	14-1,2 RESIST2	1.5
7	RSV Tank	12-1,2 RESIST3	1.5
8	RSV Tank	13-1,2 RESIST3	1.5
9	RSV Tank	14-1,2 RESIST3	1.5
10	RSV Tank	12-1,2 RESIST4	1.5
11	RSV Tank	13-1,2 RESIST4	1.5
12	RSV Tank	14-1,2 RESIST4	1.5

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5.2. System Config Parameter, Spinners (COT/BCT/ITC)

RRC NOZZLE1 / DRN CASE CLEAN / NZL/BATH CLN R# / NZL/BATH CLN CMN / NZL/BATH CLN ALL

	RRC Nozzle1 / DRN CASE CLEAN	NZL/BATH CLN R# / NZL/BATH CLN CMN / NZL/BATH CLN ALL
Process Recipe Attribute	Valid	Invalid
Dummy Dispense Attribute	Valid	Invalid

Dispense Mechanism Connection [1]

Valid, Invalid	Valid

Dispense Monitoring Mechanism Connection

Valid, Invalid	Valid

UltrasonicType flow meter

Dispense Monitoring Type	UltrasonicType flow meter

CRF Setting

Valid, Invalid	Valid

Interval for Circulation

	COT/BCT	ITC
Valid, Invalid	Valid	Valid
Time for Circulation Recovery	60	1,200
Time for Continuous Circulation	60	15

Flow Watch

Measurement Valid/Invalid	Invalid
Measurement Start Delay Time	3.0
Measurement Time	5.0
Monitoring Set Value for Warning	45

Supply System [1]

Valid, Invalid	Valid

Suckback Start Delay Time

Time (sec)	2000

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid
Sensor Channel No.	See table1
Chemical Name	SOLVENT/CYCLOHEXANONE
FRType	See table2
LL Mode	Invalid

Table1 for Sensor Channel No. [BARC tool]

RRC Nozzle1	DRN CASE CLEAN	NZL/BATH CLN R#	NZL/BATH CLN CMN
6	4	1	1

Table1 for Sensor Channel No. [Imm tool, KrF tool]

RRC Nozzle1	DRN CASE CLEAN	NZL/BATH CLN R#	NZL/BATH CLN CMN
4	2	1	1

Table2 for FRType [BARC tool]

RRC Nozzle1	DRN CASE CLEAN	NZL/BATH CLN R#	NZL/BATH CLN CMN
TYPE3(300ml)	TYPE3(300ml)	TYPE2(3000ml)	TYPE2(3000ml)

Table2 for FRType [Imm tool, KrF tool]

RRC Nozzle1	DRN CASE CLEAN	NZL/BATH CLN R#	NZL/BATH CLN CMN
TYPE3(300ml)	TYPE3(300ml)	TYPE2(3000ml)	TYPE2(3000ml)

Wash after Dispensing with Sub-Operating Panel

Set, Not set	Not Set

Wash Time after Dispensing

Time (sec)	10

Solvent 1 Supply System - [Tool Specific]

Item / Dispense	RRC NOZZLE1	DRN CASE CLEAN	NZL/BATH CLN R#	NZL/BATH CLN CMN	NZL/BATH CLN ALL
Refill Monitoring Time	180	180	180	180	N/A
Pre-Refill Decompress Time	20.0	20.0	20.0	20.0	N/A
Post-Refill Vent Time	1.0	1.0	1.0	1.0	N/A
Post-Refill Pressurize Time	15.0	15.0	15.0	15.0	N/A
Post-Refill Depressurize Time	60.0	60.0	60.0	60.0	N/A
Post-Refill Delay Time	1	1	1	1	N/A
Supply Valve Close Delay Time	0.1	0.1	0.1	0.1	N/A
N2 Dissolution Monitoring Time	0	0	0	0	N/A
Vent Time at IFF-S	150	150	150	150	N/A
Monitoring Time for Chemical Replacement	0	0	0	0	N/A
Vent Time at Chemical Replacement	150	150	150	150	N/A
Tank Switch during Dispensing	Valid	Valid	Valid	Valid	N/A
Return Mode Setting	Valid	Valid	Valid	Valid	N/A

CRF Setting

	BCT/COT/ITC
Wait Time for Circulation Recovery	240
Guarantee Time of Continuous Circulation	0
Circulation Buffer Pressure Release Time	1
Circulation Liquid Vent Monitoring Time	60
Pressurization Time for Circulation Switching	3
Vent Time for Circulation Switching	0
Small-Pressurization Time for Circulation Switching	1

Solvent* Supply System/Chemical Installation/Sequence*/Step*

see table bellow

CSS Refill System [1]

Valid, Invalid	Valid

Failsafe Valve

Failsafe Valve Close Delay Time	0.0 sec

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5.2. System Config Parameter, Spinners (COT/BCT/ITC)

Solvent1 Supply System/Chemical Installation/Sequence*/Step* (Does not matter to intel)

		Sequence(1)	Sequence(2)	Sequence(3)	Sequence(4)	Sequence(5)
STEP1	ProcessName	A1	A1	PCS Install	PCS Install	F1
	Buffer No	None	None	1	1	None
	ProcessTime	9	9	9	9	5
	Wait time	10	10	10	10	10
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP2	ProcessName	Repeat	Repeat	PCS Install	PCS Install	F2
	Buffer No	None	None	2	2	None
	ProcessTime	None	None	9	9	5
	Wait time	None	None	10	10	10
	Repeat Count	53	53	None	None	None
	Repeat Start Step No	1	1	None	None	None
STEP3	ProcessName	OpeCall	Opecall	PCS Vent	PCS Vent	PCS Vent
	Buffer No	None	None	1	1	1
	ProcessTime	None	None	3	3	3
	Wait time	None	None	10	10	10
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP4	ProcessName	F1	F1	PCS Refill	PCS Refill	PCS Refill
	Buffer No	None	None	1	1	1
	ProcessTime	5	5	5	5	5
	Wait time	10	10	10	10	10
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP5	ProcessName	F2	F2	PCS Vent	PCS Vent	PCS Vent
	Buffer No	None	None	2	2	2
	ProcessTime	9	9	3	3	3
	Wait time	10	10	10	10	10
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP6	ProcessName	PCS Install	None	PCS Refill	PCS Refill	PCS Refill
	Buffer No	1	None	2	2	2
	ProcessTime	9	None	5	5	5
	Wait time	10	None	10	10	10
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP7	ProcessName	PCS Install	None	F1	F1	F1
	Buffer No	2	None	None	None	None
	ProcessTime	9	None	1	1	1
	Wait time	10	None	10	10	10
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP8	ProcessName	PCS Vent	None	F2	F2	F2
	Buffer No	1	None	None	None	None
	ProcessTime	3	None	1	1	1
	Wait time	10	None	10	10	10
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP9	ProcessName	PCS Refill	None	Repeat	Repeat	Repeat
	Buffer No	1	None	None	None	None
	ProcessTime	5	None	None	None	None
	Wait time	10	None	None	None	None
	Repeat Count	None	None	59	29	3
	Repeat Start Step No	None	None	3	3	1
STEP10	ProcessName	PCS Vent	None	None	None	None
	Buffer No	2	None	None	None	None
	ProcessTime	3	None	None	None	None
	Wait time	10	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None

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5.2. System Config Parameter, Spinners (COT/BCT/ITC)

Solvent2 Supply System/Chemical Installation/Sequence*/Step* (Does not matter to intel)

		Sequence(1)	Sequence(2)	Sequence(3)	Sequence(4)	Sequence(5)
STEP11	ProcessName	PCS Refill	None	None	None	None
	Buffer No	2	None	None	None	None
	ProcessTime	5	None	None	None	None
	Wait time	10	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP12	ProcessName	F1	None	None	None	None
	Buffer No	None	None	None	None	None
	ProcessTime	1	None	None	None	None
	Wait time	10	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP13	ProcessName	F2	None	None	None	None
	Buffer No	None	None	None	None	None
	ProcessTime	1	None	None	None	None
	Wait time	10	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP14	ProcessName	Repeat	None	None	None	None
	Buffer No	None	None	None	None	None
	ProcessTime	None	None	None	None	None
	Wait time	None	None	None	None	None
	Repeat Count	7	None	None	None	None
	Repeat Start Step No	8	None	None	None	None
STEP15	ProcessName	None	None	None	None	None
	Buffer No	None	None	None	None	None
	ProcessTime	None	None	None	None	None
	Wait time	None	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP16	ProcessName	None	None	None	None	None
	Buffer No	None	None	None	None	None
	ProcessTime	None	None	None	None	None
	Wait time	None	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP17	ProcessName	None	None	None	None	None
	Buffer No	None	None	None	None	None
	ProcessTime	None	None	None	None	None
	Wait time	None	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP18	ProcessName	None	None	None	None	None
	Buffer No	None	None	None	None	None
	ProcessTime	None	None	None	None	None
	Wait time	None	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP19	ProcessName	None	None	None	None	None
	Buffer No	None	None	None	None	None
	ProcessTime	None	None	None	None	None
	Wait time	None	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP20	ProcessName	None	None	None	None	None
	Buffer No	None	None	None	None	None
	ProcessTime	None	None	None	None	None
	Wait time	None	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None

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5.2. System Config Parameter, Spinners (COT/BCT/ITC)

Dispense Monitoring Control Data

Item / Dispense	RRC NOZZLE1	DRN CASE CLEAN	NZL/BATH CLN R#	NZL/BATH CLN CMN	NZL/BATH CLN ALL
Pulse Rate	0.005	0.005	0.05	0.05	N/A
Delay Time	0.60	0.60	0.60	0.60	N/A
Set Flow Rate	70	See table	100	300	N/A
Flow Rate Sensor Check Timing	Dispense end	Dispense end	Dispense end	Dispense end	N/A
Calibration 1	POS = 0.85 - 0.99 PGMEA = 1.00 - 1.25 EL = 0.98 - 1.12	1.00	1.00	1.00	N/A
Offset	0	0	0	0	N/A
Upper Limit Error Level	30.00%	30.00%	30.00%	30.00%	N/A
Upper Limit Warning Leavel	20.00%	20.00%	20.00%	20.00%	N/A
Lower Limit Error Level	30.00%	30.00%	25.00%	30.00%	N/A
Lower Limit Warning Level	20.00%	20.00%	20.00%	20.00%	N/A
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid	Valid	Valid	Valid	N/A
Reporting Dispense Amount to Dispense State Monitor	Valid	Valid	Valid	Valid	N/A
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute	Execute	Execute	Execute	N/A
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0	1.0	1.0	1.0	N/A
Monitoring Flow Rate Lower Limit for Short Time Dispense	NA	NA	Non Execute	Non Execute	N/A
Flow Rate Lower Limit Non-monitoring Time for Short Time Dispense	NA	NA	1.5	1.5	N/A

KEEP ARM POS

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection

Valid, Invalid	Valid

Table for DRN CASE CLEAN

	TBF	TAP/TNP/TAF		TAW/TAJ		TBZ	TBN
	BCT	COT	ITC	COT	ITC	COT	COT
Deck11	NA	300ml/min*	275ml/min*	NA	NA	NA	NA
Deck12	NA	250ml/min	250ml/min	300ml/min*	275ml/min*	NA	275ml/min*
Deck13	350ml/min*	250ml/min	250ml/min	250ml/min	250ml/min	275ml/min*	275ml/min*
Deck14	250ml/min	NA	NA	NA	NA	275ml/min*	275ml/min*
Deck15	250ml/min	NA	NA	NA	NA	NA	NA
Deck16	250ml/min	NA	NA	NA	NA	NA	NA

* Drain Case Clean of bottom deck is branched to Resist individual drain manifold clean line.
Therefore, a higher flow rate than other decks is required.

RRC FILTDRAIN1/2

Process Recipe Attribute	Invalid
Dummy Dispense Attribute	Invalid
IFF-S Supported Nozzle	Tool Specific

Dispense Mechanism Connection

Valid, Invalid	Valid

Dispense Monitoring Mechanism Connection

Valid, Invalid	Valid

UltrasonicType flow meter

Dispense Monitoring Type	UltrasonicType flow meter

Flow Watch

Measurement Valid/Invalid	Invalid
Measurement Start Delay Time	3.0
Measurement Time	5.0
Monitoring Set Value for Warning	45

Supply System [1]

Valid, Invalid	Valid

SOLVENT-A/B/C/D Supply System

Supply System Type	Solvent super clean supply sys
Chemical Name	SOLVENT-A/B/C/D
Refill Monitoring Time	180
Pre-Refill Decompress Time	30.0
Post-Refill Vent Time	1.0
Post-Refill Pressurize Time	15.0
Post-Refill Depressurize Time	60
Post-Refill Delay Time	1
Vent Time at Chemical Drain	150
Filter Replacement Supply System No.	Tool Specific

CRF Setting

Valid, Invalid	Valid

Interval for Circulation

	RRC FILTDRAIN1	RRC FILTDRAIN2
Valid, Invalid	Valid	Valid
Time for Circulation Recovery	60	1200
Time for Continuous Circulation	60	15

Interval for Circulation*KrF

	RRC FILTDRAIN1	RRC FILTDRAIN2
Valid, Invalid	Valid	Valid
Time for Circulation Recovery	60	60
Time for Continuous Circulation	60	60

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid
Sensor Channel No.	6
Chemical Name	SOLVENT/CYCLOHEXANONE
FRType	TYPE3(300ml/min)
LL Mode	Invalid

Regular Retrieval of Flow Rate *KrF

Regular Retrieval of Flow Rate, Valid/Invalid	Valid
Sensor Channel No.	4
Chemical Name	SOLVENT/Other
FRType	TYPE3(300ml/min)
LL Mode	Invalid

Report of Divided Flow Rate

Report of Divided Flow Rate, Valid/Invalid	Valid
Chemical Usage Monitoring Report	Valid

5.2. System Config Parameter, Spinners (COT/BCT/ITC)

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Filter Replacement Sequence

		Filter Replacement Sequence(1)[1]	Filter Replacement Sequence(2)[2]	Filter Replacement Sequence(3)[3]	Filter Replacement Sequence(4)[4]	Filter Replacement Sequence(5)[5]	Filter Replacement Sequence(6)[6]	Filter Replacement Sequence(7)[7]	Filter Replacement Sequence(8)[8]	Filter Replacement Sequence(9)[9]
	Comment	IFF-1	IFF-2	IFF-3	IFF-4	IFF-5	IFF-6	IFF-7	IFF-8	IFF-9
STEP1	PressureSetting	10 sec	10 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	LL	LL	None	None	None	None	None	None	None
	ProcessTime	Hold	Hold	None	None	None	None	None	None	None
STEP2	PressureSetting	200 sec	200 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	LL	LL	None	None	None	None	None	None	None
	ProcessTime	Filter Vent	Filter Vent	None	None	None	None	None	None	None
STEP3	PressureSetting	640 sec	100 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	L	L	None	None	None	None	None	None	None
	ProcessTime	Filter Out	Filter Out	None	None	None	None	None	None	None
STEP4	PressureSetting	600 sec	1200 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	None	L	None	None	None	None	None	None	None
	ProcessTime	Hold	Filter Out	None	None	None	None	None	None	None
STEP5	PressureSetting	3200 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	L	None	None	None	None	None	None	None	None
	ProcessTime	Filter Out	None	None	None	None	None	None	None	None
STEP6	PressureSetting	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	None	None	None	None	None	None	None	None	None
	ProcessTime	None	None	None	None	None	None	None	None	None
STEP7	PressureSetting	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	None	None	None	None	None	None	None	None	None
	ProcessTime	None	None	None	None	None	None	None	None	None
STEP8	PressureSetting	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	None	None	None	None	None	None	None	None	None
	ProcessTime	None	None	None	None	None	None	None	None	None
STEP9	PressureSetting	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	None	None	None	None	None	None	None	None	None
	ProcessTime	None	None	None	None	None	None	None	None	None
STEP10	PressureSetting	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	None	None	None	None	None	None	None	None	None
	ProcessTime	None	None	None	None	None	None	None	None	None
STEP11	PressureSetting	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	None	None	None	None	None	None	None	None	None
	ProcessTime	None	None	None	None	None	None	None	None	None
STEP12	PressureSetting	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	None	None	None	None	None	None	None	None	None
	ProcessTime	None	None	None	None	None	None	None	None	None
STEP13	PressureSetting	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	None	None	None	None	None	None	None	None	None
	ProcessTime	None	None	None	None	None	None	None	None	None
STEP14	PressureSetting	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	None	None	None	None	None	None	None	None	None
	ProcessTime	None	None	None	None	None	None	None	None	None
STEP15	PressureSetting	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	None	None	None	None	None	None	None	None	None
	ProcessTime	None	None	None	None	None	None	None	None	None
STEP16	PressureSetting	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	None	None	None	None	None	None	None	None	None
	ProcessTime	None	None	None	None	None	None	None	None	None
STEP17	PressureSetting	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	None	None	None	None	None	None	None	None	None
	ProcessTime	None	None	None	None	None	None	None	None	None
STEP18	PressureSetting	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	None	None	None	None	None	None	None	None	None
	ProcessTime	None	None	None	None	None	None	None	None	None
STEP19	PressureSetting	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	None	None	None	None	None	None	None	None	None
	ProcessTime	None	None	None	None	None	None	None	None	None
STEP20	PressureSetting	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec	0 sec
	ProcessName	None	None	None	None	None	None	None	None	None
	ProcessTime	None	None	None	None	None	None	None	None	None

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5.2. System Config Parameter, Spinners (COT/BCT/ITC)

Dispense Monitoring Control Data

Pulse Rate	0.005
Delay Time	0.60
Set Flow Rate	75
Flow Rate Sensor Check Timing	None
Calibration 1	1.00
Offset	0
Upper Limit Error Level	30.00
Upper Limit Warning Leavel	20.00
Lower Limit Error Level	30.00
Lower Limit Warning Level	20.00
Reporting Dispense Amount to Dispense State Monitor	Valid
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Invalid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Not Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

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5.2. System Config Parameter, Spinners (COT/BCT/ITC)

Local Nozzle

E.B.R.1 / BACK RINSE1 / BEVEL RINSE V2 / EXH DUCT CLEAN

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid *

* Invalid for BACK RINSE1 and BEVEL RINSE

Dispense Mechanism Connection

Valid, Invalid	Valid

Dispense Monitoring Mechanism Connection

Valid, Invalid	Valid

UltrasonicType flow meter

Dispense Monitoring Type	UltrasonicType flow meter

Supply System

Valid, Invalid	Valid

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid
Sensor Channel No.	See table
Chemical Name	SOLVENT/CYCLOHEXANONE
FRType	TYPE3(300ml/min)
LL Mode	Invalid

Table for Sensor Channel No. [BARC tool]

Module / Dispense	E.B.R.1	BACK RINSE1	BEVEL RINSE V2	EXH DUCT CLEAN
1*-1	5	2	5	2
1*-2	5	3	5	3
1*-3	5	4	5	4

Table for Sensor Channel No. [Imm tool]

E.B.R.1	BACK RINSE1	BEVEL RINSE V2	EXH DUCT CLEAN
3	2	3	2

Table for Sensor Channel No. [KrF tool]

E.B.R.1	BACK RINSE1	BEVEL RINSE V2	EXH DUCT CLEAN
3	2	NA	2

Solvent 1 Supply System - [Tool Specific]

Item / Dispense	E.B.R.1	BACK RINSE1	BEVEL RINSE V2	EXH DUCT CLEAN
Refill Monitoring Time	180	180	180	180
Pre-Refill Decompress Time	20.0	20.0	20.0	20.0
Post-Refill Vent Time	1.0	1.0	1.0	1.0
Post-Refill Pressurize Time	15.0	15.0	15.0	15.0
Post-Refill Depressurize Time	60.0	60.0	60.0	60.0
Post-Refill Delay Time	1	1	1	1
Supply Valve Close Delay Time	0.10	0.10	0.10	0.10
N2 Dissolution Monitoring Time	0	0	0	0
Vent Time at IFF-S	150	150	150	150
Monitoring Time for Chemical Replacement	0	0	0	0
Vent Time at Chemical Replacement	150	150	150	150
Tank Switch during Dispensing	Valid	Valid	Valid	Valid
Return Mode Setting	Valid	Valid	Valid	Valid

CRF Setting

	COT/ITC/BCT
Wait Time for Circulation Recovery	240
Guarantee Time of Continuous Circulation	0
Circulation Buffer Pressure Release Time	1
Circulation Liquid Vent Monitoring Time	60
Pressurization Time for Circulation Switching	3
Vent Time for Circulation Switching	0
Small-Pressurization Time for Circulation Switching	1

Solvent2 Supply System/Chemical Installation/Sequence*/Step*

see below table

CSS Refill System [1]

Valid, Invalid	Valid

Failsafe Valve

Failsafe Valve Close Delay Time	0.0 sec

Dispense Monitoring Control Data

Item / Dispense	E.B.R.1	BACK RINSE1	BEVEL RINSE V2	EXH DUCT CLEAN
Pulse Rate	0.005	0.005	0.005	0.005
Delay Time	0.60	0.60	0.60	0.60
Set Flow Rate	20	100	50	200
Flow Rate Sensor Check Timing	In Dispense + Dispense End	Dispense end	Dispense end	Dispense end
Calibration 1	POS = 0.85 - 0.99 PGMEA = 1.00 - 1.25 EL = 0.98 - 1.12	1.00	1.00	1.00
Offset	0	0	0	0
Upper Limit Error Level	40.00%	30.00%	30.00%	30.00%
Upper Limit Warning Leavel	30.00%	20.00%	20.00%	20.00%
Lower Limit Error Level	30.00%	30.00%	30.00%	30.00%
Lower Limit Warning Level	20.00%	20.00%	20.00%	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid	Invalid	Invalid	Valid
Reporting Dispense Amount to Dispense State Monitor	Valid	Valid	Valid	Valid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute	Execute	Execute	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0	1.0	1.0	1.0

***KrF Tool no Bevel rinse V2**

Flow Rate during Dispense Process*

Invalidated Flow Rate Monitoring Times during Dispense Process	2 Times
Upper Limit Error Level for Flow Rate during Dispense Process	40.00%
Lower Limit Error Level for Flow Rate during Dispense Process	30.00%

* Only EBR dispense line of TBF448 present

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5.2. System Config Parameter, Spinners (COT/BCT/ITC)

Solvent2 Supply System/Chemical Installation/Sequence*/Step* (Does not matter to intel)

		Sequence(1)	Sequence(2)	Sequence(3)	Sequence(4)	Sequence(5)
STEP1	ProcessName	A1	A1	PCS Install	PCS Install	F1
	Buffer No	None	None	1	1	None
	ProcessTime	9	9	9	9	5
	Wait time	10	10	10	10	10
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP2	ProcessName	Repeat	Repeat	PCS Install	PCS Install	F2
	Buffer No	None	None	2	2	None
	ProcessTime	None	None	9	9	5
	Wait time	None	None	10	10	10
	Repeat Count	53	53	None	None	None
	Repeat Start Step No	1	1	None	None	None
STEP3	ProcessName	OpeCall	Opecall	PCS Vent	PCS Vent	PCS Vent
	Buffer No	None	None	1	1	1
	ProcessTime	None	None	3	3	3
	Wait time	None	None	10	10	10
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP4	ProcessName	F1	F1	PCS Refill	PCS Refill	PCS Refill
	Buffer No	None	None	1	1	1
	ProcessTime	5	5	5	5	5
	Wait time	10	10	10	10	10
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP5	ProcessName	F2	F2	PCS Vent	PCS Vent	PCS Vent
	Buffer No	None	None	2	2	2
	ProcessTime	9	9	3	3	3
	Wait time	10	10	10	10	10
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP6	ProcessName	PCS Install	None	PCS Refill	PCS Refill	PCS Refill
	Buffer No	1	None	2	2	2
	ProcessTime	9	None	5	5	5
	Wait time	10	None	10	10	10
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP7	ProcessName	PCS Install	None	F1	F1	F1
	Buffer No	2	None	None	None	None
	ProcessTime	9	None	1	1	1
	Wait time	10	None	10	10	10
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP8	ProcessName	PCS Vent	None	F2	F2	F2
	Buffer No	1	None	None	None	None
	ProcessTime	3	None	1	1	1
	Wait time	10	None	10	10	10
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP9	ProcessName	PCS Refill	None	Repeat	Repeat	Repeat
	Buffer No	1	None	None	None	None
	ProcessTime	5	None	None	None	None
	Wait time	10	None	None	None	None
	Repeat Count	None	None	59	29	3
	Repeat Start Step No	None	None	3	3	1
STEP10	ProcessName	PCS Vent	None	None	None	None
	Buffer No	2	None	None	None	None
	ProcessTime	3	None	None	None	None
	Wait time	10	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None

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5.2. System Config Parameter, Spinners (COT/BCT/ITC)

Solvent2 Supply System/Chemical Installation/Sequence*/Step* (Does not matter to intel)

		Sequence(1)	Sequence(2)	Sequence(3)	Sequence(4)	Sequence(5)
STEP11	ProcessName	PCS Refill	None	None	None	None
	Buffer No	2	None	None	None	None
	ProcessTime	5	None	None	None	None
	Wait time	10	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP12	ProcessName	F1	None	None	None	None
	Buffer No	None	None	None	None	None
	ProcessTime	1	None	None	None	None
	Wait time	10	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP13	ProcessName	F2	None	None	None	None
	Buffer No	None	None	None	None	None
	ProcessTime	1	None	None	None	None
	Wait time	10	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP14	ProcessName	Repeat	None	None	None	None
	Buffer No	None	None	None	None	None
	ProcessTime	None	None	None	None	None
	Wait time	None	None	None	None	None
	Repeat Count	7	None	None	None	None
	Repeat Start Step No	8	None	None	None	None
STEP15	ProcessName	None	None	None	None	None
	Buffer No	None	None	None	None	None
	ProcessTime	None	None	None	None	None
	Wait time	None	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP16	ProcessName	None	None	None	None	None
	Buffer No	None	None	None	None	None
	ProcessTime	None	None	None	None	None
	Wait time	None	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP17	ProcessName	None	None	None	None	None
	Buffer No	None	None	None	None	None
	ProcessTime	None	None	None	None	None
	Wait time	None	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP18	ProcessName	None	None	None	None	None
	Buffer No	None	None	None	None	None
	ProcessTime	None	None	None	None	None
	Wait time	None	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP19	ProcessName	None	None	None	None	None
	Buffer No	None	None	None	None	None
	ProcessTime	None	None	None	None	None
	Wait time	None	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None
STEP20	ProcessName	None	None	None	None	None
	Buffer No	None	None	None	None	None
	ProcessTime	None	None	None	None	None
	Wait time	None	None	None	None	None
	Repeat Count	None	None	None	None	None
	Repeat Start Step No	None	None	None	None	None

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5.2. System Config Parameter, Spinners (COT/BCT/ITC)

CUP EXH.

Process Recipe Attribute	Invalid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection

Valid, Invalid	Valid

Spinner Exhaust Monitoring Control Data

Item / Dispense	CUP EXH.	CUP EXH.(KrF Tool)
High Pressure	65.00/*63.00	65.00/*63.00
High Pressure (Error Lower Limit)	45.00/*43.00	45.00/*43.00
Low Pressure	23.00/*22.00	13.00/*13.00
Low Pressure (Error Upper Limit)	45.00/*43.00	45.00/*43.00
Cup EXH. Monitoring Start Delay Time	3000	3000
Offset	0.0	0.0
Cup EXH. Monitoring Valid(1)/Invalid(0)	1	1

***High altitude setting**

EXH. DRAIN PUMP

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection

Valid, Invalid	Valid

CMN CUP EXH.

Process Recipe Attribute	Invalid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection

Valid, Invalid	Valid

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5.2. System Config Parameter, Spinners (COT/BCT/ITC)

Monitoring Parameter

Resist temp. / Cup temp. / Motor flamge temp. / Cup humidity / Cup exhaust flow / BCT COT ITC Temp. Control flow rate

Item	Resist temp.	Cup temp.	Motor flange temp.	Cup humidity	Cup exhaust flow	BCT/COT/ITC Temp. Control flow rate
Valid,Invalid	Valid	Valid	Valid	Valid	Valid	Valid
Measured Data ID	Resist temp.	Cup temp.	Motor flange temp.	Cup humidity	Cup exhaust flow	BCT Temp. Control flow rate
Recipe Setting Method	System recipe	System recipe	System recipe	System recipe	System recipe	Local
Temperature Control Method	See Table	See Table	See Table	See Table	See Table	See Table
Recipe Verification Range Lower Limit	20.00	20.00	20.00	28.00	0.00	0.00
Recipe Verification Range Upper Limit	25.00	27.00	25.00	55.00	500.00	35.00

Table for Temperature Control Method [BARC tool]

Module	Resist temp.	Cup temp.	Motor flange temp.	Cup humidity	Cup exhaust flow	BCT/COT/ITC Temp. Control flow rate
13-1 (BCT)	Tmp ctl ON	Tmp ctl ON	Tmp ctl OFF	Tmp ctl ON	Tmp ctl ON	Tmp ctl ON
13-2 (BCT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
13-3 (BCT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl OFF
14-1 (BCT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl OFF
14-2 (BCT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
14-3 (BCT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl OFF
15-1 (BCT)	Tmp ctl ON	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl ON
15-2 (BCT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
15-3 (BCT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl OFF
16-1 (BCT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl OFF
16-2 (BCT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
16-3 (BCT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl OFF

Table for Temperature Control Method [Imm tool]

Module	Resist temp.	Cup temp.	Motor flange temp.	Cup humidity	Cup exhaust flow	BCT/COT/ITC Temp. Control flow rate
11-1 (COT)	Tmp ctl ON	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl OFF
11-2 (COT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
11-3 (ITC)	Tmp ctl ON	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl OFF
11-4 (ITC)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
12-1 (COT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl OFF
12-2 (COT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
12-3 (ITC)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl OFF
12-4 (ITC)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
13-1 (COT)	Tmp ctl OFF	Tmp ctl ON	Tmp ctl OFF	Tmp ctl ON	Tmp ctl ON	Tmp ctl ON
13-2 (COT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
13-3 (ITC)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl ON
13-4 (ITC)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF

Table for Temperature Control Method [EUV tool]

Module	Resist temp.	Cup temp.	Motor flange temp.	Cup humidity	Cup exhaust flow	BCT/COT/ITC Temp. Control flow rate
12-1 (COT)	Tmp ctl ON	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl OFF
12-2 (COT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
12-3 (ITC)	Tmp ctl ON	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl OFF
12-4 (ITC)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
13-1 (COT)	Tmp ctl OFF	Tmp ctl ON	Tmp ctl OFF	Tmp ctl ON	Tmp ctl ON	Tmp ctl ON
13-2 (COT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
13-3 (ITC)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl ON
13-4 (ITC)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF

Table for Temperature Control Method [KrF tool]

Module	Resist temp.	Cup temp.	Motor flange temp.	Cup humidity	Cup exhaust flow	BCT/COT/ITC Temp. Control flow rate
12-1 (COT)*	Tmp ctl ON	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl ON
12-2 (COT)*	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
12-3 (COT)*	Tmp ctl ON	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl ON
12-4 (COT)*	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
13-1 (COT)	Tmp ctl OFF**	Tmp ctl ON	Tmp ctl OFF	Tmp ctl ON	Tmp ctl ON	Tmp ctl OFF**
13-2 (COT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
13-3 (COT)	Tmp ctl OFF**	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl OFF**
13-4 (COT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
14-1 (COT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl OFF
14-2 (COT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF
14-3 (COT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl ON	Tmp ctl OFF
14-4 (COT)	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF	Tmp ctl OFF

*Not present on TBZ **TBZ = Tmp ctl ON

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5.2. System Config Parameter, Spinners (COT/BCT/ITC)

Controller TM206-CHILLER / THC

Item	Resist temp.	Cup temp.	Motor flange temp.	Cup humidity	BCT/COT/ITC Temp. Control flow rate
Controller ID	TM206-CHILLER	TM206-THC	TM206-CHILLER	TM206-THC	TM206-CHILLER
Channel No.	See Table	1	See Table	2	See Table
Monitoring Type	See Table	See Table	Use point read	See Table	N/A
Control Method	Standard	Standard	Standard	Standard	N/A
Use Point Offset	Tool specific	Tool specific	Tool specific	Tool specific	N/A
Band Monitoring Method at Process Start	Normal	Normal	Normal	Normal	N/A
Band Monitoring Invalid Time at Process Start	0.0	0.0	0.0	0.0	N/A
Band Monitoring Determination Method during Processing	No monitor	No monitor	No monitor	No monitor	N/A
Band Monitoring Determination Time during Processing	0.0	0.0	0.0	0.0	N/A
Band Monitoring Value during Processing	0.00	0.00	0.00	0.00	N/A
Source Value Monitoring Valid *	See Table	See Table	N/A	See Table	N/A
Source Value Monitoring Band *	10	10	N/A	10	N/A
Pump Frequency	Tool specific	N/A	Tool specific	N/A	N/A
Air Blower Frequency	N/A	30 ~ 60 Hz	N/A	30 ~ 60 Hz	N/A
Initial Data	22.20	22.20	22.20	40.7	N/A
Overtemperature	40.00	40.00	40.00	0.00	N/A
Setting Determination Time	5.0	5.0	5.0	5.0	N/A
Setting Time-out Time	3600.0	3600.0	3600.0	3600.0	N/A
Line No.	N/A	N/A	N/A	N/A	See Table
Set Value	N/A	N/A	N/A	N/A	2.00
Warning Range Lower Limit	N/A	N/A	N/A	N/A	100.00
Warning Range Upper Limit	N/A	N/A	N/A	N/A	100.00
Stop Range Lower Limit	N/A	N/A	N/A	N/A	100.00
Stop Range Upper Limit	N/A	N/A	N/A	N/A	100.00
Offset	N/A	N/A	N/A	N/A	0.00

*** = Only present with Temp control ON is active**

Table for TM206-CHILLER / THC(BARC tool)

Module	Resist temp.				Cup temp.		Motor flange temp.	Cup humidity		BCT Temp. Control flow rate	
	Channel No.	Monitoring Type		Source Value Monitoring Valid	Monitoring Type	Source Value Monitoring Valid	Channel No.	Monitoring Type	Source Value Monitoring Valid	Channel No.	Line No.
13-1 (BCT)	1	Use point control		Invalid	Use point control	Invalid	1	Use point control	Invalid	1	1
13-2 (BCT)	1	Use point read		N/A	Use point read	N/A	1	Use point read	N/A	1	1
13-3 (BCT)	1	Use point read		N/A	Use point read	N/A	1	Use point read	N/A	1	1
14-1 (BCT)	1	Use point read		N/A	Use point read	N/A	1	Use point read	N/A	1	1
14-2 (BCT)	1	Use point read		N/A	Use point read	N/A	1	Use point read	N/A	1	1
14-3 (BCT)	1	Use point read		N/A	Use point read	N/A	1	Use point read	N/A	1	1
15-1 (BCT)	2	Use point control		Invalid	Use point read	N/A	2	Use point read	N/A	2	2
15-2 (BCT)	2	Use point read		N/A	Use point read	N/A	2	Use point read	N/A	2	2
15-3 (BCT)	2	Use point read		N/A	Use point read	N/A	2	Use point read	N/A	2	2
16-1 (BCT)	2	Use point read		N/A	Use point read	N/A	2	Use point read	N/A	2	2
16-2 (BCT)	2	Use point read		N/A	Use point read	N/A	2	Use point read	N/A	2	2
16-3 (BCT)	2	Use point read		N/A	Use point read	N/A	2	Use point read	N/A	2	2

Table for TM206-CHILLER / THC(Imm Tool)

Module	Resist temp.				Cup temp.		Motor flange temp.	Cup humidity		COT/ITC Temp. Control flow rate	
	Channel No.	Monitoring Type		Source Value Monitoring Valid	Monitoring Type	Source Value Monitoring Valid	Channel No.	Monitoring Type	Source Value Monitoring Valid	Channel No.	Line No.
11-1 (COT)	1	Use point control		Invalid	Use point read	N/A	1	Use point read	N/A	1	1
11-2 (COT)	1	Use point read		N/A	Use point read	N/A	1	Use point read	N/A	1	1
11-3 (ITC)	2	Use point control		Invalid	Use point read	N/A	2	Use point read	N/A	2	2
11-4 (ITC)	2	Use point read		N/A	Use point read	N/A	2	Use point read	N/A	2	2
12-1 (COT)	1	Use point read		N/A	Use point read	N/A	1	Use point read	N/A	1	1
12-2 (COT)	1	Use point read		N/A	Use point read	N/A	1	Use point read	N/A	1	1
12-3 (ITC)	2	Use point read		N/A	Use point read	N/A	2	Use point read	N/A	2	2
12-4 (ITC)	2	Use point read		N/A	Use point read	N/A	2	Use point read	N/A	2	2
13-1 (COT)	1	Use point read		N/A	Use point control	Invalid	1	Use point control	Invalid	1	1
13-2 (COT)	1	Use point read		N/A	Use point read	N/A	1	Use point read	N/A	1	1
13-3 (ITC)	2	Use point read		N/A	Use point read	N/A	2	Use point read	N/A	2	2
13-4 (ITC)	2	Use point read		N/A	Use point read	N/A	2	Use point read	N/A	2	2

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Table for TM206-CHILLER / THC(EUV Tool)

Module	Resist temp.				Cup temp.		Motor flange temp.	Cup humidity		COT/ITC Temp. Control flow rate	
	Channel No.	Monitoring Type		Source Value Monitoring Valid	Monitoring Type	Source Value Monitoring Valid	Channel No.	Monitoring Type	Source Value Monitoring Valid	Channel No.	Line No.
12-1 (COT)	1	Use point control		Invalid	Use point read	N/A	1	Use point read	N/A	1	1
12-2 (COT)	1	Use point read		N/A	Use point read	N/A	1	Use point read	N/A	1	1
12-3 (ITC)	2	Use point control		Invalid	Use point read	N/A	2	Use point read	N/A	2	2
12-4 (ITC)	2	Use point read		N/A	Use point read	N/A	2	Use point read	N/A	2	2
13-1 (COT)	1	Use point read		N/A	Use point control	Invalid	1	Use point control	Invalid	1	1
13-2 (COT)	1	Use point read		N/A	Use point read	N/A	1	Use point read	N/A	1	1
13-3 (ITC)	2	Use point read		N/A	Use point read	N/A	2	Use point read	N/A	2	2
13-4 (ITC)	2	Use point read		N/A	Use point read	N/A	2	Use point read	N/A	2	2

Table for TM206-CHILLER / THC(KrF Tool)

Module	Resist temp.				Cup temp.		Motor flange temp.	Cup humidity		COT Temp. Control flow rate	
	Channel No.	Monitoring Type		Source Value Monitoring Valid	Monitoring Type	Source Value Monitoring Valid	Channel No.	Monitoring Type	Source Value Monitoring Valid	Channel No.	Line No.
13-1 (COT)	1	Use point control		Invalid	Use point control	Invalid	1	Use point control	Invalid	1	1
13-2 (COT)	1	Use point read		N/A	Use point read	N/A	1	Use point read	N/A	1	1
13-3 (COT)	2	Use point control		Invalid	Use point read	N/A	2	Use point read	N/A	2	2
13-4 (COT)	2	Use point read		N/A	Use point read	N/A	2	Use point read	N/A	2	2
14-1 (COT)	1	Use point read		N/A	Use point read	N/A	1	Use point read	N/A	1	1
14-2 (COT)	1	Use point read		N/A	Use point read	N/A	1	Use point read	N/A	1	1
14-3 (COT)	2	Use point read		N/A	Use point read	N/A	2	Use point read	N/A	2	2
14-4 (COT)	2	Use point read		N/A	Use point read	N/A	2	Use point read	N/A	2	2

Controller EPCA

Item	Cup exhasut flow
Controller ID	EPCA
Channel No.	See Table for Channel No.
Monitoring Type	No sync
Control Method	Standard
Band Monitoring Method at Process Start	Normal
Band Monitoring Invalid Time at Process Start	0.0
Band Monitoring Determination Method during Processing	No monitor
Band Monitoring Determination Time during Processing	1.0
Band Monitoring Value during Processing	300
PID Setting Method	Control setting
P Constant	30
I Constant	0.3
Exhaust Pressure Rise Time	1.0
Exhaust Pressure Drop Time	2.0
Initial Data	See Table
Setting Determination Time	3.0
Setting Time-out Time	1800.0
Pressure Sensor Type	500 Pa Sensor

Table for Channel No.(BARC Tool)

Module	Channel No.
13-1 (BCT)	4
13-2 (BCT)	4
13-3 (BCT)	5
14-1 (BCT)	6
14-2 (BCT)	6
14-3 (BCT)	7
15-1 (BCT)	8
15-2 (BCT)	8
15-3 (BCT)	9
16-1 (BCT)	10
16-2 (BCT)	10
16-3 (BCT)	11

Table for Channel No.(Imm Tool)

Module	Channel No.
11-1 (COT)	0
11-2 (COT)	0
11-3 (ITC)	1
11-4 (ITC)	1
12-1 (COT)	2
12-2 (COT)	2
12-3 (ITC)	3
12-4 (ITC)	3
13-1 (COT)	4
13-2 (COT)	4
13-3 (ITC)	5
13-4 (ITC)	5

Table for Initial Data(BARC Tool)

Module	Initial Data
13-1 (BCT)	310
13-2 (BCT)	310
13-3 (BCT)	160
14-1 (BCT)	310
14-2 (BCT)	310
14-3 (BCT)	160
15-1 (BCT)	310
15-2 (BCT)	310
15-3 (BCT)	160
16-1 (BCT)	310
16-2 (BCT)	310
16-3 (BCT)	160

Table for Initial Data(Imm Tool)

Module	Initial Data
11-1 (COT)	310
11-2 (COT)	310
11-3 (ITC)	310
11-4 (ITC)	310
12-1 (COT)	310
12-2 (COT)	310
12-3 (ITC)	310
12-4 (ITC)	310
13-1 (COT)	310
13-2 (COT)	310
13-3 (ITC)	310
13-4 (ITC)	310

Table for Channel No.(KrF Tool)

Module	Channel No.
13-1 (COT)	4
13-2 (COT)	4
13-3 (COT)	5
13-4 (COT)	5
14-1 (COT)	6
14-2 (COT)	6
14-3 (COT)	7
14-4 (COT)	7

Table for Initial Data(KrF Tool)

Module	Initial Data
13-1 (COT)	310
13-2 (COT)	310
13-3 (COT)	310
13-4 (COT)	310
14-1 (COT)	310
14-2 (COT)	310
14-3 (COT)	310
14-4 (COT)	310

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5.2. System Config Parameter, Spinners (COT/BCT/ITC)

Block Arm - Left / Module Arm - Left/Right

SPIN Arm Parameter

Item	Block Arm - Left	Block Arm - Right	Module Arm - Left/Right
Rail No.	Lower Rail	Lower Rail	Lower Rail
Arm Presence	Exist	Exist	Exist
Middle Wait	Valid	Valid	N/A
Auto Bath Cleaning	Valid	Valid	N/A
Waiting time after dispense stop during DFT	0.0 sec	0.0 sec	N/A
Nozzle Type	Resist Nozzle	Resist Nozzle	Rinse Nozzle
Y-axis Driver Type	Motor Drive	Motor Drive	Motor Drive
Z-axis Driver Type	Motor Drive	Motor Drive	Cylinder Drive
Y-axis Pulse Rate	0.004000000	0.004000000	0.004167000
Z-axis Pulse Rate	0.003000000	0.003000000	N/A
IN, OUT Speed	115000	115000	48000
IN, OUT Acceleation	187500	187500	96000
IN, OUT Deceleration	187500	187500	96000
In, OUT Speed(Outside the Cup)	0	0	N/A
In, OUT Acceleration(Outside the Cup)	0	0	N/A
In, OUT Deceleration(Outside the Cup)	0	0	N/A
UP, DOWN Speed	40000	40000	N/A
UP,DOWN Acceleation	200000	200000	N/A
UP,DOWN Deceleration	200000	200000	N/A
Maintenance Speed	50%	50%	N/A
Starting point search position from limit	103875, *92300	103875, *90000	N/A
NMA Adjustment Offset	3.00	3.00	N/A

*2CUP Imm/EUV/KrF

Home Offset

	Block Arm - Left	Module Arm - Left/Right
Z - axis Home Position Offset	Tool Specific	N/A

Arm Move Limitation

	Block Arm - Left	Module Arm - Left/Right
Allowable Radius for Arm Down to the Plus Area	5.10	160.00
Allowable Radius for Arm Down to the Minus Area	122.10	160.00

Home Position

	Block Arm - Left	Module Arm - Left/Right
Y - Position	Nozzle Specific*	Nozzle Specific
Z - Position	Nozzle Specific*	Arm Down

*Refer to Nozzle Height Home Position.

Dummy Dispense Position

	Block Arm - Left
Y - Position	Nozzle Specific
Z - Position	Nozzle Specific

Dummy Dispense Height Position

	Block Arm - Left
Dummy Dispense Height Position Z Offset	0.00

Middle Wait Position

	Block Arm - Left
Y - Position	169620

***Does not exist on Imm/Euv/KrF**

Nozzle Offset for all Layers

Nozzle Offset	Nozzle 2	Nozzle 3	Nozzle 4	Nozzle 5		Nozzle 6	Nozzle 7	Nozzle 8	Nozzle 9	Nozzle 10	RRC Nozzle	RRC Nozzle 2	M.Disp. NZL.1 /Nozzle 11	M.Disp. NZL.2 /Nozzle 12
Presence	Exist	Exist	Exist	Exist		Exist	Exist	Exist	Exist	Exist	Exist	Exist	Exist	Exist
Y - Position	-9.00	-18.00	-27.00	-36.00		-81.00	-90.00	-99.00	-108.00	-117.00	-54.00	-63.00	-45.00	-72.00
Z - Position	0.00	0.00	0.00	0.00		0.00	0.00	0.00	0.00	0.00	0.00	0.00	0.00	0.00

Reference Point

	Block Arm - Left	Module Arm - Left/Right
Y - axis	Nozzle Specific	Nozzle Specific
Z - axis	Nozzle Specific	Arm Down

Recipe Position

Recipe Position Name	Block Arm - Left (mm)		Module Arm - Left/Right (mm)	
	Y Position	Z Position	Y Position	Z Position
Module	COT/BCT/ITC	COT/BCT/ITC	COT/BCT/ITC	COT/BCT/ITC
Begin	0.00	5.00	150.00	Arm Down
Center	0.00	5.00	150.00	Arm Down
End	0.00	5.00	150.00	Arm Down
Dispense 1	0.00	30.00	150.00	Arm Down
Dispense 2	0.00	5.00	150.00	Arm Down
Dispense 3	0.00	5.00	150.00	Arm Down
Dispense 4	0.00	5.00	150.00	Arm Down
Dispense 5	See Table 1,2	34.50	150.00	Arm Up
Edge (B)	0.00	5.00	151.00	Arm Down
Edge (E)	0.00	5.00	150.00	Arm Down
Mnt1	0.00	40.00	150.00	Arm Up
Mnt2	0.00	5.00	150.00	Arm Up
Mnt3	0.00	5.00	150.00	Arm Up

Table 1

Dispense 5	BARC tool
Cup 1	275.50±3mm
Cup 2	-404.50±3mm
Cup 3	-1084.50±3mm

Table 2

Dispense 5	Imm/EUV/KrF tool
Cup 1	245.50±3mm
Cup 2	-374.5±3mm
Cup 3	245.50±3mm
Cup 4	-374.50±3mm

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5.2. System Config Parameter, Spinners (COT/BCT/ITC)

Spin Motor Parameter

Spin Motor Control Data

Rinse Arm Select	None
Maximum Speed	4000.00
Maximum Acceleration	30000.00
Speed at Resist Spin Off	2000.00
Acceleration at Resist Spin Off	3000.00
Resist Spin Off Time	15.00
Speed at Rinse	1200.00
Acceleration at Rinse	10000.00
Rinse Time	15.00
Spin Off Speed	2000.00
Spin Off Acceleration	10000.00
Spin Off Time	10.00
Sending Angle Offset	0.00

Pin Parameter

3Pin Parameter

Pulse Rate	0.019996000
UP Speed1	3000
UP Acceleration1	54000
UP Deceleration1	54000
UP Speed2	5000
UP Acceleration2	54000
UP Deceleration2	54000
DOWN Speed1	5000
DOWN Acceleration1	54000
DOWN Deceleration1	54000
DOWN Speed2	3000
DOWN Acceleration2	54000
DOWN Deceleration2	54000

3Pin Position

Item	Position	Z Position
Handling Position	Handling Position	2750
Chuck Position	Chuck Position	500

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5.2. System Config Parameter, Spinners (COT/BCT/ITC)

NMA Parameter

Function (by Arm Unit) (Valid/Invalid)	Valid

Collective Invalidation Parameters (by Arm Unit)

	NMA1.0	NMA2.0
Inspection at Dispensing (All Invalid/Set Each)	Set Each	Set Each
Inspection Alarms at Dispensing (All Invalid/Set Each)	All Invalid	-
Inspection after DFT Formation (All Invalid/Set Each)	Set Each	Set Each
Inspection Alarms after DFT Formation (All Invalid/Set Each)	All Invalid	-
Inspection after Pre-PJ Dummy Dispensing (All Invalid/Set Each)	Set Each	Set Each
Inspection Alarms after Pre-PJ DummDisp. (All Invalid/Set Each)	All Invalid	-

Alarm Warning/Error Switching

Dispense Inspection Result - Dispense Time (Warning/Error)	Warning
Dispense Inspection Result - No Dispensing (Warning/Error)	Warning
Dispense Inspection Result - Liquid Column Width (Warning/Error)	Warning
Dispense Inspection Result - Delay Time (Warning/Error)	Warning
Dispense Inspection Result - Air Bubbles (Warning/Error)	Warning
Inspection Result - Nozzle Tip (Warning/Error)	Warning
Nozzle Inspection Result - Nozzle State (Warning/Error)	Warning
Measurement Result for Process Suckback Level (Warning/Error)	Warning
Measurement Result for DFT Liquid Level (Warning/Error)	Warning
After Pre-PJ Dummy - Multiple Liquid Levels (Warning/Error)	Warning

Basic Data Settings

	NMA1.0	NMA2.0
NMA Controller No.	See table1	-
Camera Ch	See table1	-
Liquid Level Detection Threshold	120	CCV 2.0 Settings
Camera View Position Acceptable Margin	200	-

Table 1 : NMA Controller No. / Camera Ch

[BARC tool]

Module	Controller No.	Camera Ch
13-1 (BCT)	3	0
13-2 (BCT)	3	0
13-3 (BCT)	3	0
14-1 (BCT)	4	0
14-2 (BCT)	4	0
14-3 (BCT)	4	0
15-1 (BCT)	5	0
15-2 (BCT)	5	0
15-3 (BCT)	5	0
16-1 (BCT)	6	0
16-2 (BCT)	6	0
16-3 (BCT)	6	0

[IMM tool]

Module	Controller No.	Camera Ch
11-1 (COT)	1	0
11-2 (COT)	1	0
11-3 (ITC)	2	0
11-4 (ITC)	2	0
12-1 (COT)	1	1
12-2 (COT)	1	1
12-3 (ITC)	2	1
12-4 (ITC)	2	1
13-1 (COT)	3	0
13-2 (COT)	3	0
13-3 (ITC)	4	0
13-4 (ITC)	4	0

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5.2. System Config Parameter, Spinners (COT/BCT/ITC)

RESIST NOZZLE#

Nozzle information	NMA1.0	NMA2.0
Nozzle Position (Camera Swing Position)	See table2	-
Nozzle Tip Diameter	0.8	CCV 2.0 Settings
Nozzle Type	Type1	CCV 2.0 Settings
Distance between Wafer and Nozzle	5.0	-

Light Setting	NMA1.0	NMA2.0
Top Brightness	See table2	CCV 2.0 Settings
Slide1 Left Brightness	150	CCV 2.0 Settings
Slide1 Right Brightness	150	CCV 2.0 Settings
Slide2 Left Brightness	150	CCV 2.0 Settings
Slide2 Right Brightness	150	CCV 2.0 Settings
Slide3 Left Brightness*	150	CCV 2.0 Settings
Slide3 Right Brightness*	150	CCV 2.0 Settings

* Not present on IMM/EUV tools

Table2 : Nozzle position / Top brightness

[BARC tool]

Nozzle		Nozzzle Position	Top Brightness
		BCT	BCT
Nozzle1		Nozzle Specific*	155
Nozzle2		Nozzle Specific*	110
Nozzle3		Nozzle Specific*	80
Nozzle4		Nozzle Specific*	70
Nozzle5		Nozzle Specific*	70
Nozzle6		Nozzle Specific*	70
Nozzle7		Nozzle Specific*	70
Nozzle8		Nozzle Specific*	80
Nozzle9		Nozzle Specific*	110
RRC nozzle		Nozzle Specific*	70

* Auto adjustment

[IMM tool]

Nozzle	Nozzzle Position		Top Brightness	
	COT	ITC	COT	ITC
Nozzle1	Nozzle Specific*	Nozzle Specific*	155	155
Nozzle2	Nozzle Specific*	Nozzle Specific*	110	110
Nozzle3	Nozzle Specific*	Nozzle Specific*	80	80
Nozzle4	Nozzle Specific*	N/A	70	N/A
Nozzle5	Nozzle Specific*	N/A	70	N/A
Nozzle6	Nozzle Specific*	N/A	70	N/A
Nozzle7	Nozzle Specific*	N/A	70	N/A
Nozzle8	N/A	N/A	N/A	N/A
Nozzle9	N/A	N/A	N/A	N/A
RRC nozzle	Nozzle Specific*	Nozzle Specific*	70	70

* Auto adjustment

Inspection Area Setting

Liquid Column Area Setting	NMA1.0	NMA2.0
Start Point on X-Coordinate	Nozzle Specific*	-
Start Point on Y-Coordinate	Nozzle Specific*	-
Width	100	-
Height	80	-

* Auto adjustment pixel

Liquid Level Area Setting**	NMA1.0	NMA2.0
Start Point on X-Coordinate	1	-
Start Point on Y-Coordinate	1	-
Width	158	-
Height	Nozzle Specific*	-

* Auto adjustment pixel

Threshold Settings

Dispense Inspection Settings

	NMA1.0	NMA2.0
Dispense Time Acceptable Margin	250msec	Refer to CCV 2.0 Settings
Upper Limit of Average Liquid Column Width	1.6mm	Refer to CCV 2.0 Settings
Lower Limit of Average Liquid Column Width	0.0mm	CCV 2.0 Settings
Maximum Liquid Column Width	6.5mm	CCV 2.0 Settings
Minimum Liquid Column Width	0.0mm	CCV 2.0 Settings
Dispense Start Delay Warning Threshold	100msec	CCV 2.0 Settings
Dispense End Delay Warning Threshold	100msec	-
Liquid Column Frame Count for Air Detection	2	-
Air size for Nozzle Air Detection	500um	-

Liquid Level Inspection Settings**

PSB	NMA1.0	NMA2.0
Time Required for Liquid Level Inspection	75 msec	1000 msec
Warning Kind of Process S.B. Liquid Level	2	-
Upper Limit of Process S.B. Liquid Level	8.5mm	CCV 2.0 Settings
Lower Limit of Process S.B. Liquid Level	0.0mm	CCV 2.0 Settings
PSB position for Auto-adjustment	0.0	0.0

DFT	NMA1.0	NMA2.0
Process Setup Liquid Level Target Position	14.0mm	14.0mm
Suckback 1 Liquid Level Target Position	8.0mm	CCV 2.0 Settings
Suckback 2 Liquid Level Target Position	10.0mm	CCV 2.0 Settings
Suckback 3 Liquid Level Target Position	3.0mm	CCV 2.0 Settings
Suckback 1 Liquid Level Warning Range	1.0mm	CCV 2.0 Settings
Suckback 2 Liquid Level Warning Range	4.0mm	CCV 2.0 Settings
Suckback 3 Liquid Level Warning Range	3.0mm	CCV 2.0 Settings

Nozzle Inspection Settings	NMA1.0	NMA2.0
Nozzle Position Warning Range	500um	CCV 2.0 Settings
Nozzle Scratch & Stain Density Threshold	200	CCV 2.0 Settings
Nozzle Scratch & Stain Size	1500um	CCV 2.0 Settings
Nozzle Slope Threshold	1.5deg	CCV 2.0 Settings
Time Required for Nozzle Inspection	200msec	1000msec

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5.2. System Config Parameter, Spinners (COT/BCT/ITC)

Valid/Invalid Parameters (by Nozzle Unit)

Inspection at Dispensing	NMA1.0	NMA2.0
Inspection at Dispensing (Valid/Invalid)	Valid	Valid
Inspection Alarms at Dispensing (All Invalid/Set Each)	Set Each	-

Dispense Inspection Alarms (Valid/Invalid)	NMA1.0	NMA2.0
Dispense Time Judgment Setting (Valid/Invalid)	Valid	CCV 2.0 Settings
Judgment for Ave. Liquid Column Width (Valid/Invalid)	Valid(excluding N/A)	CCV 2.0 Settings
Judgment for Max. Liquid Column Width (Valid/Invalid)	Invalid	CCV 2.0 Settings
Judgment for Min. Liquid Column Width (Valid/Invalid)	Invalid	CCV 2.0 Settings
Dispense Start Delay Time Judgment Setting (Valid/Invalid)	Invalid	CCV 2.0 Settings
Dispense End Delay Time Judgment Setting (Valid/Invalid)	Invalid	-
Brightness Judgment at Dispense Inspection (Valid/Invalid)	Invalid	-
Air Judgment at Dispense Inspection (Valid/Invalid)	Valid	CCV 2.0 Settings
Background Judgment at Dispense Inspection (Valid/Invalid)	Invalid	CCV 2.0 Settings

Liquid Level Inspection Alarms (Valid/Invalid)	NMA1.0	NMA2.0
Pre-disp. Liquid Level Height Judgment (Valid/Invalid)	Valid(excluding N/A)	CCV 2.0 Settings
Post-disp. Liquid Level Height Judgment (Valid/Invalid)	Invalid	CCV 2.0 Settings

Nozzle Inspection Alarms (Valid/Invalid)**	NMA1.0	NMA2.0
Nozzle Position Judgment (Valid/Invalid)	Invalid	CCV 2.0 Settings
Judgment for Nozzle Scratch & Stain (Valid/Invalid)	Valid(excluding N/A)	CCV 2.0 Settings

Consecutive Occurrence Alarms (Valid/Invalid)**	NMA1.0	NMA2.0
Liquid Level Height Judgment (Valid/Invalid)	Invalid	CCV 2.0 Settings
Judgment for Nozzle Scratch & Stain (Valid/Invalid)	Invalid	CCV 2.0 Settings

Inspection after DFT Formation	NMA1.0	NMA2.0
Inspection after DFT Formation (Valid/Invalid)	Valid	Valid
Inspection Alarms after DFT Formation (All Inv/Set Each)	Set Each	Set Each

Liquid Level Inspection Alarms (Valid/Invalid)	NMA1.0	NMA2.0
Suckback 1 DFT Inspection Judgment (Valid/Invalid)	Invalid	CCV 2.0 Settings
Suckback 2 DFT Inspection Judgment (Valid/Invalid)	Valid(excluding N/A)	CCV 2.0 Settings
Suckback 3 DFT Inspection Judgment (Valid/Invalid)	Valid(excluding N/A)	CCV 2.0 Settings

Nozzle Inspection Alarms (Valid/Invalid)	NMA1.0	NMA2.0
Nozzle Position Judgment (Valid/Invalid)	Invalid	CCV 2.0 Settings

Inspection after Pre-PJ Dummy Dispensing	NMA1.0	NMA2.0
Liquid Level Inspection (Valid/Invalid)	Valid	Valid
Liquid Level Inspection Alarms (All Invalid/Set Each)	Set Each	CCV 2.0 Settings
Liquid Level Inspection (Valid/Invalid)	Valid	Valid
Liquid Level Inspection Alarms (All Invalid/Set Each)	Set Each	CCV 2.0 Settings

Liquid Level Inspection Alarms (Valid/Invalid)**	NMA1.0	NMA2.0
PSB Liquid Level Inspection Judgment at Pre-PJ (Valid/Invalid)	Valid(excluding N/A)	CCV 2.0 Settings

Liquid Level Inspection Alarms (Valid/Invalid)**	NMA1.0	NMA2.0
Nozzle Position Judgment (Valid/Invalid)	Valid(excluding N/A)	CCV 2.0 Settings
Nozzle Slope Judgment (Valid/Invalid)	Valid(excluding N/A)	CCV 2.0 Settings
Judgment for Nozzle Scratch & Stain (Valid/Invalid)	Valid(excluding N/A)	CCV 2.0 Settings

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5.3. System Config Parameter, Spinners (PIR/SRS)

Block 30 IFB, I-Rinse / S-Rinse

*** For Immersion Configuration ONLY**

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	1-2
Wafer Store Count	1
Start Slot	0

Dispense parameter

Local Nozzle

RINSE1

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid

Dispense Mechanism Connection [1]

Valid, Invalid	Valid

Dispense Monitoring Mechanism Connection

Valid, Invalid	Valid

UltrasonicType flow meter

Dispense Monitoring Type	UltrasonicType flow meter
Sensor Channel No.	Line Specific
Chemical Name	DI WATER
FRType	TYPE2(3000ml/min)

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid

Dispense Monitoring Control Data

Pulse Rate	0.05
Delay Time	0.60
Set Flow Rate	150
Flow Rate Sensor Check Timing	Dispense end
Calibration 1	1.00
Offset	0
Upper Limit Error Level	30.00%
Upper Limit Warn Level	20.00%
Lower Limit Error Level	30.00%
Lower Limit Warning Level	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

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All Tools except PBR tools

Dispense parameter
Local Nozzle
BACK RINSE1

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection [1]

Valid, Invalid	Valid

Dispense Monitoring Mechanism Connection

Valid, Invalid	Valid

UltrasonicType flow meter

Dispense Monitoring Type	UltrasonicType flow meter
Sensor Channel No.	Line Specific
Chemical Name	DI WATER
FRType	TYPE3(300ml/min)

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid

Dispense Monitoring Control Data

Pulse Rate	0.005
Delay Time	0.60
Set Flow Rate	200
Flow Rate Sensor Check Timing	Dispense end
Calibration 1	1.00
Offset	0
Upper Limit Error Level	30.00%
Upper Limit Warning Level	20.00%
Lower Limit Error Level	30.00%
Lower Limit Warning Level	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Invalid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

CUP EXH.

Process Recipe Attribute	Invalid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection [1]

Valid, Invalid	Valid

Spinner Exhaust Monitoring Control Data

High Pressure	0.00
High Pressure (Error Lower Limit)	0.00
Low Pressure	0.00
Low Pressure (Error Lower Limit)	0.00
Cup EXH. Monitoring Start Delay Time	2000
Offset	0.0
Cup EXH. Monitoring Valid(1)/Invalid(0)	0

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5.3. System Config Parameter, Spinners (PIR/SRS)

IE NOZZLE *

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Invalid

* For SRS Only

Dispense Mechanism Connection [1]

Valid, Invalid	Valid

Dispense Monitoring Mechanism Connection

Valid, Invalid	Valid

UltrasonicType flow meter

Dispense Monitoring Type	UltrasonicType flow meter
Sensor Channel No.	Line Specific
Chemical Name	DI WATER
FRType	TYPE3(300ml/min)

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid

Dispense Monitoring Control Data

Pulse Rate	0.005
Delay Time	0.60
Set Flow Rate	200
Flow Rate Sensor Check Timing	Dispense end
Calibration 1	1.00
Offset	0
Upper Limit Error Level	30.00%
Upper Limit Warning Level	20.00%
Lower Limit Error Level	30.00%
Lower Limit Warning Level	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Invalid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

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5.3. System Config Parameter, Spinners (PIR/SRS)

Monitoring Parameter

Motor flange temp

Item	Motor flange temp.
Valid,Invalid	Valid
Measured Data ID	Motor flange temp.
Recipe Setting Method	System recipe
Temperature Control Method	Temp Ctl OFF
Recipe Verify Range Lower Limit	20.00
Recipe Verify Range Upper Limit	25.00

Controller TM206-CHILLER

Item	Motor flange temp.
Controller ID	TM206-CHILLER
Channel No.	4
Monitoring Type	Use point read
Control Method	Standard
Use Point Offset	Tool specific
Band Monitoring Method at Process Start	Normal
Band Monitoring Invalid Time at Process Start	0.0
Band Monitoring Determination Method during Processing	No monitor
Band Monitoring Determine Time during Processing	0.0
Band Monitoring Value during Processing	0.00
Pump Frequency	Tool specific
Initial Data	22.20
Overtemperature	40.00
Settling Determination Time	5.0
Settling Time-out Time	3600.0

PIR / SRS Temp. Control flow

Item	PIR	SRS
Valid,Invalid	Valid	Valid
Measured Data ID	PIR Temp. Control flow rate	SRS Temp. Control flow rate
Recipe Setting Method	Local	Local
Temperature Control Method	Temp Ctl OFF	See Table
Recipe Verification Range Lower Limit	0.00	0.00
Recipe Verification Range Upper Limit	35.00	35.00

Table for Temperature Control Method

30-11(SRS)	Tmp Ctl On
30-12(SRS)	Tmp Ctl Off
30-13(SRS)	Tmp Ctl Off
30-14(SRS)	Tmp Ctl Off
30-15(SRS)	Tmp Ctl Off

Controller TM206-CHILLER

Controller ID	TM206-CHILLER
Channel No.	4
Line No.	6
Set Value	2.00
Warning Range Lower Limit	100.00
Warning Range Upper Limit	100.00
Stop Range Lower Limit	100.00
Stop Range Upper Limit	100.00
Offset	0.00

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5.3. System Config Parameter, Spinners (PIR/SRS)

Module Arm - Left

Spinner Arm Control Data

Item	Module Arm - Left
Rail No.	Lower Rail
Arm Presence	Exist
Nozzle Type	Rinse Nozzle
Y-axis Drive Type	Motor Drive
Z-axis Drive Type	Cylinder Drive
Y-axis Pulse Rate	0.010076
IN, OUT Speed	31262
IN, OUT Acceleration	158793
IN, OUT Deceleration	158793

Home Position

	Module Arm - Left
Y - Position	-2900 pulses
Z - Position	Arm Down

Reference Point

	Module Arm - Left
Y - Axis	Nozzle Specific
Z - Axis	Arm Down

Recipe Position

Recipe Position Name	Module Arm - Left (mm)	
	Y Position	Z Position
Begin	0.00	Arm Down
Center	0.00	Arm Down
End	0.00	Arm Down
Dispense 1	158.01	Arm Down
Dispense 2	24.00	Arm Down
Dispense 3	100.00	Arm Down
Dispense 4	130.00	Arm Down
Dispense 5	0.00	Arm Down
Edge (B)	0.00	Arm Down
Edge (E)	0.00	Arm Down
MTN 1	0.00	Arm Up
MTN 2	0.00	Arm Up
MTN 3	0.00	Arm Up

Spin Motor Parameter

Spin Motor Control Data

Rinse Arm No.	L Arm
Maximum Speed	3000.00
Maximum Acceleration	10000.00
Speed at Rinse	1000.00
Acceleration at Rinse	3000.00
Rinse Time	15.00
Spin Off Speed	1000.00
Spin Off Acceleration	3000.00
Spin Off Time	15.0
Sending Angle Offset	0.00

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5.4. System Config Parameter, Spinners (BST / BST+)

Block 30 IF Block, BST* / BST+**

* For Imm Configuration ONLY

** For EUV and KrF Configuration(except TBZ458) ONLY

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**1-2**
Wafer Store Count	**1**
Start Slot	**0**
Generate Time to Perform Maintenance Alarm after Set Number of Processed Wafers	**50000**

Type

Value	BST+

Dispense parameter

Block No.	30
Module No.	Module Specific

Local Nozzle

BRUSH RINSE 1 [1]

Nozzle No.	1
Nozzle Name	BRUSH RINSE1
Process Recipe Attribute	Valid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection [1]

Valid, Invalid	Valid

Dispense Port Connection

Hardware Registration No.	Line Specific
Dispense System Type	Dispense port

Dispense Monitoring Mechanism Connection

Valid, Invalid	Valid

UltrasonicType flow meter

Hardware Registration No.	Line Specific
Dispense Monitoring Type	UltrasonicType flow meter
Load Position Information	Line Specific

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid
Sensor Channel No.	Line Specific
Chemical Name	DI WATER
FRType	TYPE2(3000ml/min)

Dispense Monitoring Control Data

Pulse Rate	0.05	ml/pulse
Delay Time	0.60	sec
Set Flow Rate	400	ml/min
Flow Rate Sensor Check Timing	Dispense end	
Calibration 1	1.00	
Offset	0	
Upper Limit Error Level	30.00	%
Upper Limit Warning Level	20.00	%
Lower Limit Error Level	30.00	%
Lower Limit Warning Level	20.00	%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Invalid	
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute	
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0	sec

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5.4. System Config Parameter, Spinners (BST / BST+)

BRUSH RNS1(SUB) [3]

Nozzle No.	3
Nozzle Name	BRUSH RNS1(SUB)
Process Recipe Attribute	Valid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection [1]

Valid, Invalid	Valid

Dispense Port Connection

Hardware Registration No.	Line Specific
Dispense System Type	Dispense port

Dispense Monitoring Mechanism Connection

Valid, Invalid	Valid

UltrasonicType flow meter

Hardware Registration No.	Line Specific
Dispense Monitoring Type	UltrasonicType flow meter
Load Position Information	Line Specific

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid
Sensor Channel No.	Line Specific
Chemical Name	DI WATER
FRType	TYPE2(3000ml/min)

Dispense Monitoring Control Data

Pulse Rate	0.05	ml/pulse
Delay Time	0.60	sec
Set Flow Rate	400	ml/min
Flow Rate Sensor Check Timing	Dispense end	
Calibration 1	1.00	
Offset	0	
Upper Limit Error Level	30.00	%
Upper Limit Warning Level	20.00	%
Lower Limit Error Level	30.00	%
Lower Limit Warning Level	20.00	%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Invalid	
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute	
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0	sec

BRUSH BATH RINSE [4]

Nozzle No.	4
Nozzle Name	BRUSH BATH RINSE
Process Recipe Attribute	Invalid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection [1]

Valid, Invalid	Valid

Dispense Port Connection

Hardware Registration No.	Line Specific
Dispense System Type	Dispense port

Dispense Monitoring Mechanism Connection

Valid, Invalid	Valid

UltrasonicType flow meter

Hardware Registration No.	Line Specific
Dispense Monitoring Type	UltrasonicType flow meter
Load Position Information	Line Specific

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid
Sensor Channel No.	Line Specific
Chemical Name	DI WATER
FRType	TYPE2(3000ml/min)

Dispense Monitoring Control Data

Pulse Rate	0.05	ml/pulse
Delay Time	0.60	sec
Set Flow Rate	150	ml/min
Flow Rate Sensor Check Timing	In dispense＋Dispense end	
Calibration 1	1.00	
Offset	0	
Upper Limit Error Level	30.00	%
Upper Limit Warning Level	20.00	%
Lower Limit Error Level	30.00	%
Lower Limit Warning Level	20.00	%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Invalid	
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute	
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0	sec

Flow Rate during Dispense Process

Invalidated Flow Rate Monitoring Times during Dispense Process	2	Times
Upper Limit Error Level for Flow Rate during Dispense Process	30.00	%
Lower Limit Error Level for Flow Rate during Dispense Process	30.00	%
Brush Bath Rinse Constant Monitoring	Valid	

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5.4. System Config Parameter, Spinners (BST / BST+)

AIR NOZZLE1 [5]

Nozzle No.	5
Nozzle Name	AIR NOZZLE1
Process Recipe Attribute	Valid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection [1]

Valid, Invalid	Valid

Dispense Port Connection

Hardware Registration No.	Line Specific
Dispense System Type	Dispense port

IE NOZZLE [48]

Nozzle No.	48
Nozzle Name	IE NOZZLE
Process Recipe Attribute	Valid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection [1]

Valid, Invalid	Valid

Dispense Port Connection

Hardware Registration No.	Line Specific
Dispense System Type	Dispense port

Dispense Monitoring Mechanism Connection

Valid, Invalid	Valid

UltrasonicType flow meter

Hardware Registration No.	Line Specific
Dispense Monitoring Type	UltrasonicType flow meter
Load Position Information	Line Specific

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid
Sensor Channel No.	Line Specific
Chemical Name	DI WATER
FRType	TYPE3(300ml/min)

Dispense Monitoring Control Data

Pulse Rate	0.005	ml/pulse
Delay Time	0.60	sec
Set Flow Rate	200	ml/min
Flow Rate Sensor Check Timing	Dispense end	
Calibration 1	1.00	
Offset	0	
Upper Limit Error Level	30.00	%
Upper Limit Warning Level	20.00	%
Lower Limit Error Level	30.00	%
Lower Limit Warning Level	20.00	%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Invalid	
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute	
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0	sec

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5.4. System Config Parameter, Spinners (BST / BST+)

RINSE1 [49]

Nozzle No.	49
Nozzle Name	RINSE1
Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid

Dispense Mechanism Connection [1]

Valid, Invalid	Valid

Dispense Port Connection

Hardware Registration No.	Line Specific
Dispense System Type	Dispense port

Dispense Monitoring Mechanism Connection

Valid, Invalid	Valid

UltrasonicType flow meter

Hardware Registration No.	Line Specific
Dispense Monitoring Type	UltrasonicType flow meter
Load Position Information	Line Specific

Regular Retrieval of Flow Rate

Regular Retrieval of Flow Rate, Valid/Invalid	Valid
Sensor Channel No.	Line Specific
Chemical Name	DI WATER
FRType	TYPE2(3000ml/min)

Dispense Monitoring Control Data

Pulse Rate	0.005	ml/pulse
Delay Time	0.60	sec
Set Flow Rate	200	ml/min
Flow Rate Sensor Check Timing	Dispense end	
Calibration 1	1.00	
Offset	0	
Upper Limit Error Level	30.00	%
Upper Limit Warning Level	20.00	%
Lower Limit Error Level	30.00	%
Lower Limit Warning Level	20.00	%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid	
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute	
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0	sec

CUP EXH. [60]

Nozzle No.	60
Nozzle Name	CUP EXH.
Process Recipe Attribute	Invalid
Dummy Dispense Attribute	Invalid

Dispense Mechanism Connection [1]

Valid, Invalid	Valid

Dispense Port Connection

Hardware Registration No.	Line Specific
Dispense System Type	Dispense port

Spinner Exhautst Monitoring Control Data

High Pressure	0.00	Pa
High Pressure (Error Lower Limit)	0.00	Pa
Low Pressure	0.00	Pa
Low Pressure (Error Upper Limit)	0.00	Pa
Cup EXH. Monitoring Start Delay Time	3000	msec
Offset	0.0	Pa
Cup EXH. Monitoring Valid(1)/Invalid(0)	0	

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Monitoring parameter

Block No.	30
Module No.	Module Specific

Spinner Arm Control Data

Item	Rinse Arm	Brush Arm	Pad Arm
Arm Presence	Exist	N/A	N/A
X-axis Drive Type	N/A	N/A	Motor Drive
Theta-axis Drive Type	Motor Drive	Motor Drive	N/A
Z-axis Drive Type	Cylinder Drive	Motor Drive	Cylinder Drive
X-axis Pulse Rate[mm/pulse]	N/A	N/A	0.00985
Theta-axis Pulse Rate[deg/pulse]	0.00225	0.0048	N/A
Z-axis Pulse Rate[mm/pulse]	N/A	0.0025	N/A
X-axis Reference Point[pulse]	N/A	N/A	Tool Specific
X-axis Reference Point[mm]	N/A	N/A	Tool Specific
Theta-axis Reference Point[pulse]	Tool Specific	Tool Specific	N/A
Theta-axis Reference Point[deg]	Tool Specific	Tool Specific	N/A
Z-axis Reference Point (Cylinder)	Arm Up	N/A	Arm Down
Z-axis Reference Point (Motor)[pulse]	N/A	Tool Specific	N/A
Z-axis Reference Point (Motor)[mm]	N/A	Tool Specific	N/A
Theta-axis Speed[pulse/sec]	22222	37500	N/A
Theta-axis Speed[deg/sec]	50.00	180.00	N/A
Z-axis Speed[pulse/sec^2]	N/A	16000	N/A
Z-axis Speed[mm/sec^2]	N/A	40.00	N/A
X-axis Acceleration[pulse/sec^2]	N/A	N/A	48732
X-axis Acceleration[mm/sec^2]	N/A	N/A	480.01
X-axis Deceleration[pulse/sec^2]	N/A	N/A	48732
X-axis Deceleration[mm/sec^2]	N/A	N/A	480.01
Theta-axis Acceleration[pulse/sec^2]	74076	125000	N/A
Theta-axis Acceleration[deg/sec^2]	166.67	600.00	N/A
Theta-axis Deceleration[pulse/sec^2]	74076	125000	N/A
Theta-axis Deceleration[deg/sec^2]	166.67	600.00	N/A
Z-axis Acceleration[pulse/sec^2]	N/A	32000	N/A
Z-axis Acceleration[mm/sec^2]	N/A	80.00	N/A
Z-axis Deceleration[pulse/sec^2]	N/A	32000	N/A
Z-axis Deceleration[mm/sec^2]	N/A	80.00	N/A
Scan End Position[deg]	N/A	N/A	0
Scan End Position[mm]	N/A	N/A	0.0

Recipe Position

Recipe Position Name	Rinse Arm		Brush Arm		Pad Arm	
	Theta Position	Z Position-Cylinder	Theta Position	Z Position-Motor	X Position	Z Position-Cylinder
Home Position[pulse]	Tool Specific	Arm Up	0	0	Tool Specific	Arm Down
Height for Movement during Processing Z Position(Offset)[pulse]	N/A	N/A	N/A	-4000	N/A	N/A
Begin[pulse]	756	Arm Down	N/A	N/A	N/A	N/A
Center[pulse]	0	Arm Down	0	Tool Specific	11980	Arm Up
Outer[pulse]	N/A	N/A	0	0	N/A	N/A
Bath[pulse]	N/A	N/A	Tool Specific	Tool Specific	N/A	N/A
Brush Change[pulse]	N/A	N/A	N/A	Tool Specific	N/A	N/A
Humid[pulse]	N/A	N/A	N/A	-2000	N/A	N/A
End[pulse]	-15778	Arm Down	N/A	N/A	N/A	N/A
Dispense 1[pulse]	-16222	Arm Down	N/A	N/A	N/A	N/A
Dispense 2[pulse]	0	Arm Up	N/A	N/A	N/A	N/A
Dispense 3[pulse]	0	Arm Up	N/A	N/A	N/A	N/A
Dispense 4[pulse]	0	Arm Up	N/A	N/A	N/A	N/A
Dispense 5[pulse]	0	Arm Up	N/A	N/A	N/A	N/A
Edge (B)[pulse]	-15778	Arm Down	N/A	N/A	N/A	N/A
Edge (E)[pulse]	0	Arm Up	N/A	N/A	N/A	N/A

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5.4. System Config Parameter, Spinners (BST / BST+)

Spin Motor

Spin Motor Control Data

Rinse Arm Select	L Arm	
Maximum Speed	2000.00	rpm
Maximum Acceleration	2500.00	rpm^2
Speed at Rinse	200.00	rpm
Acceleration at Rinse	1000.00	rpm^2
Rinse Time	5.00	sec
Spin Off Speed	2000.00	rpm
Spin Off Acceleration	1000.00	rpm^2
Spin Off Time	15.00	sec

Brush Motor

Brush Motor Control Data

Maximum Speed	1000.00	rpm
Maximum Acceleration	1000.00	rpm/sec
Speed at Brush Wash	500	rpm
Acceleration at Brush Wash	1000	rpm/sec
Brush Wash Time	10.00	sec
Speed at Brush Humid	30	rpm
Acceleration at Brush Humid	1000	rpm/sec
Brush pressure	1.0	N
Brush Path	65.0	mm
Pressure tolerance range Upper Limit	0.30	N
Pressure tolerance range Lower Limit	0.30	N
Brush pressure settling time	30.00	sec
Brush pressure settling warning time	20.00	sec
Brush Arm full Stoke movement Function	Valid	
Brush Arm full Stoke movement Interval Time	1800	sec

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5.5. Spinner Parameter

Spinner Information Parameter

Drain Cleaning Time Ini	20.0	sec
AutoBathcleaning Time	1	sec
Z Search Drive	Valid	
Cup Exh. Alarm Detect Threshold	1.0	sec
Next Dispense Timing Control Using Pump Recipe Time	Valid	
Vent Skip function at RIA	Valid	

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Block 11,12,13,14,15,16 PR Block, [CPHP] Chilling High Precision Hot Plate Process Station for Imm/EUV

Block 12,13,14,15,16 PR Block, [CPHP] Chilling High Precision Hot Plate Process Station for KrF

Reserved Flag	Invalid
Fork Simultaneous Swapping Level	1-2
Wafer Store Count	1
Start Slot	0
Generate Time to Perform Maintenance Alarm after Set Number of Processed Wafers*	0

* Present on BST/BST+ tools

Chamber Type

Chamber Type	SNS Chamber

Plate Type

Plate Type	Type C

Controller PCU-09-O

Controller ID	PCU-09-O
Start Channel No.	0
End Channel No.	6
Monitoring Type	No sync
Control Method	Epsilon ctrl
Chamber FB Ctrl. Valid	Valid
SAG Monitor IOID	Module Specific
Band Monitoring Method at Process Start	Setting
Band Monitoring Invalid Time at Process Start	40.0
Band Monitoring Determination Method during Processing	No monitor
Band Monitoring Determination Time during Processing	1.0
Band Monitoring Value during Processing	3.00
PID Setting Method	Control setting
P Constant	1.57
I Constant	3.000
D Constant	0.750
Offset Setting Method	Table setting
Offset	0.00
Display Method Selection	Display all data
Stranded Wafer Detection Valid	Valid
Initial Data	50.00
Overtemperature	185.00
Setting Determination Time	3.0
Setting Time-out Time	1200.0

Monitoring Parameter

Plate temp.

Valid,Invalid	Valid
Measured Data ID	Plate temp.
Recipe Setting Method	Process recipe
Temperature Control Method	Tmp ctl ON
Recipe Verification Range Lower Limit	50.00
Recipe Verification Range Upper Limit	180.00

Control Table Data List

	Valid, Invalid	Set Value Lower Limit	Set Value Upper Limit	Accumulated Threshold Value	Accumulated Time	Cham FB Fixed Temp
Temp. Range	Valid	50.00	180.00	Not Input	Not Input	Not Input
Temp. Range	Valid	50.00	Not Input	Not Input	Not Input	35.00
Temp. Range	Valid	70.00	Not Input	34.00	15.00	Tool Specific
Temp. Range	Valid	75.00	Not Input	37.00	15.00	Not Input
Temp. Range	Valid	80.00	82.00	40.00	15.00	Not Input
Temp. Range	Valid	85.00	Not Input	43.00	15.00	Not Input
Temp. Range	Valid	90.00	Not Input	47.00	15.00	Not Input
Temp. Range	Valid	95.00	97.00	51.00	15.00	Not Input
Temp. Range	Valid	100.00	Not Input	53.00	15.00	Tool Specific
Temp. Range	Valid	105.00	Not Input	59.00	15.00	Not Input
Temp. Range	Valid	110.00	Not Input	63.00	15.00	Not Input
Temp. Range	Valid	115.00	Not Input	68.00	15.00	Not Input
Temp. Range	Valid	120.00	Not Input	73.00	15.00	Not Input
Temp. Range	Valid	125.00	Not Input	79.00	15.00	Tool Specific
Temp. Range	Valid	130.00	Not Input	84.00	15.00	Not Input
Temp. Range	Valid	135.00	Not Input	89.00	15.00	Not Input
Temp. Range	Valid	140.00	Not Input	95.00	15.00	Not Input
Temp. Range	Valid	145.00	Not Input	101.00	15.00	Not Input
Temp. Range	Valid	150.00	Not Input	106.00	15.00	Tool Specific

*Wafer wedge set up by 1mm ring.

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Block 11,12,13,14,15,16 PR Block, [CPHP] Chilling High Precision Hot Plate Process Station for Imm/EUV

Block 13,14,15,16 PR Block, [CPHP] Chilling High Precision Hot Plate Process Station for KrF

Control Table Data List for KrF

	Valid, Invalid	Set Value Lower Limit	Set Value Upper Limit	Accumulated Threshold Value	Accumulated Time	Cham FB Fixed Temp
Temp. Range	Valid	50.00	180.00	Not Input	Not Input	Not Input
Temp. Range	Valid	50.00	Not Input	Not Input	Not Input	35.00
Temp. Range	Valid	70.00	Not Input	34.00	15.00	Tool Specific
Temp. Range	Valid	75.00	Not Input	37.00	15.00	Not Input
Temp. Range	Valid	80.00	82.00	40.00	15.00	Not Input
Temp. Range	Valid	85.00	Not Input	43.00	15.00	Not Input
Temp. Range	Valid	90.00	Not Input	47.00	15.00	Not Input
Temp. Range	Valid	95.00	97.00	51.00	15.00	Not Input
Temp. Range	Valid	100.00	Not Input	53.00	15.00	Tool Specific
Temp. Range	Valid	105.00	Not Input	59.00	15.00	Not Input
Temp. Range	Valid	110.00	Not Input	63.00	15.00	Not Input
Temp. Range	Valid	115.00	Not Input	68.00	15.00	Not Input
Temp. Range	Valid	120.00	Not Input	73.00	15.00	Not Input
Temp. Range	Valid	125.00	Not Input	79.00	15.00	Tool Specific
Temp. Range	Valid	130.00	Not Input	84.00	15.00	Not Input
Temp. Range	Valid	135.00	Not Input	89.00	15.00	Not Input
Temp. Range	Valid	140.00	Not Input	95.00	15.00	Not Input
Temp. Range	Valid	145.00	Not Input	101.00	15.00	Not Input
Temp. Range	Valid	150.00	Not Input	106.00	15.00	Tool Specific
Temp. Range**	Valid	180.00	Not Input	140.00	15.00	Tool Specific

*Wafer wedge set up by 1mm ring.

**N2 purge CPHP only

Control Table Data (Temperature Range 50.00 - 180.00)

	Table data No.1	Table data No.2	Table data No.3	Table data No.4	Table data No.5	Table data No.6	Table data No.7
Offset	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input
P Constant	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input
I Constant	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input
D Constant	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input
Epsilin	-0.10	-0.60	-0.60	-0.40	-0.40	-0.40	-0.40

Control Table Data (Temperature Range 70,100,125,150) *KrF Temparature Range 100,125,150,180

	Table data No.1	Table data No.2	Table data No.3	Table data No.4	Table data No.5	Table data No.6	Table data No.7
Offset	Tool Specific	Tool Specific	Tool Specific	Tool Specific	Tool Specific	Tool Specific	Tool Specific
P Constant	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input
I Constant	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input
D Constant	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input
Epsilin	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input

Control Table Data (Temperature Range All Other)

	Table data No.1	Table data No.2	Table data No.3	Table data No.4	Table data No.5	Table data No.6	Table data No.7
Offset	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input
P Constant	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input
I Constant	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input
D Constant	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input
Epsilin	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input	Not Input

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6. System Config Parameter, Ovens

Block 11,12,13,14,15,16 PR Block, [CPHP] Chilling High Precision Hot Plate Process Station for Imm/EUV

Block 13,14,15,16 PR Block, [CPHP] Chilling High Precision Hot Plate Process Station for KrF

Monitoring Parameter

Chamber temp.

Valid,Invalid	Valid
Measured Data ID	Chamber temp.
Recipe Setting Method	Local
Temperature Control Method	Tmp ctl ON
Recipe Verification Range Lower Limit	50.00
Recipe Verification Range Upper Limit	250.00

Controller PCU-09-O

Controller ID	PCU-09-O
Start Channel No.	7
End Channel No.	7
Monitoring Type	No sync
Control Method	Epsilon
Band Monitoring Method at Process Start	Normal
Band Monitoring Invalid Time at Process Start	0.0
Band Monitoring Determination Method during Processing	No monitor
Band Monitoring Determination Time during Processing	1.0
Band Monitoring Value during Processing	3.00
PID Setting Method	Control setting
P Constant	4.60
I Constant	16.400
D Constant	2.500
Offset Setting Method	Table setting
Offset	0.00
Display Method Selection	Display all data
Stranded Wafer Detection Valid	Invalid
Initial Data	50.00
Overtemperature	190.00
Setting Determination Time	3.0
Setting Time-out Time	1200.0

Chamber Exhaust Pres

Valid,Invalid	Valid
Measured Data ID	Chamber Exhaust Pres
Recipe Setting Method	Local
Temperature Control Method	Tmp ctl OFF
Recipe Verification Range Lower Limit	0.00
Recipe Verification Range Upper Limit	0.00

Controller Analogue sensor

Controller ID	Analogue Sensor
Band Monitoring Valid, Invalid	Valid
Set Value	9.35/*9.10
Warning Range Lower Limit	2.50
Warning Range Upper Limit	2.50
Stop Range Lower Limit	3.00
Stop Range Upper Limit	3.00
Offset	Tool Specification

*High altitude setting

Oven Control Parameter

	Position		Initial Velocity
Item	Up Position	Heat Position	Pin HP Wafer Put Drive Low Speed
United Oven 3Pin Parameter	Module Specific	Module Specific	0.75

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Block 14,15,16 PR Block, [CPHP] Chilling High Precision Hot Plate Process Station for Imm/EUV

Block 15,16 PR Block, [CPHP] Chilling High Precision Hot Plate Process Station for KrF

Monitoring Parameter

Cool Arm Chilly Water temp.

Valid,Invalid	Valid
Measured Data ID	Cool Arm Chilly Water Temp
Recipe Setting Method	System recipe
Temperature Control Method	Tmp ctl OFF
Recipe Verification Range Lower Limit	20.00
Recipe Verification Range Upper Limit	25.00

Controller TM206-CHILLER

Controller ID	TM206-CHILLER
Channel No.	4
Monitoring Type	Use Point Read
Control Method	Standard
Use Point Offset	Tool specific
Band Monitoring Method at Process Start	Normal
Band Monitoring Invalid Time at Process Start	0.0
Band Monitoring Determination Method during Processing	No Monitor
Band Monitoring Determine Time during Processing	0.0
Band Monitoring Value during Processing	0.00
Pump Frequency	30 -60
Initial Data	22.20
Overtemperature	40.0
Settling Determination Time	5.0
Setting Time-out Time	3600.0
Offset Setting Method	Cotrol setting
Offset	0.00

Cool Arm Chilly Water flow.

Valid,Invalid	Valid
Measured Data ID	C/A cooling water flow rate
Recipe Setting Method	Local
Temperature Control Method	See Table
Recipe Verification Range Lower Limit	0.00
Recipe Verification Range Upper Limit	35.00

Controller TM206-CHILLER

Controller ID	TM206-CHILLER
Channel No.	4
Line No.	See Table
Set Value	See Table
Warning Range Lower Limit	100.00
Warning Range Upper Limit	100.00
Stop Range Lower Limit	100.00
Stop Range Upper Limit	100.00
Offset	0.00

Table for C/A cooling water flow rate - Temperature Control Method

Module	C/A cooling water flow rate	
	Imm/EUV	KrF
14-14(CPHP)	Tmp ctl ON	NA
14-15(CPHP)	Tmp ctl OFF	NA
14-16(CPHP)	Tmp ctl OFF	NA
14-24(CPHP)	Tmp ctl OFF	NA
14-25(CPHP)	Tmp ctl OFF	NA
14-26(CPHP)	Tmp ctl OFF	NA
15-14(CPHP)	Tmp ctl OFF	NA
15-15(CPHP)	Tmp ctl OFF	Tmp ctl ON
15-16(CPHP)	Tmp ctl OFF	Tmp ctl OFF
15-24(CPHP)	Tmp ctl OFF	NA
15-25(CPHP)	Tmp ctl OFF	Tmp ctl OFF
15-26(CPHP)	Tmp ctl OFF	Tmp ctl OFF
16-14(CPHP)	Tmp ctl OFF	NA
16-15(CPHP)	Tmp ctl OFF	Tmp ctl OFF
16-16(CPHP)	Tmp ctl OFF	Tmp ctl OFF
16-24(CPHP)	Tmp ctl OFF	NA
16-25(CPHP)	Tmp ctl OFF	Tmp ctl OFF
16-26(CPHP)	Tmp ctl OFF	Tmp ctl OFF

Table for Controller TM206-CHILLER

	Imm/EUV	Imm/EUV*	TBZ	TBN
Line No.	5	5	6	6
Set Value	7.2	8.4	4.0	4.8

*for dead corner counter installed

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Block 13.14.15.16 PR Block, [CGCH] Chilling General-Purpose Hot Plate Process Station with Cover Heater

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**1-2**
Wafer Store Count	**1**
Start Slot	**0**

Chamber Type

Chamber Type	STD Chamber

Plate Type

Plate Type	Type B

Monitoring Parameter

Plate temp.

Valid,Invalid	Valid
Measured Data ID	Plate temp.
Recipe Setting Method	Process recipe
Temperature Control Method	Tmp ctl ON
Recipe Verification Range Lower Limit	50.00
Recipe Verification Range Upper Limit	250.00

Controller PCU-08-R

Controller ID	PCU-08-R
Start Channel No.	0
End Channel No.	6
Monitoring Type	No sync
Control Method	PID cntrol
SAG Monitor IOID	Module Specific
Band Monitoring Method at Process Start	Setting
Band Monitoring Invalid Time at Process Start	40.0
Band Monitoring Determination Method during Processing	No monitor
Band Monitoring Determination Time during Processing	1.0
Band Monitoring Value during Processing	3.00
PID Setting Method	Control setting
P Constant	1.00
I Constant	4.000
D Constant	0.500
Offset Setting Method	Table setting
Offset	0.00
Display Method Selection	Display all data
Stranded Wafer Detection Valid	Valid
Initial Data	50.00
Overtemperature	255.00
Setting Determination Time	3.0
Setting Time-out Time	2600.0

Control Table Data List

	Valid, Invalid	Set Value Lower Limit	Set Value Upper Limit	Accumulated Threshold Value	Accumulated Time
Temp. Range	Valid	50.00	250	Not Input	Not Input
Temp. Range	Valid	170.00	Not Input	20.00	15.0
Temp. Range	Valid	205.00	Not Input	30.00	15.0
Temp. Range	Valid	225.00	Not Input	50.00	15.0
Temp. Range	Valid	250.00	Not Input	85.00	15.0

*Wafer wedge set up by 1mm ring.

Control Table Data (Temperature Range 50.00 - 250.00)

	Table data No.1	Table data No.2	Table data No.3	Table data No.4	Table data No.5	Table data No.6
Offset	No Input	No Input	No Input	No Input	No Input	No Input
P Constant	No Input	No Input	No Input	No Input	No Input	No Input
I Constant	No Input	No Input	No Input	No Input	No Input	No Input
D Constant	No Input	No Input	No Input	No Input	No Input	No Input

Control Table Data (Temperature Range 170, 205, 250)

	Table data No.1	Table data No.2	Table data No.3	Table data No.4	Table data No.5	Table data No.6
Offset	Tool Specific	Tool Specific	Tool Specific	Tool Specific	Tool Specific	Tool Specific
P Constant	No Input	No Input	No Input	No Input	No Input	No Input
I Constant	No Input	No Input	No Input	No Input	No Input	No Input
D Constant	No Input	No Input	No Input	No Input	No Input	No Input

Control Table Data (Temperature Range All Other)

	Table data No.1	Table data No.2	Table data No.3	Table data No.4	Table data No.5	Table data No.6
Offset	No Input	No Input	No Input	No Input	No Input	No Input
P Constant	No Input	No Input	No Input	No Input	No Input	No Input
I Constant	No Input	No Input	No Input	No Input	No Input	No Input
D Constant	No Input	No Input	No Input	No Input	No Input	No Input

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Block 13.14.15.16 PR Block, [CGCH] Chilling General-Purpose Hot Plate Process Station with Cover Heater

Monitoring Parameter

Cover temp.

Valid,Invalid	Valid
Measured Data ID	Cover temp.
Recipe Setting Method	Process recipe
Temperature Control Method	Tmp ctl ON
Recipe Verification Range Lower Limit	50.00
Recipe Verification Range Upper Limit	250.00

Controller PCU-08-R

Controller ID	PCU-08-R
Start Channel No.	7
End Channel No.	7
Monitoring Type	No sync
Control Method	PID cntrol
Band Monitoring Method at Process Start	Setting
Band Monitoring Invalid Time at Process Start	40.0
Band Monitoring Determination Method during Processing	No monitor
Band Monitoring Determination Time during Processing	1.0
Band Monitoring Value during Processing	3.00
PID Setting Method	Control setting
P Constant	2.60
I Constant	24.000
D Constant	6.000
Offset Setting Method	Table setting
Offset	0.00
Display Method Selection	Display all data
Stranded Wafer Detection Valid	Invalid
Initial Data	50.00
Overtemperature	185.00
Setting Determination Time	3.0
Setting Time-out Time	2600.0

Control Table Data List

	Valid, Invalid	Set Value Lower Limit	Set Value Upper Limit	Accumulated Threshold Value	Accumulated Time
Temp. Range	Invalid	Not Input	Not Input	Not Input	Not Input
Temp. Range	Valid	180.00	Not Input	Not Input	Not Input

Control Table Data (Temperature Range Not Input - Not Input)

	Table data No.1	Table data No.2	Table data No.3	Table data No.4	Table data No.5	Table data No.6	Table data No.7
Offset	No Input	No Input	No Input	No Input	No Input	No Input	No Input
P Constant	No Input	No Input	No Input	No Input	No Input	No Input	No Input
I Constant	No Input	No Input	No Input	No Input	No Input	No Input	No Input
D Constant	No Input	No Input	No Input	No Input	No Input	No Input	No Input

Control Table Data (Temperature Range 180.00 - Not Input)

	Table data No.1	Table data No.2	Table data No.3	Table data No.4	Table data No.5	Table data No.6	Table data No.7
Offset	Tool Specific	No Input	No Input	No Input	No Input	No Input	No Input
P Constant	No Input	No Input	No Input	No Input	No Input	No Input	No Input
I Constant	No Input	No Input	No Input	No Input	No Input	No Input	No Input
D Constant	No Input	No Input	No Input	No Input	No Input	No Input	No Input

Chamber Exhaust Pres

Valid,Invalid	Valid
Measured Data ID	Chamber Exhaust Pres
Recipe Setting Method	Local
Temperature Control Method	Tmp ctl OFF
Recipe Verification Range Lower Limit	0.00
Recipe Verification Range Upper Limit	0.00

Controller Analogue sensor

Controller ID	Analogue Sensor
Band Monitoring Valid, Invalid	Valid
Set Value	16.00/*15.50
Warning Range Lower Limit	2.70
Warning Range Upper Limit	2.70
Stop Range Lower Limit	3.00
Stop Range Upper Limit	3.00
Offset	Tool Specification

*High altitude setting

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Block 13.14.15.16 PR Block, [CGCH] Chilling General-Purpose Hot Plate Process Station with Cover Heater

Monitoring Parameter

Cool Arm Chilly Water temp.

Valid,Invalid	Valid
Measured Data ID	Cool Arm Chilly Water temp.
Recipe Setting Method	System recipe
Temperature Control Method	Tmp ctl OFF
Recipe Verification Range Lower Limit	20.00
Recipe Verification Range Upper Limit	25.00

C/A cooling water flow rate

Valid,Invalid	Valid
Measured Data ID	C/A cooling water flow rate
Recipe Setting Method	Local
Temperature Control Method	See Table
Recipe Verification Range Lower Limit	0.00
Recipe Verification Range Upper Limit	35.00

Table for C/A cooling water flow rate - Temperature Control Method

Module	C/A cooling water flow rate
13-15(CGCH)	Tmp ctl ON
13-16(CGCH)	Tmp ctl OFF
13-24(CGCH)	Tmp ctl OFF
13-25(CGCH)	Tmp ctl OFF
13-26(CGCH)	Tmp ctl OFF
14-15(CGCH)	Tmp ctl OFF
14-16(CGCH)	Tmp ctl OFF
14-24(CGCH)	Tmp ctl OFF
14-25(CGCH)	Tmp ctl OFF
14-26(CGCH)	Tmp ctl OFF
15-15(CGCH)	Tmp ctl OFF
15-16(CGCH)	Tmp ctl OFF
15-24(CGCH)	Tmp ctl OFF
15-25(CGCH)	Tmp ctl OFF
15-26(CGCH)	Tmp ctl OFF
16-15(CGCH)	Tmp ctl OFF
16-16(CGCH)	Tmp ctl OFF
16-24(CGCH)	Tmp ctl OFF
16-25(CGCH)	Tmp ctl OFF
16-26(CGCH)	Tmp ctl OFF

Controller TM206-CHILLER

Item	Cool Arm Chilly Water temp.	C/A cooling water flow rate
Controller ID	TM206-CHILLER	TM206-CHILLER
Channel No.	4	4
Monitoring Type	Use point read	N/A
Control Method	Standard	N/A
Use Point Offset	0	N/A
Band Monitoring Method at Process Start	Normal	N/A
Band Monitoring Invalid Time at Process Start	0.0	N/A
Band Monitoring Determination Method during Processing	No monitor	N/A
Band Monitoring Determination Time during Processing	0.0	N/A
Band Monitoring Value during Processing	0.00	N/A
Pump Frequency	Tool Specific	N/A
Initial Data	23.00	N/A
Overtemperature	40.00	N/A
Setting Determination Time	5.0	N/A
Setting Time-out Time	3600.0	N/A
Offset Setting Method	Control setting	0
Line No.	NA	5
Set Value	NA	8.00
Set Value*	NA	9.60
Warning Range Lower Limit	NA	100.00
Warning Range Upper Limit	NA	100.00
Stop Range Lower Limit	NA	100.00
Stop Range Upper Limit	NA	100.00
Offset	0	0.00

*for dead corner counter installed

Oven Control Parameter

Item	Up Position	Heat Position
United Oven 3Pin Parameter	Module Specific	Module Specific

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Block 11.12.13.14.15.16 PR Block, [CVIP] Chilling Very High Temperature Hot Plate with VE Chamber Process Station

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**1-2**
Wafer Store Count	**1**
Start Slot	**0**

Chamber Type

Chamber Type	CE Chamber

Plate Type

Plate Type	Type 52

Monitoring Parameter

Plate temp.

Valid,Invalid	Valid
Measured Data ID	Plate temp.
Recipe Setting Method	Process recipe
Temperature Control Method	Tmp ctl ON
Recipe Verification Range Lower Limit	50.00
Recipe Verification Range Upper Limit	450

Controller PCU-08-R

Controller ID	PCU-08-R
Start Channel No.	0
End Channel No.	6
Monitoring Type	No sync
Control Method	PID cntrol
SAG Monitor IOID	Module Specific
Band Monitoring Method at Process Start	Setting
Band Monitoring Invalid Time at Process Start	50
Band Monitoring Determination Method during Processing	No monitor
Band Monitoring Determination Time during Processing	1.0
Band Monitoring Value during Processing	3.00
PID Setting Method	Control setting
P Constant	2.1
I Constant	3.3
D Constant	0.4
Offset Setting Method	Table setting
Offset	0.00
Display Method Selection	Display all data
Stranded Wafer Detection Valid	Valid
Initial Data	23.00
Overtemperature	460
Setting Determination Time	3.0
Setting Time-out Time	5000

Control Table Data List

	Valid, Invalid	Set Value Lower Limit	Set Value Upper Limit	Accumulated Threshold Value	Accumulated Time
Temp. Range	Valid	350.00	Not Input	150.00	15.0
Temp. Range	Valid	380.00	Not Input	300.00	15.0
Temp. Range	Valid	400.00	Not Input	500.00	15.0
Temp. Range	Valid	450.00	Not Input	No Input	No Input

*Wafer wedge set up by 1mm ring.

Control Table Data (Temperature Range 350 - Not Imput)

	Table data No.1	Table data No.2	Table data No.3	Table data No.4	Table data No.5	Table data No.6	Table data No.7
Offset	Tool Specific	Tool Specific	Tool Specific	Tool Specific	Tool Specific	Tool Specific	Tool Specific
P Constant	No Input	No Input	No Input	No Input	No Input	No Input	No Input
I Constant	No Input	No Input	No Input	No Input	No Input	No Input	No Input
D Constant	No Input	No Input	No Input	No Input	No Input	No Input	No Input

Control Table Data (Temperature Range 380 - Not Imput)

	Table data No.1	Table data No.2	Table data No.3	Table data No.4	Table data No.5	Table data No.6	Table data No.7
Offset	No Input	No Input	No Input	No Input	No Input	No Input	No Input
P Constant	No Input	No Input	No Input	No Input	No Input	No Input	No Input
I Constant	No Input	No Input	No Input	No Input	No Input	No Input	No Input
D Constant	No Input	No Input	No Input	No Input	No Input	No Input	No Input

Control Table Data (Temperature Range 400 - Not Input)

	Table data No.1	Table data No.2	Table data No.3	Table data No.4	Table data No.5	Table data No.6	Table data No.7
Offset	Tool Specific	Tool Specific	Tool Specific	Tool Specific	Tool Specific	Tool Specific	Tool Specific
P Constant	No Input	No Input	No Input	No Input	No Input	No Input	No Input
I Constant	No Input	No Input	No Input	No Input	No Input	No Input	No Input
D Constant	No Input	No Input	No Input	No Input	No Input	No Input	No Input

Control Table Data (Temperature Range 450 - Not Input)

	Table data No.1	Table data No.2	Table data No.3	Table data No.4	Table data No.5	Table data No.6	Table data No.7
Offset	Tool Specific	Tool Specific	Tool Specific	Tool Specific	Tool Specific	Tool Specific	Tool Specific
P Constant	No Input	No Input	No Input	No Input	No Input	No Input	No Input
I Constant	No Input	No Input	No Input	No Input	No Input	No Input	No Input
D Constant	No Input	No Input	No Input	No Input	No Input	No Input	No Input

***After temperature calibration verify all offset values are not greater than +2**

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Block 11.12.13.14.15.16 PR Block, [CVIP] Chilling Very High Temperature Hot Plate with VE Chamber Process Station

Monitoring Parameter

Cover Temp

Valid,Invalid	Valid
Measured Data ID	Cover temp.
Recipe Setting Method	Process recipe
Temperature Control Method	Tmp ctl ON
Recipe Verification Range Lower Limit	50.00
Recipe Verification Range Upper Limit	350.00

Controller PCU-08-R

Controller ID	PCU-08-R
Start Channel No.	7
End Channel No.	7
Monitoring Type	No sync
Control Method	PID cntrol
SAG Monitor IOID	Module Specific
Band Monitoring Method at Process Start	Setting
Band Monitoring Invalid Time at Process Start	50
Band Monitoring Determination Method during Processing	No monitor
Band Monitoring Determination Time during Processing	1.0
Band Monitoring Value during Processing	3.00
PID Setting Method	Control setting
P Constant	1.4
I Constant	30.2
D Constant	6.7
Offset Setting Method	Table setting
Offset	0.00
Display Method Selection	Display all data
Stranded Wafer Detection Valid	Invalid
Initial Data	23.00
Overtemperature	360
Setting Determination Time	3.0
Setting Time-out Time	5000

Control Table Data List

	Valid, Invalid	Set Value Lower Limit	Set Value Upper Limit	Accumulated Threshold Value	Accumulated Time
Temp. Range2	Valid	Not Input	Not Input	Not Input	Not Input

Outer Chamber Exhaust Pres

Valid,Invalid	Valid
Measured Data ID	Chamber Exhaust Pres F
Recipe Setting Method	Local
Temperature Control Method	Tmp ctl OFF
Recipe Verification Range Lower Limit	0.00
Recipe Verification Range Upper Limit	0.00

Controller Analogue sensor

Controller ID	Analogue Sensor
Band Monitoring Valid, Invalid	Valid
Set Value	26.00/*25.1
Warning Range Lower Limit	8.00
Warning Range Upper Limit	8.00
Stop Range Lower Limit	10.00
Stop Range Upper Limit	10.00
Offset	Tool Specification

*High altitude setting

Chamber Exhaust Pres

Valid,Invalid	Valid
Measured Data ID	Chamber Exhaust Pres
Recipe Setting Method	Local
Temperature Control Method	Tmp ctl OFF
Recipe Verification Range Lower Limit	0.00
Recipe Verification Range Upper Limit	0.00

Controller Analogue sensor

Controller ID	Analogue Sensor
Band Monitoring Valid, Invalid	Valid
Set Value	26.00/*25.1
Warning Range Lower Limit	6.00
Warning Range Upper Limit	6.00
Stop Range Lower Limit	8.00
Stop Range Upper Limit	8.00
Offset	Tool Specification

*High altitude setting

Controller Analogue sensor

Controller ID	Analogue Sensor
Band Monitoring Valid, Invalid	Valid
Set Value 2	0.00
Warning Range Lower Limit	2.00
Warning Range Upper Limit	2.00
Stop Range Lower Limit	3.00
Stop Range Upper Limit	3.00
Offset	Tool Specification

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Block 16 PR Block, [CXHN] Chilling Extreme High Temperature Hot Plate Process Station under Nitrogen Ambient

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**Invalid**
Wafer Store Count	**1**
Start Slot	**0**

Chamber Type

Chamber Type	STD Chamber

Plate Type

Plate Type	Type B

Monitoring Parameter

Plate temp.

Valid,Invalid	Valid
Measured Data ID	Plate temp.
Recipe Setting Method	Process recipe
Temperature Control Method	Tmp ctl ON
Recipe Verification Range Lower Limit	50.00
Recipe Verification Range Upper Limit	600

Controller PCU-08-R

Controller ID	PCU-08-RE
Start Channel No.	0
End Channel No.	2
Monitoring Type	No sync
Control Method	Overshoot Restraint ctr
SAG Monitor IOID	Module Specific
Band Monitoring Method at Process Start	Setting
Band Monitoring Invalid Time at Process Start	50
Band Monitoring Determination Method during Processing	No monitor
Band Monitoring Determination Time during Processing	1.0
Band Monitoring Value during Processing	3.00
PID Setting Method	Table Ssetting
P Constant	4
I Constant	100
D Constant	20
Offset Setting Method	Table setting
Offset	0.00
Display Method Selection	Display all data
Stranded Wafer Detection Valid	Valid
Initial Data	23.00
Overtemperature	620
Setting Determination Time	3.0
Setting Time-out Time	3600

* Place Holder

Control Table Data List

	Valid, Invalid	Set Value Lower Limit	Set Value Upper Limit	Accumulated Threshold Value	Accumulated Time
Temp. Range	Valid	0.00	600	Not Input	Not Input
Temp. Range	Valid	450.00	Not Input	Not Input	Not Input
Temp. Range	Valid	450.00	475	Not Input	Not Input
Temp. Range	Valid	475.01	525	Not Input	Not Input
Temp. Range	Valid	525.01	575	Not Input	Not Input
Temp. Range	Valid	575.01	600	Not Input	Not Input

Control Table Data (Temperature Range 0 - 600)

	Table data No.1	Table data No.2	Table data No.3
Offset	Not Input	Not Input	Not Input
P Constant	4	9.6	9.6
I Constant	80	100	100
D Constant	20	200	200

Control Table Data (Temperature Range 450 - Not Input)

	Table data No.1	Table data No.2	Table data No.3
Offset	Tool Specific	Tool Specific	Tool Specific
P Constant	Not Input	Not Input	Not Input
I Constant	Not Input	Not Input	Not Input
D Constant	Not Input	Not Input	Not Input

* place holder

Control Table Data (Temperature Range 450 - 475)

	Table data No.1	Table data No.2	Table data No.3
Offset	Not Input	Not Input	Not Input
P Constant	4	8.4	10.8
I Constant	80	100	100
D Constant	20	20	20

Control Table Data (Temperature Range 475.01 - 525)

	Table data No.1	Table data No.2	Table data No.3
Offset	Not Input	Not Input	Not Input
P Constant	4	9.6	10.4
I Constant	80	100	100
D Constant	20	200	200

Control Table Data (Temperature Range 525.01 - 575)

	Table data No.1	Table data No.2	Table data No.3
Offset	Not Input	Not Input	Not Input
P Constant	4	9.6	10
I Constant	80	100	100
D Constant	20	20	20

Control Table Data (Temperature Range 575.01 - 600

	Table data No.1	Table data No.2	Table data No.3
Offset	Not Input	Not Input	Not Input
P Constant	4	9.6	9.6
I Constant	80	100	100
D Constant	20	20	20

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Block 16 PR Block, [CXHN] Chilling Extreme High Temperature Hot Plate Process Station under Nitrogen Ambient

Chamber Exhaust Pres

Valid,Invalid	Valid
Measured Data ID	Chamber Exhaust Pres
Recipe Setting Method	Local
Temperature Control Method	Tmp ctl OFF
Recipe Verification Range Lower Limit	0.00
Recipe Verification Range Upper Limit	0.00

Controller Analogue sensor

Controller ID	Analogue Sensor
Band Monitoring Valid, Invalid	Invalid
Set Value	0.00
Warning Range Lower Limit	500.00
Warning Range Upper Limit	500.00
Stop Range Lower Limit	500.00
Stop Range Upper Limit	500.00
Offset	Tool Specification

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Block 11.12.13.14.15.16 PR Block, [SCPL] Slim Chill Plate Process Station

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**1-2***
Wafer Store Count	**1**
Start Slot	**0**

* 1*-33, 34 Invalid

Plate Vacuum

Plate Vacuum	With

Monitoring Parameter

Plate temp. / Plate Chilly water flow rate

Item	Plate temp.	Plate Chilly water flow rate
Valid,Invalid	Valid	Valid
Measured Data ID	Plate Chilly Water temp.	Plate Chilly water flow rate
Recipe Setting Method	System recipe	Local
Temperature Control Method	See Table	See Table
Recipe Verification Range Lower Limit	20.00	0.00
Recipe Verification Range Upper Limit	25.00	35.00

Controller TM206-CHILLER

Item	Plate temp.	Plate Chilly water flow rate
Controller ID	TM206-CHILLER	TM206-CHILLER
Channel No.	See Table	See Table
Monitoring Type	See Table	N/A
Control Method	Standard	N/A
Use Point Offset	See Table	N/A
Band Monitoring Method at Process Start	Normal	N/A
Band Monitoring Invalid Time at Process Start	0.0	N/A
Band Monitoring Determination Method during Processing	No monitor	N/A
Band Monitoring Determination Time during Processing	0.0	N/A
Band Monitoring Value during Processing	0.00	N/A
Source Value Monitoring Valid	See Table	N/A
Source Value Monitoring Band	See Table	N/A
Pump Frequency	30 ~ 60	N/A
Initial Data	See Table	N/A
Overtemperature	40.00	N/A
Setting Determination Time	5.0	N/A
Setting Time-out Time	3600.0	N/A
Line No.	NA	See Table
Set Value	NA	See Table
Warning Range Lower Limit	NA	100.00
Warning Range Upper Limit	NA	100.00
Stop Range Lower Limit	NA	100.00
Stop Range Upper Limit	NA	100.00
Offset	NA	0.00

Table for Temperature Control Method

Configuration	Module	Plate temp.	Plate Chilly water flow rate
BARC tool	13-31 (SCPL)	Tmp ctl ON	Tmp ctl ON
BARC tool	13-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	14-31 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	14-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	15-31 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	15-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	16-31 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	16-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
PBR tool	11-31 (SCPL)	Tmp ctl ON	Tmp ctl ON
PBR tool	11-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
PBR tool	12-31 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
PBR tool	12-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
PBR tool	13-31 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
PBR tool	13-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
PBR tool	14-31 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
PBR tool	14-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
PBR tool	15-31 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
PBR tool	15-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
PBR tool	16-31 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
PBR tool	16-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	11-31 (SCPL)	Tmp ctl ON	Tmp ctl ON
Imm tool	11-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	11-33 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	11-34 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	12-31 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	12-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	12-33 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	12-34 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	13-31 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	13-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	13-33 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	13-34 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	14-31 (SCPL)	Tmp ctl ON	Tmp ctl ON
Imm tool	14-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	15-31 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	15-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	16-31 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	16-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
EUV tool	12-31 (SCPL)	Tmp ctl ON	Tmp ctl ON
EUV tool	12-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
EUV tool	12-33 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
EUV tool	12-34 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
EUV tool	13-31 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
EUV tool	13-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
EUV tool	13-33 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
EUV tool	13-34 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
EUV tool	14-31 (SCPL)	Tmp ctl ON	Tmp ctl ON
EUV tool	14-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
EUV tool	15-31 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
EUV tool	15-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
EUV tool	16-31 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
EUV tool	16-32 (SCPL)	Tmp ctl OFF	Tmp ctl OFF
TBN only	12-31 SCPL	Tmp ctl ON	Tmp ctl ON
TBN only	12-32 SCPL	Tmp ctl OFF	Tmp ctl OFF
KrF tool	13-31 SCPL	Tmp ctl ON	Tmp ctl ON
KrF tool	13-31 SCPL	Tmp ctl ON	Tmp ctl ON
KrF tool	13-32 SCPL	Tmp ctl OFF	Tmp ctl OFF
KrF tool	14-31 SCPL	Tmp ctl OFF	Tmp ctl OFF
KrF tool	14-32 SCPL	Tmp ctl OFF	Tmp ctl OFF
KrF tool	15-31 SCPL	Tmp ctl ON	Tmp ctl ON
KrF tool	15-32 SCPL	Tmp ctl OFF	Tmp ctl OFF
TBN only	15-33 SCPL	Tmp ctl OFF	Tmp ctl OFF
TBN only	15-34 SCPL	Tmp ctl OFF	Tmp ctl OFF
KrF tool	16-31 SCPL	Tmp ctl OFF	Tmp ctl OFF
KrF tool	16-32 SCPL	Tmp ctl OFF	Tmp ctl OFF
TBN only	16-33 SCPL	Tmp ctl OFF	Tmp ctl OFF
TBN only	16-34 SCPL	Tmp ctl OFF	Tmp ctl OFF

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Block 11.12.13.14.15.16 PR Block, [SCPL] Slim Chill Plate Process Station

Table for Channel No. / Monitoring Type / Use Point Offset / Initial Data / Source Value Monitoring Valid/ Source Value Monitoring Band / Line No. / Set Value

Configuration	Module	Channel No.	Monitoring Type	Use Point Offset	Initial Data	Source Value Monitoring Valid	Source Value Monitoring Band	Line No.	Set Value
BARC tool	13-31 SCPL	4	Use point control	Tool Specific	22.2	Valid	10	4	25.00
BARC tool	13-32 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	25.00
BARC tool	14-31 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	25.00
BARC tool	14-32 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	25.00
BARC tool	15-31 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	25.00
BARC tool	15-32 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	25.00
BARC tool	16-31 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	25.00
BARC tool	16-32 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	25.00
PBR tool	11-31 SCPL	4	Use point control	Tool Specific	22.2	Valid	10	4	37.00
PBR tool	11-32 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
PBR tool	12-31 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
PBR tool	12-32 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
PBR tool	13-31 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
PBR tool	13-32 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
PBR tool	14-31 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
PBR tool	14-32 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
PBR tool	15-31 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
PBR tool	15-32 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
PBR tool	16-31 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
PBR tool	16-32 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
Imm tool	11-31 SCPL	4	Use point control	Tool Specific	22.2	Valid	10	4	37.00
Imm tool	11-32 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
Imm tool	11-33 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
Imm tool	11-34 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
Imm tool	12-31 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
Imm tool	12-32 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
Imm tool	12-33 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
Imm tool	12-34 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
Imm tool	13-31 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
Imm tool	13-32 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
Imm tool	13-33 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
Imm tool	13-34 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
Imm tool	14-31 SCPL	5	Use point control	Tool Specific	23.0	Valid	10	8	19.00
Imm tool	14-32 SCPL	5	Use point read	0.00	23.0	N/A	N/A	8	19.00
Imm tool	15-31 SCPL	5	Use point read	0.00	23.0	N/A	N/A	8	19.00
Imm tool	15-32 SCPL	5	Use point read	0.00	23.0	N/A	N/A	8	19.00
Imm tool	16-31 SCPL	5	Use point read	0.00	23.0	N/A	N/A	8	19.00
Imm tool	16-32 SCPL	5	Use point read	0.00	23.0	N/A	N/A	8	19.00
EUV tool	12-31 SCPL	4	Use point control	Tool Specific	22.2	Valid	10	4	37.00
EUV tool	12-32 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
EUV tool	12-33 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
EUV tool	12-34 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
EUV tool	13-31 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
EUV tool	13-32 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
EUV tool	13-33 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
EUV tool	13-34 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	37.00
EUV tool	14-31 SCPL	5	Use point control	Tool Specific	23.0	Valid	10	8	19.00
EUV tool	14-32 SCPL	5	Use point read	0.00	23.0	N/A	N/A	8	19.00
EUV tool	15-31 SCPL	5	Use point read	0.00	23.0	N/A	N/A	8	19.00
EUV tool	15-32 SCPL	5	Use point read	0.00	23.0	N/A	N/A	8	19.00
EUV tool	16-31 SCPL	5	Use point read	0.00	23.0	N/A	N/A	8	19.00
EUV tool	16-32 SCPL	5	Use point read	0.00	23.0	N/A	N/A	8	19.00
TBN only	12-31 SCPL	4	Use point control	Tool Specific	22.2	Valid	10	4	19.00
TBN only	12-32 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	19.00
TBZ only	13-31 SCPL	4	Use point control	Tool Specific	22.2	Valid	10	4	19.00
TBN only	13-31 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	19.00
KrF tool	13-32 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	19.00
KrF tool	14-31 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	19.00
KrF tool	14-32 SCPL	4	Use point read	0.00	22.2	N/A	N/A	4	19.00
KrF tool	15-31 SCPL	5	Use point control	Tool Specific	23.0	Valid	10	8	25.00
KrF tool	15-32 SCPL	5	Use point read	0.00	23.0	N/A	N/A	8	25.00
TBN only	15-33 SCPL	5	Use point read	0.00	23.0	N/A	N/A	8	25.00
TBN only	15-34 SCPL	5	Use point read	0.00	23.0	N/A	N/A	8	25.00
KrF tool	16-31 SCPL	5	Use point read	0.00	23.0	N/A	N/A	8	25.00
KrF tool	16-32 SCPL	5	Use point read	0.00	23.0	N/A	N/A	8	25.00
TBN only	16-33 SCPL	5	Use point read	0.00	23.0	N/A	N/A	8	25.00
TBN only	16-34 SCPL	5	Use point read	0.00	23.0	N/A	N/A	8	25.00

Plate VAC pressure

Valid,Invalid	Valid
Measured Data ID	Plate VAC pressuer
Recipe Setting Method	Local
Temperature Contol Method	Tmp ctl OFF
Recipe Verification Range Lower Limit	0.00
Recipe Verification Range Lower Limit	0.00

Controller Analogue sensor

Controller ID	Analogue sensor
Band Monitoring Valid,Invalid	Invalid
Set Value	0.00
Warning Range Lower Limit	0.00
Warning Range Upper Limit	0.00
Stop Range Lower Limit	0.00
Stop Range Upper Limit	0.00
Offset	0.00

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Block IFB Block, [ICPL] Interface Chill Plate Process Station

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**Invalid**
Wafer Store Count	**1**
Start Slot	**0**

Plate Vacuum

Plate Vacuum	With

Monitoring Parameter

Plate temp. / Plate Chilly water flow rate

Item	Plate Chilly Water temp.	Plate Chilly water flow rate
Valid,Invalid	Valid	Valid
Measured Data ID	Plate Chilly Water temp.	Plate Chilly water flow rate
Recipe Setting Method	System recipe	Local
Temperature Control Method	See Table	See Table
Recipe Verification Range Lower Limit	20.00	0.00
Recipe Verification Range Upper Limit	25.00	35.00

Table for Temperature Control Method

Module	Plate temp.	Plate Chilly water flow rate
30-6 (ICPL)	Tmp ctl ON	Tmp ctl ON
30-7 (ICPL)	Tmp ctl OFF	Tmp ctl OFF
30-8 (ICPL)	Tmp ctl OFF	Tmp ctl OFF

Controller TM206-CHILLER

Item	Plate temp.	Plate Chilly water flow rate
Controller ID	TM206-CHILLER	TM206-CHILLER
Channel No.	See Table	3
Monitoring Type	See Table	N/A
Control Method	Standard	N/A
Use Point Offset	See Table	N/A
Band Monitoring Method at Process Start	Normal	N/A
Band Monitoring Invalid Time at Process Start	0.0	N/A
Band Monitoring Determination Method during Processing	No monitor	N/A
Band Monitoring Determination Time during Processing	0.0	N/A
Band Monitoring Value during Processing	0.00	N/A
Source Value Monitoring Valid	See Table	N/A
Source Value Monitoring Band	See Table	N/A
Pump Frequency	30-60	N/A
Initial Data	See Table	N/A
Overtemperature	40.00	N/A
Setting Determination Time	5.0	N/A
Setting Time-out Time	3600.0	N/A
RTCtrl*	Valid	N/A
Slope*	Tool Specific	N/A
Intercept*	Tool Specific	N/A
Threshold*	0.05	N/A
Line No.	NA	3
Set Value	NA	6.20
Warning Range Lower Limit	NA	100.00
Warning Range Upper Limit	NA	100.00
Stop Range Lower Limit	NA	100.00
Stop Range Upper Limit	NA	100.00
Offset	NA	0.00

* =Only "Use point control" module present

Table

Configuration	Module	Controller TM206-CHILLER		Use Point Offset	Initial Data	Source Value Monitoring Valid	Source Value Monitoring Band
		Channel No.	Monitoring Type	Temperature Control Method	Temperature		
Imm/EUV tool	30-6 ICPL	3	Use point control	Tool Specific	22.20	Invalid	10
Imm/EUV tool	30-7 ICPL	3	Use point read	0.00	22.20	N/A	N/A
Imm/EUV tool	30-8 ICPL	3	Use point read	0.00	22.20	N/A	N/A
KrF tool	30-6 ICPL	4	Use point control	Tool Specific	22.20	Invalid	10
KrF tool	30-7 ICPL	4	Use point read	0.00	22.20	N/A	N/A
KrF tool	30-8 ICPL	4	Use point read	0.00	22.20	N/A	N/A

IFBS Temp.

Valid,Invalid	Valid
Measured Data ID	IFBS Temp
Recipe Setting Method	Local
Temperature Contol Method	Tmp ctl OFF
Recipe Verification Range Lower Limit	0.00
Recipe Verification Range Lower Limit	0.00

Controller Analogue sensor

Controller ID	Analogue sensor
Band Monitoring Valid,Invalid	Valid
Set Value	24.00
Warning Range Lower Limit	3.00
Warning Range Upper Limit	3.00
Stop Range Lower Limit	5.00
Stop Range Upper Limit	5.00
Offset	0.00

Plate VAC pressure

Valid,Invalid	Valid
Measured Data ID	Plate VAC pressuer
Recipe Setting Method	Local
Temperature Contol Method	Tmp ctl OFF
Recipe Verification Range Lower Limit	0.00
Recipe Verification Range Lower Limit	0.00

Controller Analogue sensor

Controller ID	Analogue sensor
Band Monitoring Valid,Invalid	Invalid
Set Value	0.00
Warning Range Lower Limit	0.00
Warning Range Upper Limit	0.00
Stop Range Lower Limit	0.00
Stop Range Upper Limit	0.00
Offset	0.00

Oven Control Parameter

Item	Up Position	Heat Position
CPL 3Pin Parameter	Module Specific	Module Specific

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Block IFB Block, [RSM] Resuming Stage

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**Invalid**
Wafer Store Count	**1**
Start Slot	**0**

Block IFB Block, [RSMC] Resuming Chill Plate

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**Invalid**
Wafer Store Count	**1**
Start Slot	**0**

Plate Vacuum

Plate Vacuum	With

Monitoring Parameter

Plate temp. / Plate Chilly water flow rate

Item	Plate Chilly Water temp.	Plate Chilly Water flow rate
Valid,Invalid	Valid	Valid
Measured Data ID	Plate Chilly Water temp.	Plate Chilly water flow rate
Recipe Setting Method	System recipe	Local
Temperature Control Method	Tmp ctl OFF	Tmp ctl OFF
Recipe Verification Range Lower Limit	20.00	0.00
Recipe Verification Range Upper Limit	25.00	35.00

Controller TM206-CHILLER

Item	Plate temp.	Plate Chilly Water flow rate
Controller ID	TM206-CHILLER	TM206-CHILLER
Channel No.	3	3
Monitoring Type	Use point read	N/A
Control Method	Standard	N/A
Use Point Offset	0.00	N/A
Band Monitoring Method at Process Start	Normal	N/A
Band Monitoring Invalid Time at Process Start	0.0	N/A
Band Monitoring Determination Method during Processing	No monitor	N/A
Band Monitoring Determination Time during Processing	0.0	N/A
Band Monitoring Value during Processing	0.00	N/A
Pump Frequency	30-60	N/A
Initial Data	22.20	N/A
Overtemperature	40.00	N/A
Setting Determination Time	5.0	N/A
Setting Time-out Time	3600.0	N/A
Line No.	NA	3
Set Value	NA	6.20
Warning Range Lower Limit	NA	100.00
Warning Range Upper Limit	NA	100.00
Stop Range Lower Limit	NA	100.00
Stop Range Upper Limit	NA	100.00
Offset	NA	0.00

Plate VAC pressure

Valid,Invalid	Valid
Measured Data ID	Plate VAC pressuer
Recipe Setting Method	Local
Temperature Contol Method	Tmp ctl OFF
Recipe Verification Range Lower Limit	0.00
Recipe Verification Range Lower Limit	0.00

Controller Analogue sensor

Controller ID	Analogue sensor
Band Monitoring Valid,Invalid	Invalid
Set Value	0.00
Warning Range Lower Limit	0.00
Warning Range Upper Limit	0.00
Stop Range Lower Limit	0.00
Stop Range Upper Limit	0.00
Offset	0.00

Block IFB Block, [EIF] Exposure Interface

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**Invalid**
Wafer Store Count	**15**
Start Slot	**0**

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Block 13.14.15.16 PR Block, [CADH] Chilling Adhesion Process Station for BARC tool*

*N/A for no CADH tool TBFna / TBFlt / TBFcn

Block 11.12.13 PR Block, [CADH] Chilling Adhesion Process Station for Imm tool
Block 13.14 PR Block, [CADH] Chilling Adhesion Process Station for KrF tool

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**1-2**
Wafer Store Count	**1**
Start Slot	**0**

Chamber Type

Chamber Type	STD Chamber

Plate Type

Plate Type	Type A

Monitoring Parameter - Local Nozzle - HMDS VAPOR

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid

Dispense Mechanism Connection

Valid, Invalid	Valid

Dispense Port Connection

Dispense System Type	Dispense port

Press Watch

Port Press Watch Valid	Valid
Delay Time Before Press Watch	5.0
Press Watch Upper Limit	0.00
Press Watch Lower Limit	0.70

Dispense Monitoring Mechanism Connection

Valid, Invalid	Valid

Mass flow meter

Dispense Monitoring Type	Mass flow meter

Dispense Monitoring Control Data

Pulse Rate	0.05
Delay Time	0.60
Set Flow Rate	2500
Flow Rate Sensor Check Timing	Dispense end
Calibration 1	0.90 ~ 1.05
Offset	0
Upper Limit Error Level	30.00%
Upper Limit Warning Level	20.00%
Lower Limit Error Level	30.00%
Lower Limit Warning Level	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Invalid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

Supply System

Valid, Invalid	Valid

HMDS Supply System

Refill Monitoring Time	180 sec	
Exhaust Valve Close Delay Time	1.0sec	
*Dispense Count Upper Limit	Invalid	*Dose not matter to INTEL
HL Sensor Watch Time	4 sec	

Container Refill System

Valid, Invalid	Valid
Prior Pressurization Time	20 sec

Automatic Air Vent

Air Vent Monitoring Time	30 sec
Delay Time after LE Sensor Detection	1 sec
Prior Pressurization Time	5 sec

CHAMBER EXH.

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid

Dispense Mechanism Connection

Valid, Invalid	Valid

Dispense Monitoring Mechanism Connection

Valid, Invalid	Valid

Mass flow meter

Dispense Monitoring Type	Mass flow meter

Dispense Monitoring Control Data

Pulse Rate	0.05
Delay Time	0.60
Set Flow Rate	5000
Flow Rate Sensor Check Timing	Dispense end
Calibration 1	0.90 ~ 1.05
Offset	0
Upper Limit Error Level	30.00%
Upper Limit Warning Level	20.00%
Lower Limit Error Level	30.00%
Lower Limit Warning Level	20.00%
Dummy Dispense Flow Rate Monitoring Valid/Invalid	Valid
Monitoring Flow Rate Upper Limit for Short Time Dispense	Execute
Flow Rate Upper Limit Non-monitoring Time for Short Time Dispense	1.0

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Block 13.14.15.16 PR Block, [CADH] Chilling Adhesion Process Station for BARC tool*

*N/A for no CADH tool TBFna / TBFlt / TBFcn

Block 11.12.13 PR Block, [CADH] Chilling Adhesion Process Station for Imm tool
Block 13.14 PR Block, [CADH] Chilling Adhesion Process Station for KrF tool

BUFFER BUBBLING

Process Recipe Attribute	Valid
Dummy Dispense Attribute	Valid

Dispense Mechanism Connection

Valid, Invalid	Valid

Controller PCU-01-R

Controller ID	PCU-01-R
Channel No.	0
Monitoring Type	No sync
Control Method	Overshoot Restraint ctrl
SAG Monitor IOID	Module Specific
Band Monitoring Method at Process Start	Normal
Band Monitoring Invalid Time at Process Start	0.0
Band Monitoring Determination Method during Processing	No monitor
Band Monitoring Determination Time during Processing	1.0
Band Monitoring Value during Processing	3.00
PID Setting Method	Table setting
P Constant	0.90
I Constant	15.000
D Constant	2.400
Offset Setting Method	Table setting
Offset	0.00
Stranded Wafer Detection Valid	Valid
Initial Data	50.00
Overtemperature	185.00
Setting Determination Time	30.00
Setting Time-out Time	1800.00

Monitoring Parameter

Plate temp.

Valid,Invalid	Valid
Measured Data ID	Plate temp.
Recipe Setting Method	Process recipe
Temperature Control Method	Tmp ctl ON
Recipe Verification Range Lower Limit	50.00
Recipe Verification Range Upper Limit	180.00

Control Table Data List for BARC/Imm/EUV

	Valid, Invalid	Set Value Lower Limit	Set Value Upper Limit	Accumulated Threshold Value	Accumulated Time
Temp. Range	Valid	0.00	180.00	Not Input	Not Input
Temp. Range	Valid	90	Not Input	37.00	10.00
Temp. Range	Valid	110.0	Not Input	52.00	10.00
Temp. Range	Valid	150.0	Not Input	80.00	10.00

*Wafer wedge set up by 3mm ring.

Control Table Data List for KrF

	Valid, Invalid	Set Value Lower Limit	Set Value Upper Limit	Accumulated Threshold Value	Accumulated Time
Temp. Range	Valid	0.00	180.00	Not Input	Not Input
Temp. Range	Valid	90.00	Not Input	37.00	10.00
Temp. Range	Valid	110.00	Not Input	52.00	10.00
Temp. Range	Valid	150.00	Not Input	20.00	10.00
Temp. Range	Valid	150.10	Not Input	80.00	10.00

*Wafer wedge set up by 3mm ring.

Control Table Data 1
(Temperature Range 0.00 - 180.00)

	Table data No.1
Offset	Not Input
P Constant	0.90
I Constant	15.000
D Constant	2.400

Control Table Data 3
(Temperature Range 110.00)

	Table data No.1
Offset	Not Input
P Constant	0.85
I Constant	15.300
D Constant	2.700

Control Table Data 5* * KrF only
(Temperature Range 150.10)

	Table data No.1
Offset	Not Input
P Constant	0.85
I Constant	14.700
D Constant	2.700

Control Table Data 2
(Temperature Range 90.00)

	Table data No.1
Offset	Not Input
P Constant	0.90
I Constant	15.000
D Constant	2.400

Control Table Data 4
(Temperature Range 150.00)

	Table data No.1
Offset	Module Specific
P Constant	0.85
I Constant	14.700
D Constant	2.700

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6. System Config Parameter, Ovens

Block 13.14.15.16 PR Block, [CADH] Chilling Adhesion Process Station for BARC tool

*N/A for no CADH tool TBFna / TBFlt / TBFcn

Block 11.12.13 PR Block, [CADH] Chilling Adhesion Process Station for Imm tool
Block 13.14 PR Block, [CADH] Chilling Adhesion Process Station for KrF tool

Monitoring Parameter

HMDS Bubbler Tank temp.

Valid,Invalid	Valid
Measured Data ID	HMDS Bubbler Tank temp.
Recipe Setting Method	System recipe
Temperature Control Method	See Table
Recipe Verification Range Lower Limit	20.00
Recipe Verification Range Upper Limit	25.00

HMDS Temp. Control flow rate

Valid,Invalid	Valid
Measured Data ID	HMDS Temp. Control flow rate
Recipe Setting Method	Local
Temperature Control Method	See Table
Recipe Verification Range Lower Limit	0.00
Recipe Verification Range Upper Limit	35.00

Controller TM206-CHILLER

Item	HMDS Bubbler Tank temp.	HMDS Temp. Control flow rate
Controller ID	TM206-CHILLER	TM206-CHILLER
Channel No.	0	0
Monitoring Type	Use point control	N/A
Control Method	Standard	N/A
Use Point Offset	Tool Specific	N/A
Band Monitoring Method at Process Start	Normal	N/A
Band Monitoring Invalid Time at Process Start	0.0	N/A
Band Monitoring Determination Method during Processing	No monitor	N/A
Band Monitoring Determination Time during Processing	0.0	N/A
Band Monitoring Value during Processing	0.00	N/A
Source Value Monitoring Valid	Invalid	N/A
Source Value Monitoring Band	10	N/A
Pump Frequency	Tool Specific	N/A
Initial Data	22.00	N/A
Overtemperature	40.00	N/A
Setting Determination Time	5.0	N/A
Setting Time-out Time	3600.0	N/A
Line No.	NA	0
Set Value	NA	2.00
Warning Range Lower Limit	NA	100.00
Warning Range Upper Limit	NA	100.00
Stop Range Lower Limit	NA	100.00
Stop Range Upper Limit	NA	100.00
Offset	NA	0.00

Table for 13-11 CADH HMDS Bubbler Tank temp.

TBZ	TBN
Tmp ctl ON	Tmp ctl OFF

Table for Temperature Control Method

Configuration	Module	HMDS Bubbler Tank temp.	HMDS Temp. Control flow rate
BARC tool	13-11 (CADH)	Tmp ctl ON	Tmp ctl ON
BARC tool	13-12 (CADH)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	13-21 (CADH)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	13-22 (CADH)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	14-11 (CADH)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	14-12 (CADH)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	14-21 (CADH)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	14-22 (CADH)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	15-11 (CADH)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	15-12 (CADH)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	15-21 (CADH)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	15-22 (CADH)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	16-11 (CADH)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	16-12 (CADH)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	16-21 (CADH)	Tmp ctl OFF	Tmp ctl OFF
BARC tool	16-22 (CADH)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	11-11 (CADH)	Tmp ctl ON	Tmp ctl ON
Imm tool	11-12 (CADH)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	11-21 (CADH)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	11-22 (CADH)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	12-11 (CADH)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	12-12 (CADH)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	12-21 (CADH)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	12-22 (CADH)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	13-11 (CADH)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	13-12 (CADH)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	13-21 (CADH)	Tmp ctl OFF	Tmp ctl OFF
Imm tool	13-22 (CADH)	Tmp ctl OFF	Tmp ctl OFF
EUV tool	12-11 (CADH)	Tmp ctl ON	Tmp ctl ON
EUV tool	12-12 (CADH)	Tmp ctl OFF	Tmp ctl OFF
EUV tool	12-21 (CADH)	Tmp ctl OFF	Tmp ctl OFF
EUV tool	12-22 (CADH)	Tmp ctl OFF	Tmp ctl OFF
EUV tool	13-11 (CADH)	Tmp ctl OFF	Tmp ctl OFF
EUV tool	13-12 (CADH)	Tmp ctl OFF	Tmp ctl OFF
EUV tool	13-21 (CADH)	Tmp ctl OFF	Tmp ctl OFF
EUV tool	13-22 (CADH)	Tmp ctl OFF	Tmp ctl OFF
TBN	12-11 (CADH)	Tmp ctl ON	Tmp ctl ON
TBN	12-12 (CADH)	Tmp ctl OFF	Tmp ctl OFF
TBN	12-21 (CADH)	Tmp ctl OFF	Tmp ctl OFF
KrF tool	13-11 (CADH)	See table	Tmp ctl ON
KrF tool	13-12 (CADH)	Tmp ctl OFF	Tmp ctl OFF
KrF tool	13-21 (CADH)	Tmp ctl OFF	Tmp ctl OFF
TBZ	13-22 (CADH)	Tmp ctl OFF	Tmp ctl OFF
KrF tool	14-11 (CADH)	Tmp ctl OFF	Tmp ctl OFF
KrF tool	14-12 (CADH)	Tmp ctl OFF	Tmp ctl OFF
KrF tool	14-21 (CADH)	Tmp ctl OFF	Tmp ctl OFF
TBZ	14-22 (CADH)	Tmp ctl OFF	Tmp ctl OFF

Chamber High Exhaust Pres

Valid,Invalid	Valid
Measured Data ID	Chamber High Exhaust Pres
Recipe Setting Method	Local
Temperature Control Method	Tmp ctl OFF
Recipe Verification Range Lower Limit	0.00
Recipe Verification Range Upper Limit	0.00

Contoroller Analogue sensor

Controller ID	Analogue sensor
Band Monitoring Valid, Invalid	Valid
Set Value	4.70/*4.50
Warning Range Lower Limit	0.50
Warning Range Upper Limit	0.50
Stop Range Lower Limit	0.80
Stop Range Upper Limit	0.80
Offset	0.00

*High altitude setting

Oven Control Parameter

Item	Up Position	Heat Position
United Oven 3Pin Parameter	Module Specific	Module Specific

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6. System Config Parameter, Ovens

Block 1 CS Block, [SBU] Stationery Buffering Stage

Module Parameter

Item / Module	1-5 (SBU)	1-7 (SBU)	1-28 (SBU)	1-29 (SBU)
Reserved Flag	**Valid**	**Valid**	**Invalid**	**Invalid**
Fork Simultaneous Swapping Level	**Invalid**	**Invalid**	**Invalid**	**Invalid**
Wafer Store Count	**5**	**3**	**3**	**5**
Start Slot	**1**	**1**	**1**	**1**

Position Data

	HCRA-B / HCRA-F
Pitch between Slots	5213

Carrier Mapping Data

Item / Module	1-5 (SBU)	1-7 (SBU)	1-28 (SBU)	1-29 (SBU)
Pitch between Slots	**1990**	**1990**	**1990**	**1990**

Block 1 CS Block / Block 13 /Block 14 / Block 15 / Block 16 PR Block, [TRS] Transition Stage

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**Invalid**
Wafer Store Count	**1**
Start Slot	**0**

Block 13 /Block 14 / Block 15 / Block 16 PR Block, [CWH] Cup Washer Holding Stage

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**Invalid**
Wafer Store Count	**1**
Start Slot	**0**

Block 1 CS Block, [WEX] Wafer Exchange Stage

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**1-2**
Wafer Store Count	**1**
Start Slot	**0**

Block 1 CS Block / Block 13 /Block 14 / Block 15 / Block 16 PR Block, [THS] Temporarily Hold Stage

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**Invalid**
Wafer Store Count	**1**
Start Slot	**0**

		BARC	Imm/EUV/KrF
Item / Module	1-9 / 1-26 (THS)	13-14 / 14-14 / 15-14 / 16-14 (THS)	11-43* / 12-43** / 13-43 / 14-43*** (THS)
Module Type	Gap pin type	PRB rear type	Low clearance

* EUV and KrF not present
** TBZ not present
*** Imm/EUV not present

Block 1 CS Block / Block 13 /Block 14 / Block 15 / Block 16 PR Block, [TTS]

Reserved Flag	**Invalid**
Fork Simultaneous Swapping Level	**Invalid**
Wafer Store Count	**1**
Start Slot	**0**

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7. AMHS Parameter

AMHS Monitor Timer

AMHS Maker	**E84**
AMHS TYPE	**Type 4**
Timer1 Load(Unload) Request ON => TR Requset ON	**2**
Timer2 Ready ON => Busy ON	**2**
Timer3 Busy ON => Carrier Detect(Remove)	**60**
Timer4 Load(Unload) Request => Busy OFF	**60**
Timer5 ready OFF => Valid OFF	**2**
Timer6 Valid OFF => Valid ON(Continuous Handoff)	**2**
Curtain Sensor	**Invalid**

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8. System Parameter

GJG

SW Access before Carrier Load	**Unnecessary**
SW Access after Carrier Load	**Unnecessary**
SW Access before Carrier Unload	**Unnecessary**
SW Access after Carrier Unload	**Unnecessary**
Carrier Detect Timer	**20000 msec**
Carrier Confirm Timer	**10000 msec**
Carrier Load Complete Timer	**20000 msec**
Carrier Unload Complete Timer	**20000 msec**
Unclamp Control in Automatic Mode	**After Undock**
\"CJ Pausing\" Alarm Issue	**Execute**
\"PJ Pausing\" Alarm Issue	**Execute**
Verify Skip Setting in Local Mode	**Not Execute**
Option AMHS Access Inhibit Function at Interlock	**Valid**

Others

Automatic Registration Editor Level	**Initialize Screen Level**
LoadPortTransfer Operation Level	**User Service**
Alarm Recovery Operation Level	**User Service**
Ingenio GL user account	**Fixed Ingenio GL user account**
Time before Screen Saver Activation	**10 (Default) min**
Prevention of Dispensing Outside of Cup by Spinner Recipe Verification	**Valid**
Dispensing Invalidation during Wafer Processing	**Invalid**
Monitoring Time Setting for Resist Un-dispensing	**300 sec**
Protection Against Incorrect Setting of Exhaust Control in COT Recipes	**Invalid**
Protection Against Incorrect Setting of Exhaust Control in DEV Recipes	**Invalid**
Acceptable Delay Time before Reporting Macro Inspection Result	**30 sec**
MCI Heart Beat	**Invalid**
DDS mis-detection prevention function at time equipped with DDS	**Invalid**
New Transfer Arm Control	**Valid**
Belt Break Detection for Spin Arms	**Valid**
DCI Heart Beat	**Invalid**
Wafer Flow Recipe Optimization at Saving	**Optimize**
Control Instrument Software Update Mode	**Invalid**
ADH Support Ring Purge Function	**Valid*** **
Verification Warning for Process Recipes Set in Multi-Module Step of Wafer Flow Recipe	**Valid**
Verification Warning for Resist Dispense Time in Spinner Recipe	**Invalid**
Data confirm function for service user.	**Valid**
Brush Pressure Settling during BST Wafer Processing	**Invalid**
Automatic ESD Collection	**Valid**
WEE Illuminance Measurement for Each Wafer	**Invalid**
Default Value Setting for the "Collective Setting of Lower-Link Recipes for Multi-Module"	**Valid**
Transfer Arm FDC Function	**Valid**
Automatic CPL Insertion at Wafer Flow Recipe Optimization	**Invalid**
Recipe Verification Warning Display for Unset External Control Data	**Display**
Process Data Processing Result Error Alarm	**Execute**
Estimated Disp. Press. Display	**Display**
Selection of Wafer Status at Oven Exhaust Pressure Warning Detection	**Normal**
Guard against Interference of Arm and Cup in Spinner Module	**Valid**
Display of Reload Time Monitoring Upper and Lower Limits for ACRD Pump	**Display**
LIS Periodic Inspection Interval	**24**
OVEN FDC Function	**1sec Cycle**
Reports on the Deleted Module Recipe	**Valid**
SPIN FDC Function	**Valid**
Resist Nozzle Usage Limitation on Muti Wafer Flow	**Allow only one nozzle number**
Time Interval between Rechecking of Upstream Linked Recipes	**200 msec**
Cycle Stop When Module Exhaust Pressure Error	**Cycle Stop**
Detect Abnormal Vent Pressure Function	**Invalid**
Recipe Verification Warning for Liquid Spinning-off Time	**Valid**
Invalidation of Verification for Warning of Insufficient Cooling Time in United Oven Module	**Invalid**
Exclude Automatic ESD Collection (Delay in wafer send to exposure system)	**Exclude**
STHC Data Collection Function	**Invalid**
Recipe Security for TEL User	**Valid**
TEL User Creation Function	**Create**
Detection of Disk Remaining after Cup Wash	**Invalid**
Simultaneous Dispensing from Multiple EBR Lines in Same Step	**Dispense**
Belt Break Detection for ASTR Plate	**Valid**
Backflow Prevention during Pump Operation to Multi-tank Supply System	**Invalid**
Change in Arm Data Display on Spinner Recipe Edit Screen*	**Invalid**
Verification for Dispense Time in Pump Recipe**	**Invalid**
Button to Switch Step Data Valid/Invalid on Recipe Edit Screen	**Invalid**

* New UI only

** Dose not matter to INTEL

*** N/A for no CADH tool TBFna/TBFlt/TBFcn

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Others

Option Upper Limit of Spin Speed When Dispensing with IE NOZZLE	**0 rpm**	
Option Lower Limit of Spin Speed When Dispensing with IE NOZZLE	**0 rpm**	
Option Wafer Spin Speed Upper Limit at Bevel Rinse V2 Dispensing	**0 rpm**	
Option Upper Limit of Wafer Acceleration When Dispensing with IE NOZZLE	**3000 rpm/sec**	
Option Retry Count for Automatic NMA Liquid Level Adjustment (Arbitrary Movement)	**7 times**	
Option Target Threshold for Automatic NMA Liquid Level Adjustment	**0.5 mm**	
Option Dummy Dispense Execution Condition for Automatic NMA Liquid Level Adjustment	**Execute Every Time**	
Option Approximation Adjustment Parameter 1 for Automatic NMA Liquid Level Adjustment	**0.500**	
Option Approximation Adjustment Parameter 2 for Automatic NMA Liquid Level Adjustment	**10.000**	
Option Target Threshold for Automatic NMA Liquid Level Adjustment (SB1)	**0.5 mm**	
Option Target Threshold for Automatic NMA Liquid Level Adjustment (SB2)	**0.5 mm**	
Option Target Threshold for Automatic NMA Liquid Level Adjustment (SB3)	**1.0 mm**	
Option Automatic NMA Liquid Level Adjustment for Each Layer (SB2, SB3)	**Not Execute**	
Option Automatic NMA Liquid Level Adjustment after DFT Formation (SB2, SB3)	**Execute**	
Option Approximation Adjustment Parameter 1 for Automatic NMA Liquid Level Adjustment (Stable Liquid Level)	**0.394**	
Option Approximation Adjustment Parameter 2 for Automatic NMA Liquid Level Adjustment (Stable Liquid Level)	**8.984**	
Option Lighting Duration for Real-Time Display	**3 min**	
Option Target Liquid Level Height for PSB Adjustment of NMA	**3 mm**	
Option Setting for Excluding Specified Module from Wafer Flow in Online Remote	**Host**	
Option Dispense Line Monitor	**Valid**	
Option Resist Dispense Amount Display in Grams	**Invalid**	
Option Initial Display Unit of Resist Flow Meter Detection Level	**% Data**	
Option Plate vacuum error consecutive detection frequency	**1**	
Option Advanced Wafer Level Monitor	**Valid***	*Does not exist on PBR
Option Chemical Install Assist Function(Main Screen) limited number of concurrent execution	**1**	*Does not matter to intel
Option FIMS Door Interference Detection for High Throughput CSB	**Invalid**	
Option ACDR Pump Vent Operation Switching Function	**Vent Operation Type1**	
Option Resist Dispensing Interval Verification	**Valid**	
Option Change of Initial Value for Refill Source Selection	**Valid**	
Option Switch container number of Chemical usage monitor	**Valid**	
Option Process Suspension when PCS Refilling is Impossible	**Valid***	*Does not exist on PBR
Option Continuation of PCS Process during Source Trouble	**Valid***	*Does not exist on PBR
Option Default Value of Recipe Comparison Detailed Condition Setting Function	**Valid**	
Option Execution of Auto Bath Wash Only at the End of Last Shot in each Step of Nozzle Purge Recipe	**Valid**	
Button to Switch Step Data Valid/Invalid on Recipe Edit Screen	**Invalid**	
Option-Chemical Install Assist Function(Main Screen) limited number of concurrent execution	**1**	

Wafer Collection

Wait Time for Wafer Collection from Exposure	**180000 msec**
Rejected Wafer Collected in:	**End Carrier**
Real-time Save Recovery Info	**Valid**

Cup Wash

Executing Cup Wash Alarm Issue	**Invalid**
Alarm Output during Duct Wash	**Valid**
Washing Nozzle Tip Alarm Issue	**Invalid**
Setting of Simultaneous Condition Fulfillment for Same Type Wash Item	**All Spinners**
Cup Wash Execution When Wafer Exists in Another Cup in Same Layer	**Not Execute Cup Wash**
Interlock against Unset Nozzle Tip Wash	**Warning and Stop**
Early Wash: Execution Triggered by Control of SBU before Exposure System	**Invalid**
Early Wash: Execution Triggered by No PJ Start	**Invalid**
Option Automatic Cup Wash Skip	**Valid(Alarm Off)**
Option Post-Cup-Wash Cooling Time	**0 sec**
Option-Improvement of Automatic CWH Specification Method for Manual Cup Wash	**Valid**

Monitoring

Wafer Status Change at Stranded Wafer Detection	**Error Wafer**
Change Hot Plate Temperature during Cooling Processing	**Invalid**
Recipe Verification against Unset Monitoring Parameter	**Warning Setting**
Waf.transfer pausing against Unset Monitoring Parameter	**Warning Setting**
Wafer Status Change at Chamber F/B Sensor Error Detection	**Error Wafer**
Ramp down delay detect*	**99 sec**
Option Interlock Setting at Stranded Wafer Detection	**No Cycle Stop**
Option Collective Setting of Stranded Wafer Detection Function for Heat Process	**Module Individual Setting**

* It is not used parameter in Intel operation.

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8. System Parameter

Maintenance

Notify Time to Replace Chemical, etc.	**Invalid**
Transfer Stop Cause Alarm	**Valid**
Option Consecutive Execution of Replacing Chemical Bottle and Clearing Dispense information	**Valid**
Option Operation-Less RIA Alarms	**Valid(PURGE Class Only)**
Option RIA without Arm Blocking Function	**Valid**

Basic Transfer Control

PJ End Specification for Multiple PJs Execution	**PJ End**
Wafer Send OUT Stop due to Inspect,Measure Tool Error	**Execute**
Wafer Send OUT Control at Resist Temperature Change	**Valid**
Wafer Send OUT Control at Hot Plate Temperature Change	**Invalid**
	PBR Only = Valid
Cascade Process for High Speed Temperature Change	**Valid (Wait Just before Spin)**
	PBR Only = Invalid
Upper Limit of Wafer Stay Time in Exposure	**180000 msec**
FIMS Door in Down Position Check	**Valid**
Control of Wafer Send Out to Exposure System	**Valid**
Monitoring Time Setting for Transfer Delay after Exposure System Trouble	**0 sec**
Wafer Transfer during Pump Reloading	**Valid**
Correcting Wafer Position by Temporary Wafer Placement	**Valid**
Control of SBU before Exposure System	**Valid**
Wait Time for Wafer Transfer to Exposure System	**30 sec**
Wait Time for Wafer Transfer from Exposure System	**30 sec**
event of wafer transfer end	**Invalid**
Wait Time for Wafer Transfer from Process Modules in MPB	**0 sec**
CSB rewrite	**CSB conventional control**
The Status of wafer whose position is corected by temporary wafer placement	**Invalid Setting**
Option RSM Cooling Time	**12 sec**
Option RSM Plate Vacuum Setting	**Valid(Always mon.)**

Special Transfer Control

Wafer Transfer Excluding Specified Module	**Invalid**
TRANS Arm Init Wafer Count	**0**
TRANS Arm ALM Output Wafer Count	**0**
Cup Wash Cascade	**Valid**
WISD Bypass Control to Maintain Equipment Productivity	**Invalid**
Step Count Available for Sending PJ_CREATE to IM	**5 step**
Coter Cascade Parallel Flow Improvement	**Valid**
Wafer transfer wait function in WEX	**Invalid**
Automatic Layer Bypass at Impossible-to-Transfer Step Occurrence	**Invalid**
Number of Waiting Cycles for Transfer of Transition Between PRA**	**1 cycle**
Option Prime Cascade Mode (Coating Flow)	**Prioritize Throughput**
Option Prime Cascade Mode (Development Flow)	**Prioritize Throughput**
Option Skip EIF for Trouble Wafer in Immersion Supported Equipment*	**Valid**
Option Specifying Fork for Sending Out Wafer from Exposure System When PIR Is Not Used	**Wet Fork**
Option Specifying Exclusion Alarm	**Not Execute**
Option Smart Bypass Function	**Valid**
Option Wafer Uncollect Alarm	**Execute**
Option Smart Bypass Transfer End Alarm	**Not Execute**
Option Module Blocking Alarm	**Execute**
Option Wafer Information Alarm	**Not Execute**
Option Wafer transfer to exposure SBU of the exposure local flow when a parallel flow control function is effective	**Valid**
Option Production PJ Parallel Flow Control	**Execute**
Option Alarm Output of Specifying Nozzle Exclusion	**Not Execute**
Option Mutual Exclusion of RIA and PJ which Use Same Module	**Valid(Nozzle Purge)**
Option Wafer Transfer during Interval dummy when Shared Arm is not used	**Valid**
Option Access Fork Fixation for 2nd Spinner function	**Valid**

* Not present to BARC tool

** It is not used parameter in Intel operation.

Bare-Si Thickness Unit

Bare-Si Thickness Unit	**nm**
Option Base Barometric Pressure	*** hPa**

*** Portland / Ireland: 1010.00hPa**

*** Phoenix: 970.00hPa**

*** Albuquerque: 840.00hPa**

*** Israel: 1000.00hPa**

*** PBR: NA**

Equipment State Management

The "PAST Log Output" function	**Valid**
Resource Logging Interval	**60sec**

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8. System Parameter

Exposure Interface

Exposure Maker	**Tool Specific ***
Exposure Type	**Tool Specific ****
Exposure Carrier End Setting	**Invalid**
Exposure in Local Interlock Setting	**Valid**
Exposure APR Setting	**Tool Specific *****
EIF IN READY Wait Time	**10000 msec**
EIF Initialize Condition	**Confirm ARM-signal**
Exposure In Near Ready Setting	**Invalid**
Option Exposure Lot End Output	**Execute**
Option Linked Litho Application	**Valid**
Option Linked Litho Alarm Auto Recovery	**Valid**
Option Linked Litho Alarm Auto Timer	**1000 msec**
Option Linked Litho Advance Function	**Invalid********

* Select "Nikon" or "ASML" or "NONE" for BARC, linked STP dependant.

** ASML: TYPE 2, Nikon: TYPE 4, BARC : Type 1

*** Valid for all ASML links, Invalid for others

**** Only applied to Nikon scanner

Dummy Dispense

Interlock with Dummy Dispense Recipe Unregistered	**Valid**
Prevention of Chemical Stream Crossing during Dummy Dispense Process	**Valid**
Forced Fulfillment Setting for Pre-PJ Dummy Dispensing Condition After Nozzle Wash of DFT-Invalidated Nozzle	**Make to consist**
Front-Loaded Execution of Pre-PJ Dummy Dispense Process	**Invalid**
Monitoring Time of Wafer Transfer Stop for Regular Interval Dummy Dispense Execution	**0 sec**
Ring Purge ON time before Interval Dummy Dispense for ADH and CADH	**0.0 sec***
Ring Purge OFF time after Interval Dummy Dispense for ADH and CADH	**0.0 sec***
Option Start Time of Periodic Resist Return Operation during Wafer Transfer Stop	**300 sec**
Option Lower Input Limit of Non-Dispense Time of Interval Return Execution Condition	**180 sec**
Option Interval Return Mode during Wafer Transfer	**Productivity Priority Mode**

* N/A for no CADH tool TBFna/TBFlt/TBFcn

FOUP Exchanger

Option FOUP Exchanger	**Valid**
Option FOUP Exchanger Frame Type	**Expanded Frame**
Option CarrierOut Skip Setting in Local Mode	**Not Execute**
Option Use of Continue Button for Cannot Continue Initialization Alarm for FEX	**Valid**
Option Number of Remaining Steps at End Carrier Preparation	**1**
Option Source carrier transfer improvement	**Valid**
Option Suspension of Forced Preparation of Receiver Carrier	**Invalid**
Option Priority on Wafer Send Out from CSB In-Buffer	**Invalid**
Option Carrier to transfer which takes first priority	**Receiver**
Option FTRA High Throughput	**Invalid**
Option Carrier to transfer to sender from receiver in High speed CSB	**Valid**
Option Destination XSTK optimization	**Valid**
Option-CarrierID Re-reading at FOUP Exchanger Initialization	**Valid**

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Wafer in Carrier Send OUT/IN Order Definition Group

Wafer in Carrier Send OUT/IN Order Information

Stage Type	**Uni-Cassette**
Send OUT Order/Send	**Bottom**

Wafer in Carrier Send OUT/IN Order Information

Stage Type	**Pickup Stage**
Send OUT Order/Send	**Top**

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10. BST Control Parameter

Block 30 IF Block, BST* / BST+**

* For Imm Configuration ONLY
** For EUV and KrF Configuration(except TBZ458) ONLY

BST Motor Parameter

Spin Motor Info.

Upper Limit of Spin Speed at Outer Wash	1000	rpm
Lower Limit of Spin Speed at Outer Wash	10	rpm
Upper Limit of Spin Speed at Surface Wash	2500	rpm
Lower Limit of Spin Speed at Surface Wash	10	rpm
Upper Limit of Spin Speed at Special Wash	1000	rpm
Lower Limit of Spin Speed at Special Wash	10	rpm
Upper Limit of Spin Speed at Dry	2500	rpm
Lower Limit of Spin Speed at Dry	500	rpm
BST+ Upper Limit of Spin Speed at Outer Wash*	50	rpm
BST+ Lower Limit of Spin Speed at Outer Wash*	10	rpm
BST+ Upper Limit of Spin Speed at Special Wash*	50	rpm
BST+ Lower Limit of Spin Speed at Special Wash*	10	rpm
Upper Limit of Spin Speed at Dry with Air Nozzle*	50	rpm
Lower Limit of Spin Speed at Dry with Air Nozzle*	10	rpm

* Only BST+ module present

BST Module Info. Parameter

Pad Vacuum ON without Wafer	Valid
Auto Retry function for Brush Pressure Error	Valid
Auto Retry function for Pin Up Error	Invalid
Local Exhaust	CONTINUOUS
EV output value changing process	Valid

AirNozzle

Pressure Monitoring during Processing	Valid	
Pressure Monitoring Delay Time	0.50	sec

Module Info.

Version Info.	2

BST Pin Parameter

PinDriveType	PositionOffset

UP Speed1	3000	pulse/sec
UP Acceleration1	54000	pulse/sec^2
UP Deceleration1	54000	pulse/sec^2
UP Speed2	5000	pulse/sec
UP Acceleration2	54000	pulse/sec^2
UP Deceleration2	54000	pulse/sec^2
DOWN Speed1	5000	pulse/sec
DOWN Acceleration1	54000	pulse/sec^2
DOWN Deceleration1	54000	pulse/sec^2
DOWN Speed2	3000	pulse/sec
DOWN Acceleration2	54000	pulse/sec^2
DOWN Deceleration2	54000	pulse/sec^2

Pin Position

	Z Position[pulse]
Handling Position	2400
Chuck Position	300

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11. Adjustment Tool Parameter

Transfer Arm No. 1-0 Caribration Data

Wafer in Carrier Send OUT/IN Order Information

ArmBlockNo	**1**
ArmModuleNo	**0**

Tool Specific

DataId	**Tool Specific**
CalibModuleBlockNo	**1**
CalibModuleModuleNo	**8*, 9****
ToolSerialNo	**Tool Specific**

*for BARC/EUV tool ** for IMM tool

ForkPosition[0]

ForkNo	**1**
PositionX	**Tool Specific**
PositionY	**Not Input**
PositionZ	**Tool Specific**
PositionTh	**Tool Specific**

ForkPosition[1]

ForkNo	**2**
PositionX	**Tool Specific**
PositionY	**Not Input**
PositionZ	**Tool Specific**
PositionTh	**Tool Specific**

Transfer Arm No. 1-10 Caribration Data

Wafer in Carrier Send OUT/IN Order Information

ArmBlockNo	**1**
ArmModuleNo	**10**

Tool Specific

DataId	**Tool Specific**
CalibModuleBlockNo	**1**
CalibModuleModuleNo	**1**
ToolSerialNo	**Tool Specific**

ForkPosition

ForkNo	**1**
PositionX	**Not Input**
PositionY	**Not Input**
PositionZ	**Not Input**
PositionTh	**Not Input**

Transfer Arm No. 1-20 Caribration Data

Wafer in Carrier Send OUT/IN Order Information

ArmBlockNo	**1**
ArmModuleNo	**20**

Tool Specific

DataId	**Tool Specific**
CalibModuleBlockNo	**1**
CalibModuleModuleNo	**25*,26****
ToolSerialNo	**Tool Specific**

*for BARC/EUV tool ** for IMM tool

ForkPosition[0]

ForkNo	**1**
PositionX	**Tool Specific**
PositionY	**Not Input**
PositionZ	**Tool Specific**
PositionTh	**Tool Specific**

ForkPosition[1]

ForkNo	**2**
PositionX	**Tool Specific**
PositionY	**Not Input**
PositionZ	**Tool Specific**
PositionTh	**Tool Specific**

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11. Adjustment Tool Parameter

Transfer Arm No. 11-0 Caribration Data *IMM tool only

Wafer in Carrier Send OUT/IN Order Information

ArmBlockNo	**11**
ArmModuleNo	**0**

Tool Specific

DataId	**Tool Specific**
CalibModuleBlockNo	**11**
CalibModuleModuleNo	**1**
ToolSerialNo	**Tool Specific**

ForkPosition[0]

ForkNo	**1**
PositionX	**Tool Specific**
PositionY	**Tool Specific**
PositionZ	**Tool Specific**
PositionTh	**0**

ForkPosition[1]

ForkNo	**2**
PositionX	**Tool Specific**
PositionY	**Tool Specific**
PositionZ	**Tool Specific**
PositionTh	**0**

Transfer Arm No. 12-0 Caribration Data *IMM/EUV tool only

Wafer in Carrier Send OUT/IN Order Information

ArmBlockNo	**12**
ArmModuleNo	**0**

Tool Specific

DataId	**Tool Specific**
CalibModuleBlockNo	**12**
CalibModuleModuleNo	**1**
ToolSerialNo	**Tool Specific**

ForkPosition[0]

ForkNo	**1**
PositionX	**Tool Specific**
PositionY	**Tool Specific**
PositionZ	**Tool Specific**
PositionTh	**0**

ForkPosition[1]

ForkNo	**2**
PositionX	**Tool Specific**
PositionY	**Tool Specific**
PositionZ	**Tool Specific**
PositionTh	**0**

Transfer Arm No. 13-0 Caribration Data

Wafer in Carrier Send OUT/IN Order Information

ArmBlockNo	**13**
ArmModuleNo	**0**

Tool Specific

DataId	**Tool Specific**
CalibModuleBlockNo	**13**
CalibModuleModuleNo	**1**
ToolSerialNo	**Tool Specific**

ForkPosition[0]

ForkNo	**1**
PositionX	**Tool Specific**
PositionY	**Tool Specific**
PositionZ	**Tool Specific**
PositionTh	**0**

ForkPosition[1]

ForkNo	**2**
PositionX	**Tool Specific**
PositionY	**Tool Specific**
PositionZ	**Tool Specific**
PositionTh	**0**

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11. Adjustment Tool Parameter

Transfer Arm No. 14-0 Caribration Data

Wafer in Carrier Send OUT/IN Order Information

ArmBlockNo	**14**
ArmModuleNo	**0**

Tool Specific

DataId	**Tool Specific**
CalibModuleBlockNo	**14**
CalibModuleModuleNo	**1**
ToolSerialNo	**Tool Specific**

ForkPosition[0]

ForkNo	**1**
PositionX	**Tool Specific**
PositionY	**Tool Specific**
PositionZ	**Tool Specific**
PositionTh	**0**

ForkPosition[1]

ForkNo	**2**
PositionX	**Tool Specific**
PositionY	**Tool Specific**
PositionZ	**Tool Specific**
PositionTh	**0**

Transfer Arm No. 15-0 Caribration Data

Wafer in Carrier Send OUT/IN Order Information

ArmBlockNo	**15**
ArmModuleNo	**0**

Tool Specific

DataId	**Tool Specific**
CalibModuleBlockNo	**15**
CalibModuleModuleNo	**1**
ToolSerialNo	**Tool Specific**

ForkPosition[0]

ForkNo	**1**
PositionX	**Tool Specific**
PositionY	**Tool Specific**
PositionZ	**Tool Specific**
PositionTh	**0**

ForkPosition[1]

ForkNo	**2**
PositionX	**Tool Specific**
PositionY	**Tool Specific**
PositionZ	**Tool Specific**
PositionTh	**0**

Transfer Arm No. 16-0 Caribration Data

Wafer in Carrier Send OUT/IN Order Information

ArmBlockNo	**16**
ArmModuleNo	**0**

Tool Specific

DataId	**Tool Specific**
CalibModuleBlockNo	**16**
CalibModuleModuleNo	**1**
ToolSerialNo	**Tool Specific**

ForkPosition[0]

ForkNo	**1**
PositionX	**Tool Specific**
PositionY	**Tool Specific**
PositionZ	**Tool Specific**
PositionTh	**0**

ForkPosition[1]

ForkNo	**2**
PositionX	**Tool Specific**
PositionY	**Tool Specific**
PositionZ	**Tool Specific**
PositionTh	**0**

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11. Adjustment Tool Parameter

Transfer Arm No. 30-0 Caribration Data *IMM/EUV/KrF tool only

Wafer in Carrier Send OUT/IN Order Information

ArmBlockNo	**30**
ArmModuleNo	**0**

Tool Specific

DataId	**Tool Specific**
CalibModuleBlockNo	**30**
CalibModuleModuleNo	**4**
ToolSerialNo	**Tool Specific**

ForkPosition[0]

ForkNo	**1**
PositionX	**Tool Specific**
PositionY	**Tool Specific**
PositionZ	**Tool Specific**
PositionTh	**0**

ForkPosition[1]

ForkNo	**2**
PositionX	**Tool Specific**
PositionY	**Tool Specific**
PositionZ	**Tool Specific**
PositionTh	**0**

Transfer Arm No. 30-10 Caribration Data *IMM/EUV/KrF tool only

Wafer in Carrier Send OUT/IN Order Information

ArmBlockNo	**30**
ArmModuleNo	**10**

Tool Specific

DataId	**Tool Specific**
CalibModuleBlockNo	**30**
CalibModuleModuleNo	**31**
ToolSerialNo	**Tool Specific**

ForkPosition[0]

ForkNo	**1**
PositionX	**Tool Specific**
PositionY	**Not Input**
PositionZ	**Tool Specific**
PositionTh	**Tool Specific**

ForkPosition[1]

ForkNo	**2**
PositionX	**Tool Specific**
PositionY	**Not Input**
PositionZ	**Tool Specific**
PositionTh	**Tool Specific**

Transfer Arm No. 30-20 Caribration Data *IMM/EUV/KrF tool only

Wafer in Carrier Send OUT/IN Order Information

ArmBlockNo	**30**
ArmModuleNo	**20**

Tool Specific

DataId	**Tool Specific**
CalibModuleBlockNo	**30**
CalibModuleModuleNo	**51**
ToolSerialNo	**Tool Specific**

ForkPosition[0]

ForkNo	**1**
PositionX	**Tool Specific**
PositionY	**Not Input**
PositionZ	**Tool Specific**
PositionTh	**Tool Specific**

ForkPosition[1]

ForkNo	**2**
PositionX	**Tool Specific**
PositionY	**Not Input**
PositionZ	**Tool Specific**
PositionTh	**Tool Specific**

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12. FOUP Control Parameter*

Auto Flow Adjustment Group

Serial Port

	Block No.	Module No.	Serial Port No Of Elec. Balance
1-1	1	1	1450
1-2	1	2	1451
1-3	1	3	1452
1-4	1	4	1453

Delay Time

Zero Point Adjustment After Dock	3sec
Weight Measurement After Door Up	5sec

Weight Measurement

Mesurment Time	30sec
Period Time	0.5sec

*= It is not used parameter in Intel operation.

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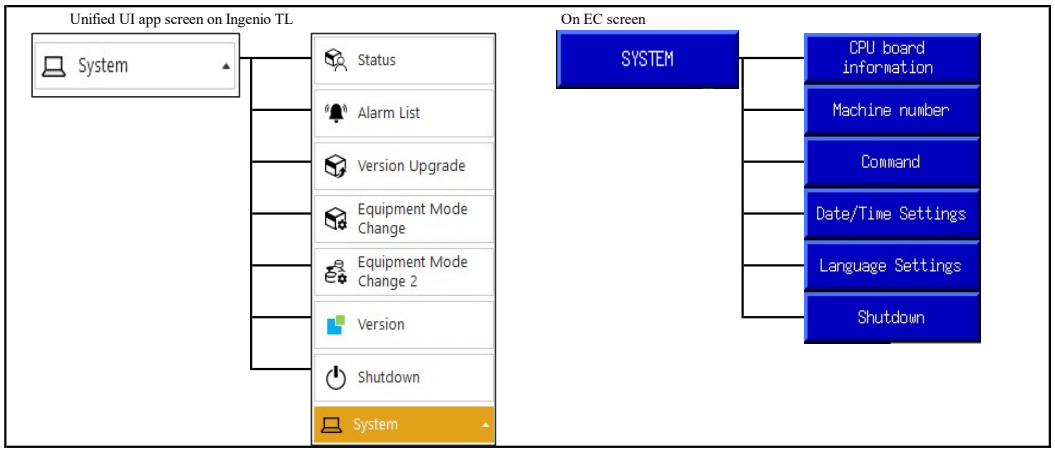
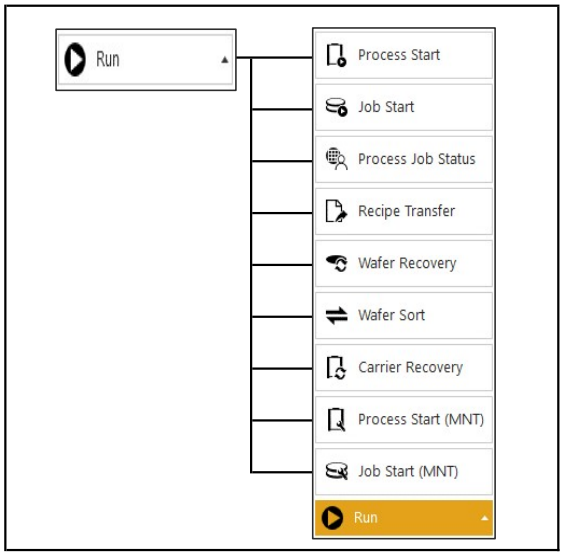
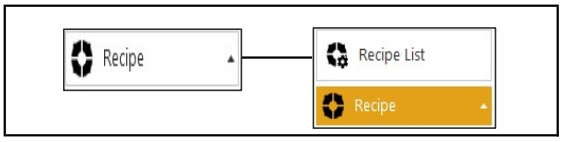
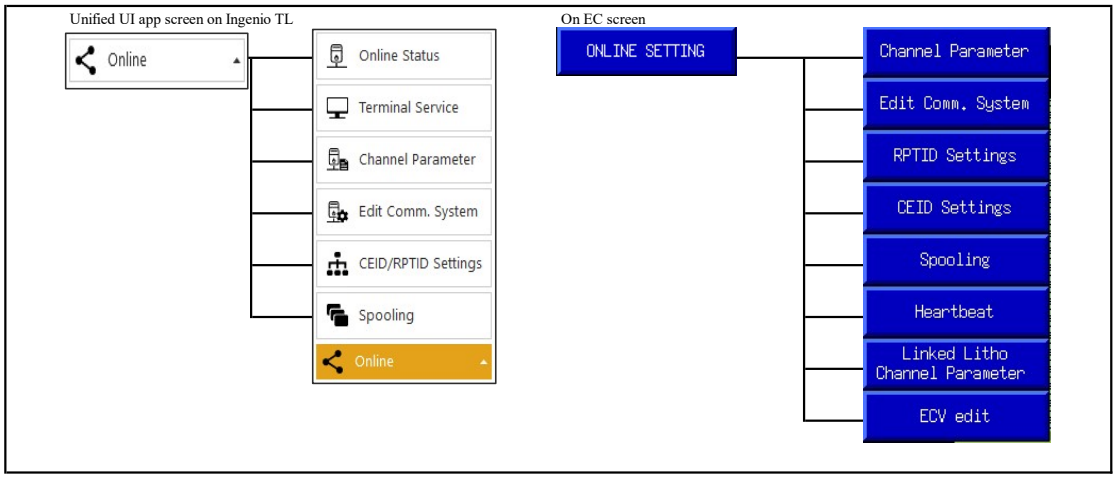
13. Unified UI App Screen (New UI)

Screen Tree









13. Unified UI app screen (New UI)

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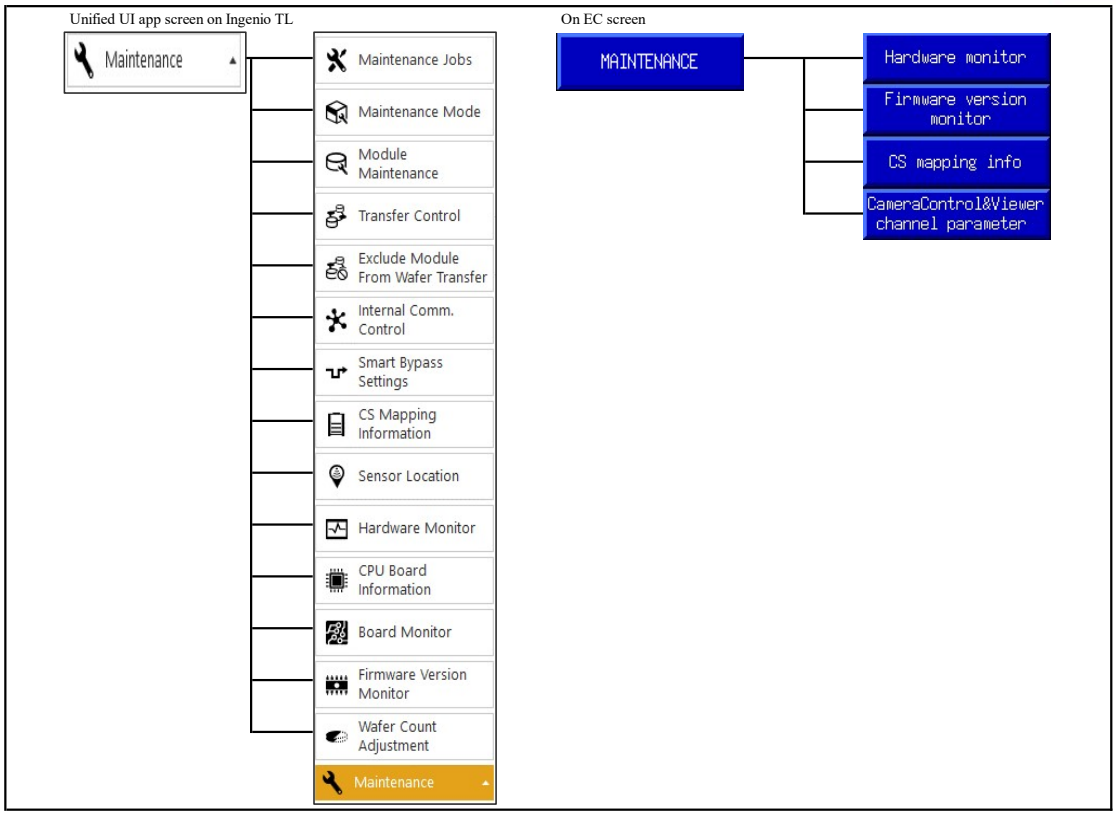
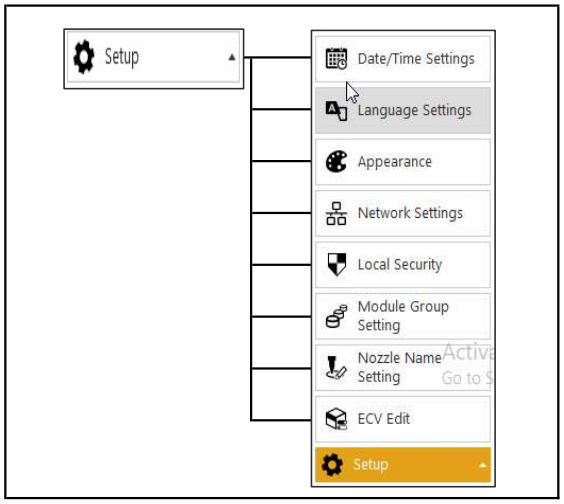
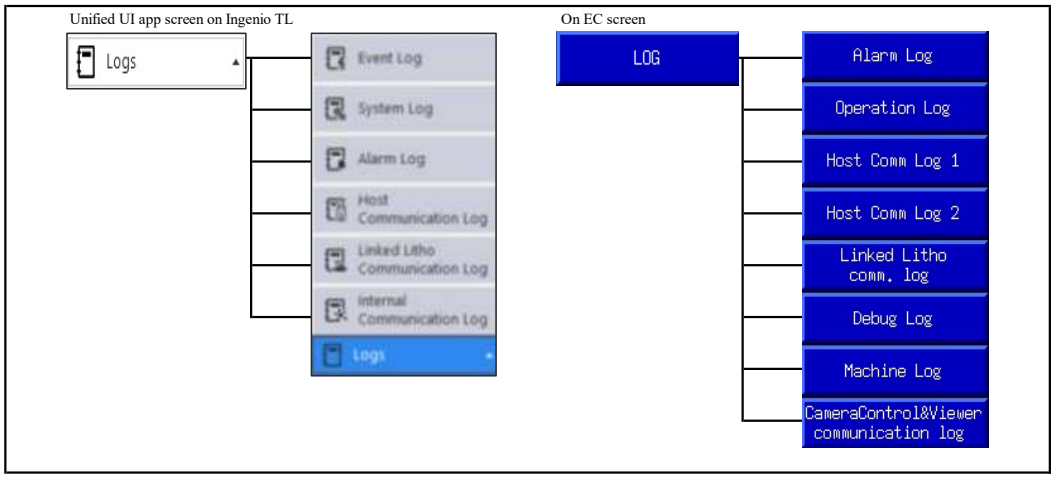
Screen Tree







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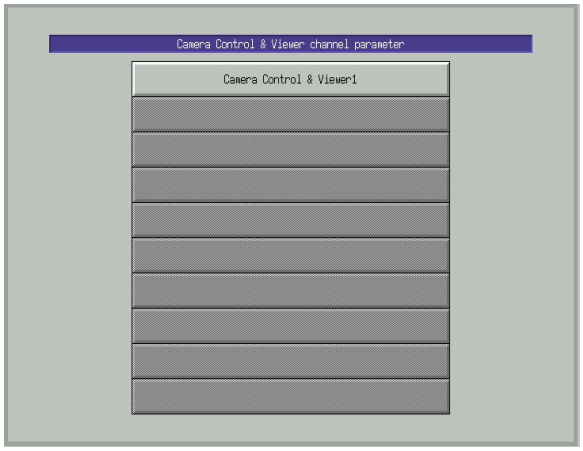
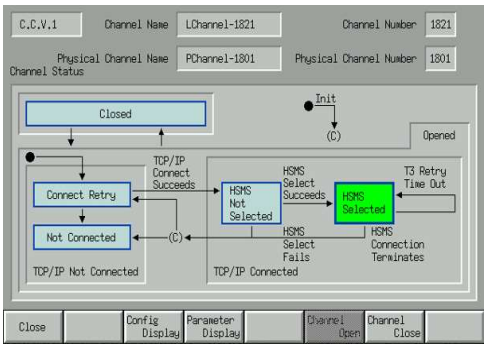
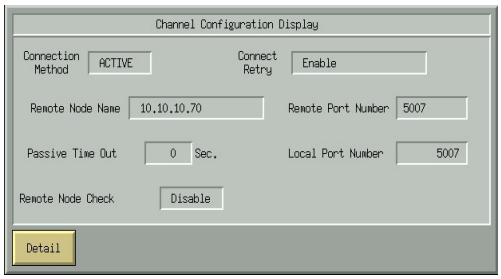
CameraControl&Viwer channel parameter



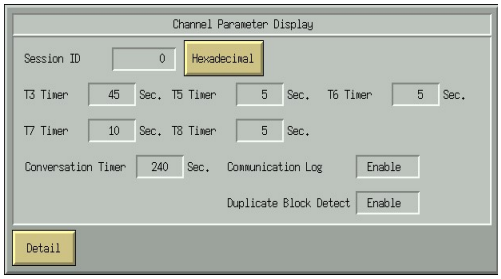


Config Display

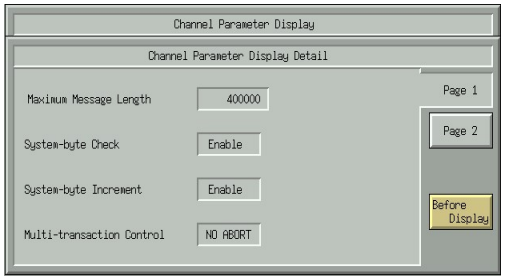


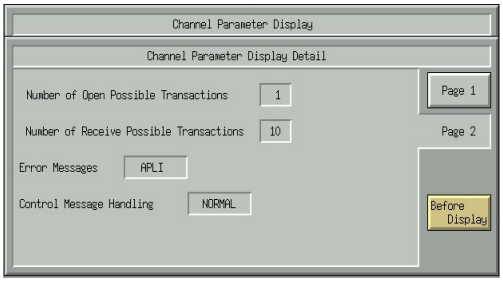
Config Display Detail

Parameter Display



Parameter Display Detail





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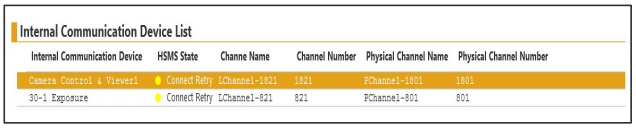
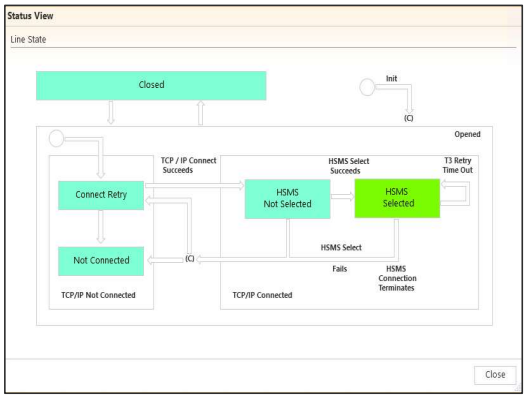
14. Unified UI App Maintenance Setting (New UI)

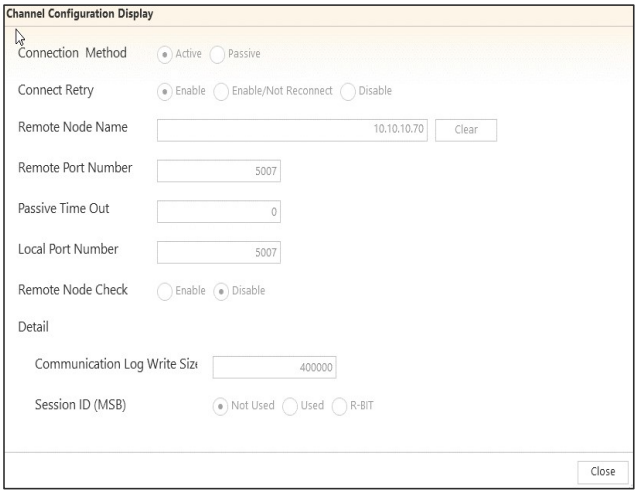
CameraControl&Viwer channel parameter



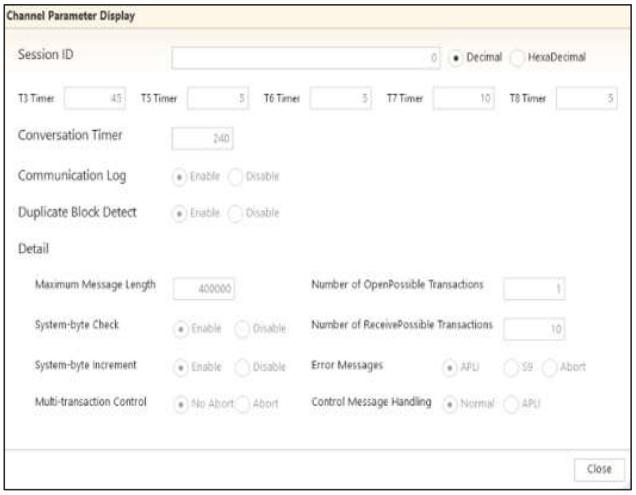
Status View



Config Display & Detail

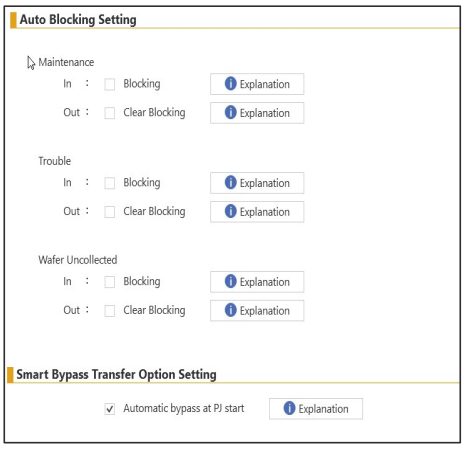


Parameter Display & Detail



14. Unified UI App Maintenance Setting (New UI)

Smart Bypass Settings



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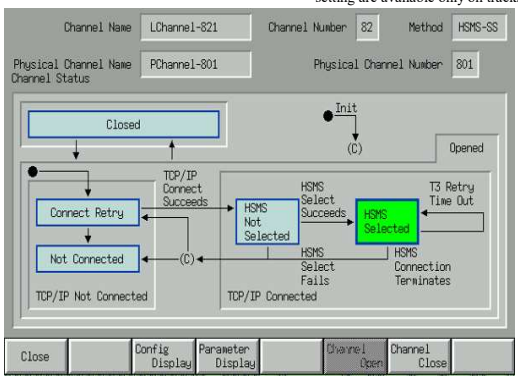
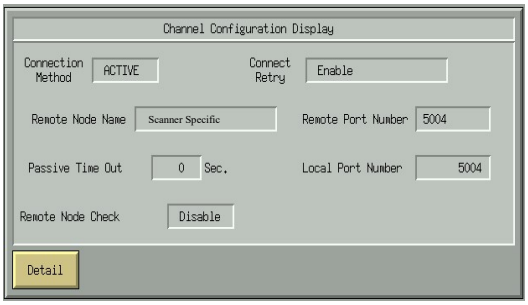
Linked Litho Chanel Parameter*

*setting are available only on tracks linked to scanners.



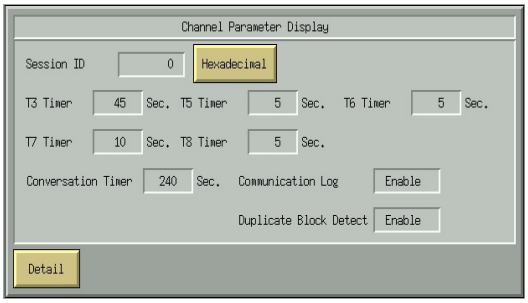
Config Display



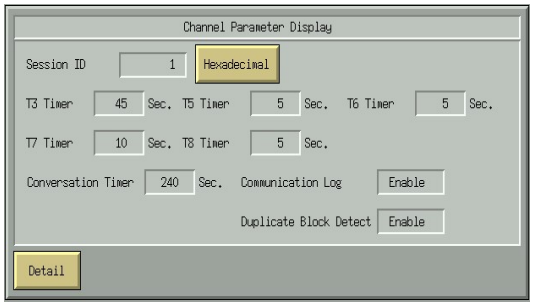
Config Display Detail

Parameter Display

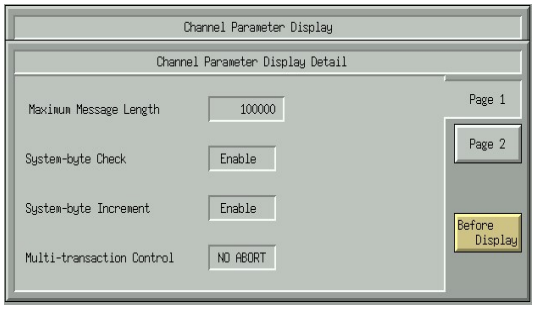
ASML SCREEN SHOT

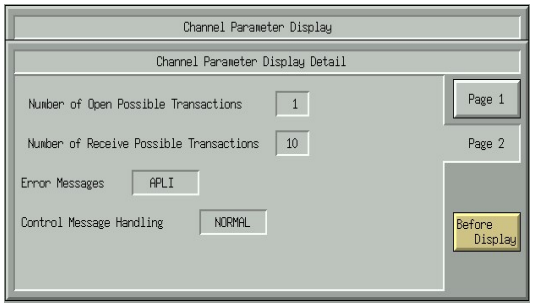


NIKON SCREEN SHOT

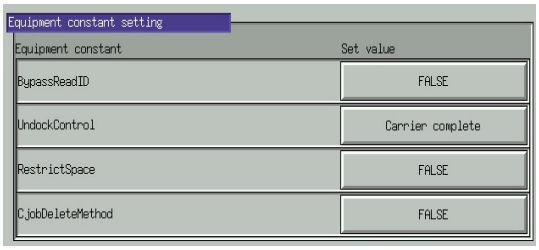


Parameter Display Detail





ECV edit



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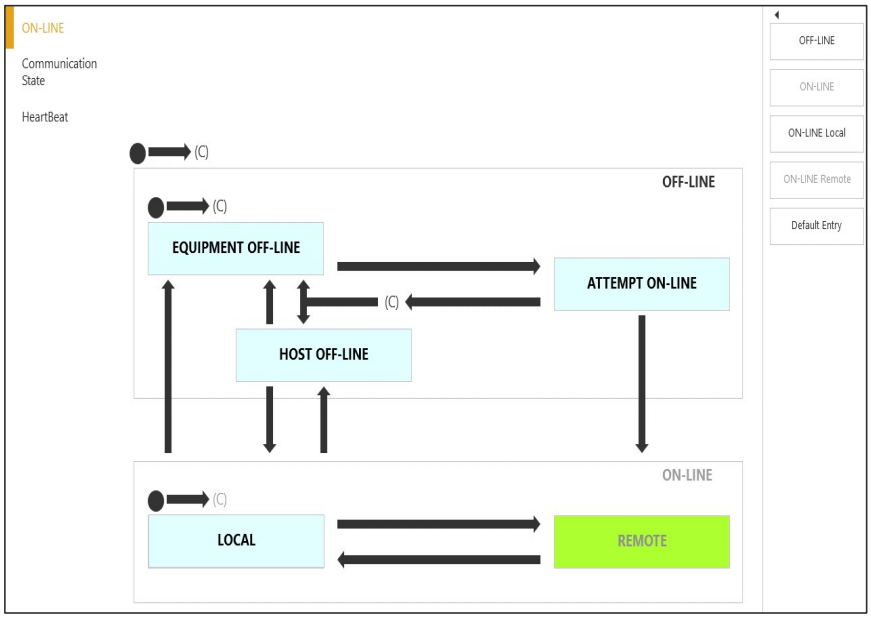
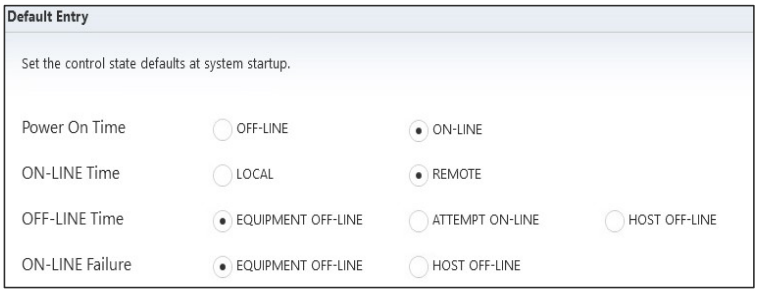
15. Unified UI App Online Setting (New UI)

Online Status

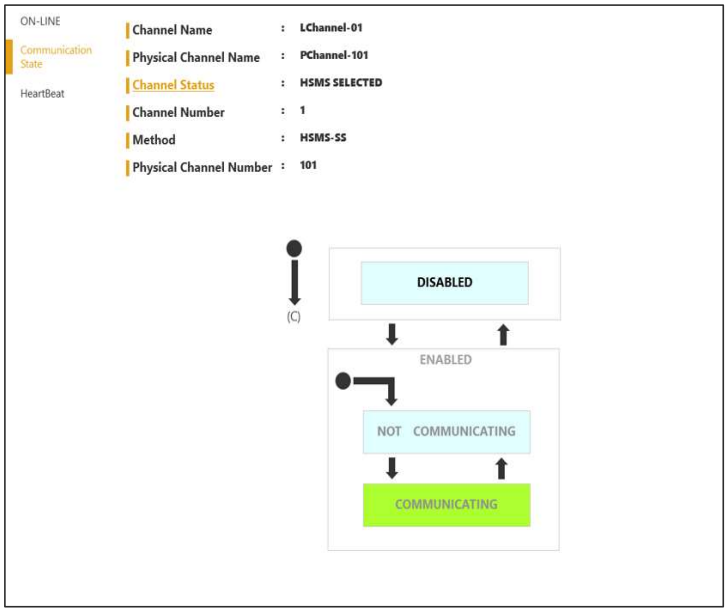
ON-LINE



Default Entry



Communication State



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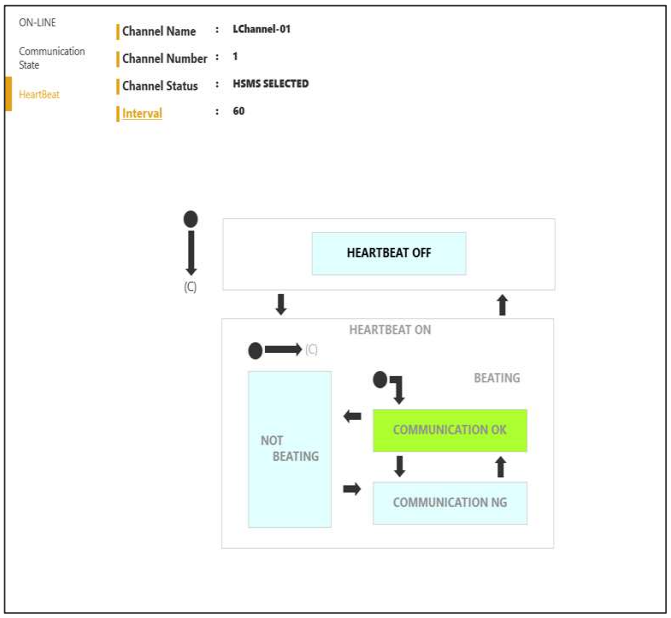
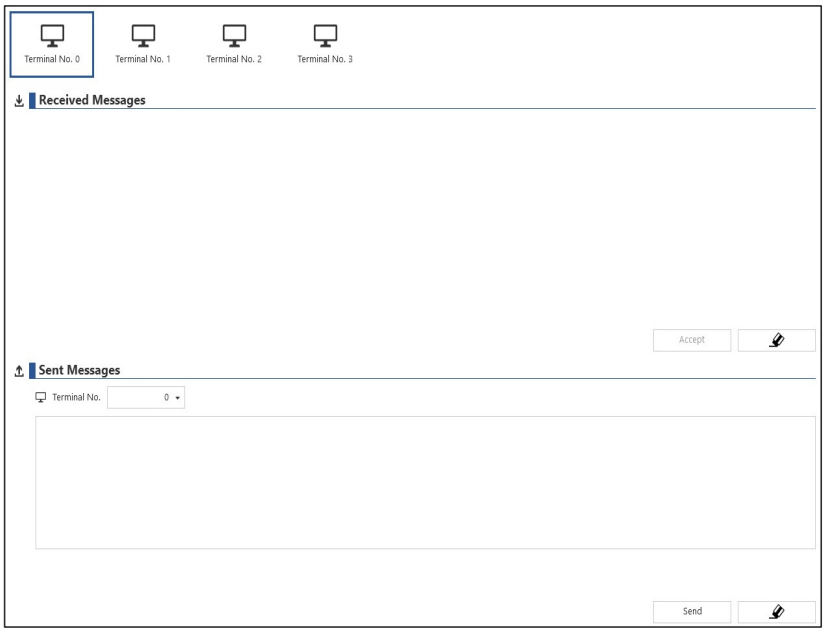
15. Unified UI App Online Setting (New UI)

Online Status

HeartBeat



Terminal service



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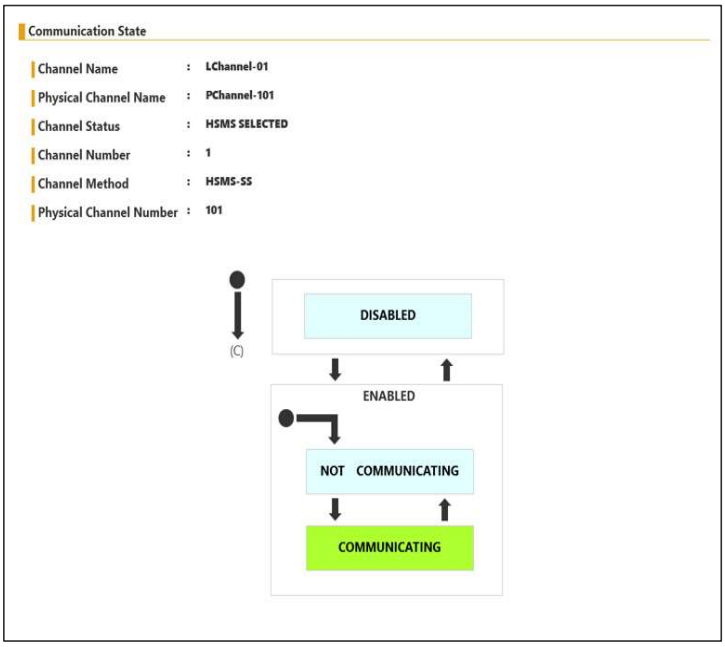
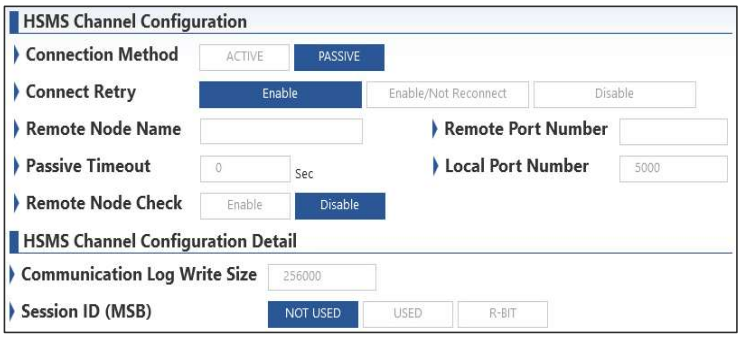
15. Unified UI App Online Setting (New UI)

Chanel Parameter

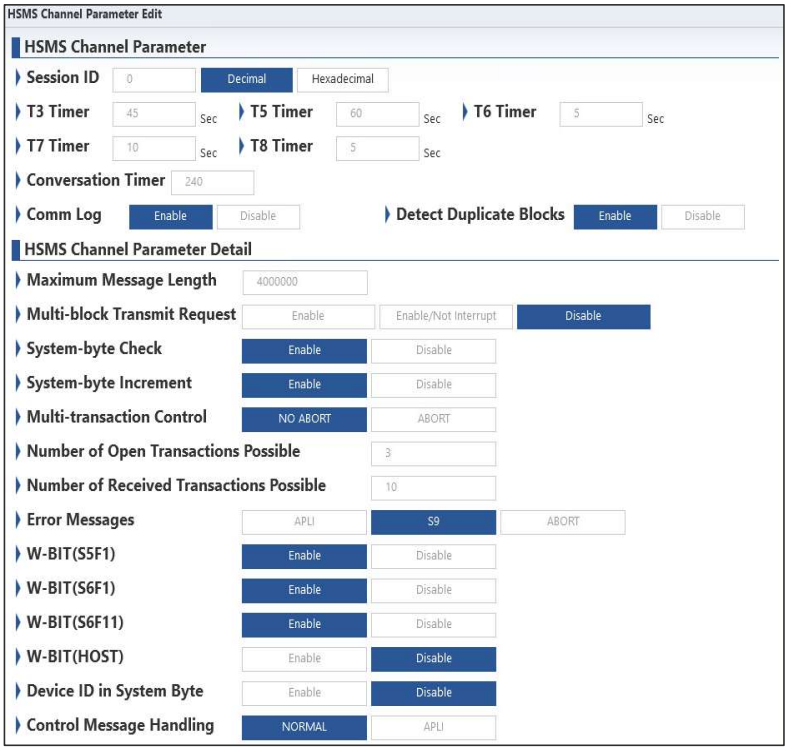


HSMS Channel Configuration Edit

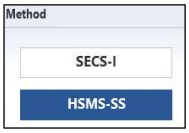


Communication Parameter

HSMS Channel Parameter Edit



Method



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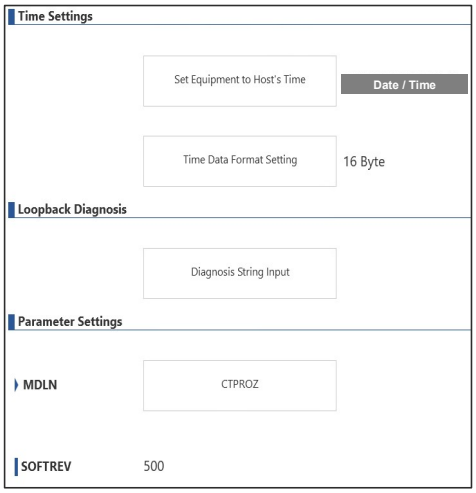
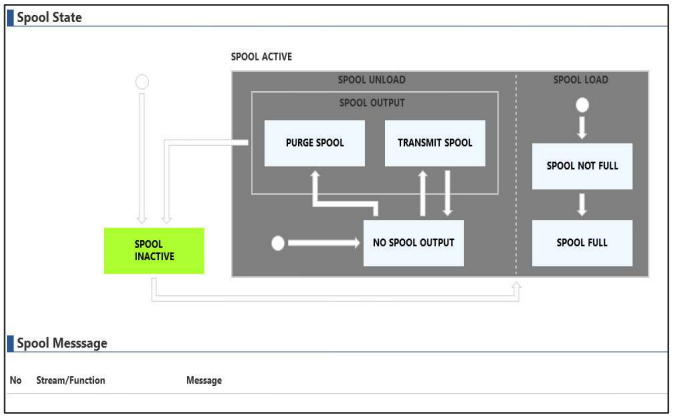
15. Unified UI App Online Setting (New UI)

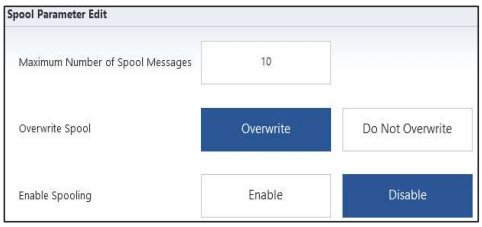
Edit Comm. System



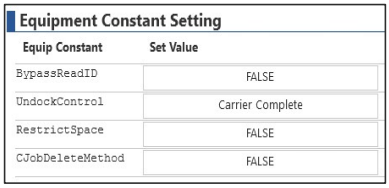
Spool State



Edit Parameter



ECV Edit



Equipment Constant Setting

Equip Constant	Set Value
BypassReadID	FALSE
UndockControl	Carrier Complete
RestrictSpace	FALSE
CJobDeleteMethod	FALSE

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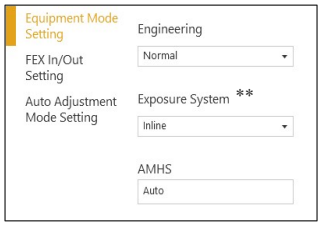
16. Unified UI App System Setting (New UI)

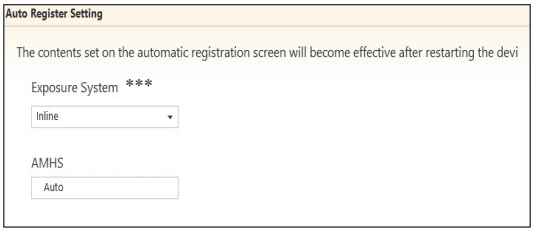
Equipment mode change

Equipment Mode Setting



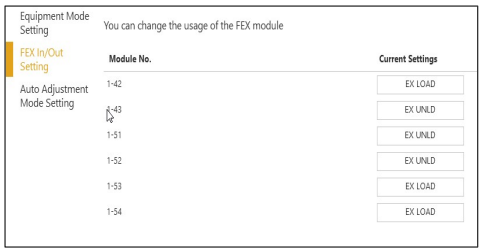
** Local For BARC tools.

Automatic Registration



*** Local For BARC tools.

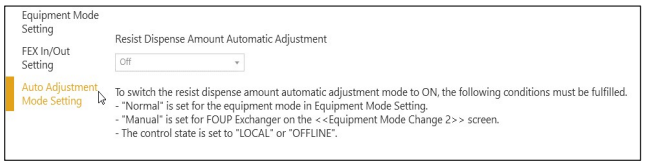
FEX In/Out Setting****



****1-41 and 1-44 are `EX STK` for BARC tools.

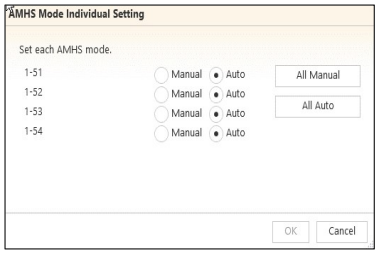
****Picture is for IMM/EUV tools

Auto Adjustment Mode Setting*****

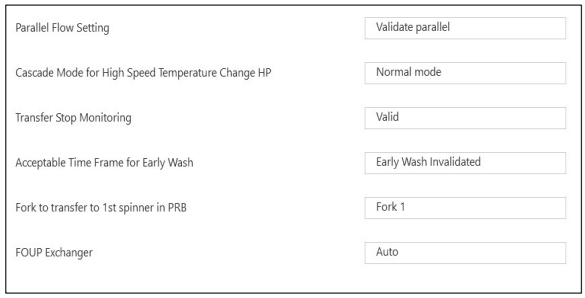


***** It is not used setting in Intel operation.

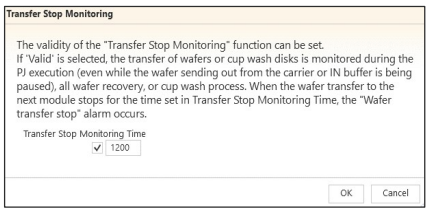
Individual Setting



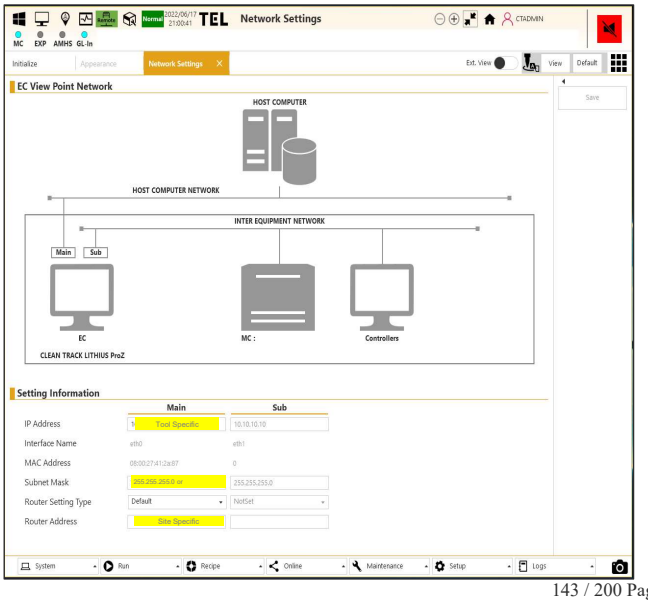
Equipment mode change2



Transfer Stop Monitoring



Network Settings



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16. Unified UI App System Setting (New UI)

Local Secutity

Item Level Setting

Contents

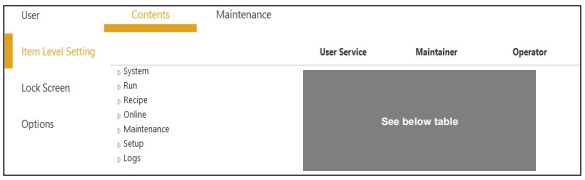


Table for item level(Content tab) Vendor Service has access to all items and menus.

	User Service	Maintainer	Operator
System			
Status	Admit	Admit	Admit
Alarm List	Admit	Admit	Admit
Version Upgrade	Deny	Deny	Deny
Equipment Mode Change	Admit	Admit	Deny
Equipment Mode Change 2	Admit	Deny	Deny
Version	Admit	Deny	Deny
Shutdown	Admit	Deny	Deny
Run			
Initialize	Admit	Admit	Deny
Process Start	Admit	Admit	Admit
Job Start	Admit	Admit	Admit
Process Job Status	Admit	Admit	Admit
Recipe Transfer	Admit	Admit	Admit
Wafer Recovery	Admit	Admit	Deny
Wafer Sort	Deny	Deny	Deny
Carrier Recovery	Admit	Admit	Deny
Process Start (MNT)	Admit	Admit	Deny
Job Start (MNT)	Admit	Admit	Deny
Recipe			
Recipe List	Admit	Admit	Admit
Online			
Online Status	Admit	Admit	Admit
Termical Service	Admit	Admit	Admit
Channel Parameter	Admit	Admit	Admit
Edit Comm. System	Admit	Deny	Deny
CEID/RPTID Setting	Admit	Deny	Deny
Spooling	Admit	Deny	Deny
Maintenance			
Maintenance Jobs	Admit	Admit	Deny
Maintenance Mode	Admit	Admit	Deny
Module Maintenance	Admit	Admit	Deny
Transfer Control	Admit	Admit	Deny
Exclude Module From Wafer Transfer	Admit	Deny	Deny
Internal Comm. Control	Admit	Deny	Deny
Smart Bypass Settings	Admit	Deny	Deny
CS Mapping Information	Admit	Admit	Deny
Sensor Location	Admit	Admit	Deny
Hardware Monitor	Admit	Admit	Admit
CPU Board Information	Deny	Deny	Deny
Board Monitor	Admit	Deny	Deny
Firmware Version Monitor	Admit	Deny	Deny
Wafer Count Adjustment	Admit	Admit	Deny
Setup			
Date/Time Settings	Admit	Deny	Deny
Language Settings	Admit	Deny	Deny
Apperance	Admit	Deny	Deny
Network Settings	Admit	Deny	Deny
Local Security	Deny	Deny	Deny
Module Group Setting	Admit	Deny	Deny
Nozzle Name Setting	Admit	Deny	Deny
ECV Edit	Admit	Deny	Deny
Logs			
Event Log	Admit	Deny	Deny
System Log	Admit	Deny	Deny
Alarm Log	Admit	Admit	Admit
Host Communication Log	Admit	Deny	Deny
Internal Communication Log	Admit	Deny	Deny

Maintenance

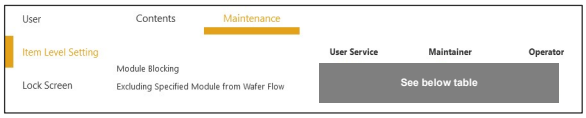
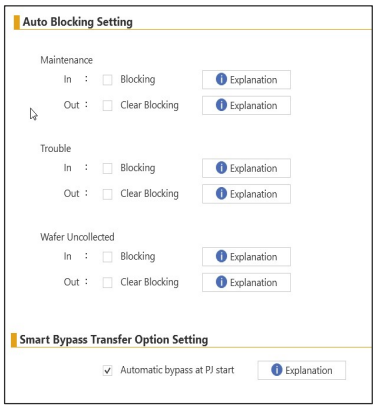


Table for item level(Maintenance tab) Vendor Service has access to all items and menus.

	User Service	Maintainer	Operator
Module Blocking	Admit	Deny	Deny
Excluding Specified Module from Wafer Flow	Admit	Deny	Deny

Smart Bypass Setting



Local Secutity

Lock Screen

ECV Edit

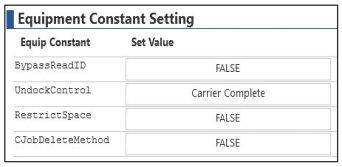


Table for Global Security settings

Engineering user groups can be created and are site specific

	Function	Admin	Maintainers	Operators	Users
Security					
	Security Setting	Write	None	None	None
	Security Role Setting	Enable	Disable	Disable	Disable
Monitroning					
	Equipment Status Monitoring	Enable	Enable	Enable	Disable
Production					
	Alarm Recovery	Enable	Enable	Disable	Disable
	Alarm Recovery Privileger	Enable	Disable	Disable	Disable
	Product Processing	Enable	Enable	Enable	Disable
	Advanced Product Processing	Enable	Enable	Disable	Disable
	Critical Product Processing	Enable	Disable	Disable	Disable
	Product Recovery	Enable	Enable	Enable	Disable
	Advanced Product Recovery	Enable	Enable	Disable	Disable
	Critical Product Recovery	Enable	Disable	Disable	Disable
Maintenance					
	Maintenance Operation	Enable	Enable	Enable	Disable
	Advanced Maintenance Operation	Enable	Enable	Disable	Disable
	Critical Maintenance Operation	Enable	Disable	Disable	Disable
	Module Blocking	Enable	Disable	Disable	Disable
	Excluding Specific Module from Wafer	Enable	Enable	Disable	Disable
Recipe					
	Recipe Adminstrator Privileger	Enable	Disable	Disable	Disable
	Recipe Data Access	Write	Write	Read	None
	Recipe Backup	Enable	Disable	Disable	Disable
	Recipe Export	Enable	Disable	Disable	Disable
	Recipe Verification Condition Setting	Enable	Disable	Disable	Disable
	Recipe Partial Revise	Enable	Enable	Enable	Disable
System					
	System Setting	Enable	Enable	Enable	Disable
	Advanced System Setting	Enable	Enable	Disable	Disable
	Critical System Setting	Enable	Disable	Disable	Disable
	Equipment Time Setting	Enable	Enable	Disable	Disable
	Equipment System Update	Enable	Disable	Disable	Disable
	Equipment Initialization	Enable	Disable	Disable	Disable
	Equipment Shutdown	Enable	Disable	Disable	Disable

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17. Data Collect Condition Editor

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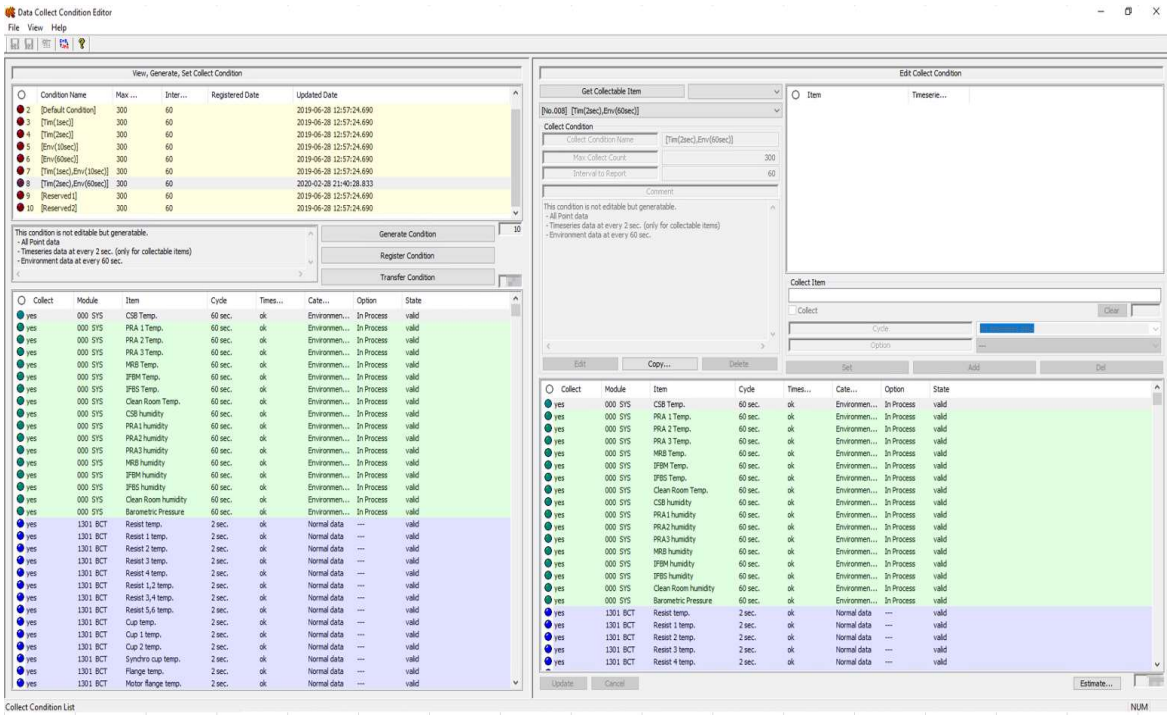
Data Collect Condition Editor can be found in the Ingenio within the Start\CLEAN TRACK LITHIUS directory

Verify that Data Collect Condition Editor has been set up with the following condition name generated, registered, and transferred

Condition Name: [Time (2sec),Env(60sec)]



18. Parameter Editor

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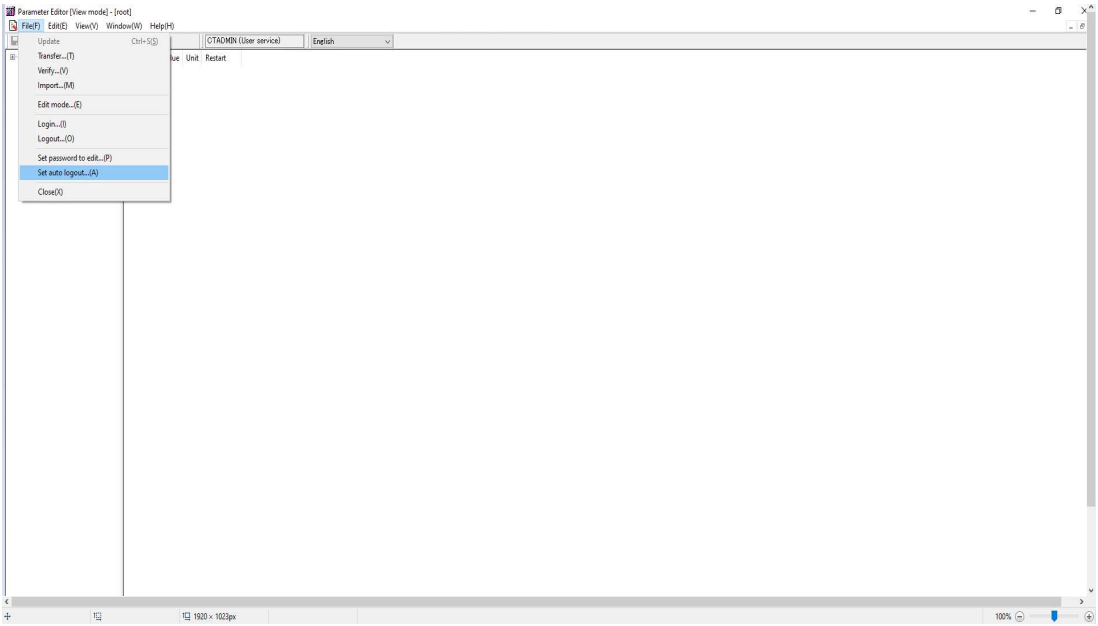
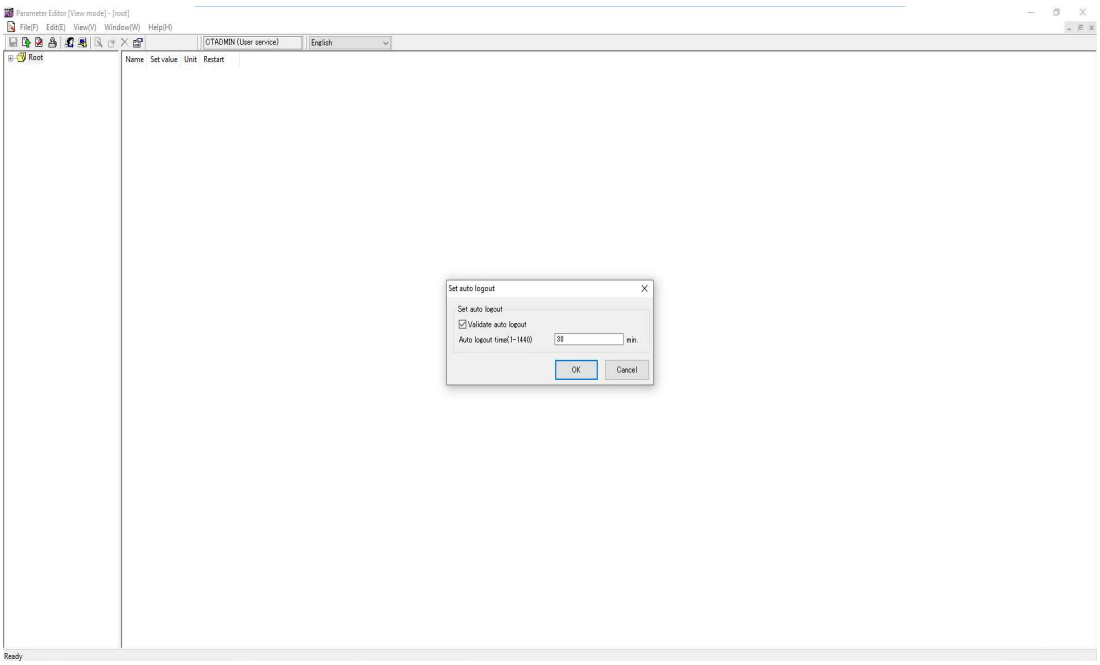
(Parameter Editor can be found in the Ingenio within the Start\CLEAN TRACK LITHIUS directory)

Auto logout setting

Validate Auto Logout	Validate
Auto Logout Time	30 min.

*Location of setting is shown in the picture as below.





19. Ingenio TL Utility

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(Ingenio TL Utility can be found in the Ingenio within the Start\CLEAN TRACK LITHIUS directory)

Option - Productivity Loss Analysis Sytem

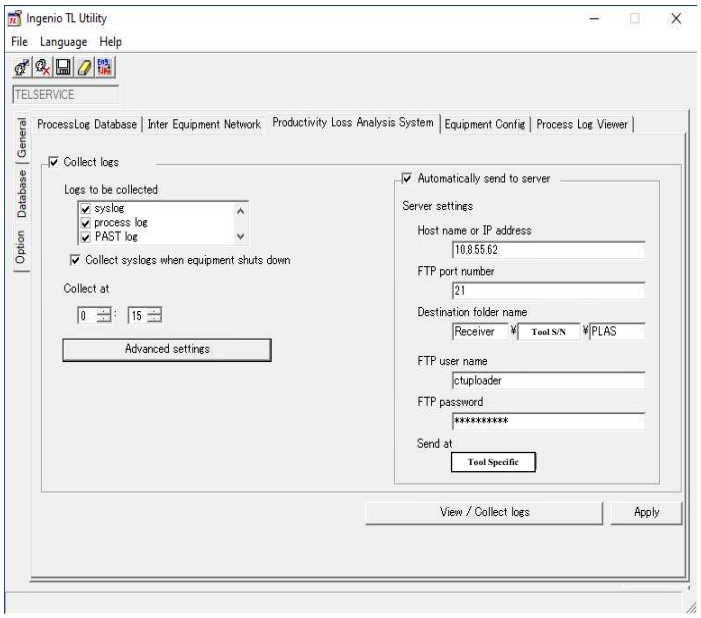
Collect logs	Validate

Logs to be collected

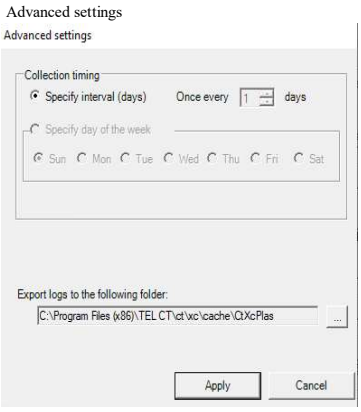
syslog	Validate
process log	Validate
PAST log	Validate
Alarm log	Validate

Collect syslogs when equipment shuts down	Invalidate
Collect at	0:15
Collection timing	Specify interval (days) Once every 1 days

*Location of setting is shown in the picture as below.



Advanced settings



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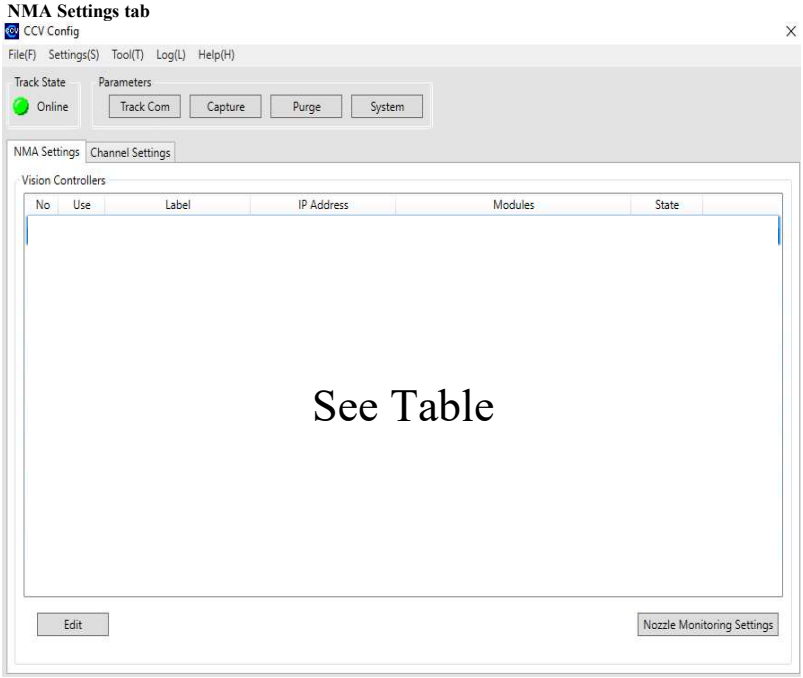
20.1 CCV Setting

CCV Config

(CCV Config can be found in the Other desktop)

NMA Settings tab



BARC Tool Setting Table

No	Use	Label	IP Address	Modules	Statue
1	OFF	11	10.10.10.60		
2	OFF	12	10.10.10.61		
3	ON	13	10.10.10.62	13-1 BCT, 13-2 BCT, 13-3 BCT	Online
4	ON	14	10.10.10.63	14-1 BCT, 14-2 BCT, 14-3 BCT	Online
5	ON	15	10.10.10.64	15-1 BCT, 15-2 BCT, 15-3 BCT	Online
6	ON	16	10.10.10.65	16-1 BCT, 16-2 BCT, 16-3 BCT	Online
7	OFF	21_22L	10.10.10.80		
8	OFF	21_22R	10.10.10.81		
9	OFF	23_24L	10.10.10.82		
10	OFF	23_24R	10.10.10.83		
11	OFF	25_26L	10.10.10.84		
12	OFF	25_26R	10.10.10.85		

IMM Tool Setting Table

No	Use	Label	IP Address	Modules	Statue
1	ON	11_12L	10.10.10.60	11-1 COT, 11-12 COT, 12-1 COT, 12-2COT	Online
2	ON	11_12R	10.10.10.61	11-3 ITC, 11-4 ITC, 12-3 ITC, 12-4 ITC	Online
3	ON	13L	10.10.10.62	13-1 COT, 13-2 COT	Online
4	ON	13R	10.10.10.63	13-3 ITC, 13-4 ITC	Online
5	OFF	15_16L	10.10.10.64		
6	OFF	15_16R	10.10.10.65		
7	OFF	21_22L	10.10.10.80		
8	OFF	21_22R	10.10.10.81		
9	OFF	23_24L	10.10.10.82		
10	OFF	23_24R	10.10.10.83		
11	OFF	25_26L	10.10.10.84		
12	OFF	25_26R	10.10.10.85		

EUV Tool Setting Table

No	Use	Label	IP Address	Modules	Statue
1	ON	12L	10.10.10.60	12-1 COT, 12-2 COT	Online
2	ON	12R	10.10.10.61	12-3 ITC, 12-4 ITC	Online
3	ON	13L	10.10.10.62	13-1 COT, 13-2 COT	Online
4	ON	13R	10.10.10.63	13-3 ITC, 13-4 ITC	Online
5	OFF	15_16L	10.10.10.64		
6	OFF	15_16R	10.10.10.65		
7	OFF	21_22L	10.10.10.80		
8	OFF	21_22R	10.10.10.81		
9	OFF	23_24L	10.10.10.82		
10	OFF	23_24R	10.10.10.83		
11	OFF	25_26L	10.10.10.84		
12	OFF	25_26R	10.10.10.85		

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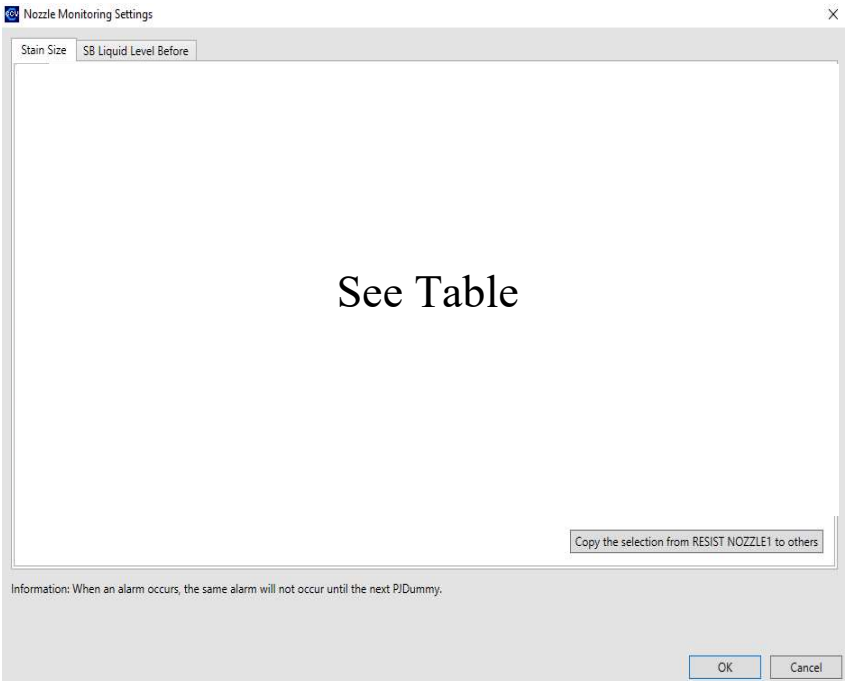
20.1 CCV Setting

CCV Config

Nozzle Monitoring Settings

Stain Size tab



BARC Tool Setting Table

13-L,14-L,15-L,16-L

Alarm Criteria		Nozzle Name									
No.	Criteria	RESIST NOZZLE1	RESIST NOZZLE2	RESIST NOZZLE3	RESIST NOZZLE4	RESIST NOZZLE5	RESIST NOZZLE6	RESIST NOZZLE7	RESIST NOZZLE8	RESIST NOZZLE9	RRC NOZZLE1
1	More than 1.000mm in 10 consecutive.	●	●	●	●	●	●	●	●	●	●
2											
3											
4											
5											
6											
7											
8											
9											
10											

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20.1 CCV Setting

CCV Config

IMM/EUV Tool Setting Table

11-L*,12-L,13-L

Alarm Criteria		Nozzle Name							
No.	Criteria	RESIST NOZZLE1	RESIST NOZZLE2	RESIST NOZZLE3	RESIST NOZZLE4	RESIST NOZZLE5	RESIST NOZZLE6	RESIST NOZZLE7	RRC NOZZLE1
1	More than 1.000mm in 10 consecutive.	●	●	●	●	●	●	●	●
2									
3									
4									
5									
6									
7									
8									
9									
10									

*EUV not present

11-R*,12-R,13-R

Alarm Criteria		Nozzle Name			
No.	Criteria	RESIST NOZZLE1	RESIST NOZZLE2	RESIST NOZZLE3	RRC NOZZLE1
1	More than 1.000mm in 10 consecutive.	●	●	●	●
2					
3					
4					
5					
6					
7					
8					
9					
10					

*EUV not present

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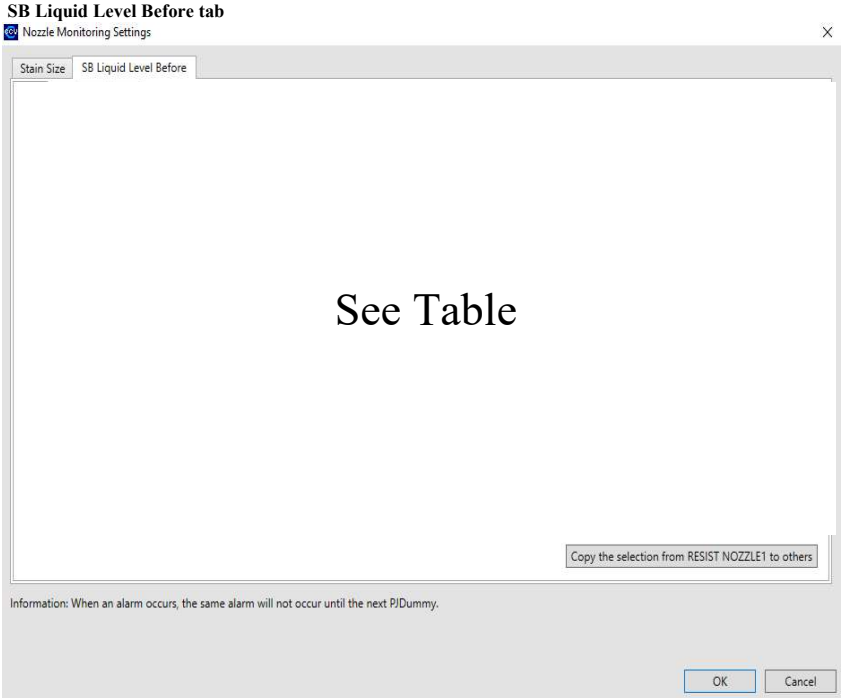
20.1 CCV Setting

CCV Config

Nozzle Monitoring Settings

SB Liquid Level Before tab



BARC Tool Setting Table

13-L,14-L,15-L,16-L

Alarm Criteria		Nozzle Name									
No.	Criteria	RESIST NOZZLE1	RESIST NOZZLE2	RESIST NOZZLE3	RESIST NOZZLE4	RESIST NOZZLE5	RESIST NOZZLE6	RESIST NOZZLE7	RESIST NOZZLE8	RESIST NOZZLE9	RRC NOZZLE1
1	Less than 0.500mm or more than 8.200mm in 10 consecutive.	●	●	●	●	●	●	●	●	●	●
2											
3											
4											
5											
6											
7											
8											
9											
10											

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20.1 CCV Setting

CCV Config

IMM/EUV Tool Setting Table

11-L*,12-L,13-L

Alarm Criteria		Nozzle Name							
No.	Criteria	RESIST NOZZLE1	RESIST NOZZLE2	RESIST NOZZLE3	RESIST NOZZLE4	RESIST NOZZLE5	RESIST NOZZLE6	RESIST NOZZLE7	RRC NOZZLE1
1	Less than 0.500mm or more than 8.200mm in 10 consecutive.	●	●	●	●	●	●	●	●
2									
3									
4									
5									
6									
7									
8									
9									
10									

*EUV not present

11-R*,12-R,13-R

Alarm Criteria		Nozzle Name			
No.	Criteria	RESIST NOZZLE1	RESIST NOZZLE2	RESIST NOZZLE3	RRC NOZZLE1
1	Less than 0.500mm or more than 8.200mm in 10 consecutive.	●	●	●	●
2					
3					
4					
5					
6					
7					
8					
9					
10					

*EUV not present

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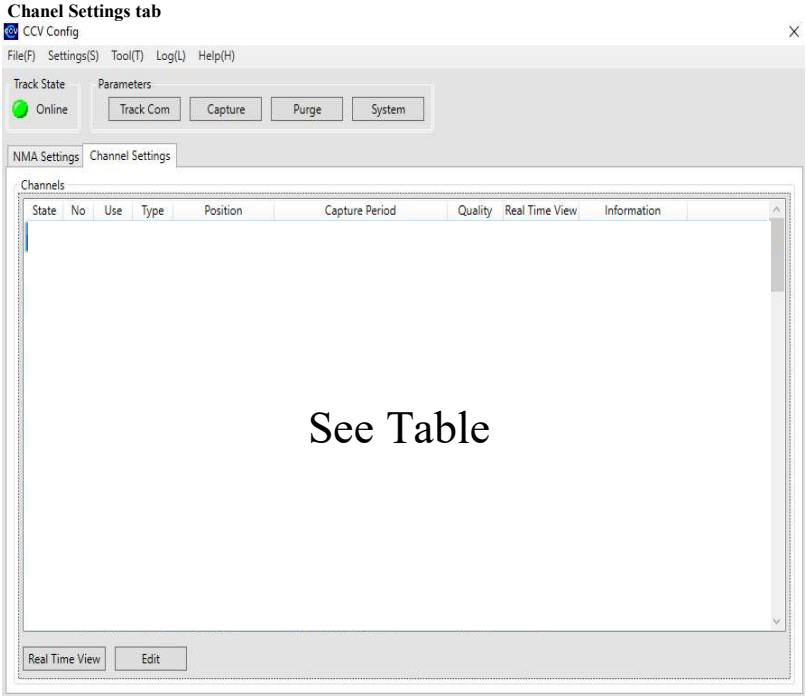
20.1 CCV Setting

CCV Config

Chanel Settings tab



BARC Tool Setting Table

No	Use	Type	Position	Capture Period	Quality	Real Time View	Information
0	ON	Cup	16-1 BCT	[Wafer In] - [Wafer Out]	Middle	□	
1	ON	Cup	16-2 BCT	[Wafer In] - [Wafer Out]	Middle	□	
2	ON	Cup	16-3 BCT	[Wafer In] - [Wafer Out]	Middle	□	
3	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
4	ON	Cup	15-1 BCT	[Wafer In] - [Wafer Out]	Middle	□	
5	ON	Cup	15-2 BCT	[Wafer In] - [Wafer Out]	Middle	□	
6	ON	Cup	15-3 BCT	[Wafer In] - [Wafer Out]	Middle	□	
7	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
8	ON	Cup	14-1 BCT	[Wafer In] - [Wafer Out]	Middle	□	
9	ON	Cup	14-2 BCT	[Wafer In] - [Wafer Out]	Middle	□	
10	ON	Arm	1-0 HCRA	3 min Interval	Middle	□	
11	ON	Arm	1-20 HCRA	3 min Interval	Middle	□	
12	OFF	Arm		3 min Interval	Middle	□	
13	OFF	Arm		3 min Interval	Middle	□	
14	OFF	Arm		3 min Interval	Middle	□	
15	OFF	Arm		3 min Interval	Middle	□	
16	ON	Cup	14-3 BCT	[Wafer In] - [Wafer Out]	Middle	□	
17	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
18	ON	Cup	13-1 BCT	[Wafer In] - [Wafer Out]	Middle	□	
19	ON	Cup	13-2 BCT	[Wafer In] - [Wafer Out]	Middle	□	
20	ON	Cup	13-3 BCT	[Wafer In] - [Wafer Out]	Middle	□	
21	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
22	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
23	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
24	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
25	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
26	OFF	Arm		3 min Interval	Middle	□	
27	OFF	Arm		3 min Interval	Middle	□	
28	ON	Arm	13-0 PRA	3 min Interval	Middle	□	
29	ON	Arm	14-0 PRA	3 min Interval	Middle	□	
30	ON	Arm	15-0 PRA	3 min Interval	Middle	□	
31	ON	Arm	16-0 PRA	3 min Interval	Middle	□	

20.1 CCV Setting

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CCV Config

Chanel Setting

IMM Tool Setting Table

No	Use	Type	Position	Capture Period	Quality	Real Time View	Information
0	ON	Cup	16-1 ADEV	[Wafer In] - [Wafer Out]	Middle	□	
1	ON	Cup	16-2 ADEV	[Wafer In] - [Wafer Out]	Middle	□	
2	ON	Cup	16-3 ADEV	[Wafer In] - [Wafer Out]	Middle	□	
3	ON	Cup	16-4 ANTD	[Wafer In] - [Wafer Out]	Middle	□	
4	ON	Cup	16-5 ANTD	[Wafer In] - [Wafer Out]	Middle	□	
5	ON	Free	16-1 BATH	3 min Interval	Middle	□	
6	ON	Free	16-2 BATH	3 min Interval	Middle	□	
7	ON	Free	16-3 BATH	3 min Interval	Middle	□	
8	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
9	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
10	ON	Cup	15-1 ADEV	[Wafer In] - [Wafer Out]	Middle	□	
11	ON	Cup	15-2 ADEV	[Wafer In] - [Wafer Out]	Middle	□	
12	ON	Cup	15-3 ADEV	[Wafer In] - [Wafer Out]	Middle	□	
13	ON	Cup	15-4 ANTD	[Wafer In] - [Wafer Out]	Middle	□	
14	ON	Cup	15-5 ANTD	[Wafer In] - [Wafer Out]	Middle	□	
15	ON	Free	15-1 BATH	3 min Interval	Middle	□	
16	ON	Free	15-2 BATH	3 min Interval	Middle	□	
17	ON	Free	15-3 BATH	3 min Interval	Middle	□	
18	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
19	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
20	ON	Cup	14-1 ADEV	[Wafer In] - [Wafer Out]	Middle	□	
21	ON	Cup	14-2 ADEV	[Wafer In] - [Wafer Out]	Middle	□	
22	ON	Cup	14-3 ADEV	[Wafer In] - [Wafer Out]	Middle	□	
23	ON	Cup	14-4 ANTD	[Wafer In] - [Wafer Out]	Middle	□	
24	ON	Cup	14-5 ANTD	[Wafer In] - [Wafer Out]	Middle	□	
25	ON	Free	14-1 BATH	3 min Interval	Middle	□	
26	ON	Free	14-2 BATH	3 min Interval	Middle	□	
27	ON	Free	14-3 BATH	3 min Interval	Middle	□	
28	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
29	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
30	ON	Cup	13-1 COT	[Wafer In] - [Wafer Out]	Middle	□	
31	ON	Cup	13-2 COT	[Wafer In] - [Wafer Out]	Middle	□	
32	ON	Arm	1-0 HCRA	3 min Interval	Middle	□	
33	ON	Arm	1-20 HCRA	3 min Interval	Middle	□	
34	OFF	Arm		3 min Interval	Middle	□	
35	OFF	Arm		3 min Interval	Middle	□	
36	ON	Arm	11-0 PRA	3 min Interval	Middle	□	
37	ON	Arm	12-0 PRA	3 min Interval	Middle	□	
38	ON	Arm	13-0 PRA	3 min Interval	Middle	□	
39	ON	Arm	14-0 PRA	3 min Interval	Middle	□	
40	ON	Arm	15-0 PRA	3 min Interval	Middle	□	
41	ON	Arm	16-0 PRA	3 min Interval	Middle	□	
42	ON	Arm	30-0 IRAI	3 min Interval	Middle	□	
43	ON	Arm	30-10 IRAM	3 min Interval	Middle	□	
44	ON	Arm	30-20 IRAM	3 min Interval	Middle	□	
45	OFF	Arm		3 min Interval	Middle	□	
46	ON	Free	TOOL	3 min Interval	Middle	□	
47	OFF	Arm		3 min Interval	Middle	□	
48	ON	Cup	13-3 ITC	[Wafer In] - [Wafer Out]	Middle	□	
49	ON	Cup	13-4 ITC	[Wafer In] - [Wafer Out]	Middle	□	
50	OFF	Cup		[Process Start] - [Process End]	Middle	□	
51	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
52	ON	Cup	12-1 COT	[Wafer In] - [Wafer Out]	Middle	□	
53	ON	Cup	12-2 COT	[Wafer In] - [Wafer Out]	Middle	□	
54	ON	Cup	12-3 ITC	[Wafer In] - [Wafer Out]	Middle	□	
55	ON	Cup	12-4 ITC	[Wafer In] - [Wafer Out]	Middle	□	
56	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
57	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
58	ON	Cup	11-1 COT	[Wafer In] - [Wafer Out]	Middle	□	
59	ON	Cup	11-2 COT	[Wafer In] - [Wafer Out]	Middle	□	
60	ON	Cup	11-3 ITC	[Wafer In] - [Wafer Out]	Middle	□	
61	ON	Cup	11-4 ITC	[Wafer In] - [Wafer Out]	Middle	□	
62	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
63	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	

20.1 CCV Setting

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CCV Config

Chanel Setting

EUV Tool Setting Table

No	Use	Type	Position	Capture Period	Quality	Real Time View	Information
0	ON	Cup	16-1 ADEV	[Wafer In] - [Wafer Out]	Middle	□	
1	ON	Cup	16-2 ADEV	[Wafer In] - [Wafer Out]	Middle	□	
2	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
3	ON	Cup	16-4 ANTD	[Wafer In] - [Wafer Out]	Middle	□	
4	ON	Cup	16-5 ANTD	[Wafer In] - [Wafer Out]	Middle	□	
5	ON	Free	16-1 BATH	3 min Interval	Middle	□	
6	ON	Free	16-2 BATH	3 min Interval	Middle	□	
7	OFF	Free	16-3 BATH	3 min Interval	Middle	□	
8	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
9	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
10	ON	Cup	15-1 ADEV	[Wafer In] - [Wafer Out]	Middle	□	
11	ON	Cup	15-2 ADEV	[Wafer In] - [Wafer Out]	Middle	□	
12	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
13	ON	Cup	15-4 ANTD	[Wafer In] - [Wafer Out]	Middle	□	
14	ON	Cup	15-5 ANTD	[Wafer In] - [Wafer Out]	Middle	□	
15	ON	Free	15-1 BATH	3 min Interval	Middle	□	
16	ON	Free	15-2 BATH	3 min Interval	Middle	□	
17	OFF	Free	15-3 BATH	3 min Interval	Middle	□	
18	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
19	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
20	ON	Cup	14-1 ADEV	[Wafer In] - [Wafer Out]	Middle	□	
21	ON	Cup	14-2 ADEV	[Wafer In] - [Wafer Out]	Middle	□	
22	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
23	ON	Cup	14-4 ANTD	[Wafer In] - [Wafer Out]	Middle	□	
24	ON	Cup	14-5 ANTD	[Wafer In] - [Wafer Out]	Middle	□	
25	ON	Free	14-1 BATH	3 min Interval	Middle	□	
26	ON	Free	14-2 BATH	3 min Interval	Middle	□	
27	OFF	Free	14-3 BATH	3 min Interval	Middle	□	
28	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
29	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
30	ON	Cup	13-1 COT	[Wafer In] - [Wafer Out]	Middle	□	
31	ON	Cup	13-2 COT	[Wafer In] - [Wafer Out]	Middle	□	
32	ON	Arm	1-0 HCRA	3 min Interval	Middle	□	
33	ON	Arm	1-20 HCRA	3 min Interval	Middle	□	
34	OFF	Arm		3 min Interval	Middle	□	
35	OFF	Arm		3 min Interval	Middle	□	
36	OFF	Arm		3 min Interval	Middle	□	
37	ON	Arm	12-0 PRA	3 min Interval	Middle	□	
38	ON	Arm	13-0 PRA	3 min Interval	Middle	□	
39	ON	Arm	14-0 PRA	3 min Interval	Middle	□	
40	ON	Arm	15-0 PRA	3 min Interval	Middle	□	
41	ON	Arm	16-0 PRA	3 min Interval	Middle	□	
42	ON	Arm	30-0 IRAI	3 min Interval	Middle	□	
43	ON	Arm	30-10 IRAM	3 min Interval	Middle	□	
44	ON	Arm	30-20 IRAM	3 min Interval	Middle	□	
45	OFF	Arm		3 min Interval	Middle	□	
46	OFF	Free	TOOL	3 min Interval	Middle	□	
47	OFF	Arm		3 min Interval	Middle	□	
48	ON	Cup	13-3 ITC	[Process Start] - [Process End]	Middle	□	
49	ON	Cup	13-4 ITC	[Process Start] - [Process End]	Middle	□	
50	OFF	Cup		[Process Start] - [Process End]	Middle	□	
51	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
52	ON	Cup	12-1 COT	[Wafer In] - [Wafer Out]	Middle	□	
53	ON	Cup	12-2 COT	[Wafer In] - [Wafer Out]	Middle	□	
54	ON	Cup	12-3 ITC	[Wafer In] - [Wafer Out]	Middle	□	
55	ON	Cup	12-4 ITC	[Wafer In] - [Wafer Out]	Middle	□	
56	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
57	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
58	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
59	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
60	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
61	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
62	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	
63	OFF	Cup		[Wafer In] - [Wafer Out]	Middle	□	

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20.2 CCV Setting (NMA2.0)

CCV Config

(CCV Config can be found in the Other desktop)

NMA Settings tab

BARC Tool Setting Table

No	Use	Nozzle Arm	Modules	Statue
1	ON	13-L BCT	13-1 BCT, 13-2 BCT, 13-3 BCT	OK
2	ON	14-L BCT	14-1 BCT, 14-2 BCT, 14-3 BCT	OK
3	ON	15-L BCT	15-1 BCT, 15-2 BCT, 15-3 BCT	OK
4	ON	16-L BCT	16-1 BCT, 16-2 BCT, 16-3 BCT	OK
5	OFF			
6	OFF			
7	OFF			
8	OFF			
9	OFF			
10	OFF			
11	OFF			
12	OFF			

IMM Tool Setting Table

No	Use	Nozzle Arm	Modules	Statue
1	ON	11-L COT	11-1 COT, 11-2 COT	OK
2	ON	11-R ITC	11-3 ITC, 11-4 ITC	OK
3	ON	12-L COT	12-1 COT, 12-2COT	OK
4	ON	12-R ITC	12-3 ITC, 12-4 ITC	OK
5	ON	13-L COT	13-1 COT, 13-2 COT	OK
6	ON	13-R ITC	13-3 ITC, 13-4 ITC	OK
7	OFF			
8	OFF			
9	OFF			
10	OFF			
11	OFF			
12	OFF			

EUV Tool Setting Table

No	Use	Nozzle Arm	Modules	Statue
1	ON	12-L COT	12-1 COT, 12-2 COT	OK
2	ON	12-R ITC	12-3 ITC, 12-4 ITC	OK
3	ON	13-L COT	13-1 COT, 13-2 COT	OK
4	ON	13-R ITC	13-3 ITC, 13-4 ITC	OK
5	OFF			
6	OFF			
7	OFF			
8	OFF			
9	OFF			
10	OFF			
11	OFF			
12	OFF			

KrF Tool Setting Table

No	Use	Nozzle Arm	Modules	Statue
1	ON	13-L COT	13-1 COT, 13-2 COT	OK
2	ON	13-R COT	13-3 COT, 13-4 COT	OK
3	ON	14-L COT	14-1 COT, 14-2COT	OK
4	ON	14-R ITC	14-3 COT, 14-4 COT	OK
5	OFF			
6	OFF			
7	OFF			
8	OFF			
9	OFF			
10	OFF			
11	OFF			
12	OFF			

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20.2 CCV Setting (NMA2.0)

CCV Config

Nozzle Monitoring Settings

Stain Size tab

BARC Tool Setting Table

13-L,14-L,15-L,16-L

Alarm Criteria		Nozzle Name									
No.	Criteria	RESIST NOZZLE1	RESIST NOZZLE2	RESIST NOZZLE3	RESIST NOZZLE4	RESIST NOZZLE5	RESIST NOZZLE6	RESIST NOZZLE7	RESIST NOZZLE8	RESIST NOZZLE9	RRC NOZZLE1
1	More than 1.000mm in 10 consecutive.	●	●	●	●	●	●	●	●	●	●
2											
3											
4											
5											
6											
7											
8											
9											
10											

20.2 CCV Setting (NMA2.0)

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CCV Config

IMM/EUV Tool Setting Table

11-L*,12-L,13-L

Alarm Criteria		Nozzle Name							
No.	Criteria	RESIST NOZZLE1	RESIST NOZZLE2	RESIST NOZZLE3	RESIST NOZZLE4	RESIST NOZZLE5	RESIST NOZZLE6	RESIST NOZZLE7	RRC NOZZLE1
1	More than 1.000mm in 10 consecutive.	●	●	●	●	●	●	●	●
2									
3									
4									
5									
6									
7									
8									
9									
10									

*EUV not present

11-R*,12-R,13-R

Alarm Criteria		Nozzle Name			
No.	Criteria	RESIST NOZZLE1	RESIST NOZZLE2	RESIST NOZZLE3	RRC NOZZLE1
1	More than 1.000mm in 10 consecutive.	●	●	●	●
2					
3					
4					
5					
6					
7					
8					
9					
10					

*EUV not present

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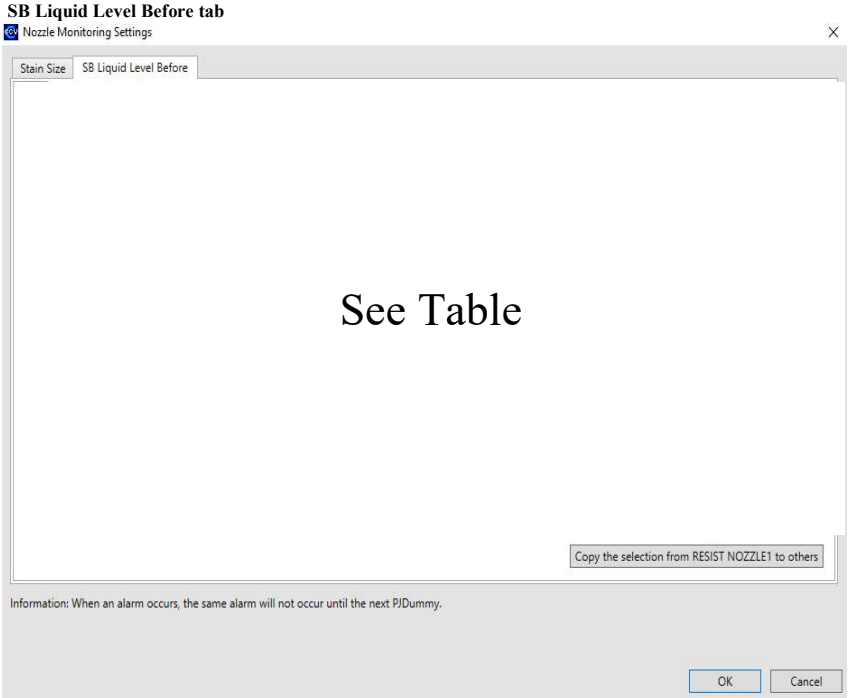
20.2 CCV Setting (NMA2.0)

CCV Config

Nozzle Monitoring Settings

SB Liquid Level Before tab



BARC Tool Setting Table

13-L,14-L,15-L,16-L

Alarm Criteria		Nozzle Name									
No.	Criteria	RESIST NOZZLE1	RESIST NOZZLE2	RESIST NOZZLE3	RESIST NOZZLE4	RESIST NOZZLE5	RESIST NOZZLE6	RESIST NOZZLE7	RESIST NOZZLE8	RESIST NOZZLE9	RRC NOZZLE1
1	Less than 0.500mm or more than 8.200mm in 10 consecutive.	●	●	●	●	●	●	●	●	●	●
2											
3											
4											
5											
6											
7											
8											
9											
10											

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20.2 CCV Setting (NMA2.0)

CCV Config

IMM/EUV Tool Setting Table

11-L*,12-L,13-L

Alarm Criteria		Nozzle Name							
No.	Criteria	RESIST NOZZLE1	RESIST NOZZLE2	RESIST NOZZLE3	RESIST NOZZLE4	RESIST NOZZLE5	RESIST NOZZLE6	RESIST NOZZLE7	RRC NOZZLE1
1	Less than 0.500mm or more than 8.200mm in 10 consecutive.	●	●	●	●	●	●	●	●
2									
3									
4									
5									
6									
7									
8									
9									
10									

*EUV not present

11-R*,12-R,13-R

Alarm Criteria		Nozzle Name			
No.	Criteria	RESIST NOZZLE1	RESIST NOZZLE2	RESIST NOZZLE3	RRC NOZZLE1
1	Less than 0.500mm or more than 8.200mm in 10 consecutive.	●	●	●	●
2					
3					
4					
5					
6					
7					
8					
9					
10					

*EUV not present

KrF Tool Setting Table

13-L,13-R,14-L,14R

Alarm Criteria		Nozzle Name				
No.	Criteria	RESIST NOZZLE1	RESIST NOZZLE2	RESIST NOZZLE3	RESIST NOZZLE4	RRC NOZZLE1
1	Less than 0.500mm or more than 8.200mm in 10 consecutive.	●	●	●	●	●
2						
3						
4						
5						
6						
7						
8						
9						
10						

20.2 CCV Setting (NMA2.0)

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CCV Config

Inspection Setting

Inspection For Process/Inspection Before Dispensing/Nozzle Position	
Position Tolerance(mm)	-
Inspection For Process/Inspection Before Dispensing/Nozzle Scratch & Stain	
Scratch & Stain Detection Gray Level	-
Scratch & Stain Size(mm)	-
Inspection For Process/Inspection At Dispensing/DispenseTime	
Dispense Time Tolerance(msec)	250
Inspection For Process/Inspection At Dispensing/Liquid Column	
Liquid Column Detection Gray Level	-
Liquid Column Width Average Upper Limit(mm)	1.6
Liquid Column Width Average Lower Limit(mm)	0.0
Liquid Column Width Widest Upper Limit(mm)	6.5
Liquid Column Width Narrowest Lower Limit(mm)	0.0
Inspection For Process/Inspection At Dispensing/Dispense Start Delay	
Dispense Start Delay Time Tolerance(msec)	100
Inspection For Process/Inspection At Dispensing/Bubble	
Bubble Detection Gray Level	-
Inspection For Process/ Inspection After Dispensing/Liquid Level	
Liquid Level Detection Gray Level	-
Upper Limit(mm)	-
Lower Limit(mm)	-
Inspection For Process/Inspection After Dispensing/Nozzle Position	
Position Tolerance(mm)	-
Inspection For Process/Inspection After Dispensing/Nozzle Scratch & Stain	
Scratch & Stain Detection Gray Level	-
Scratch & Stain Size(mm)	-

Inspection For PJ Dummy /Inspection After PJ Dummy/Liquid Level	
Liquid Level Detection Gray Level	-
Upper Limit(mm)	8.5
Lower Limit(mm)	0.00
Inspection For PJ Dummy /Inspection After PJ Dummy/Nozzle Position	
Position Tolerance(mm)	-
Inspection For PJ Dummy /Inspection After PJ Dummy/Nozzle Scratch & Stain	
Scratch & Stain Detection Gray Level	-
Scratch & Stain Size(mm)	-
Inspection For PJ Dummy /Inspection After PJ Dummy/Nozzle Tilt	
Tilt Limit(deg)	-
Inspection For DFT /Inspection At DFT/Liquid Level	
Liquid Level Detection Gray Level	-
Liquid Level1 Upper Limit(mm)	8.0
Liquid Level1 Lower Limit(mm)	10.0
Liquid Level2 Upper Limit(mm)	3.0
Liquid Level2 Lower Limit(mm)	1.0
Liquid Level3 Upper Limit(mm)	4.0
Liquid Level3 Lower Limit(mm)	3.0
Inspection For DFT/Inspection At DFT/Nozzle Position	
Position Tolerance(mm)	-
Inspection For DFT/Inspection At DFT/Nozzle Scratch & Stain	
Scratch & Stain Detection Gray Level	-
Scratch & Stain Size(mm)	-

Inspection For After Maintenance /Inspection After Maintenance/Nozzle Position	
Position Tolerance(mm)	-
Inspection For After Maintenance /Inspection After Maintenance/Nozzle Scratch & Stain	
Scratch & Stain Detection Gray Level	-
Scratch & Stain Size(mm)	-
Inspection For After Maintenance /Inspection After Maintenance/Nozzle Tilt	
Tilt Limit(deg)	-

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Alarms For Process/Inspection At Dispensing/Dispense	
Dispense	-
Alarms For Process/Inspection At Dispensing/DispenseTime	
Dispense Time	Valid
Alarms For Process/Inspection At Dispensing/Liquid Column	
Liquid Column Width Average	Valid(excluding N/A)
Liquid Column Width Widest	Invalid
Liquid Column Width Narrowest	Invalid
Alarms For Process/Inspection At Dispensing/Dispense Start Delay	
Dispense Start Delay	Invalid

Alarms For Process/Inspection At Dispensing/Bubble	
Bubble	-
Alarms For Process/Inspection At Dispensing/Background	
DispenseArea Background Brightness	-

Alarms For Process/ Inspection Before Dispensing/Liquid Level	
Liquid Level	Valid(excluding N/A)
Alarms For Process/ Inspection After Dispensing/Liquid Level	
Liquid Level	Invalid

Alarms For Process/Inspection Before Dispensing/Nozzle Position	
Position	Invalid
Alarms For Process/Inspection Before Dispensing/Nozzle Scratch & Stain	
Scratch & Stain	Valid(excluding N/A)
Alarms For Process/Inspection After Dispensing/Nozzle Position	
Position	-
Alarms For Process/Inspection After Dispensing/Nozzle Scratch & Stain	
Scratch & Stain	-
Alarms For DFT/Inspection At DFT/LiquidLevel	
Liquid Level1	Invalid
Liquid Level2	Valid(excluding N/A)
Liquid Level3	Valid(excluding N/A)
Alarms For DFT/Inspection At DFT/Nozzle Position	
Position	-
Alarms For DFT/Inspection At DFT/Nozzle Scratch & Stain	
Scratch & Stain	-
Alarms For After Maintenance/Inspection After Maintenance/Nozzle Position	
Position	-
Alarms For After Maintenance/Inspection After Maintenance/Nozzle Tilt	
Tilt	-
Alarms For After Maintenance/Inspection After Maintenance/Nozzle Scratch & Stain	
Scratch & Stain	-
Alarms For PJ Dummy/Inspection After PJ Dummy/LiquidLevel	
Liquid Level	Valid(excluding N/A)
Alarms For PJ Dummy/Inspection After PJ Dummy/Nozzle Position	
Position	Valid(excluding N/A)
Alarms For PJ Dummy/Inspection After PJ Dummy/Nozzle Tilt	
Tilt	Valid(excluding N/A)
Alarms For PJ Dummy/Inspection After PJ Dummy/Nozzle Scratch & Stain	
Scratch & Stain	Valid(excluding N/A)
Common/Common/Common	
Nozzle Non Recognized	-

21. FD Manager Setting

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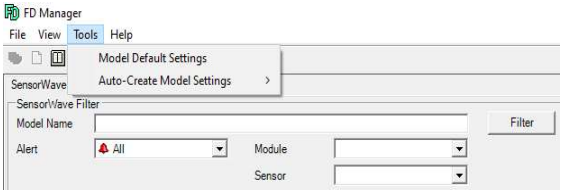
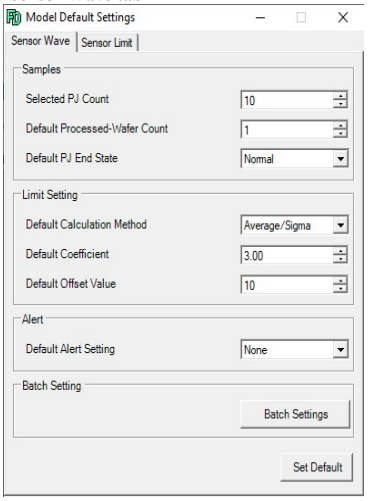
(FD Manager can be found in the Process Log Viwer in IngenioTL)

Tool/Model Default Settings*

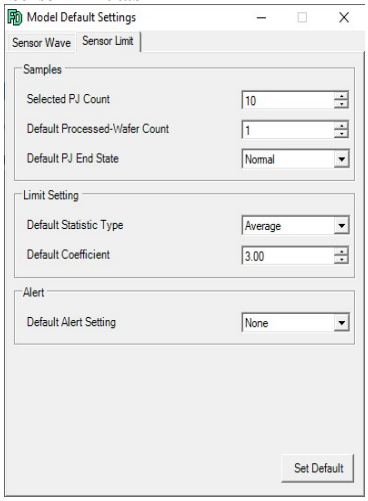
*This setting is not used in Intel operation.



Sensor Wave tab

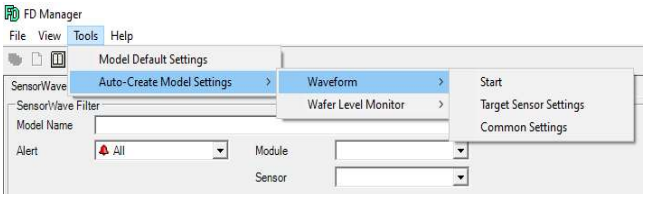


Sensor Limit tab



Tool/Auto-Create Model Setting/Waveform*

*This setting is not used in Intel operation.



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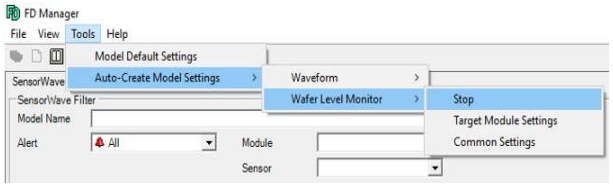
21. FD Manager Setting

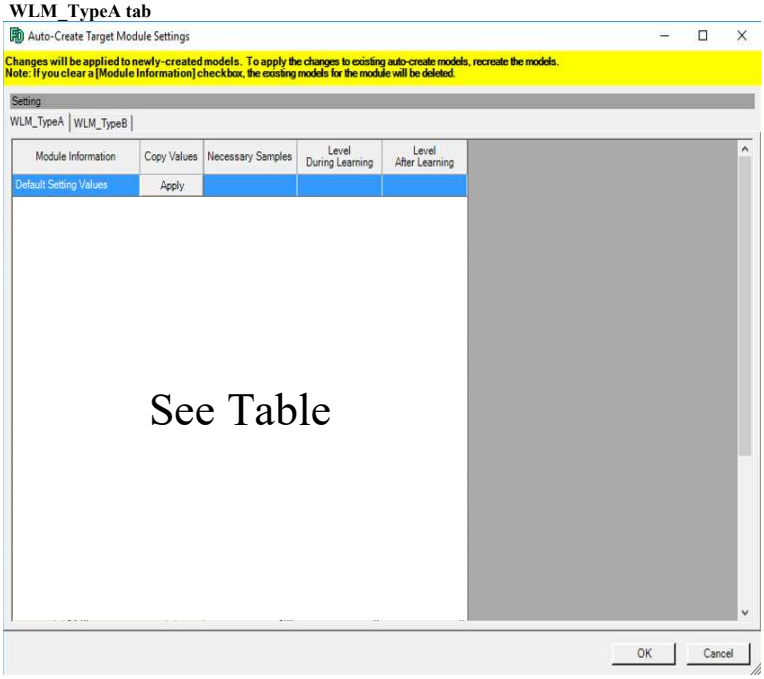
Tool/Auto-Create Model Setting/Wafer Level Monitor*

*This setting is using AWLM. "Stop" is displayed on the screen.



Tool/Auto-Create Model Setting/Wafer Level Monitor/Target Module Settings

WLM_TypeA tab



21. FD Manager Setting

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Table for BARC Tools

Module Information	Copy Values	Nesessary Samples	Level During Learning	Level After Learning
Default Setting Values	Apply			
☐ All	☐			
☐ CGCH	☐			
☐ 13-15	☐	100	3	2
☐ 13-16	☐	100	3	2
☐ 13-24	☐	100	3	2
☐ 13-25	☐	100	3	2
☐ 13-26	☐	100	3	2
☐ 14-15	☐	100	3	2
☐ 14-16	☐	100	3	2
☐ 14-24	☐	100	3	2
☐ 14-25	☐	100	3	2
☐ 14-26	☐	100	3	2
☐ 15-15	☐	100	3	2
☐ 15-16	☐	100	3	2
☐ 15-24	☐	100	3	2
☐ 15-25	☐	100	3	2
☐ 15-26	☐	100	3	2
☐ 16-15	☐	100	3	2
☐ 16-16	☐	100	3	2
☐ 16-24	☐	100	3	2
☐ 16-25	☐	100	3	2
☐ 16-26	☐	100	3	2

Table for KrF Tools*

Module Information	Copy Values	Nesessary Samples	Level During Learning	Level After Learning
Default Setting Values	Apply			
☐ All	☐			
☐ CPHP	☐			
☐ 13-13	☐	100	3	2
☐ 13-14	☐	100	3	2
☐ 13-15	☐	100	3	2
☐ 13-16	☐	100	3	2
☐ 13-23	☐	100	3	2
☐ 13-24	☐	100	3	2
☐ 13-25	☐	100	3	2
☐ 14-13	☐	100	3	2
☐ 14-14	☐	100	3	2
☐ 14-15	☐	100	3	2
☐ 14-16	☐	100	3	2
☐ 14-23	☐	100	3	2
☐ 14-24	☐	100	3	2
☐ 14-25	☐	100	3	2
☐ 15-15	☐	100	3	2
☐ 15-16	☐	100	3	2
☐ 15-25	☐	100	3	2
☐ 15-26	☐	100	3	2
☐ 16-15	☐	100	3	2
☐ 16-16	☐	100	3	2
☐ 16-25	☐	100	3	2
☐ 16-26	☐	100	3	2

Table for Imm/EUV Tools* *Deck11 does not exist on EUV tools

Module Information	Copy Values	Nesessary Samples	Level During Learning	Level After Learning
Default Setting Values	Apply			
☐ All	☐			
☐ CPHP	☐			
☐ 11-13	☐	100	3	2
☐ 11-14	☐	100	3	2
☐ 11-15	☐	100	3	2
☐ 11-16	☐	100	3	2
☐ 11-23	☐	100	3	2
☐ 11-26	☐	100	3	2
☐ 12-13	☐	100	3	2
☐ 12-14	☐	100	3	2
☐ 12-15	☐	100	3	2
☐ 12-16	☐	100	3	2
☐ 12-23	☐	100	3	2
☐ 12-26	☐	100	3	2
☐ 13-13	☐	100	3	2
☐ 13-14	☐	100	3	2
☐ 13-15	☐	100	3	2
☐ 13-16	☐	100	3	2
☐ 13-23	☐	100	3	2
☐ 13-26	☐	100	3	2
☐ 14-14	☐	100	3	2
☐ 14-15	☐	100	3	2
☐ 14-16	☐	100	3	2
☐ 14-24	☐	100	3	2
☐ 14-25	☐	100	3	2
☐ 14-26	☐	100	3	2
☐ 15-14	☐	100	3	2
☐ 15-15	☐	100	3	2
☐ 15-16	☐	100	3	2
☐ 15-24	☐	100	3	2
☐ 15-25	☐	100	3	2
☐ 15-26	☐	100	3	2
☐ 16-14	☐	100	3	2
☐ 16-15	☐	100	3	2
☐ 16-16	☐	100	3	2
☐ 16-24	☐	100	3	2
☐ 16-25	☐	100	3	2
☐ 16-26	☐	100	3	2

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21. FD Manager Setting

Tool/Auto-Create Model Setting/Wafer Level Monitor/Target Module Settings

WLM_TypeB tab

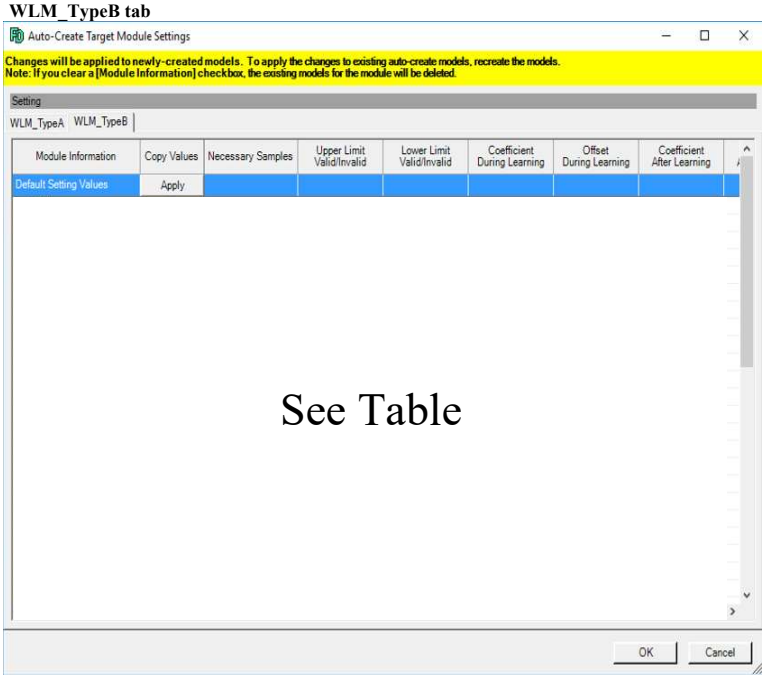

Table for BARC Tools* *CADH does not exist on TBFna/TBFlt/TBFcn

Module Information	Copy Values	Nesessary Samples	Upper Limit Valid/Invalid	Lower Limit Valid/Invalid	Coefficient During Learning	Offset During Learning	Coefficient After Learning	Offset After Learning
Default Setting Values	Apply							
☑ All	☐							
☑ CADH	☐							
☑ 13-11	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 13-12	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 13-21	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 13-22	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 14-11	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 14-12	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 14-21	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 14-22	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 15-11	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 15-12	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 15-21	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 15-22	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 16-11	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 16-12	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 16-21	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 16-22	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ CGCH	☐							
☑ 13-15	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 13-16	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 13-24	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 13-25	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 13-26	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 14-15	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 14-16	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 14-24	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 14-25	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 14-26	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 15-15	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 15-16	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 15-24	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 15-25	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 15-26	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 16-15	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 16-16	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 16-24	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 16-25	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 16-26	☐	100	Invalid	Valid	3.00	60	3.00	60

21. FD Manager Setting

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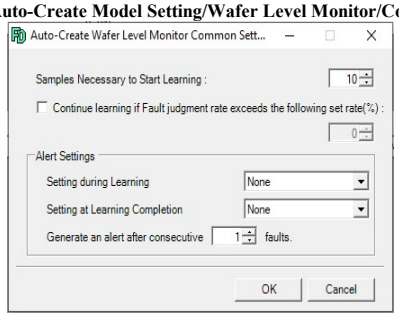
Table for Imm/EUV Tools* *EUV tools doesn't exist Deck11 modules

Module Information Default Setting Values	Copy Values Apply	Nesessary Samples	Upper Limit Valid/Invalid	Lower Limit Valid/Invalid	Coefficient During Learning	Offset During Learning	Coefficient After Learning	Offset After Learning
☑ All	☐							
☑ CADH	☐							
☑ 11-11	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 11-12	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 11-21	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 11-22	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 12-11	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 12-12	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 12-21	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 12-22	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 13-11	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 13-12	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 13-21	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ 13-22	☐	100	Invalid	Valid	3.00	60	3.00	60
☑ CPHP	☐							
☑ 11-13	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 11-14	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 11-15	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 11-16	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 11-23	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 11-26	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 12-13	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 12-14	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 12-15	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 12-16	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 12-23	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 12-26	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 13-13	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 13-14	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 13-15	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 13-16	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 13-23	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 13-26	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 14-14	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 14-15	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 14-16	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 14-24	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 14-25	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 14-26	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 15-14	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 15-15	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 15-16	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 15-24	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 15-25	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 15-26	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 16-14	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 16-15	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 16-16	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 16-24	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 16-25	☐	100	Invalid	Valid	3.00	50	3.00	50
☑ 16-26	☐	100	Invalid	Valid	3.00	50	3.00	50

Tool/Auto-Create Model Setting/Wafer Level Monitor/Common Settings



22. PM Reminder

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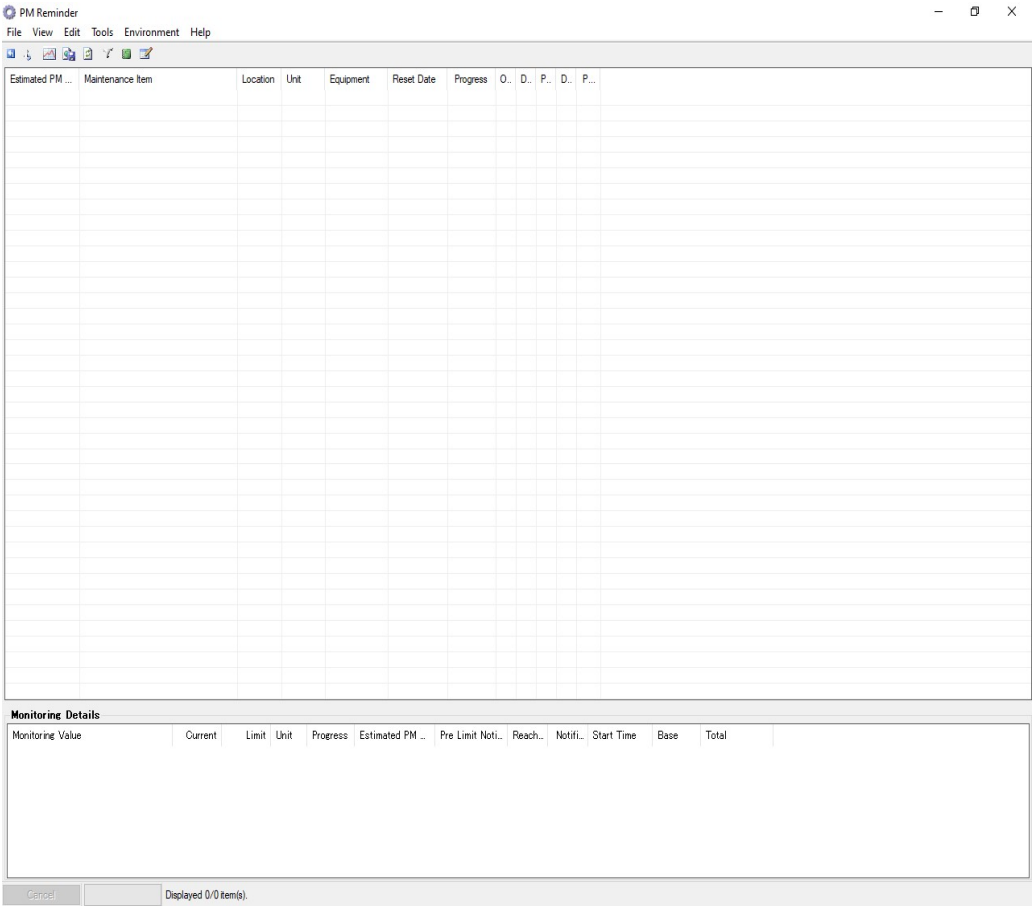
PM Reminder can be found in the Ingenio within the Start\CLEAN TRACK LITHIUS directory

Verify that PM Reminder has been set up with the following screen(Displayed 0/0 item).



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Date	Rev.	Approval		Location	Old	New
		Intel	TEL			
04/20/2020	1.00	K.Proctor	Red	First Edition	N/A	N/A
05/04/2020	1.01	K.Proctor	Red	Section 1. Cover - Teaching Version	1.38.1	1.39.0
				Section 2. SYSTEM(FAB) - FEX - FEX Chemical EXH.(E15C,E15D) - Tool Setting	100.0	25.0
				Section 2. SYSTEM(FAB) - FEX - FEX Chemical EXH.(E15C,E15D) - Tolerance	100 or More	25 or More
				Section 2. SYSTEM(FAB) - FEX - FEX Chemical EXH.(E15C,E15D) - Remarks	NA	TARGET CFM 14.1
				Section 2. SYSTEM(FAB) - CSB/HCSB - HCRA Back area ULPA wind pressure - Tool Setting	Tool Specific	170.0
				Section 2. SYSTEM(FAB) - CSB/HCSB - HCRA Back area ULPA wind pressure - Tolerance	---	150 ~ 190
				Section 2. SYSTEM(FAB) - CSB/HCSB - HCSB transfer area FAN UNIT wind pressure - Tool Setting	Tool Specific	270
				Section 2. SYSTEM(FAB) - CSB/HCSB - HCSB transfer area FAN UNIT wind pressure - Tolerance	Tool Specific	250 ~ 300
				Section 2. SYSTEM(FAB) - CSB/HCSB - HCSB transfer area FAN UNIT wind pressure (L/L Setting)	NA	
				Section 2. SYSTEM(FAB) - CSB/HCSB - HMDS Chemical EXH. (E13A) - Tolerance	110 ~ 200	100 ~ 250
				Section 2. SYSTEM(FAB) - CSB/HCSB - HMDS Chemical EXH. (E13A) - Remarks	NA	TARGET CFM 29.3
				Section 2. SYSTEM(FAB) - CSB/HCSB - Load Port Door TURN-IN Speed - Tool Setting	4.8	6.0
				Section 2. SYSTEM(FAB) - CSB/HCSB - Load Port Door TURN-IN Speed - Remarks	Set by Sub-Op display (Without FOUP)	Set by Sub-Op display (Without FOUP) Under normal system operations, the speed of the FIMS lifting axis reuires readjustment when exceeds ±1.0sec.
				Section 2. SYSTEM(FAB) - CSB/HCSB - Load Port Door TURN-OUT Speed - Remarks	Set by Sub-Op display (Without FOUP)	Set by Sub-Op display (Without FOUP) Under normal system operations, the speed of the FIMS lifting axis reuires readjustment when exceeds ±1.0sec.
				Section 2. SYSTEM(FAB) - PRB - SPIN Chemical(L)(R) EXH.(E1A,E1B) - Tolerance	150 or More	100 or More
				Section 2. SYSTEM(FAB) - PRB - SPIN Chemical(L)(R) EXH.(E1A,E1B) - Remarks	NA	TARGET CFM 28.3
				Section 2. SYSTEM(FAB) - PRB - RSV N2 Press - Tool Setting	0.1	0.05
				Section 2. SYSTEM(FAB) - PRA(L) area FAN UNIT wind pressure - Tool Setting	Tool Specific	650
				Section 2. SYSTEM(FAB) - PRA(L) area FAN UNIT wind pressure - Tolerance	Tool Specific	500 ~ 800
				Section 2. SYSTEM(FAB) - PRA(L) area FAN UNIT wind pressure (L/L Setting)	NA	SV-25
				Section 2. SYSTEM(FAB) - PRA(R) area FAN UNIT wind pressure - Tool Setting	NA	650
				Section 2. SYSTEM(FAB) - PRA(R) area FAN UNIT wind pressure - Tolerance	NA	500 ~ 800
				Section 2. SYSTEM(FAB) - PRA(R) area FAN UNIT wind pressure (L/L Setting)	NA	SV-25
				Section 3. SYSTEM(Sub-FAB) - COT Cabinet1 - N2 Source Secondary(NA1) Label name "HPN2" - Tool Setting	0.4	0.5
				Section 3. SYSTEM(Sub-FAB) - COT Cabinet1 - N2 Source Secondary(NA1) Label name "HPN2" - Tolerance	0.4 or More	0.5 ~ 0.55
				Section 3. SYSTEM(Sub-FAB) - COT Cabinet1 - N2 Source Secondary(NA1) Label name "UN2" - Tool Setting	0.4	0.5
				Section 3. SYSTEM(Sub-FAB) - COT Cabinet1 - N2 Source Secondary(NA1) Label name "UN2" - Tolerance	0.4 or More	0.5 ~ 0.55
				Section 3. SYSTEM(Sub-FAB) - COT Cabinet1 - Solvent PCS(1,2,3,4) Drive - Tool Setting	0.25	0.3
				Section 3. SYSTEM(Sub-FAB) - COT Cabinet1 - Solvent PCS(1,2,3,4) Drive - Tolerance	0.1 ~ 0.3	0.25 ~ 0.35
				Section 3. SYSTEM(Sub-FAB) - COT Cabinet1 - Solvent Supply System Line Valve Drive - Tool Setting	0.2	0.25
				Section 3. SYSTEM(Sub-FAB) - COT Cabinet1 - Solvent Supply System Line Valve Drive - Tolerance	---	0.24 ~ 0.26
				Section 3. SYSTEM(Sub-FAB) - System THC - Condensation pressure - Tolerance	0.6~	0.60 ~ 0.80
				Section 7. OVEN - CGCH - CGCH Cover EXH. For Deck13(E8B) - Tool Setting	490	330
				Section 7. OVEN - CGCH - CGCH Cover EXH. For Deck13(E8B) - Tolerance	450 ~ 530	300 ~ 360
				Section 7. OVEN - CGCH - CGCH Cover EXH. For Deck13 U/L Setting (E8B) - Tool Setting	570	370
				Section 7. OVEN - CGCH - CGCH Cover EXH. For Deck13 L/L Setting (E8B) - Tool Setting	410	290
				Section 7. OVEN - CGCH - CGCH Cover EXH. For Deck14(E8B) - Tool Setting	510	350
				Section 7. OVEN - CGCH - CGCH Cover EXH. For Deck14(E8B) - Tolerance	470 ~ 550	320 ~ 380
				Section 7. OVEN - CGCH - CGCH Cover EXH. For Deck14 U/L Setting (E8B) - Tool Setting	590	390
				Section 7. OVEN - CGCH - CGCH Cover EXH. For Deck14 L/L Setting (E8B) - Tool Setting	430	310
				Section 7. OVEN - CGCH - CGCH Cover EXH. For Deck15(E8B) - Tool Setting	200	130
				Section 7. OVEN - CGCH - CGCH Cover EXH. For Deck15(E8B) - Tolerance	180 ~ 220	100 ~ 160
				Section 7. OVEN - CGCH - CGCH Cover EXH. For Deck15 U/L Setting (E8B) - Tool Setting	240	170
				Section 7. OVEN - CGCH - CGCH Cover EXH. For Deck15 L/L Setting (E8B) - Tool Setting	160	90
				Section 7. OVEN - CGCH - CGCH Cover EXH. For Deck16(E8B) - Tool Setting	230	140
				Section 7. OVEN - CGCH - CGCH Cover EXH. For Deck16(E8B) - Tolerance	210 ~ 250	110 ~ 170
				Section 7. OVEN - CGCH - CGCH Cover EXH. For Deck16 U/L Setting (E8B) - Tool Setting	270	180
				Section 7. OVEN - CGCH - CGCH Cover EXH. For Deck16 L/L Setting (E8B) - Tool Setting	190	100
				Section 7. OVEN - CGCH - CGCH Individual Chamber Exhaust Pressure - Tool Setting	25.7 (100ml/min)	16 (80L/min)
				Section 7. OVEN - CGCH - CGCH Individual Chamber Exhaust Pressure - Tolerance	20.8 ~ 31.1	13.0 ~ 19.0 (71.1 ~ 86.1L/min)
				Section 7. OVEN - CGCH - CGCH Individual Chamber Exhaust Pressure - TEL Std.	12.6±1.0 (70ml/min)	12.6±1.0 (70L/min)
				Section 7. OVEN - CGCH - CGCH Individual Chamber Exhaust Pressure U/L Setting - Tool Setting	31.1	19.0 (86.1L/min)
				Section 7. OVEN - CGCH - CGCH Individual Chamber Exhaust Pressure L/L Setting - Tool Setting	20.8	13.0 (71.1L/min)

Hardware FPD Revision History

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Date	Rev.	Approval		Location	Old	New
		Intel	TEL			
07/27/2020	1.03	K.Proctor	Red	Section 2. SYSTEM(FAB) - FEX - FEX Chemical EXH.(E15C,E15D) - Tolerance	25 or More	25 ~ 300
				Section 2. SYSTEM(FAB) - PRB - SPIN Chemical(L)(R) EXH.(E1A,E1B) - Tolerance	100 or More	100 ~ 300
				Section 2. SYSTEM(FAB) - PRB - Description of Setting - RSV N2 Press	RSV N2 Press	Resist Tank Pressure
				Section 2. SYSTEM(FAB) - PRB - Flow rate of cooling water from factory(C5A,C6A) (COOL ARM: PCW) - Tool Setting	Tool Specific (BARC : 22.2)	TBF : 23.0 TAP/TNP/TAF : 20.0 TAW : 22.0
				Section 2. SYSTEM(FAB) - PRB - Flow rate of cooling water from factory(C5A,C6A) (COOL ARM: PCW) - Tolerance	---	TBF : 22.0 ~ 24.0 TAP/TNP/TAF : 19.0 ~ 21.0 TAW : 21.0 ~ 23.0
				Section 2. SYSTEM(FAB) - PRB - SPIN CUP EXH. (E3A,E4A,E5A,E6A) - Tolerance	340 ~ 460	340 ~ 380
				Section 2. SYSTEM(FAB) - PRB - SPIN CUP EXH. (E3A,E4A,E5A,E6A) - TEL Std.	410±50	360±50
				Section 2. SYSTEM(FAB) - PRB - SPIN CUP EXH. (E3B,E4B,E5B,E6B) - Tolerance	200 ~ 250	180 ~ 220
				Section 2. SYSTEM(FAB) - PRB - SPIN CUP EXH. (E3B,E4B,E5B,E6B) - TEL Std.	225±25	200±25
				Section 2. SYSTEM(FAB) - PRB - CADH - Vaporize CADH - Tolerance	---	0.1 ~ 0.12
				Section 2. SYSTEM(FAB) - PRB - CADH - Vaporize CADH - TEL Std.	0.01±0.00	0.1±0.00
				Section 2. SYSTEM(FAB) - PRB - CADH - Chamber Purge CADH - Tolerance	---	0.04 ~ 0.05
				Section 2. SYSTEM(FAB) - PRB - CADH - Ejector Chamber EXH. Setting - Tolerance	0.46 ~ 0.48	4.6 ~ 4.8
				Section 2. SYSTEM(FAB) - PRB - CADH - Ejector Chamber EXH. Setting (U/L Settingh) - TEL Std.	4.7±0.1	5.5
				Section 2. SYSTEM(FAB) - PRB - CADH - Ejector Chamber EXH. Setting (L/L Settingh) - TEL Std.	4.7±0.1	3.9
				Section 2. SYSTEM(FAB) - PRB - CADH - CADH Ring Purge - Tool Setting	Tool Specific (BARC : 88.0)	TBF : 88.0 TAP/TNP/TAF : Lower 88.0/Upper 44.0 TAW : 44.0
				Section 2. SYSTEM(FAB) - PRB - CADH - CADH Ring Purge (U/L Setting) - Tool Setting	NA	TBF : 104.0 TAP/TNP/TAF : Lower 104.0/Upper 52.0 TAW : 52.0
				Section 2. SYSTEM(FAB) - PRB - CADH - CADH Ring Purge (L/L Setting) - Tool Setting	NA	TBF: 72.0 TAP/TNP/TAF : Lower 72.0/Upper 36.0 TAW : 36.0
				Section 3. SYSTEM(Sub-FAB) - System THC - THC Description of Setting - Utility Supply (DIW)	Utility Supply (DIW)	D.I.WATER.P(THC)
				Section 3. SYSTEM(Sub-FAB) - System THC - THC Description of Setting - Utility Supply (PCW)	Utility Supply (PCW)	P.C.WATER.P(THC)
				Section 3. SYSTEM(Sub-FAB) - System THC - Chiller Description of Setting - Utility Supply (PCW)	Utility Supply (PCW)	P.C.WATER.P(CHR)
				Section 9. Sensor Setting - AM-125A - Object - Positive Pressure	Positive Pressure	HCSB Positive Pressure
				Add item for Imm tool	---	---
				Section 2. SYSTEM(FAB) - HCSB - HCSB Chemical EXH.(E15A & E15B) - Tolerance	100 or More	25 ~ 280
				Section 2. SYSTEM(FAB) - HCSB - HCSB Chemical EXH.(E15A & E15B) - Remark	NA	TARGET CFM E15A is 29.0 E15B is 18.4
09/16/2020	1.04	K.Proctor	Red	Section 2. SYSTEM(FAB) - PRB - CADH - CADH Ring Purge Pressure - Tool Setting	NA	TBF : 0.35
				Section 2. SYSTEM(FAB) - PRB - CADH - CADH Ring Purge Pressure - Tolerance	NA	TBF : 0.25 ~ 0.45
				Section 2. SYSTEM(FAB) - PRB - CADH - CADH Ring Purge Pressure - TEL Std.	NA	---
				Section 2. SYSTEM(FAB) - PRB - CADH - CADH Ring Purge Pressure - Remark	NA	As reference
				Section 4. BCT-COT-ITC - PRB - BCT - Knife Edge Height - Tolerance	2.0 ~ 3.0	-2.3 ~ -2.7
				Section 4. BCT-COT-ITC - PRB - BCT - Knife Edge Height - TEL Std.	2.5±0.5	-2.5±0.5
10/23/2020	1.05	K.Proctor	Red	Section 1. Cover - Software version	500.0.57.0	500.0.59.100
				Section 1. Cover - Sub Operation Panel version	5.32.10	5.32.11
				Section 2. SYSTEM(FAB) - PRB - SYSTEM - PRA(L) area FAN UNIT wind pressure - Remark	Adjustment based on the positive pressure of the block alone.	Adjustment based on the positive pressure of the block alone. PRA-L and PRA-R FFU to be within 20 Pa
				Section 2. SYSTEM(FAB) - PRB - SYSTEM - PRA(R) area FAN UNIT wind pressure - Remark	Adjustment based on the positive pressure of the block alone.	Adjustment based on the positive pressure of the block alone. PRA-L and PRA-R FFU to be within 20 Pa
				Section 2. SYSTEM(FAB) - PRB - BCT TBF Deck13 Drain Case Cleaning + Resist individual Drain Manifold Clean (Dispense Rate)	NA	Tool Setting : 350ml/min Tolerance : 325 ~ 375ml/min TEL Std. : 350ml/min
				Section 2. SYSTEM(FAB) - PRB - COT TAP/TNP/TAF Deck11 Drain Case Cleaning + Resist individual Drain Manifold Clean (Dispense Rate)	NA	Tool Setting : 300ml/min Tolerance : 275 ~ 325ml/min TEL Std. : 350ml/min
				Section 2. SYSTEM(FAB) - PRB - ITC TAP/TNP/TAF Deck11 Drain Case Cleaning + Resist individual Drain Manifold Clean (Dispense Rate)	NA	Tool Setting : 275ml/min Tolerance : 250 ~ 300ml/min TEL Std. : 350ml/min
				Section 2. SYSTEM(FAB) - PRB - COT TAW Deck12 Drain Case Cleaning + Resist individual Drain Manifold Clean (Dispense Rate)	NA	Tool Setting : 300ml/min Tolerance : 275 ~ 325ml/min TEL Std. : 350ml/min
				Section 2. SYSTEM(FAB) - PRB - ITC TAW Deck12 Drain Case Cleaning + Resist individual Drain Manifold Clean (Dispense Rate)	NA	Tool Setting : 275ml/min Tolerance : 250 ~ 300ml/min TEL Std. : 350ml/min

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Hardware FPD Revision History

Date	Rev.	Approval		Location	Old	New
		Intel	TEL			
10/23/2020	1.05	K.Proctor	Red	Section 3. SYSTEM(Sub-FAB) - External - DEV Cabinet DEV Rinse Nozzle(ADR) / MGP1 SUB DIW - Tool Setting	0.20	0.25
				Section 3. SYSTEM(Sub-FAB) - External - DEV Cabinet DEV Rinse Nozzle(ADR) / MGP1 SUB DIW - Tolerance	0.20~0.22	0.25~0.27
				Section 3. SYSTEM(Sub-FAB) - External - DEV Cabinet C.P.V for D.I. Water (1) - Tool Setting	0.15	0.20
				Section 3. SYSTEM(Sub-FAB) - External - DEV Cabinet C.P.V for D.I. Water (1) - Tolerance	0.14 ~ 0.16	0.19 ~ 0.21
10/30/2020	1.06	K.Proctor	Red	Section 2. SYSTEM(FAB) - HSCB - SCPL - Plate Temperature	Plate Temperature	Plate Temperature for pre BCT/COT/ITC modules
				Section 2. SYSTEM(FAB) - HSCB - SCPL - Plate Temperature for pre DEV/NTD modules	NA	Tool Setting : 23.0 Tolerance : 22.8 ~ 23.2 TEL Std. : SV±0.15 Remarks : Only IMM/EUV tools 14-31,14-32,15-31,15-32,16-31,16-32
				Section 2. SYSTEM(FAB) - PRB - ADEV - GP DEV (Dispense Rate) - Tool Setting	NA	Tool Setting : 600.0 Tolerance : 540 ~ 660 TEL Std. : 600.0 Remarks : Dynamic Setting
				Section 5. DEV-NTD - PRB - ANTD - NTD Rinse Nozzle Height - Remarks	NA	As reference
				Section 5. DEV-NTD - PRB - ANTD - N2 Nozzle Height - Remarks	NA	As reference
				Section 7. Oven - IFB - ICPL - Plate Vac.(w/ Wafer)	NA	Tool Setting : 1.5 Tolerance : 1.4 ~ 1.6 TEL Std. : 1.5±0.1
				Section 7. Oven - IFB - ICPL - Plate Vac. U/L Setting	NA	Tool Setting : 5.0 TEL Std. : 5.0
				Section 7. Oven - IFB - ICPL - Plate Vac. L/L Setting	NA	Tool Setting : 0.5 TEL Std. : 0.5
				Section 7. Oven - IFB - ICPL - Plate Gap Pin	NA	Tool Setting : 0.05 Tolerance : 0.045 ~ 0.05 TEL Std. : 0.05+0/-0.005
				Section 7. Oven - IFB - ICPL - Plate Pull/Push Pin	NA	Tool Setting : 0.50 Tolerance : 0.4 ~ 0.7 TEL Std. : 0.5+0.2/-0.1
				Section 7. Oven - IFB - ICPL - CP Surface ~ The End of 3-Pin(Up)	NA	Tool Setting : 19.0 Tolerance : 18.5 ~ 19.5 TEL Std. : 19.5±0.5 Remarks : 3-Pin is Up, For All Pins of 3-Pin.
				Section 7. Oven - IFB - ICPL - CP Surface ~ The End of 3-Pin(Down)	NA	Tool Setting : 1.0 Tolerance : 0.5 ~ 1.5 TEL Std. : 1.0±0.5 Remarks : 3-Pin is Down, For All Pins of 3-Pin.
				Section 7. Oven - IFB - ICPL - Plate Level	NA	Tool Setting : 0.0 Tolerance : -0.05 ~ 0.05 TEL Std. : 0.0±0.05
				Section 7. Oven - IFB - ICPL - 3-Pin Level	NA	Tool Setting : 0.0 Tolerance : -0.05 ~ 0.05 TEL Std. : 0.0±0.05
12/04/2020	1.07	K.Proctor	Red	1.Overview (Configuration) - 1.3 EUV Tool Configuration [TAW] - 30-11~15 Module Name	SRS	BST+
				2.SYSTEM (FAB) - PRB - SYSTEM Flow rate of cooling water from factory(C5A,C6A) (COOL ARM: PCW)* - Tool Setting	NA	TBF : 11.0
				2.SYSTEM (FAB) - PRB - SYSTEM Flow rate of cooling water from factory(C5A,C6A) (COOL ARM: PCW)* - Tolerance	NA	TBF : 10.0 ~ 12.0
				2.SYSTEM (FAB) - PRB - SYSTEM Flow rate of cooling water from factory(C5A,C6A) (COOL ARM: PCW)* - TEL Std.	NA	SV±1.0
				2.SYSTEM (Sub-FAB) - System THC - STHC CHILLER FLOW RATE SETTING CHART For TBF CGCH and HMDS Tank TCW modified tool	NA	Add
				2.SYSTEM (Sub-FAB) - System THC - STHC CHILLER FLOW RATE SETTING CHART For TAP/TAF/TNP/TAW HMDS Tank TCW modified tool	NA	Add
				Add item for EUV tool	---	---

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		Intel	TEL			
02/05/2021	1.08	K.Proctor	Red	1.Overview (Configuration) - FEX module number and name	---	Add
				2.SYSTEM (FAB) - CSB/HCSB - CADH - HMDS Buffer Tank Temperature	Tolerance : 21.5 ~ 22.5 Remark : Control by Facility	Tolerance : 21.5 ~ 22.5 *21.7 ~ 22.3 Remark : Control by Facility *Cpntrol by STHC(TCW modify done tool)
				2.SYSTEM (FAB) - PRB - COT/BCT/ITC - SPIN wind speed	Tool Setting : Tool Specific Tolerance : ---	Tool Setting : 0.2 Tolerance : 0.14 ~ 0.26
				2.SYSTEM (Sub-FAB) - COT Cabinet - Solvent PCS(1,2,3,4) Drive	Tool Setting : 0.3 Tolerance : 0.25 ~ 0.35 Remark : Static Pressure *Imm no PCS(4) / EUV no PCS(3) and PCS(4)	Tool Setting : 0.25 Tolerance : 0.20 ~ 0.30 Remark : Static Pressure *Imm no PCS(4) / EUV no PCS(3) and PCS(4) *EBR/Bevel and Back Rinse/Exh. Duct clean/Drain Case clean line CPV should bypass.
				2.SYSTEM (Sub-FAB) - COT Cabinet - Solvent PCS(1,2,3,4) Fill Pressure - Remark	Static Pressure	Dynamic Pressure
				2.SYSTEM (Sub-FAB) - COT Cabinet - PCS(1,2,3,4) VAC. Setting Sol.(1,2) - Remark	Static Pressure	Dynamic Pressure
				2.SYSTEM (Sub-FAB) - COT Cabinet - Solvent Supply System IFF-S Control box P_3 setting	Tool Setting : 0.25 Tolerance : 0.20 ~ 0.25 Remark : P_3 is 0.05 less than PCS drive pressure.	Tool Setting : 0.20 Tolerance : 0.18 ~ 0.22 Remark : P_3 is 0.05 less than PCS drive pressure. *EBR/Bevel and Back Rinse/Exh. Duct clean/Drain Case clean line CPV should bypass.
				2.SYSTEM (Sub-FAB) - COT Cabinet - Solvent Supply System Line Valve Drive	Tool Setting : 0.25 Tolerance : 0.24 ~ 0.26 Remark : Dynamic Pressure SV=PCS drive pressure - 0.05 (MPa)	Tool Setting : 0.20 Tolerance : 0.19 ~ 0.21 Remark : Dynamic Pressure SV=PCS drive pressure - 0.05 (MPa) *EBR/Bevel and Back Rinse/Exh. Duct clean/Drain Case clean line CPV should bypass. *Apply for Nozzle/Bath clean line.
				2.SYSTEM (Sub-FAB) - COT Cabinet2 - Solvent Supply System IFF-S Control box P_3 setting	Tool Setting : 0.25 Tolerance : 0.20 ~ 0.25 Remark : P_3 is 0.05 less than PCS drive pressure.	Tool Setting : 0.20 Tolerance : 0.18 ~ 0.22 Remark : P_3 is 0.05 less than PCS drive pressure. *Back Rinse line CPV should bypass.
				2.SYSTEM (Sub-FAB) - COT Cabinet2 - NTD Solvent Supply System Line Valve Drive	Tool Setting : 0.2 Tolerance : 0.19 ~ 0.21 TEL Std : SV+0/-0.05	Delete
				2.SYSTEM (Sub-FAB) - DEV Cabinet - DIW C.P.V pressure	C.P.V for D.I. Water(1)	DIW Line Drive
				2.SYSTEM (Sub-FAB) - DEV Cabinet - SRS C.P.V pressure	C.P.V for SRS	SRS Line Drive
				2.SYSTEM (Sub-FAB) - DEV Cabinet - PIR C.P.V pressure	C.P.V for PIR	PIR Line Drive
				2.SYSTEM (Sub-FAB) - DEV Cabinet - BST Rinse	NA	Tool Setting : 0.20 Tolerance : 0.20 ~ 0.22 TEL Std. : 0.10 ~ 0.30
				2.SYSTEM (Sub-FAB) - DEV Cabinet - BST Brush Rinse	NA	Tool Setting : 0.20 Tolerance : 0.20 ~ 0.22 TEL Std. : 0.10 ~ 0.30
				2.SYSTEM (Sub-FAB) - DEV Cabinet - BST C.P.V pressure	NA	Tool Setting : 0.15 Tolerance : 0.14 ~ 0.16 TEL Std. : 0.15
				6.PIR-SRS-BST - BST+ - Flow rate of the backside air nozzle	Tool Setting : Tool Specific Tolerance : Tool Specific TEL Std : 80.0±1.0	Deleted (Change to Backside air nozzle Flow Setting)
				6.PIR-SRS-BST - BST+ - Backside air nozzle Flow Setting	NA	Tool Setting : 80.0 Tolerance : 79.0 ~ 81.0 TEL Std : 80.0±1.0
				6.PIR-SRS-BST - BST+ - Backside air nozzle Pressure Setting	NA	Tool Setting : Module Specific Tolerance : Module Specific TEL Std : ---
				6.PIR-SRS-BST - BST+ - Flow rate of the backside air nozzle U/L Setting	Tool Setting : Tool Specific Tolerance : Tool Specific TEL Std : 90.0	Deleted (Change to Backside air nozzle Flow Setting U/L Setting)
				6.PIR-SRS-BST - BST+ - Backside air nozzle Pressure Setting U/L Setting	NA	Tool Setting : Module Specific Tolerance : Module Specific TEL Std : Module Specific
				6.PIR-SRS-BST - BST+ - Flow rate of the backside air nozzle L/L Setting	Tool Setting : Tool Specific Tolerance : Tool Specific TEL Std : 65.0	Deleted (Change to Backside air nozzle Flow Setting L/L Setting)
				6.PIR-SRS-BST - BST+ - Backside air nozzle Pressure Setting L/L Setting	NA	Tool Setting : Module Specific Tolerance : Module Specific TEL Std : Module Specific

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		Intel	TEL			
02/05/2021	1.08	K.Proctor	Red	6.PIR-SRS-BST - BST+ - Flow rate of the wafer edge air nozzle	Tool Setting : Tool Specific Tolerance : Tool Specific TEL Std : 12.0±0.2	Deleted (Change to Wafer edge air nozzle Flow Setting)
				6.PIR-SRS-BST - BST+ - Wafer edge air nozzle Flow Setting	NA	Tool Setting : 12.0 Tolerance : 11.8 ~ 12.2 TEL Std : 12.0±0.2
				6.PIR-SRS-BST - BST+ - Wafer edge air nozzle Pressure Setting	NA	Tool Setting : Module Specific Tolerance : Module Specific TEL Std : ---
				6.PIR-SRS-BST - BST+ - Flow rate of the wafer edge air nozzle U/L Setting	Tool Setting : Tool Specific Tolerance : Tool Specific TEL Std : 13.0	Deleted (Change to Wafer edge air nozzle Pressure U/L Setting)
				6.PIR-SRS-BST - BST+ - Wafer edge air nozzle Pressure U/L Setting	NA	Tool Setting : Module Specific Tolerance : Module Specific TEL Std : Module Specific
				6.PIR-SRS-BST - BST+ - Flow rate of the wafer edge air nozzle L/L Setting	Tool Setting : Tool Specific Tolerance : Tool Specific TEL Std : 9.0	Deleted (Change to Wafer edge air nozzle Pressure L/L Setting)
				6.PIR-SRS-BST - BST+ - Wafer edge air nozzle Pressure L/L Setting	NA	Tool Setting : Module Specific Tolerance : Module Specific TEL Std : Module Specific
				7.Oven - CPHP - CPHP Chamber (R) EXH. (E9B)	Tool Setting : 110 Tolerance : 108 ~ 112 TEL Std : 110±2	Tool Setting : 120 Tolerance : 100 ~ 140 TEL Std : ---
				7.Oven - CPHP - CPHP Chamber (R) EXH U/L Setting (E9B)	Tool Setting : 125 Tolerance : --- TEL Std : 125	Tool Setting : 145 Tolerance : --- TEL Std : ---
				7.Oven - CPHP - CPHP Chamber (R) EXH L/L Setting (E9B)	Tool Setting : 95 Tolerance : --- TEL Std : 95	Tool Setting : 95 Tolerance : --- TEL Std : ---
				7.Oven - CPHP - CPHP Chamber (L) EXH. (E9A)	Tool Setting : 110 Tolerance : 108 ~ 112 TEL Std : 110±2	Tool Setting : 120 Tolerance : 100 ~ 140 TEL Std : ---
				7.Oven - CPHP - CPHP Chamber (L) EXH U/L Setting (E9A)	Tool Setting : 125 Tolerance : --- TEL Std : 125	Tool Setting : 145 Tolerance : --- TEL Std : ---
				7.Oven - CPHP - CPHP Chamber (L) EXH L/L Setting (E9A)	Tool Setting : 95 Tolerance : --- TEL Std : 95	Tool Setting : 95 Tolerance : --- TEL Std : ---
				7.Oven - CPHP - Individual Chamber Exhaust flowrate	Tool Setting : 4.0 Unit : L/min Tolerance : 3.8 ~ 4.2 TEL Std : 4±0.2	Tool Setting : 9.0 Unit : Pa Tolerance : 8.0 ~ 10.0 TEL Std : 9.0±1.0
				7.Oven - CPHP - Individual Chamber Exhaust flowrate U/L Setting	Tool Setting : 4.5 Unit : L/min TEL Std : 4.5	Tool Setting : 11.3 Unit : Pa TEL Std : 11.3
				7.Oven - CPHP - Individual Chamber Exhaust flowrate L/L Setting	Tool Setting : 3.5 Unit : L/min TEL Std : 3.5	Tool Setting : 7.4 Unit : Pa TEL Std : 7.4
03/01/2021	1.09	K. Proctor	C.Gertz	1. Overview (Configuration) 2. System (FAB) - PRB*** 3. System (Sub-Fab) - STHC CHILLER FLOW RATE SETTING CHART 7. Oven - CXHN, CVVP	ADD	Initial Oven SA [PBR] Several Additions

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Hardware FPD Revision History

Date	Rev.	Approval		Location	Old	New
		Intel	TEL			
03/26/2021	1.10	K. Proctor	Red	2. System (FAB) - HCSB - CADH - HMDS Chemical EXH.(E13A) - Tolerance	100 ~ 250Pa	20 ~ 250Pa
				2. System (FAB) - HCSB - CADH - HMDS Chemical EXH. (L/L Setting) (E13A) - Tool Setting	100Pa	15Pa
				2. System (FAB) - PRB - BCT/COT/ITC - SPIN CUP EXH. - Remarks	EPC damper must be held Open and use EXH BKM.	Add specific value when system recipe transferd
				2. System (FAB) - PRB - ADEV - SPIN CUP EXH.	Tolerance : 470Pa TEL Std. : 470Pa	Tolerance : 420~520Pa TEL Std. : 470±50PaPa
				2. System (FAB) - PRB - ANTD - SPIN CUP EXH.	Tool Setting : 210Pa Tolerance : 210~310Pa TEL Std. : 260±50Pa	Tool Setting : 450Pa Tolerance : 400~500Pa TEL Std. : 450±50Pa
				2. System (FAB) - IFB - BST+ - Positive pressure	NA	Tool Setting : 0.1Pa Tolerance : 0.1~0.2Pa TEL Std. : 0.1+0.1/-0.0Pa
				2. System (FAB) - IFB - BST+ - BST Front area FAN UNIT wind pressure	NA	Tool Setting : Tool Specific Tolerance : --- TEL Std. : Tool Specific
				7. Oven - PRB - SCPL - Plate Vac.(w/ Wafer) - TEL Std.	1.5±0.1	1.5±0.2/-0.1
				9. Sensor Setting - E3X-MD36T-T Sensor - RSV Tank(L,LL) - 5-dP	Income Light Amount/Threshold Value	Income Light Amount/Threshold Value=1600
				9. Sensor Setting - E3X-MD36T-T Sensor - RSV Tank(H) - 5-dP	Income Light Amount/Threshold Value	Income Light Amount/Threshold Value=1700
04/28/2021	1.11	K. Proctor	Red	1. Overview (Configuration) - XLD and XULD swap	1-51 : XLD 1-52 : XLD 1-53 : XULD 1-54 : XULD	1-51 : XULD 1-52 : XULD 1-53 : XLD 1-54 : XLD
				2.SYSTEM (FAB) - PRB - CADH - Chamber Purge CADH	Tool Setting : 0.04MPa Tolerance : 0.04 ~ 0.05MPa	Tool Setting : 0.1MPa Tolerance : 0.1 ~ 0.12MPa
				4.BCT / COT / ITC - PRB - COT/BCT/ITC - Shared Auto Damper Close Speed	Tool Setting : 0.4sec Tolerance : 0.3 ~ 0.5sec	Tool Setting : 0.3sec Tolerance : 0.2 ~ 0.3sec
05/27/2021	1.12	K. Proctor	Kono	2.SYSTEM (FAB) - PRB - SYSTM - Flow rate of cooling water from factory(C5A,C6A) - (COOL ARM: PCW) (L/L Setting)	NA	TBF : 9.0 TAP/TAF/TNP: 17.0 TAW : 15.0
				2.SYSTEM (FAB) - PRB - ADEV - SPIN CUP EXH - (E4A,E5A,E6A)	Tool Setting : 470Pa Tolerance : 420 ~ 520Pa	Tool Setting : --- Tolerance : --- no monito on the tool
				2.SYSTEM (FAB) - PRB - ADEV - SPIN CUP EXH (L/L Setting) - (E4A,E5A,E6A)	Tool Setting : 20Pa Tolerance : ---Pa	Tool Setting : --- Tolerance : --- no monito on the tool
				3.SYSTEM (Sub-FAB) - External - COT Cabinet - N2 Source Primary(NA1) Label name "HPN2"	Remark : Static Pressure	Remark : Static Pressure, located back side cab
				3.SYSTEM (Sub-FAB) - External - COT Cabinet - N2 Source Primary(NA1) Label name "HPN2(N-1)"	Tool Setting : 0.5MPa Tolerance : 0.5 ~0.55 Remark : Static Pressure	Tool Setting : 0.5MPa Tolerance : 0.5 ~0.55 Remark: Static Pressure, BARC only
				3.SYSTEM (Sub-FAB) - External - COT Cabinet - N2 Source Primary(NA1) Label name "HPN2"	Add	Tool Setting : 0.5MPa Tolerance : 0.5 ~0.55 Remark : Static pressure, Imm/EUV only
				3.SYSTEM (Sub-FAB) - External - COT Cabinet - N2 Source Primary(NA1) Label name "HPN2(N-8)"	N2 Source Primary(NA8) Label name "HPN2(N-8)" Tool setting : 0.4MPa Tolerance : 0.4 or more Remark : Static Pressure	N2 Source Primary(NA1) Label name "HPN2(N-8)" Tool setting : 0.4MPa Tolerance : 0.4 or more Remark: Static Pressure, BARC only
				3.SYSTEM (Sub-FAB) - External - COT Cabinet - N2 Source Primary(NA8) Label name "UN2"	N2 Source Primary(NA1) Label name "UN2" Tool setting : 0.5MPa Tolerance : 0.5 ~ 0.55 Remark: Static Pressure	N2 Source Primary(NA8) Label name "UN2" Tool setting : 0.4MPa Tolerance : 0.4 or more Remark: Static Pressure
				3.SYSTEM (Sub-FAB) - External - STHC CHILLER FLOW RATE SETTING CHART - TBF before TCW modification	Ch1=2.0L/min, Ch2=2.0L/min, Ch3=4.0L/min Ch4-1=25.0L/min, Ch4-2=11.0L/min Ch5-1=49.0L/min, Ch5-2=13.0L/min	Delete

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Hardware FPD Revision History

Date	Rev.	Approval		Location	Old	New
		Intel	TEL			
06/30/2021	1.13	K. Proctor	Red	1. Overview (Configuration) - IMM/EUV	---	Add 9CPHPs and BST modify config Add TAJ config
				3.SYSTEM (Sub-FAB) - COT Cabinet - External - COT Cabinet - Solvent Supply System IFF-S Control box P_1 setting	Tool Setting : 0.10 Tolerance : 0.08 ~ 0.12	Tool Setting : 0.13 Tolerance : 0.10 ~ 0.16
				3.SYSTEM (Sub-FAB) - COT Cabinet - External - COT Cabinet - Solvent Supply System IFF-S Control box P_2 setting	Tool Setting : 0.14 Tolerance : 0.12 ~ 0.16	Tool Setting : 0.16 Tolerance : 0.13 ~ 0.19
				3.SYSTEM (Sub-FAB) - COT Cabinet - External - COT Cabinet - Solvent Supply System IFF-S Control box P_3 setting	Tool Setting : 0.20 Tolerance : 0.18 ~ 0.22	Tool Setting : 0.21 Tolerance : 0.18 ~ 0.24
				3.SYSTEM (Sub-FAB) - COT Cabinet2 Only Imm - External - COT Cabinet2 - Solvent Supply System IFF-S Control box P_1 setting	Tool Setting : 0.10 Tolerance : 0.08 ~ 0.12	Tool Setting : 0.13 Tolerance : 0.10 ~ 0.16
				3.SYSTEM (Sub-FAB) - COT Cabinet2 Only Imm - External - COT Cabinet2 - Solvent Supply System IFF-S Control box P_2 setting	Tool Setting : 0.14 Tolerance : 0.12 ~ 0.16	Tool Setting : 0.16 Tolerance : 0.13 ~ 0.19
				3.SYSTEM (Sub-FAB) - COT Cabinet2 Only Imm - External - COT Cabinet2 - Solvent Supply System IFF-S Control box P_3 setting	Tool Setting : 0.20 Tolerance : 0.18 ~ 0.22	Tool Setting : 0.21 Tolerance : 0.18 ~ 0.24
				3.SYSTEM (Sub-FAB) - DEV Cabinet Only Imm/EUV - External - DEV Cabinet - DEV Back Rinse Nozzle	Tool Setting : 0.20 Tolerance : 0.20 ~ 0.22	Tool Setting : 0.25 Tolerance : 0.25 ~ 0.27
				3.SYSTEM (Sub-FAB) - DEV Cabinet Only Imm/EUV - External - DEV Cabinet - DIW Line Drive	Tool Setting : 0.20 Tolerance : 0.19 ~ 0.21	Tool Setting : 0.25 Tolerance : 0.23 ~ 0.27
				3.SYSTEM (Sub-FAB) - DEV Cabinet Only Imm/EUV - External - DEV Cabinet - SRS Line Drive	Tool Setting : 0.15 Tolerance : 0.14 ~ 0.16	Tool Setting : 0.20 Tolerance : 0.18 ~ 0.22
				3.SYSTEM (Sub-FAB) - DEV Cabinet Only Imm/EUV - External - DEV Cabinet - PIR Line Drive	Tool Setting : 0.15 Tolerance : 0.14 ~ 0.16	Tool Setting : 0.20 Tolerance : 0.18 ~ 0.22
				3.SYSTEM (Sub-FAB) - DEV Cabinet Only Imm/EUV - External - DEV Cabinet - BST Line Drive	Tool Setting : 0.15 Tolerance : 0.14 ~ 0.16	Tool Setting : 0.22 Tolerance : 0.20 ~ 0.24
				3.SYSTEM (Sub-FAB) - STHC CHILLER FLOW RATE SETTING CHART - IMM/EUV	---	Deleted before TCW modify setting Deleted before 9CPHPs modify setting Add after 9CPHPs setting
				7.Oven - PRB - CGCH - Ring Shutter(L/R) Up Speed - Remark	---	L/R must match within 0.1s
				7.Oven - PRB - CGCH - Ring Shutter(L/R) Down Speed - Remark	---	L/R must match within 0.1s
				7.Oven - PRB - CADH - Chamber Open Speed L/R - Remark	---	L/R must match within 0.1s
				7.Oven - PRB - CADH - Chamber Close Speed L/R - Remark	---	L/R must match within 0.1s
				7.Oven - PRB - CPHP - Chamber-L/R OPEN / CLOSED - Remark	---	L/R must match within 0.1s
08/10/2021	1.14	K. Proctor	Red	1. Overview (Configuration) - BARC	Only TBF config present	Add TBFna//TBFlt/TBFcn Config
				1. Overview (Configuration) - EUV	TAJ is same config with TAW(BST)	Separated the TAW and TAJ config(SRS)
				2.SYSTEM (FAB) - PRB - ANTD - SPIN CUP EXH (E4B,E5B,E6B)	Tool Setting : 400 Tolerance : 400 ~ 500 TEL Std. : 450±50	Tool Setting : 425 Tolerance : 350 ~ 500 TEL Std. : 425±75
				3.SYSTEM (Sub-FAB) - COT Cabinet2 Only Imm/EUV - External - COT Cabinet2 - NTD Rinse PCS VAC. Setting	Tolerance: -50.0 ~ -40.0	Tolerance: -60.0 ~ -70.0
				3.SYSTEM (Sub-FAB) - COT Cabinet2 Only Imm/EUV - External - COT Cabinet2 - NTD Rinse PCS VAC. U/L Setting	Tool Setting: -29.0	Tool Setting: -49.0
				3.SYSTEM (Sub-FAB) - DEV Cabinet Only Imm/EUV - External - DEV Cabinet - DEV Rinse Nozzle(ADR) / MGP1 SUB DIW	Tool Setting : 0.25 Tolerance : 0.25 ~ 0.27	Tool Setting : 0.30 Tolerance : 0.30 ~ 0.32
				3.SYSTEM (Sub-FAB) - DEV Cabinet Only Imm/EUV - External - DEV Cabinet - DEV Back Rinse Nozzle	Tool Setting : 0.25 Tolerance : 0.25 ~ 0.27	Tool Setting : 0.30 Tolerance : 0.30 ~ 0.32
				3.SYSTEM (Sub-FAB) - DEV Cabinet Only Imm/EUV - External - DEV Cabinet - SRS Rinse / Back Rinse	Tool Setting : 0.20 Tolerance : 0.20 ~ 0.22	Tool Setting : 0.25 Tolerance : 0.25 ~ 0.27
				3.SYSTEM (Sub-FAB) - DEV Cabinet Only Imm/EUV - External - DEV Cabinet - PIR Rinse / Back Rinse	Tool Setting : 0.20 Tolerance : 0.20 ~ 0.22	Tool Setting : 0.25 Tolerance : 0.25 ~ 0.27
				3.SYSTEM (Sub-FAB) - DEV Cabinet Only Imm/EUV - External - DEV Cabinet - BST Rinse	Tool Setting : 0.20 Tolerance : 0.20 ~ 0.22	Tool Setting : 0.27 Tolerance : 0.27 ~ 0.29
				3.SYSTEM (Sub-FAB) - DEV Cabinet Only Imm/EUV - External - DEV Cabinet - BST Brush Rinse	Tool Setting : 0.20 Tolerance : 0.20 ~ 0.22	Tool Setting : 0.27 Tolerance : 0.27 ~ 0.29
				6.PIR* / SRS** / BST*** - IFB - BST+ - SPIN chuck top surface - PAD top surface	Tolerance: 0.5 ~ 1.5 TEL Std: 1.0±0.5	Tolerance: 1.0 ~ 2.0 TEL Std: 1.5±0.5
				9.Sensor Setting - DP100 Sensor / GC30 Sensor / PSE310M Sensor	Without BST related Sensor setting	Add BST related Sensor setting
09/13/2021	1.15	K. Proctor	Red	2.SYSTEM (FAB) - IFB** - Module	BST+	BST/BST+
				3.SYSTEM (Sub-FAB) - DEV Cabinet Only Imm / EUV - External - DEV Cabinet - BST Rinse / BST Brush Rinse - Remarks	NA	Supply Regulator for both BST / BST+
				3.SYSTEM (Sub-FAB) - DEV Cabinet Only Imm / EUV - External - DEV Cabinet - BST Line Drive - Remarks	NA	for both BST / BST+
				3.SYSTEM (Sub-FAB) - External - STHC CHILLER FLOW RATE SETTING CHART - Warning Detect / Warning Recover / Stop Detect / Stop Recover setting	NA	Add
				6.PIR* / SRS** / BST** / BST+*** - Module (Except Air Nozzle item)	BST+	BST/BST+
				9.Sensor Setting - GC30 Sensor	Without FFU Wind Pressure Sensor setting	Add FFU Wind Pressure Sensor setting

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Hardware FPD Revision History

Date	Rev.	Approval		Location	Old	New
		Intel	TEL			
11/08/2021	1.16	K. Proctor	Red	2.SYSTEM (FAB) - PRB - COT/BCT/ITC/ADEV/ANTD - SPIN wind speed	Tool Setting COT/BCT/ITC: 0.2m/sec ADEV/ANTC: Tool Specific Tolerance COT/BCT/ITC: 0.14 ~ 0.26m/sec ADEV/ANTC: Tool Specific	Tool Setting COT/BCT/ITC: 0.22m/sec ADEV/ANTC: 0.22m/sec Tolerance COT/BCT/ITC: 0.14 ~ 0.30m/sec ADEV/ANTC: 0.14 ~ 0.30m/sec
				2.SYSTEM (FAB) - PRB - CADH - CADH Ring Purge Pressure	Tool Setting TBF: 0.35MPa Tolerance TBF: 0.25 ~ 0.45MPa	Tool Setting Imm tool D12/13 and BARC tool (ie 88L/min lines) : 0.35 Imm tool D11 and EUV tool (ie 44L/min lines) : 0.20 Tolerance 0.15 ~ 0.45MPa
				2.SYSTEM (FAB) - PRB - CADH - CADH Ring Purge Flow Rate	Tool Setting TBF:88.0L/min TAP/TAF/TNP:88.0L/min(11/12deck),44L/min(13deck) Tolerance TBF:87~89L/min TAP/TAF/TNP:87~89L/min(11/12deck),43~45L/min(13deck)	Tool Setting BARC tool D13/14:88.0L/min,D15/16:88.0L/min Imm tool D11:44.0L/min,D12/13:88.0L/min EUV tool D12:44.0L/min,D13:44.0L/min Tolerance BARC tool D13/14:87.0~89.0L/min D15/16:87.0~89.0L/min Imm tool D11:43.0~45.0L/min D12/13:87.0~89.0L/min EUV tool D12:43.0~45.0L/min D13:43.0~45.0L/min
				2.SYSTEM (FAB) - PRB - CADH - CADH Ring Purge (U/L Setting)	TBF:104.0L/min TAP/TAF/TNP:104.0L/min(11/12deck),52.0L/min(13deck)	BARC tool D13/14:104.0L/min D15/16:104.0L/min Imm tool D11:52.0L/min D12/13:104.0L/min EUV tool D12:52.0L/min D13:52.0L/min
				2.SYSTEM (FAB) - PRB - CADH - CADH Ring Purge (L/L Setting)	TBF:72.0L/min TAP/TAF/TNP:72.0L/min(11/12deck),36.0L/min(13deck)	BARC tool D13/14:72.0L/min D15/16:72.0L/min Imm tool D11:36.0L/min D12/13:72.0L/min EUV tool D12:36.0L/min D13:36.0L/min
				2.SYSTEM (FAB) - IFB - PIR - PIR Front area FAN UNIT wind pressure	Description of Setting: PIR Front area FAN UNIT wind pressure Tool Setting: Tool Specific Tolerance: Tool Specific	Description of Setting: Wind pressure PIR Tool Setting: 45.0Pa Tolerance: 25.0 ~ 65.0Pa
				2.SYSTEM (FAB) - IFB - SRS - SRS Front area FAN UNIT wind pressure	Description of Setting: SRS Front area FAN UNIT wind pressure Tool Setting: Tool Specific Tolerance: Tool Specific	Description of Setting: Wind pressure SRS Tool Setting: 45.0Pa Tolerance: 25.0 ~ 65.0Pa
				2.SYSTEM (FAB) - IFB - BST/BST+ - BST Front area FAN UNIT wind pressure	Description of Setting: BST Front area FAN UNIT wind pressure Tool Setting: Tool Specific Tolerance: Tool Specific	Description of Setting: Wind pressure BST/BST+ Tool Setting: 45.0Pa Tolerance: 25.0 ~ 65.0Pa
				6.PIR* / SRS** / BST** / BST+*** - IFB - BST+ - Backside air nozzle Pressure Setting	Tool Setting: Module Specific Tolerance: Module Specific	Tool Setting: 30.0 ~ 60.0KPa Tolerance: 30.0 ~ 60.0KPa
				6.PIR* / SRS** / BST** / BST+*** - IFB - BST+ - Backside air nozzle Pressure Setting U/L Setting	Tool Setting: Module Specific Tolerance: Module Specific	Tool Setting: 35.0 ~ 65.0KPa Tolerance: 35.0 ~ 65.0KPa
				6.PIR* / SRS** / BST** / BST+*** - IFB - BST+ - Backside air nozzle Pressure Setting L/L Setting	Tool Setting: Module Specific Tolerance: Module Specific	Tool Setting: 18.0 ~ 38.0KPa Tolerance: 18.0 ~ 38.0KPa
				6.PIR* / SRS** / BST** / BST+*** - IFB - BST+ - Wafer edge air nozzle Pressure Setting	Tool Setting: Module Specific Tolerance: Module Specific	Tool Setting: 35.0 ~ 45.0KPa Tolerance: 35.0 ~ 45.0KPa
				6.PIR* / SRS** / BST** / BST+*** - IFB - BST+ - Wafer edge air nozzle Pressure U/L Setting	Tool Setting: Module Specific Tolerance: Module Specific	Tool Setting: 40.0 ~ 50.0KPa Tolerance: 40.0 ~ 50.0KPa
				6.PIR* / SRS** / BST** / BST+*** - IFB - BST+ - Wafer edge air nozzle Pressure L/L Setting	Tool Setting: Module Specific Tolerance: Module Specific	Tool Setting: 20.0 ~ 30.0KPa Tolerance: 20.0 ~ 30.0KPa
				7.Oven - ICPL - IFB - ICPL - CP Surface ~ The End of 3-Pin(Up) - TEL Std.	19.5±0.5mm	19.0±0.5mm

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Hardware FPD Revision History

Date	Rev.	Approval		Location	Old	New
		Intel	TEL			
12/17/2021	1.17	K. Proctor	Red	2.SYSTEM (FAB) - PRB - CADH - CADH Ring Purge	Imm tool D12/13 and BARC tool (ie 88L/min lines) : 0.35 Imm tool D11 and EUV tool (ie 44L/min lines) : 0.20	Imm tool D11/12 and BARC tool (ie 88L/min lines) : 0.35 Imm tool D13 and EUV tool (ie 44L/min lines) : 0.20
				2.SYSTEM (FAB) - PRB - CADH - CADH Ring Purge Flow Rate	Tool Setting Imm tool D11:44.0L/min,D12/13:88.0L/min Tolerance Imm tool D11:43.0–45.0L/min D12/13:87.0–89.0L/min	Tool Setting Imm tool D11/12:88.0L/min,D13:44.0L/min Tolerance Imm tool D11/12:87.0–89.0L/min D13:43.0–45.0L/min
				2.SYSTEM (FAB) - PRB - CADH - CADH Ring Purge (U/L Setting)	BARC tool D13/14:104.0L/min D15/16:104.0L/min Imm tool D11:52.0L/min D12/13:104.0L/min	BARC tool D13/14:100.0L/min D15/16:100.0L/min Imm tool D11/12:100.0L/min D13:52.0L/min
				2.SYSTEM (FAB) - PRB - CADH - CADH Ring Purge (L/L Setting)	Imm tool D11:36.0L/min D12/13:72.0L/min	Imm tool D11/12:72.0L/min D13:36.0L/min
				3.SYSTEM (Sub-FAB) - COT Cabinet1 - External - COT Cabinet - HMDS Canister Pressurization	Tool Setting: 0.11MPa Tolerance: 0.10 ~ 0.12MPa	Tool Setting: 0.08MPa Tolerance: 0.075 ~ 0.085MPa
				3.SYSTEM (Sub-FAB) - Ultrasonic flowmeter setting for "Liquid Kind" table	NA	Add
				4.BCT / COT / ITC - PRB - COT/BCT/ITC - Spin Chuck VAC.	TEL Std. -75±0.4	TEL Std. -75±4.0
				5.ADEV / ANTD - PRB - ADEV/ANTD - Spin Chuck VAC.	TEL Std. -75±0.4	TEL Std. -75±4.0
				6.PIR* / SRS** / BST** / BST+*** - IFB - PIR/SRS - Spin Chuck VAC.	TEL Std. -75±0.4	TEL Std. -75±4.0
				6.PIR* / SRS** / BST** / BST+*** - IFB - BST/BST+ - Spin Chuck VAC.	TEL Std. -75±0.4	TEL Std. -75±4.0
				6.PIR* / SRS** / BST** / BST+*** - IFB - BST+ - Brush base levelness -pad levelness - Remarks	Home and cleaning positions with PAD up.	Home and cleaning positions with PAD up. Direction of installing the level CSB Side is +X, SPIN Door Side is +Y.
				6.PIR* / SRS** / BST** / BST+*** - IFB - BST+ - IDR nozzle dispense position - Remarks	Bevel cleaning position (edge B). Distance from wafer periphery.	Bevel cleaning position (edge B). Distance from wafer periphery. Dispense STREAM should be 0.5mm from the edge.
				6.PIR* / SRS** / BST** / BST+*** - IFB - BST+ - Pad VAC. L/L Setting	-99.9KPa	-99.8KPa
				9.Sensor Setting - AM-125A Sensor - Condition Data	AYG:40 MAY:16	AYG:200 MAY:32
02/10/2022	1.18	K. Proctor	Red	10.High Altitude Setting Fab/Sub-Fab	NA	Add

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Hardware FPD Revision History

Date	Rev.	Approval		Location	Old	New
		Intel	TEL			
04/26/2022	1.19	K. Proctor	John V Red	1. Overview (Configuration) - 1.7 Oven S/A Tool Configuration [PBR]	16-11 CXHN 16-12 CXHN 16-13 CXHN 16-14 CXHN 16-15 CXHN	16-11 CVVP 16-12 CVVP 16-13 CVVP 16-14 CVVP 16-15 CVVP
				2. SYSTEM (FAB) - PRB (PBR Tools)	Tool Setting	Tool Setting
				Box EXH	Add	TEL Std. >150
				Box EXH Lower Limit	Added from Remark	110.0 Pa
				Flowmeter N2/Air Purge D15-D16	Add	60 (Air) L/min
				Flowmeter O2 Purge D15-D16	Add	0.0 L/min
				Flowmeter N2/Air Purge D13-D14	Add	60 (Air) L/min
				Flowmeter O2 Purge D13-D14	Add	0.0 L/min
				Flowmeter N2/Air Purge D11-D12	Add	60 (Air) L/min
				Flowmeter O2 Purge D11-D12	Add	0.0 L/min
				2. SYSTEM (FAB) - PRB (PBR402 Only)	Tool Setting	Tool Setting
				Box EXH	Add	TEL Std. >150
				Box EXH Lower Limit	Added from Remark	110.0 Pa
				Flowmeter N2/Air Purge D15	23.5 L/min	D15: 30 (Air) L/min
				Flowmeter O2 Purge D15	6.5 L/min	D15: 0.0 L/min
				Flowmeter N2/Air Purge D13-D14	47.6 L/min	D13-D14: 60 (Air) L/min
				Flowmeter O2 Purge D13-D14	13.4 L/min	D13-D14: 0.0 L/min
				Flowmeter N2/Air Purge D11-D12	47.6 L/min	D11-D12: 60 (Air) L/min
				Flowmeter O2 Purge D11-D12	13.4 L/min	D11-D12: 0.0 L/min
				3.SYSTEM (Sub-FAB) - System THC - External - THC - AIR Digital Pressure Gauge - Remark	NA	Manually actuate drain pump to ensure pressure is not lower than low limit.
				3.SYSTEM (Sub-FAB) - System THC - STHC CHILLER FLOW RATE SETTING CHART - Using Setting and Range for each Channel	NA	Add
				4.BCT / COT / ITC - PRB - COT/BCT/ITC - Bevel Rinse Nozzle Height	NA	Tool Setting: Cup height±0.0 Tolerance: Cup height+0/-0.5 TEL Std.: Cup height±0.5 Remark: If Cup Height=-2.5, Nozzle Height=-2.5 ~ -3.0
				7. OVEN - CVVP (pg 1 of 2)	Tool Setting	Tool Setting
				Descritpion of Setting	"PBR1" , "PBR2", "PBR3", "PBR4", "PBR5"	Changed to "D11, D12, D13, etc."
				Local exhaust (E27B : D16)	Add	15.0 Pa ± 1
				Local exhaust UL Setting (E27B : D16)	Add	20.0 Pa
				Local exhaust LL Setting (E27B : D16)	Add	10.0 Pa
				Chamber purge U/L	Add	6.5 L/min
				Chamber purge L/L	Add	5.5 L/min
				7. OVEN - CVVP (pg 2 of 2)	Tool Setting	Tool Setting
				Descritpion of Setting	"PBR1" , "PBR2", "PBR3", "PBR4", "PBR5"	Changed to "D11, D12, D13, etc."
				Local exhaust (E27A : D16)	Add	15.0 Pa ± 1
				Local exhaust UL Setting (E27A : D16)	Add	20.0 Pa
				Local exhaust LL Setting (E27A : D16)	Add	10.0 Pa
				9.Sensor Setting PC-3 Sensor/WFK2 Sensor - BARC / WFK2 Sensor - Inm,EUV / WFK2 Sensor - PBR PFMB7201 Flowmeter (CXHN N2) PF2M721 Flowmeter (CXHN N2)	NA	Added
				10.High Altitude Setting - PRB - BCT - Cup Exhaust - Open	F32: 22.2 Tolerance F32: 21.2 ~ 23.2	F32: 22 Tolerance F32: 21 ~ 23
				10.High Altitude Setting - PRB - BCT - Cup Exhaust - Close	F32: 62.8 Tolerance F32: 61.8 ~ 63.8	F32: 63 Tolerance F32: 62 ~ 64
				10.High Altitude Setting - PRB - BCT - Cup Exhaust - Cup EXH U/L Setting	F32: 101.4	F32: 101
				10.High Altitude Setting - PRB - BCT - Cup Exhaust - Cup EXH L/L Setting	F32: 19.3	F32: 19
				10.High Altitude Setting - PRB - BCT - Cup Exhaust - Open	F32: 22.2 Tolerance F32: 21.2 ~ 23.2	F32: 22 Tolerance F32: 21 ~ 23
				10.High Altitude Setting - PRB - COT/ITC - Cup Exhaust - Close	F32: 62.8 Tolerance F32: 61.8 ~ 63.8	F32: 63 Tolerance F32: 62 ~ 64
				10.High Altitude Setting - PRB - COT/ITC - Cup Exhaust - Cup EXH U/L Setting	F32: 101.4	F32: 101
				10.High Altitude Setting - PRB - COT/ITC - Cup Exhaust - Cup EXH L/L Setting	F32: 19.3	F32: 19
				10.High Altitude Setting - PRB - ADEV/ANTD - Cup Exhaust - Open	F32: 9.7 Tolerance F32: 4.7 ~ 14.7	F32: 10 Tolerance F32: 5 ~ 15
				10.High Altitude Setting - PRB - ADEV/ANTD - Cup Exhaust - Close	F32: 38.6 Tolerance F32: 33.6 ~ 43.6	F32: 39 Tolerance F32: 34 ~ 44
				10.High Altitude Setting - PRB - ADEV/ANTD - Cup Exhaust - Cup EXH U/L Setting	F32: 77.3	F32: 77
				10.High Altitude Setting - IFB - SRS - Cup Exhaust - Open	F32: 19.3 Tolerance F32: 17.3 ~ 21.3	F32: 19 Tolerance F32: 17 ~ 21
				10.High Altitude Setting - IFB - SRS - Cup Exhaust - Cup EXH U/L Setting	F32: 33.8	F32: 34
				10.High Altitude Setting - IFB - SRS - Cup Exhaust - Cup EXH L/L Setting	F32: 11.6	F32: 12
				10.High Altitude Setting - PRB - PIR - Cup Exhaust - Open	F32: 14.5 Tolerance F32: 9.5 ~ 19.5	F32: 14 Tolerance F32: 9 ~ 19
				10.High Altitude Setting - IFB - PIR - Cup Exhaust - Cup EXH L/L Setting	F32: 6.8	F32: 7
				10.High Altitude Setting - IFB - BST/BST+ - Cup Exhaust - Open	F32: 38.6 Tolerance F32: 33.6 ~ 43.6	F32: 39 Tolerance F32: 34 ~ 44
				10.High Altitude Setting - IFB - BST/BST+ - Cup Exhaust - Cup EXH U/L Setting	F32: 48.3	F32: 48
				10.High Altitude Setting - IFB - BST/BST+ - Cup Exhaust - Cup EXH L/L Setting	F32: 33.8	F32: 34

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Hardware FPD Revision History

Date	Rev.	Approval		Location	Old	New
		Intel	TEL			
6/3/2022	2.0	K. Proctor	Sato	2.SYSTEM (FAB) - HCSB - HCRA - HCSB transfer area FAN UNIT wind pressure(L/L Setting)	SV-15	SV-90
				2.SYSTEM (FAB) - PRB - SYSTEM - PRA(L) area FAN UNIT wind pressure (L/L Setting)	SV-25	
				2.SYSTEM (FAB) - PRB - SYSTEM - PRA(R) area FAN UNIT wind pressure (L/L Setting)	SV-25	
				2.SYSTEM (FAB) - IFB - IRA - IRA Front area FAN UNIT wind pressure(L/L Setting)	SV-30	
				2.SYSTEM (FAB) - IFB - IRA - IRA Back area FAN UNIT wind pressure(L/L Setting)	SV-30	
				7.Oven - PRB - SCPL - Plate Vac.(w/Wafer)	Remark N/A	Remark Setting is positive value representing differential pressure on the plate. Set by using touch wafers on all SCPL in the deck at the same time
				7.Oven	Module	Module
					ICPL	ICPL/RSMC
				7.Oven - IFB - ICPL - Plate Vac.(w/Wafer)	Remark N/A	Remark Setting is positive value representing differential pressure on the plate. Set by using touch wafers on all SCPL in the deck at the same time
				10. High Altitude Setting - HCSB - HCRA - HCSB transfer area FAN UNIT wind pressure(L/L Setting)	SV-15	SV-90
				10. High Altitude Setting - PRB - SYSTEM - PRA(L) area FAN UNIT wind pressure (L/L Setting)	SV-25	
				10. High Altitude Setting - PRB - SYSTEM - PRA(R) area FAN UNIT wind pressure (L/L Setting)	SV-25	
				10. High Altitude Setting - IFB - IRA - IRA Front area FAN UNIT wind pressure(L/L Setting)	SV-30	
				10. High Altitude Setting - IFB - IRA - IRA Back area FAN UNIT wind pressure(L/L Setting)	SV-30	
				Add KrF item	---	---
7/13/2022	2.01	K. Proctor	Sato Terry	10.High Altitude Setting Fab/Sub-Fab CVVP	N/A	
				Chamber exhaust (Center) ONChamber temperature: 300 to 350 degrees C		25.1
				Chamber exhaust (Center) ON U/L SettingChamber temperature: 300 to 350 degrees C		30.9
				Chamber exhaust (Center) ON L/L SettingChamber temperature: 300 to 350 degrees C		19.3
				Chamber exhaust (Periphery)Chamber temperature: 300 to 350 degrees C		25.1
				Chamber exhaust (Periphery) U/L SettingChamber temperature: 300 to 350 degrees C		32.8
				Chamber exhaust (Periphery) L/L SettingChamber temperature: 300 to 350 degrees C		17.4
				2.SYSTEM (FAB) PRB Flow rate of cooling water from factory(C5A,C6A)(COOL ARM: PCW)	TBF : 11.0 TAP/TAF/TNP: 20.0 TAW : 17.0 TBZ: 16.0	TBF : 11.0 no-CADH TBF : 8.0 TAP/TAF/TNP: 20.0 TAW/TAJ : 17.0 TBZ: 16.0
				2.SYSTEM (FAB) PRB Flow rate of cooling water from factory(C5A,C6A)(COOL ARM: PCW)	TBF : 9.0 TAP/TAF/TNP: 17.0 TAW : 15.0 TBZ : 13.0	TBF : 9.0 no-CADH TBF : 6.0 TAP/TAF/TNP: 17.0 TAW/TAJ : 15.0 TBZ : 13.0
8/15/2022	2.02	K. Proctor	John V	1. Overview (Configuration) - 1.7 Oven S/A Tool Configuration [PBR]	CVVP	CVIP
				2. SYSTEM (FAB) - PRB (PBR Tools)	CVVP	CVIP
				2. SYSTEM (FAB) - PRB (PBR402 Only)	CVVP	CVIP
				7. OVEN - CVIP (pg 1 of 2)	CVVP	CVIP
				7. OVEN - CVIP (pg 2 of 2)	CVVP	CVIP
9/15/2022	2.03	C.Pratik	Terry	3. SYSTEM(Sub-FAB) Chemical Cabinet Exhaust Setting for all Configrations TBF/TBFna/TBFlt/TBFcn - COT Cabinet - Exhaust Solvent(EA1)	Tolerance : 5–100	Tolerance : 10–325
				3. SYSTEM(Sub-FAB) Chemical Cabinet Exhaust Setting for all Configrations TBF/TBFna/TBFlt/TBFcn - COT Cabinet - Exhaust HMDS(EA5)	Tolerance : 5–100	Tolerance : 5–325
				3. SYSTEM(Sub-FAB) Chemical Cabinet Exhaust Setting for all Configrations TAP/TAF/TNP/TAW/TAJ - COT Cabinet - Exhaust Solvent(EA1)	Tolerance : 5–100 Remarks : TARGET CFM	Tolerance : 10–325 Remarks : TARGET CFM 21.2
				3. SYSTEM(Sub-FAB) Chemical Cabinet Exhaust Setting for all Configrations TAP/TAF/TNP/TAW/TAJ - COT Cabinet - Exhaust HMDS(EA5)	Tolerance : 5–100 Remarks : TARGET CFM	Tolerance : 10–325 Remarks : TARGET CFM 14.1
				3. SYSTEM(Sub-FAB) Chemical Cabinet Exhaust Setting for all Configrations TAP/TAF/TNP/TAW/TAJ - COT Cabinet - Exhaust Solvent(EB1)	Tolerance : 5–100 Remarks : TARGET CFM	Tolerance : 10–325 Remarks : TARGET CFM 17.7
				3. SYSTEM(Sub-FAB) Chemical Cabinet Exhaust Setting for all Configrations TAP/TAF/TNP/TAW/TAJ - DEV Cabinet - Exhaust(EC1)	Tolerance : 5–100 Remarks : TARGET CFM	Tolerance : 10–325 Remarks : TARGET CFM 21.2
				3. SYSTEM(Sub-FAB) Chemical Cabinet Exhaust Setting for all Configrations TAP/TAF/TNP/TAW/TAJ - DEV Cabinet - Exhaust(EC2)	Tolerance : 5–100 Remarks : TARGET CFM	Tolerance : 10–325 Remarks : TARGET CFM 14.1
				3. SYSTEM(Sub-FAB) Chemical Cabinet Exhaust Setting for all Configrations KrF - COT Cabinet - Exhaust Solvent(EA1)	Tolerance : 5–100	Tolerance : 10–325
				3. SYSTEM(Sub-FAB) Chemical Cabinet Exhaust Setting for all Configrations KrF - COT Cabinet - Exhaust HMDS(EA5)	Tolerance : 5–100	Tolerance : 5–325

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Date	Rev.	Approval		Location	Old	New
		Intel	TEL			
9/15/2022	2.03	C.Pratik	Terry	3. SYSTEM(Sub-FAB) Chemical Cabinet Exhaust Setting for all Configrations KrF - DEV Cabinet - Exhaust Solvent(EC1)	Tolerance : 5~100	Tolerance : 10~325
				3. SYSTEM(Sub-FAB) Chemical Cabinet Exhaust Setting for all Configrations KrF - DEV Cabinet - Exhaust Solvent(EC2)	Tolerance : 5~100	Tolerance : 10~325
				7. Oven - PRB-CADH-Local EXH For Deck*	Remark : For BARC tool config -E11A = 8CADH units -E11C = 8CADH units For KrF tool config -E11A = 8CADH units	Remark : For BARC tool config -E11A = 8CADH units -E11C = 8CADH units
				7. Oven - PRB-CADH-Local EXH For Deck13/14(E11A)	NA	Tool Setting : 230 Pa Tplerance : 200~260 Pa TEL Std : 230±30 Pa Remarks : For KrF tool config -E11A = 8CADH units
				7. Oven - PRB-CADH-Local EXH For Deck13/14 U/L Setting(E11A)	NA	Tool Setting : 260 Pa TEL Std : 260 Pa
				7. Oven - PRB-CADH-Local EXH For Deck13/14 L/L Setting(E11A)	NA	Tool Setting : 200 Pa TEL Std : 200 Pa
				9. Sensor Setting PF3W30C-MT Sensor - PRB - SYSTEM - PCW Flow Meter 40L/min	NA	Range : 40 oUI : HYS Iot : 1_P P1 : Setting Value HI : 0 COL : SoG rES : 1 ANA : FLOW FrE : OFF
12/21/2022	2.04	K. Proctor	Terry	3. SYSTEM(Sub-FAB)-COT Cabinet-HMDS Canister Pressurization	P(setting pressure: MPa)=0.03(MPa)+0.008(coefficient)×H(lifting height: m) *Lifting height = Difference in height between the CAB and the floor where the main body is installed.	P(setting pressure: MPa)=0.03(MPa)+0.008(coefficient)×H(lifting height: m) *Lifting height = Difference in height between the CAB and the floor where the main body is installed. Dynamic Pressure
				3. SYSTEM(Sub-FAB) Ultrasonic flowmeter setting for "Liquid Kind" Solvet(EL)-Solvent/Other	Solvet(EL)-Solvent/Other	Delete and add Solvent(POS,PGMEA,EL)
				7. Oven-PRB CADH- EUV section	NA	Add
				7. Oven-PRB CPHP-CPHP Chamber (R) EXH U/L Setting (E9B)	NA	155
				7. Oven-PRB CPHP-CPHP Chamber (R) EXH L/L Setting (E9B)	NA	85
				7. Oven-PRB CPHP-CPHP Chamber (R) EXH U/L Setting (E9A)	NA	155
				7. Oven-PRB CPHP-CPHP Chamber (R) EXH L/L Setting (E9A)	NA	85
				10. High Altitude Setting-PRB-CGCH-CGCH Cover EXH. For Deck13(E8B)	319	251
				10. High Altitude Setting-PRB-CGCH-CGCH Cover EXH. For Deck13 U/L Setting (E8B)	357	289
				10. High Altitude Setting-PRB-CGCH-CGCH Cover EXH. For Deck13 L/L Setting (E8B)	289	289
				10. High Altitude Setting-PRB-CGCH-CGCH Cover EXH. For Deck14(E8B)	338	298
				10. High Altitude Setting-PRB-CGCH-CGCH Cover EXH. For Deck14 U/L Setting (E8B)	377	337
				10. High Altitude Setting-PRB-CGCH-CGCH Cover EXH. For Deck14 L/L Setting (E8B)	299	259
				10. High Altitude Setting-PRB-CGCH-CGCH Cover EXH. For Deck15(E8B)	126	122
				10. High Altitude Setting-PRB-CGCH-CGCH Cover EXH. For Deck15 U/L Setting (E8B)	164	160
				10. High Altitude Setting-PRB-CGCH-CGCH Cover EXH. For Deck15 L/L Setting (E8B)	87	83
				10. High Altitude Setting-PRB-CGCH-CGCH Cover EXH. For Deck16(E8B)	135	124
				10. High Altitude Setting-PRB-CGCH-CGCH Cover EXH. For Deck16 U/L Setting (E8B)	174	163
				10. High Altitude Setting-PRB-CGCH-CGCH Cover EXH. For Deck16 L/L Setting (E8B)	97	86
				10. High Altitude Setting-CADH EUV section	N/A	Add
				10. High Altitude Setting-CADH KrF section	N/A	Add

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Date	Rev.	Approval		Location	Old	New
		Intel	TEL			
2/3/2023	2.05	K. Proctor	Terry	1. Overview (Configuration) 1.9 KrF Tool Configuration [TBN]	NA	Add
				2. SYSTEM(FAB)-PRB-SYSTEM Flow rate of cooling water from factory(C5A,C6A)(COOL ARM: PCW)	TBF : 11.0 no-CADH TBF : 8.0 TAP/TAF/TNP: 20.0 TAW/TAJ : 17.0 TBZ: 16.0	TBF : 11.0 TAP/TAF/TNP/TAA/TBN: 20.0 TAW/TAJ : 17.0 TBZ: 16.0
				2. SYSTEM(FAB)-PRB-SYSTEM Flow rate of cooling water from factory(C5A,C6A)(COOL ARM: PCW)(L/L Setting)	TBF : 9.0 no-CADH TBF : 6.0 TAP/TAF/TNP: 17.0 TAW/TAJ : 15.0 TBZ : 13.0	TBF : 9.0 TAP/TAF/TNP/TAA/TBN: 17.0 TAW/TAJ : 15.0 TBZ : 13.0
				2. SYSTEM(FAB)-PRB-SYSTEM P.C.Water(3) In (C5A)	NA	Add
				2. SYSTEM(FAB)-PRB-COT,ITC Drain Case Cleaning + Resist individual Drain Manifold Clean (Dispense Rate)	NA	Add TAA
				2. SYSTEM(FAB)-PRB-COT,ITC TBN Deck12 Drain Case Cleaning + Resist individual Drain Manifold Clean (Dispense Rate)	NA	Add
				2. SYSTEM(FAB)-PRB-COT Deck13,D14 Drain Case Cleaning + Resist individual Drain Manifold Clean (Dispense Rate)	NA	Add TBZ
				2. SYSTEM(FAB)-PRB-CADH CADH Ring Purge Pressure	Imm tool D11/12 and BARC tool, KrF tool (ie 88L/min lines) : 0.35 Imm tool D13 and EUV tool (ie 44L/min lines) : 0.20	Separate each configration
				2. SYSTEM(FAB)-PRB-CADH CADH Ring Purge Flow Rate	BARC tool D13/14:88.0,D15/16:88.0 Imm tool D11/12:88.0,D13:44.0 EUV tool D12:44.0,D13:44.0	Separate each configration
				2. SYSTEM(FAB)-PRB-CADH CADH Ring Purge (U/L Setting)	BARC tool D13/14:100.0,D15/16:100.0 KrF tool D13/14:100.0 Imm tool D11/12:100.0,D13:52.0 EUV tool D12:52.0,D13:52.0	Separate each configration
				2. SYSTEM(FAB)-PRB-CADH CADH Ring Purge (L/L Setting)	BARC tool D13/14:72.0 D15/16:72.0 KrF tool D13/14:72.0 Imm tool D11/12:72.0,D13:36.0 EUV tool D12:36.0,D13:36.0	Separate each configration
				2. SYSTEM(FAB)-PRB-ADEV RINSE (Dispense Rate)	1000	Imm/EUV=1000 KrF=1050
				2. SYSTEM(Sub-FAB)-External-COT Cabinet2 NTD PCS(1,2) Drive, NTD PCS(1,2) Ejector Drive, NTD PCS(1,2) Fill Pressure, NTD Rinse PCS Drive, NTD Rinse PCS Ejector Drive, NTD Rinse PCS Fill Pressure,	NA	Add "0 MPa on no-LND/LNR tracks" at Remarks
				2. SYSTEM(Sub-FAB)-External-COT Cabinet2 NTD PCS(1,2) VAC. Setting, NTD PCS(1,2) VAC. U/L Setting, NTD PCS(1,2)VAC. L/L Setting NTD Rinse PCS VAC. Setting, NTD Rinse PCS VAC. U/L Setting, NTD Rinse PCS VAC. L/L Setting	NA	Add "N/A on no-LND/LNR tracks" at Remarks
				2. SYSTEM(Sub-FAB)-External-COT Cabinet2 Solvent Supply System IFF-S Control box P_1 setting Solvent Supply System IFF-S Control box P_2 setting Solvent Supply System IFF-S Control box P_3 setting Solvent Supply System IFF-S Control box P_4 setting Solvent Supply System CRF Return Line Flow Rate Solvent Supply SystemCRF Drain Line Flow Rate	NA	Add "IFFS ENABLED TOOL CONFIGURATIONS" at Remarks
				2. SYSTEM(Sub-FAB)-External-COT Cabinet2 N.T.Dev.Solution(1) PCS1 Line Valve Drive	NA	Add
				2. SYSTEM(Sub-FAB)-STHC CHILLER FLOW RATE SETTING CHART TBF/TBFna/TBFlt/TBFcn Ch4-2**	NA	Add
				2. SYSTEM(Sub-FAB)-STHC CHILLER FLOW RATE SETTING CHART TAP/TAF/TNP/TAA/TAW/TAJ Ch4-2**	NA	Add

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2/3/2023	2.05	K. Proctor	Terry	2. SYSTEM(Sub-FAB)-STHC CHILLER FLOW RATE SETTING CHART	NA	Add TBN
				4. BCT-COT-ITC -PRB-BCT Cup EXH U/L Setting	105.0	85.0
				4. BCT-COT-ITC -PRB-COT/ITC Cup EXH U/L Setting	105.0	85.0
				4. BCT-COT-ITC -PRB-COT* Cup EXH U/L Setting	105.0	85.0
				5. DEV-NTD -PRB-ADEV MGP main Nozzle Home Height	NA	Add
				5. DEV-NTD -PRB-ANTD NTD Nozzle Home Height	NA	Add
				5. DEV-NTD -PRB-ANTD NTD Rinse Home Nozzle Height	NA	Add
				5. DEV-NTD -PRB-ADEV ADR Rinse Nozzle Home Height	NA	Add
				7. OVEN-PRB-CADH Local EXH. For Deck12 (E11A) Local EXH. For Deck12 U/L Setting (E11A) Local EXH. For Deck12 L/L Setting (E11A)	NA	Add at KrF tool config
04/03/2023	2.06	K. Proctor	Matt B / John V	Cover	Software Version 500.1.16.200 Temperature Version: 1.49.0 Software Version 500.1.7.100 Sub Operation Panel version 5.32.13	Software Version 500.1.17.200 Temperature Version: 1.50.0 Date: 02/20/2023 Software Vesion: 500.1.16.200 Sub Operation Panel version 5.32.13
				1.Overview (Configuration)	TBN 13-16 CPHP was highlighted	TBN 13-16 unhighlighted (confirmed no module)
				2. SYSTEM (FAB) PBR (PBR402 Only)	Number of CVVP	Number of CVIP
				3.SYSTEM (SUB-FAB) COT Cabinet2 Only IMM / EUV N.T.Dev.Solution(1) PCS1 Line Valve Drive	0.19 ~ 0.21	0.15 ~ 0.25
				3.SYSTEM (SUB-FAB)COT Cabinet1 Solvent Supply System Line Valve Drive	Tolerence: 0.19 ~ 0.21	Tolerence: 0.15 ~ 0.25
				3.SYSTEM (SUB-FAB)Chiller Flow Rate Settings Chart	Typo	22.3' 23.7 L/min
				5.DEV-NTD MGP main Nozzle Home Height NTD Nozzle Height NTD Rinse Home Nozzle Height ADR Rinse Nozzle Home Height	Tool Specific	Nozzle Specific / Home Position Adjusted by Fixture
				7.OVEN CVIP (pg 2 of 2)	Chamber EXH (E27B) Chamber EXH U/L Setting (E27B) Chamber EXH L/L Setting (E27B)	Chamber EXH (E28B) Chamber EXH U/L Setting (E28B) Chamber EXH L/L Setting (E28B)
07/12/2023	2.07	K. Proctor	Matt B.	Cover	For the P1274 and P1276 Tools 4/3/2023	For the P1274 / P1276 / P1278 Tools 7/14/2023
				Index	HW and SW previous page numbers	HW and SW new page numbers
08/11/2023	2.07	K.Proctor	Matt B.	Cover	7/12/2023	8/12/2023
				3.System (Sub-Fab) STHC Chiller Flow Rate Setting Chart - TBZ and TBN	Line 0 - 12 out of order.	Changed the Line 0 - 12 in corect order

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Date	Rev.	Approval		Location	Old	New
		Intel	TEL			
04/23/2020	1.00	K.Proctor	Red	First Edition	NA	NA
05/04/2020	1.01	K.Proctor	Red	Section 6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block,[CGCH] - Controller Analogue sensor - Set Value	25.70	16.00
				Section 6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block,[CGCH] - Controller Analogue sensor - Warning Range Lower Limit	4.00	3.00
				Section 6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block,[CGCH] - Controller Analogue sensor - Warning Range Upper Limit	4.00	3.00
				Section 13. EC SYSTEM Setting - Item Level Settings - SYSTEM - Equipment mod	Service	User service
05/14/2020	1.02	K.Proctor	Red	Section 5.1. System Config Parameter, Spiners(COT/BCT) - RRC NOZZLE1 / DRN CASE CLEAN / NZL/BATH CLN R# / NZL/BATH CLN CMN / NZL/BATH CLN ALL - Dispense Monitoring Control D - Monitoring Flow Rate Lower Limit for Short Time Dispense	NA	Non Execute
				Section 5.1. System Config Parameter, Spiners(COT/BCT) - RRC NOZZLE1 / DRN CASE CLEAN / NZL/BATH CLN R# / NZL/BATH CLN CMN / NZL/BATH CLN ALL - Dispense Monitoring Control D - Flow Rate Lower Limit Non-monitoring Time for Short Time Dispense	NA	1.5
				Section 5.1. System Config Parameter, Spiners(COT/BCT) - Block Arm - Left - Recipe Position - Dispense 1 - Z Position	5.00	30.00
				Section 5.1. System Config Parameter, Spiners(COT/BCT) - Block Arm - Left - Recipe Position - Dispense 5 - Z Position	33.50	34.50
				Section 5.1. System Config Parameter, Spiners(COT/BCT) - Block Arm - Left - Recipe Position - Dispense 5 - Y Position - Table 1	CUP 1 : 245.50mm CUP 2 : -347.50mm CUP 3 : -347.50mm	CUP 1 : 275.50±3mm CUP 2 : -404.50±3mm CUP 3 : -1084.50±3mm
				Section 8. System Parameter - Others - Option Advanced Wafer Level Monitor	NA	Invalid
				Section 8. System Parameter - Monitoring - Option Collective Setting of Stranded Wafer Detection Function for Heat Process	NA	Module Individual Setting
07/27/2020	1.03	K.Proctor	Red	Section 1. Cover - Software Version	500.0.54.200	500.0.54.201
				Section 5.4. Spinner Parameter, Spinner Information Parameter - Resist film thickness Correction Factor	300	NA(Parameter detele)
				Section 5.4. Spinner Parameter, Spinner Information Parameter - Resist film thickness Correction Control	4000	NA(Parameter detele)
				Section 6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block,[CGCH] - Monitoring Parameter - Control Table Data List - Temp Range	Temp Range1 : 50.00 ~ 250 Temp Range2 : 170.00 ~ Not Input Temp Range3 : 175.00 ~ Not Input Temp Range4 : 190.00 ~ Not Input Temp Range5 : 205.00 ~ Not Input Temp Range6 : 225.00 ~ Not Input Temp Range7 : 250.00 ~ Not Input	Temp Range1 : 50.00 ~ 250.00 Temp Range2 : 170.00 ~ Not Input Temp Range3 : 190.00 ~ Not Input Temp Range4 : 205.00 ~ Not Input Temp Range5 : 225.00 ~ Not Input Temp Range6 : 250.00 ~ Not Input
				Section 6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block,[CGCH] - Monitoring Parameter - Control Table Data List - Accumulated Threshold Value	170.00 degC : Need onsite evaluation 175.00degC : Need onsite evaluation 190.00degC : Need onsite evaluation 205.00 degC : Need onsite evaluation 225.00degC : Need onsite evaluation	170.00 degC : 35.00 175.00degC : NA(Delete) 190.00degC : 46.00 205.00 degC : 55.00 225.00degC : 72.50 250.00 degC : 110.00
				Section 6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block,[CGCH] - Monitoring Parameter - Control Table Data List - Accumulated Time	170.00 degC : Need onsite evaluation 175.00degC : Need onsite evaluation 190.00degC : Need onsite evaluation 205.00 degC : Need onsite evaluation 225.00degC : Need onsite evaluation	170.00 degC : 15.00 175.00degC : NA(Delete) 190.00degC : 15.00 205.00 degC : 15.00 225.00degC : 15.00 250.00 degC : 15.00
				Section 6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block,[CADH] - Monitoring Parameter - Control Table Data List - Temp Range	Temp Range1 : 0.00 ~ 99.00 Temp Range2 : 90.00 ~ Not Input Temp Range3 : 100.00 ~ 129.99 Temp Range4 : 110.00 ~ Not Input Temp Range5 : 130.00 ~ 180.00 Temp Range6 : 150.00 ~ Not Input	Temp Range1 : 0.00 ~ 180.00 Temp Range2 : 90.00 ~ Not Input Temp Range3 : 110.00 ~ Not Input Temp Range4 : 150.00 ~ Not Input
				Section 6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block,[CADH] - Monitoring Parameter - Control Table Data List - Accumulated Threshold Value	90.00degC : Need onsite evaluation 100.00degC : Need onsite evaluation 110.00degC : Need onsite evaluation 130.00degC : Need onsite evaluation 150.00degC : Need onsite	90.00degC : 37.00 100.00degC : NA(Delete) 110.00degC : 52.00 130.00degC : NA(Delete) 150.00degC : 80.00
				Section 6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block,[CADH] - Monitoring Parameter - Control Table Data List - Accumulated Time	0.00degC - 99.00degC : 15.00 90.00degC : Need onsite evaluation 100.00degC : 15.00 110.00degC : Need onsite evaluation 130.00degC : 15.00 150.00degC : Need onsite evaluation	0.00degC - 180.00degC : Not Input 90.00degC : 10.00 100.00degC : NA(Delete) 110.00degC : 10.00 130.00degC : NA(Delete) 150.00degC : 10.00
				Section 8. System Parameter - Others - Belt Break Detection for Spin Arms	NA	Valid
				Section 8. System Parameter - Others - Option Resist Dispensing Interval Verificatio	NA	Valid
				Section 8. System Parameter - Special Transfer Control - Option Prime Cascade Mode (Coating Flow)	NA	Prioritize Throughput
				Section 8. System Parameter - Special Transfer Control - Option Prime Cascade Mode (Development Flow)	NA	Prioritize Throughput
				Add item for lmm tool	---	---

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Software FPD Revision History

Date	Rev.	Approval		Location	Old	New
		Intel	TEL			
				Section 1. Cover - Software Version	500.0.54.201	500.0.57.0
				Section 1. Cover - Sub Operation Panel Version	5.32.05	5.32.10
				Section 3. System Configuration Parameter, System - System - Monitoring Parameter - Chiller BYPASS1 / Chiller BYPASS2 / Chiller BYPASS3 / Chiller BYPASS4 - Valid, Invalid	NA	Valid
				Section 3. System Configuration Parameter, System - System - Monitoring Parameter - Chiller BYPASS1 / Chiller BYPASS2 / Chiller BYPASS3 / Chiller BYPASS4 - Mesured Data ID	NA	Chller BYPASS1,2,3,4
				Section 3. System Configuration Parameter, System - System - Monitoring Parameter - Chiller BYPASS1 / Chiller BYPASS2 / Chiller BYPASS3 / Chiller BYPASS4 - Recipe Setting Method	NA	Local
				Section 3. System Configuration Parameter, System - System - Monitoring Parameter - Chiller BYPASS1 / Chiller BYPASS2 / Chiller BYPASS3 / Chiller BYPASS4 - Temperature Control Method	NA	Tmp ctl ON
				Section 3. System Configuration Parameter, System - System - Monitoring Parameter - Chiller BYPASS1 / Chiller BYPASS2 / Chiller BYPASS3 / Chiller BYPASS4 - Recipe Verification Range Lower Limit	NA	0.00
				Section 3. System Configuration Parameter, System - System - Monitoring Parameter - Chiller BYPASS1 / Chiller BYPASS2 / Chiller BYPASS3 / Chiller BYPASS4 - Recipe Verification Range Upper Limit	NA	35.00
				Section 3. System Configuration Parameter, System - System - Monitoring Parameter - Chiller BYPASS1 / Chiller BYPASS2 / Chiller BYPASS3 / Chiller BYPASS4 - Controller TM206-CHILLER - Controller ID	NA	TM206-CHILLER
				Section 3. System Configuration Parameter, System - System - Monitoring Parameter - Chiller BYPASS1 / Chiller BYPASS2 / Chiller BYPASS3 / Chiller BYPASS4 - Controller TM206-CHILLER - Channel No.	NA	[TBF] BYPASS-1:3 / BYPASS-2:4 BYPASS-3:5 / BYPASS-4:5 [TAP/TNP/TAF] BYPASS-1:4 / BYPASS-2:5
				Section 3. System Configuration Parameter, System - System - Monitoring Parameter - Chiller BYPASS1 / Chiller BYPASS2 / Chiller BYPASS3 / Chiller BYPASS4 - Controller TM206-CHILLER - Line No.	NA	[TBF] BYPASS-1:3 / BYPASS-2:5 BYPASS-3:8 / BYPASS-4:9 [TAP/TNP/TAF] BYPASS-1:7 / BYPASS-2:12
				Section 3. System Configuration Parameter, System - System - Monitoring Parameter - Chiller BYPASS1 / Chiller BYPASS2 / Chiller BYPASS3 / Chiller BYPASS4 - Controller TM206-CHILLER - Set Value	NA	[TBF] BYPASS-1:4.00 / BYPASS-2:11.00 BYPASS-3:49.00 / BYPASS-4:13.00 [TAP/TNP/TAF] BYPASS-1:6.00 / BYPASS-2:6.00
09/16/2020	1.04	K.Proctor	Red	Section 3. System Configuration Parameter, System - System - Monitoring Parameter - Chiller BYPASS1 / Chiller BYPASS2 / Chiller BYPASS3 / Chiller BYPASS4 - Controller TM206-CHILLER - Warning Range Lower Limit, Upper Limit	NA	100.00
				Section 3. System Configuration Parameter, System - System - Monitoring Parameter - Chiller BYPASS1 / Chiller BYPASS2 / Chiller BYPASS3 / Chiller BYPASS4 - Controller TM206-CHILLER - Stop Range Lower Limit, Upper Limit	NA	100.00
				Section 3. System Configuration Parameter, System - System - Monitoring Parameter - Chiller BYPASS1 / Chiller BYPASS2 / Chiller BYPASS3 / Chiller BYPASS4 - Controller TM206-CHILLER - Offset	NA	0.00
				Section 4. System Configuration Parameter, Arm - Block 1 CS Block - Position Data - 1-0 / 1-20 HCRA -Z and Theta axis Offset - Z and Theta axis Offset - 1-0 / 1-20 H - FOUP - Offset(Z Send - Z Receive)	990 pulse	Tool Specific* (Add comment)
				Section 4. System Configuration Parameter, Arm - Block 1 CS Block - Position Data - 1-0 / 1-20 HCRA -Z and Theta axis Offset - Z and Theta axis Offset - 1-0 / 1-20 H - TTS - Offset(Z Send - Z Receive)	2310 pulse	Tool Specific** (Add comment)
				Section 4. System Configuration Parameter, Arm - Block 1 CS Block - Position Data - 1-0 / 1-20 HCRA -Z and Theta axis Offset - Z and Theta axis Offset - 1-0 / 1-20 H - All Others - Offset(Z Send - Z Receive)	1955 pulse	1955 pulse*** (Add comment)
				Section 4. System Configuration Parameter, Arm - Block 1 CS Block - Position Data - 1-0 / 1-20 HCRA -Z and Theta axis Offset - 1-0 / 1-20 HCRA X2 - TTS - Offset(Z Send - Z Receive)	2310 pulse	Tool Specific** (Add comment)
				Section 4. System Configuration Parameter, Arm - Block 1 CS Block - 1-0 / 1-20 HCRA - Transfer Arm Control Parameter - EDR Function	NA	Valid
				Section 4. System Configuration Parameter, Arm - Block 11, 12, 13, 14, 15, 16 PR E - Z and Theta axis Offset - 11-0 / 12-0 / 13-0 / 14-0 / 15-0 /16-0 PRA - TTS - Offset(Z Send - Z Receive)	3400 pulse	Tool Specific** (Add comment)
				Section 4. System Configuration Parameter, Arm - Block 11, 12, 13, 14, 15, 16 PR E - 11-0 / 12-0 / 13-0 / 14-0 / 15-0 /16-0 PRA - Transfer Arm Control Parameter - EDR	NA	Valid
				Section 4. System Configuration Parameter, Arm - Block 30 IFB Block - 30-0 IRAI , 30-10 / 30-20 IRAM - Transfer Arm Control Parameter - EDR Functio	NA	Valid
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - Disoense Parameter - Supply System - Resist Nozzle# - Transfer control/Chemical Amount to be Countinue After Bottle Empty	50	0
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - Disoense Parameter - Supply System - Resist Nozzle# - Transfer control/Chemical Amount to be Countinue After Bottle Empty	NA	EUV TCT:0ml / EUV BCT:0ml EUV COT:0ml BARC,Immersion:50ml
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - Disoense Parameter - RRC NOZZLE1 - Dispense Monitoring Mechanism Connecti - UltrasonicType flow meter - Regular Retrieval of Flow Rate - Sensor Channel No.	1	6

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Software FPD Revision History

Date	Rev.	Approval		Location	Old	New
		Intel	TEL			
09/16/2020	1.04	K.Proctor	Red	Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - Disoense Parameter - RRC NOZZLE1 / DRN CASE CLEAN / NZL/BATH CLN R - TH CLN CMN / NZL/BATH CLN ALL - Dispense Monitoring Mechanism Connec - UltrasonicType flow meter - Regular Retrieval of Flow Rate - FRType	TYPE2(3000ml/min)	RRC Nozzle:Type3(300ml) DRN CASE CLEAN:Type3(300ml) NZL/BATH CLN R#:Type2(3000ml) NZL/BATH CLN CMN:Type2(3000ml)
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - Disoense Parameter - RRC NOZZLE1 / DRN CASE CLEAN / NZL/BATH CLN I - TH CLN CMN / NZL/BATH CLN ALL - Supply System - Dispense Monitoring Co - Monitoring Flow Rate Lower Limit for Short Time Dispense - RRC NOZZLE1, DRN CASE CLEAN	Note Execute	NA
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - Disoense Parameter - RRC NOZZLE1 / DRN CASE CLEAN / NZL/BATH CLN R - TH CLN CMN / NZL/BATH CLN ALL - Supply System - Dispense Monitoring Co - Flow Rate Lower Limit Non-monitoring Time for Short Time Dispense - RRC NOZZLE1, DRN CASE CLEAN	1.5	NA
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - Disoense Parameter - RRC FILTDRAIN1 - Dispense Monitoring Control Data - Reporting Dispense Amount to Dispense State Monitor	NA	Valid
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - NMA Parameter - Collective Invalidation Parameters(by Arm Unit) - Inspection Alarms at Dispensing (All Invalid/Set Each)	Set Each	All Invalid
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - NMA Parameter - Collective Invalidation Parameters(by Arm Unit) - Inspection Alarms after DFT Formation (All Invalid/Set Each)	Set Each	All Invalid
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - NMA Parameter - Collective Invalidation Parameters(by Arm Unit) - Inspection Alarms after Pre-PJ DummDisp. (All Invalid/Set Each)	Set Each	All Invalid
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - NMA Parameter - Basic Data Settings - Controller No. - [BARC tool] table	NA	13-1(BCT):3 / 13-2(BCT):3 / 13-3(BCT):3 14-1(BCT):4 / 14-2(BCT):4 / 13-4(BCT):4 15-1(BCT):5 / 15-2(BCT):5 / 15-3(BCT):5 16-1(BCT):6 / 13-6(BCT):6 / 16-
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - NMA Parameter - Basic Data Settings - Camera Ch - [BARC tool] table	NA	13-1(BCT):0 / 13-2(BCT):0 / 13-3(BCT):0 14-1(BCT):0 / 14-2(BCT):0 / 13-4(BCT):0 15-1(BCT):0 / 15-2(BCT):0 / 15-3(BCT):0 16-1(BCT):0 / 13-6(BCT):0 / 16-
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - NMA Parameter - RESIST NOZZLE# - Nozzle information - Nozzle Position (Camera Swing Position) - [BARC tool] table	NA	Nozzle Specific*
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - NMA Parameter - RESIST NOZZLE# - Light Setting - Top Brightness - [BARC to	NA	NZL1:155 / NZL2:110 / NZL3:80 NZL4–7:70 / NZL8:80 / NZL9:110 RRC NZL:70
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - NMA Parameter - RESIST NOZZLE# - Light Setting - Slide3 Left Brightness*	NA	150
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - NMA Parameter - RESIST NOZZLE# - Light Setting - Slide3 Right Brightness*	NA	150
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - NMA Parameter - RESIST NOZZLE# - Threshold Settings - Liquid Level Inspectio - PSB - PSB position for Auto-adjustment	NA	0.0
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - NMA Parameter - RESIST NOZZLE# - Valid/Invalid Parameters (by Nozzle Unit) - Inspection at Dispensing - Liquid Level Inspection Alarms (Valid/Invalid) - Pre-disp. Liquid Level Height Judgment (Valid/Invalid)	NA	Valid(excluding N/A)
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - NMA Parameter - RESIST NOZZLE# - Valid/Invalid Parameters (by Nozzle Unit) - Inspection at Dispensing - Liquid Level Inspection Alarms (Valid/Invalid) - Post-disp. Liquid Level Height Judgment (Valid/Invalid)	NA	Invalid
				Section 5.4. Spinner Parameter - Spinner Information Parameter - Cup Exh. Alarm Detect Threshold	NA	1.0
				Section 6. System Config Parameter, Ovens(CADH) - Block 11,12,13,14,15,16 - Monitaring Parameter - Dispense Parameter - Local Nozzle - HMDS Vapor -Supply - HMDS Supply System - Refill Monitoring Time	300	180
				Section 8. System Parameter - Others - Option ACDR Pump Vent Operation Switchi	NA	Vent Operation Type1
				Section 8. System Parameter - Maintenance - Option Operation-Less RIA Alarms	NA	Valid(PURGE Class Only)
				Section 8. System Parameter - Basic Transfer Control - CSB rewrite	NA	CSB conventional control
				Section 8. System Parameter - Special Transfer Control - Option Alarm Output of Specifying Nozzle Exclusion	NA	Not Execute
				Section 8. System Parameter - Special Transfer Control - Option Mutual Exclusion of RIA and PJ which Use Same Module	NA	Valid
				Section 8. System Parameter - FOUP Exchanger - Option FTRA High Throughput	Valid	Invalid

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Software FPD Revision History

Date	Rev.	Approval		Location	Old	New
		Intel	TEL			
10/23/2020	1.05	K.Proctor	Red	Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - Dispense Parameter - Shared Nozzle - Possible Number of Simultaneous Resist Dispense Processes	BARC : 10 IMM : 4	10
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - Dispense Parameter - Bottle Empty Detectction Setting - Refill Stop Sensor Watch Invalid Time	1.5	6.0
				Section 5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Block 11,12,13,14 - DRN CASE CLEAN - Dispense Monitoring Control Data - Set Flow Rate	250	See table (Each tool and deck different setting)
				Section 6. System Config Parameter, Ovens(CADH) - Block 11,12,13,14,15,16 - Monitoring Parameter - Local Nozzle - HMDS VAPOR - Dispense Monitoring Control Data - Caribration 1	Tool Specific	0.90 – 1.05
				Section 6. System Config Parameter, Ovens(CADH) - Block 11,12,13,14,15,16 - Monitoring Parameter - CHAMBER EXH. - Dispense Monitoring Control Data - Caribration 1	Tool Specific	0.90 – 1.05
				Section 6. System Config Parameter, Ovens - Block 11.12.13.14.15.16 PR Block,[C - Monitoring Parameter - Control Table Data List - Control Table Data1	Temprature Range 0.00 - 99.99	Temprature Range 0.00 - 180.00
				Section 6. System Config Parameter, Ovens - Block 11.12.13.14.15.16 PR Block,[C - Monitoring Parameter - Control Table Data List - Control Table Data3	Temprature Range 100.00 - 129.99	Temprature Range 110.00
				Section 6. System Config Parameter, Ovens - Block 11.12.13.14.15.16 PR Block,[C - Monitoring Parameter - Control Table Data List - Control Table Data4	Temprature Range 110.00	Temprature Range 150.00
				Section 6. System Config Parameter, Ovens - Block 11.12.13.14.15.16 PR Block,[C - Monitoring Parameter - Control Table Data List - Control Table Data4 - Offset	Not Input	Module Specific
				Section 6. System Config Parameter, Ovens - Block 11.12.13.14.15.16 PR Block,[C - Monitoring Parameter - Control Table Data List - Control Table Data4 - I Constant	15.300	14.700
				Section 6. System Config Parameter, Ovens - Block 11.12.13.14.15.16 PR Block,[C - Monitoring Parameter - Control Table Data List - Control Table Data5	Temprature Range 130.00 - 180.00	NA
				Section 6. System Config Parameter, Ovens - Block 11.12.13.14.15.16 PR Block,[C - Monitoring Parameter - Control Table Data List - Control Table Data6	Temprature Range 150.00	NA
				Section 8. System Parameter - Others - Option Change of Initial Value for Refill Source Selection	NA	Valid
				Section 8. System Parameter - Dummy Dispense - Ring Purge ON time before Interval Dummy Dispense for ADH and CADH	NA	0.0
				Section 8. System Parameter - Dummy Dispense - Ring Purge OFF time after Interval Dummy Dispense for ADH and CADH	NA	0.0
10/30/2020	1.06	K.Proctor	Red	Section 5.1. System Config Parameter, Spinners (ADEV) - Back Rinse1 - Dispense Monitoring Control Data - Pulse Rate	0.05	0.005
				Section 5.1. System Config Parameter, Spinners (ADEV) - ADR1 RINSE - Dispense Monitoring Control Data - Upper Limit Error Level	20.00%	30.00%
				Section 5.1. System Config Parameter, Spinners (ADEV) - ADR1 RINSE - Dispense Monitoring Control Data - Upper Limit Warning Level	15.00%	20.00%
				Section 5.1. System Config Parameter, Spinners (ADEV) - ADR1 RINSE - Dispense Monitoring Control Data - Lower Limit Error Level	20.00%	30.00%
				Section 5.1. System Config Parameter, Spinners (ADEV) - ADR1 RINSE - Dispense Monitoring Control Data - Lower Limit Warning Level	15.00%	20.00%
				Section 5.1. System Config Parameter, Spinners (ADEV) - Block Arm - Left/ Block Arm - Right/ Module Arm - Left - NTD - Rinse Arm - Begin - X Position	0.00	140.00
				Section 5.1. System Config Parameter, Spinners (ADEV) - Block Arm - Left/ Block Arm - Right/ Module Arm - Left - NTD - Rinse Arm - Dispense 1 - X Position	-13.00	-10.00
				Section 5.1. System Config Parameter, Spinners (ADEV) - Block Arm - Left/ Block Arm - Right/ Module Arm - Left - NTD - Rinse Arm - Begin ~ Edge(B) - Z Position	Arm Down	16.00
				Section 5.1. System Config Parameter, Spinners (ADEV) - Block Arm - Left/ Block Arm - Right/ Module Arm - Left - NTD - Rinse Arm - MNT1 ~ MNT3 - Z Position	Arm Up	5.00
				6. System Config Parameter, Ovens - Block 11.12.13.14.15.16 PR Block, [SCPL] Slim Chill Plate Process Station - Controller TM206-CHILLER - Initial Data - Imm tool - 14-31/14-32/15-31/15-32/16-31/16-32 SCPL	22.2	23.0
12/04/2020	1.07	K.Proctor	Red	5.1. System Config Parameter, Spinners (ADEV,ANTD) - ADEV Module Arm - Left - Arm Move Limitation - Allowable Radius for Arm Down to the Plus Area	NA	59.00
				5.1. System Config Parameter, Spinners (ADEV,ANTD) - ADEV Module Arm - Left - Arm Move Limitation - Allowable Radius for Arm Down to the Minus Area	NA	159.00
				5.1. System Config Parameter, Spinners (ADEV,ANTD) - ADEV Module Arm - Rig - Arm Move Limitation - Allowable Radius for Arm Down to the Plus Area	NA	25.50
				5.1. System Config Parameter, Spinners (ADEV,ANTD) - ADEV Module Arm - Rig - Arm Move Limitation - Allowable Radius for Arm Down to the Minus Area	NA	163.00
				5.1. System Config Parameter, Spinners (ADEV,ANTD) - ANTD Module Arm - Left - Arm Move Limitation - Allowable Radius for Arm Down to the Plus Area	NA	44.00
				5.1. System Config Parameter, Spinners (ADEV,ANTD) - ANTD Module Arm - Left - Arm Move Limitation - Allowable Radius for Arm Down to the Minus Area	NA	151.00
				6. System Config Parameter, Ovens - Block 11,12,13.14.15.16 PR Block, [CPHP] Chilling High Precision Hot Plate Pro - Oven Control Parameter - United Oven 3Pin Parameter - Initial Velocity - Pin HP Wafer Put Drive Low Speed	NA	0.75

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Software FPD Revision History

Date	Rev.	Approval		Location	Old	New
		Intel	TEL			
12/04/2020	1.07	K.Proctor	Red	3.SYSTEM (Sub-FAB) - STHC CHILLER FLOW RATE SETTING CHART For TBF CGCH and HMDS Tank TCW modified tool	NA	Tool Setting / Tolerance / TEL Std. CH0 : 2.0 / 1.8 ~ 2.2 / 2.0±0.2 CH1 : 2.0 / 1.8 ~ 2.2 / 2.0±0.2 CH2 : 2.0 / 1.8 ~ 2.2 / 2.0±0.2 CH3 : 4.0 / 3.3 ~ 4.7 / 4.0±0.7 CH4-1 : 25.0 / 24.5 ~ 25.5 / 25.0±0.5 CH4-2 : 8.0 / 7.3 ~ 8.7 / 8.0±0.7 CH4-3 : 4.0 / 3.3 ~ 4.7 / 4.0±0.7 CH5-1 : 49.0 / 46.0 ~ 52.0 / 49.0±3.0 CH5-2 : 13.0 / 12.3 ~ 13.7 / 13.0±0.7
				3. System Configuration Parameter, System - System - Monitoring Parameter Chiller BYPASS1 / Chiller BYPASS2 / Chiller BYPASS3 / Chiller BYPASS4 Table for Chanel No. / Line No. / Set Value [TBF CGCH and HMDS Tank TCW modified tool]	NA	Chanel No / Line No / Set Value BYPASS-1 : 3 / 3 / 4.00 BYPASS-2 : 4 / 6 / 4.00 BYPASS-3 : 5 / 8 / 49.00 BYPASS-4 : 5 / 8 / 13.00
				5.1. System Config Parameter, Spinners (ADEV, ANTD) Block Arm - Left/ Block Arm - Right/ Module Arm - Left - Spinner Arm Control Da Arm Move Limitation - Allowable Radius for Arm Down to the Plus Area	NA	ADEV Module Arm - Left : 59.00 ADEV Module Arm - Right : 25.50 ANTD Module Arm - Left : 44.00
				5.1. System Config Parameter, Spinners (ADEV, ANTD) Block Arm - Left/ Block Arm - Right/ Module Arm - Left - Spinner Arm Control Da Arm Move Limitation - Allowable Radius for Arm Down to the Minus Area	NA	ADEV Module Arm - Left : 159.00 ADEV Module Arm - Right : 163.00 ANTD Module Arm - Left : 151.00
				5.3. System Config Parameter, Spinners (PIR/SRS) - Module Arm - Left Spinner Arm Control Data - Home Position - Y - Position	0	-2900
				6. System Config Parameter, Ovens Block 11,12,13.14.15.16 PR Block, [CPHP] Chilling High Precision Hot Plate Proc Oven Control Parameter - Initial Velocity - Pin HP Wafer Put Drive Low Speed	NA	0.75
				6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block [CGCH] Chilling General-Purpose Hot Plate Process Station with Cover Heater Monitoring Parameter - Cool Arm Chilly Water temp.*	NA	Valid,Invalid : Valid Measured Data ID : Cool Arm Chilly Water temp. Recipe Setting Method : System recipe Temperature Control Method : Tmp ctl ON Recipe Verification Range Lower Limit : 20.00 Recipe Verification Range Upper Limit : 25.00
				6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block [CGCH] Chilling General-Purpose Hot Plate Process Station with Cover Heater Monitoring Parameter - Cool Arm Chilly Water temp.* - Controller TM206-CHILL	NA	Controller ID : TM206-CHILLER Channel No : 4 Monitoring Type : Use point read Control Method : Standard Use Point Offset : 0 Band Monitoring Method at Process Start : Normal Band Monitoring Invalid Time at Process Start : 0.0 Band Monitoring Determination Method during Processing : No monitor Band Monitoring Determination Time during Processing : 0.0 Band Monitoring Value during Processing : 0.00 Pump Frequency : Tool Specific Initial Data : 23.00 Overtemperature : 40.00 Setting Determination Time : 5.0 Setting Time-out Time : 3600.0 Offset Setting Meathod : Control setting Offset : 0
				6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block [CGCH] Chilling General-Purpose Hot Plate Process Station with Cover Heater Monitoring Parameter - C/A cooling water flow rate*	NA	Valid,Invalid : Valid Measured Data ID : C/A cooling water flow rate Recipe Setting Method : Local Temperature Control Method : Tmp ctl ON Recipe Verification Range Lower Limit : 0.00 Recipe Verification Range Upper Limit : 35.00
				6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block [CGCH] Chilling General-Purpose Hot Plate Process Station with Cover Heater Monitoring Parameter - C/A cooling water flow rate* - Controller TM206-CHILLER	NA	Controller ID : TM206-CHILLER Channel No : Use point read Offset Setting Meathod : Control setting Line No : 5 Set Value : 8.00 Warning Range Lower Limit 100.00 Warning Range Upper Limit 100.00 Stop Range Lower Limit 100.00 Stop Range Upper Limit : 100.00 Offset : 0.00

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Date	Rev.	Approval		Location	Old	New
		Intel	TEL			
12/04/2020	1.07	K.Proctor	Red	6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block [CADH] Chilling Adhesion Process Station for BARC tool - Monitoring Parameter HMDS Bubbler Tank temp.*	NA	Valid,Invalid : Valid Measured Data ID : HMDS Bubbler Tank temp. Recipe Setting Method : System Recipe Temperature Control Method : Tmp ctl ON Recipe Verification Range Lower Limit : 20.00 Recipe Verification Range Upper Limit : 25.00
				6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block [CGCH] Chilling General-Purpose Hot Plate Process Station with Cover Heater Monitoring Parameter - HMDS Bubbler Tank temp.* - Controller TM206-CHILLER	NA	Controller ID : TM206-CHILLER Channel No : 0 Monitoring Type : Use point control Control Method : Standard Use Point Offset : Tool Specific Band Monitoring Method at Process Start : Normal Band Monitoring Invalid Time at Process Start : 0.0 Band Monitoring Determination Method during Processing : No monitor Band Monitoring Determination Time during Processing : 0.0 Band Monitoring Value during Processing : 0.00 Pump Frequency : Tool Specific Initial Data : 22.00 Overtemperature : 40.00 Setting Determination Time : 5.0 Setting Time-out Time : 3600.0 Offset : 0
				6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block [CADH] Chilling Adhesion Process Station for BARC tool - Monitoring Parameter HMDS Temp. Control flow rate*	NA	Valid,Invalid : Valid Measured Data ID : HMDS Temp. Control flow rate Recipe Setting Method : Local Temperature Control Method : Tmp ctl ON Recipe Verification Range Lower Limit : 0.00 Recipe Verification Range Upper Limit : 35.00
				6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block [CGCH] Chilling General-Purpose Hot Plate Process Station with Cover Heater Monitoring Parameter - HMDS Temp. Control flow rate* - Controller TM206-CHIL	NA	Controller ID : TM206-CHILLER Channel No : 0 Line No : 0 Set Value : 2.00 Warning Range Lower Limit 100.00 Warning Range Upper Limit 100.00 Stop Range Lower Limit 100.00 Stop Range Upper Limit : 100.00 Offset : 0
				12. EC Display Overview - Screen Tree - RUN - Wafer List	NA	Add
				14. EC Display Overview - Screen Tree - RUN - Consecutive exec. Job start	Oparator	NA
				14. EC Display Overview - Screen Tree - RUN - Automatic adjustment job start	NA	Add
				14. EC SYSTEM Setting - Item Level Settings - RUN - Wafer List	NA	Operator
				14. EC SYSTEM Setting - Smart Bypass Setting - Smart Bypass Transfer Option Set Options - Automatic bypass at PJ start	Invalid	Valid
02/05/2021	1.08	K.Proctor	Red	5.2. System Config Parameter, Spinners(COT/BCT/ITC) - Dispense Monitoring Cont NZL/BATH CLN R# - Lower Limit Warning Level	15.00%	20.00%
				6. System Config Parameter, Ovens - Block 11,12,13.14.15.16 PR Block [CPHP] Chilling High Precision Hot Plate Process Station Monitoring Parameter - Plate temp. - Control Table Data List	Temp Range1 ~ Temp Range4	Temp Range1 ~ Temp Range19 (Add 50C,70C,75C,80C,85C,90C,95C,105C,110C,115C,120C,130C,135C,140C,145C settings)
				6. System Config Parameter, Ovens - Block 11.12.13.14.15.16 PR Block, [SCPL] Slim Chill Plate Process Station - Fork Simultaneous Swapping Level	1-2	1-2* * 1*-33,34 Invalid
				6. System Config Parameter, Ovens - Block 11.12.13.14.15.16 PR Block, [SCPL] Slim Chill Plate Process Station - Monitoring Parameter Plate temp. / Plate Chilly water flow rate - Controller TM206-CHILLER - Plate Chi	Channel No : 4 Line No : 5	Channel No : See Table Line No : See Table
				6. System Config Parameter, Ovens - Block 11.12.13.14.15.16 PR Block, [SCPL] Slim Chill Plate Process Station - Monitoring Parameter Plate temp. / Plate Chilly water flow rate - Controller TM206-CHILLER Table - Plate Chilly Water temp.	"Tmp ctl ON" or "Tmp ctl OFF"	Delete
				6. System Config Parameter, Ovens - Block 11.12.13.14.15.16 PR Block, [SCPL] Slim Chill Plate Process Station - Monitoring Parameter Plate temp. / Plate Chilly water flow rate - Controller TM206-CHILLER Table - Line No.	NA	Add
				14. EC SYSTEM Setting - Equipment mode change 2 - Transfer Stop Monitoring for	NA	Invalid
03/01/2021	1.09	K. Proctor	C.Gertz	3. Sys Config(Sys) - Monitoring Parameter 6. Sys Config (Oven)	ADD	Initial Oven SA [PBR] Several Additions
				4. sys Config(Arm) - Transfer Arm Control Parameter All arrm speed except HCRA	100%	50%
				PRA Multistep, PRA offset data	ADD	Added CVVP / CXHN
				8. System Prm - Basic Transfer Control The Status of wafer whose position is corected by temporary wafer placement	ADD	Invalid Setting
				Bare-Si Thickness Unit	ADD	NA
				14.EC SYSTEM Setting	Cahnge, Cahnge2	Typo Change (Change, Change 2)

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		Intel	TEL			
03/26/21	1.10	K. Procto	Red	4. Sys Config(Arm) - Block 1 CS Block - 1-0/1-20 HCSB Arm - Position Data - Auto Flow Adjustment X-axis Offset	NA	0pulse
				4. Sys Config(Arm) - Block 1 CS Block - 1-0/1-20 HCSB Arm - Position Data - Auto Flow Adjustment Z-axis Offset	NA	19550pulse
				4. Sys Config(Arm) - Block 1 CS Block - 1-0/1-20 HCSB Arm - Position Data - Auto Flow Adjustment Th-axis Offset	NA	0pulse
				4. Sys Config(Arm) - Block 1 CS Block - 1-0/1-20 HCSB Arm - Transfer Arm Contr - Auto Flow Adjustment Move Module Speed	NA	X1:100%, X2:100% Z:100%, Th:100%
				4. Sys Config(Arm) - Block 1 CS Block - 1-0/1-20 HCSB Arm - Transfer Arm Contr - Auto Flow Adjustment Wafer In/Out Speed	NA	X1:100%, X2:100% Z:100%, Th:100%
				4. Sys Config(Arm) - Block 11,12,13,14,15,15 PR Block - 11-0/12-0/13-0/14-0/15-0 - Transfer Arm Control Parameter - Auto Flow Adjustment Move Module Speed	NA	X1:100%, X2:100% Y:100%, Z:100%, Th:100%
				4. Sys Config(Arm) - Block 11,12,13,14,15,15 PR Block - 11-0/12-0/13-0/14-0/15-0 - Transfer Arm Control Parameter - Auto Flow Adjustment Wafer In/Out Speed	NA	X1:100%, X2:100% Y:100%, Z:100%, Th:100%
				5.1. System Config Parameter, Spinners (ADEV) - DEV6(Local Arm) / DEV6 Sub L / RINSE1 / BACK RINSE - CRF Setting - Circulation Liquid Vent Monitoring Time	30sec	60sec
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) - RRC NOZZLE1 / DRN C / NZL/BATH CLN R# / NZL/BATH CLN CMN / NZL/BATH CLN ALL - CRF Setting - Circulation Liquid Vent Monitoring Time	30sec	60sec
				8. System Parameter - Others - Belt Break Detection for ASTR Plate	NA	Valid
				8. System Parameter - Equipment State Management - Resource Logging Interval	NA	60sec
				12.FOUP Control Parameter	NA	Add
04/28/21	1.11	K. Procto	Red	Cover - Software/Sub Operation Panel version	All tools expect PBR Software version : 500.0.61 Sub Operation Panel version : 5.32.13	Only TBF tools Software version : 500.0.62 Sub Operation Panel version : 5.32.14
				6. System Config Parameter, Ovens - Block 11,12,13.14.15.16 PR Block, [CPHP] - Monitoring Parameter - Control Table Data List - Accumulated Threshold Value	70.00 degC : 20.00 75.00 degC : 23.33 80.00-81.00 degC : 26.67 85.00 degC : 30.00 90.00 degC : 33.33 95.00-97.00 degC : 36.67 100.00 degC : 40.00 105.00 degC : 44.00 110.00 degC : 48.00 115.00 degC : 52.00 120.00 degC : 56.00 125.00 degC : 60.00 130.00 degC : 64.00 135.00 degC : 68.00 140.00 degC : 72.00 145.00 degC : 76.00 150.00 degC : 80.00	70.00 degC : 34.00 75.00 degC : 37.00 80.00-81.00 degC : 40.00 85.00 degC : 43.00 90.00 degC : 47.00 95.00-97.00 degC : 51.00 100.00 degC : 53.00 105.00 degC : 59.00 110.00 degC : 63.00 115.00 degC : 68.00 120.00 degC : 73.00 125.00 degC : 79.00 130.00 degC : 84.00 135.00 degC : 89.00 140.00 degC : 95.00 145.00 degC : 101.00 150.00 degC : 106.00
				6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block,[CGCH] - Monitoring Parameter - Control Table Data List - Accumulated Threshold Value	170.00 degC : 35.00 190.00 degC : 46.00 205.00 degC : 55.00 225.00 degC : 72.50 250.00 degC : 110.00	170.00 degC : 20.00 190.00 degC : NA(Delete) 205.00 degC : 30.00 225.00 degC : 50.00 250.00 degC : 85.00
				8. System Parameter - FOUP Exchanger - Option Carrier to transfer to sender from receiver in High speed CSB	NA	Invalid
				8. System Parameter - FOUP Exchanger - Option Destination XSTK optimization	NA	Valid
				15. EC SYSTEM Setting - FEX In/Out Setting	1-51 : XLD 1-52 : XLD 1-53 : XULD 1-54 : XULD	1-51 : XULD 1-52 : XULD 1-53 : XLD 1-54 : XLD
05/27/2021	1.12	K. Procto	Kono	5.2. System Config Parameter, Spinners (COT/BCT/ITC) - RRC NOZZLE1 / DRN C / NZL/BATH CLN R# / NZL/BATH CLN CMN / NZL/BATH CLN ALL - Interval for Circulation	Valid, Invalid=Invalid Time for Circulation Recovery=60 Time for Continuous Circulation=60	Valid, Invalid=Valid for ITC Time for Circulation Recovery=1,200 for ITC Time for Continuous Circulation=15 for ITC
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) - RRC NOZZLE1 / DRN C / NZL/BATH CLN R# / NZL/BATH CLN CMN / NZL/BATH CLN ALL - CRF Setting - Guarantee Time of Continuous Circulation	60	0 for ITC
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) - Monitoring Parameter - Controller TM206-CHILLER / THC - Cup humidity - Source Value Monitoring Ba	20	10
				5.3. System Config Parameter, Spinners (PIR/SRS) - Spin Motor Parameter - Spin Motor Control Data - Maximum Speed	2000	3000

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		Intel	TEL			
06/30/2021	1.13	K. Procto	Red	3. System Configuration Parameter, System - Monitoring Parameter - - Table for Chanel No. / Line No. / Set Value - [TBF]	---	Deleted before TCW modify setting li
				3. System Configuration Parameter, System - Monitoring Parameter - - Table for Chanel No. / Line No. / Set Value - [TAP/TNP/TAF/TAW/TAJ] - BYPA	6.00	2.00
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) - Monitoring Parameter - - Controller TM206-CHILLER / THC - BCT/COT/ITC Temp. Control flow rate - Se	100.00	2.00
				6. System Config Parameter, Ovens - Block 14.15.16 PR Block, [CPHP] - Monitorir - Controller TM206-CHILLER - Cool Arm Chilly Water flow. - Temperature Contr	Tmp ctl ON	See Table
				6. System Config Parameter, Ovens - Block 14.15.16 PR Block, [CPHP] - Monitorir - Controller TM206-CHILLER - Cool Arm Chilly Water flow. - Set Value	100.00	7.2
				6. System Config Parameter, Ovens - Block 14.15.16 PR Block, [CPHP] - Monitorir - Controller TM206-CHILLER - Table for C/A cooling water flow rate - Temperature Control Method	NA	Add
				6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block, [CGCH] - Monit - Controller TM206-CHILLER - Cool Arm Chilly Water temp. - Temperature Contr	Tmp ctl ON	Tmp ctl OFF
				6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block, [CGCH] - Monit - Controller TM206-CHILLER - C/A cooling water flow rate. - Temperature Contr	Tmp ctl ON	See Table
				6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block, [CGCH] - Monit - Controller TM206-CHILLER - Table for C/A cooling water flow rate - Temperature Control Method	NA	Add
				6. System Config Parameter, Ovens - Block 11.12.13.14.15.16 PR Block, [SCPL] - Monitoring Parameter - Controller TM206-CHILLER - Plate Chilly water flow rat	100	See Table
				6. System Config Parameter, Ovens - Block 11.12.13.14.15.16 PR Block, [SCPL] - Monitoring Parameter - Controller TM206-CHILLER - Table for Plate Chilly wat - Set Value	NA	Add
				6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block, [CADH] / Block 11.12.13 PR Block, [CADH] - Monitoring Parameter - HMDS Bubbler Tan - Temperature Control Method	Tmp ctl ON	See Table
				6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block, [CADH] / Block 11.12.13 PR Block, [CADH] - Monitoring Parameter - HMDS Bubbler Tan -Table for Temperature Control Method	NA	Add
				8. System Parameter - Basic Transfer Control - Wait Time for Wafer Transfer to Exposure System	40	30
				8. System Parameter - Basic Transfer Control - Wait Time for Wafer Transfer from Exposure System	40	30
08/10/2021	1.14	K. Procto	Red	Cover - Software/Sub Operation Panel version/Teaching Version/Temperature/Tempe	TBF Software version : 500.0.62 IMM/EUV Software version : 500.0.61 Teaching Version : 1.39.0 Temperature Version : 1.35	All tools expect PBR Software version : 500.0.63 Teaching Version : 1.41.0 Temperature Version : 1.40.0
				3. System Configuration Parameter, System - Monitoring Parameter - - Table for Chanel No. / Line No. / Set Value - [TAP/TNP/TAF/TAW/TAJ] - BYPA	6.00	2.00
				3. System Configuration Parameter, System - N2 Ring Purge flow1 / N2 Ring Purge flow2 - Controller Analogue Sensor - Band Monitoring Refernce Value, Warning Range Lower Limit, Stop Range Uppe	NA	Add Table
				4. System Configuration Parameter, Arm - Block 11, 12, 13, 14, 15, 16 PR Block - Transfer Arm Control Parameter	X1/X2 Wafer OUT Speed: 100% X1/X2 Wafer IN Speed: 100% Y/Th/Z Movement between Modules Speed: 100%	X1/X2 Wafer OUT Speed: 90% X1/X2 Wafer IN Speed: 90% Y/Th/Z Movement between Modules Speed: 80%
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) - RRC NOZZLE1 / DRN C / NZL/BATH CLN R# / NZL/BATH CLN CMN / NZL/BATH CLN ALL - CRF Setting - Guarantee Time of Continuous Circulation	60	0 for COT
				6. System Config Parameter, Ovens - Block IFB Block, [ICPL] Slim Chill Plate Proc - Monitoring Parameter - Plate temp. - Controller TM206-CHILLER	NA	RTCtrl*: Valid Slope*: Tool Specific Intercept*: Tool Specific Threshold*: 0.05
				6. System Config Parameter, Ovens - Block IFB Block, [RSM] Resuming Stage	NA	Add
				6. System Config Parameter, Ovens - Block IFB Block, [RSMC] Resuming Chill Pla	NA	Add
				8. System Parameter - Others - Backflow Prevention during Pump Operation to Multi-tank Supply System	NA	Invalid
				8. System Parameter - Others - Change in Arm Data Display on Spinner Recipe Edit Screen* (New UI only)	NA	Invalid
				19. CCV Setting	NA	Add
09/13/2021	1.15	K. Procto	Red	5.2. System Config Parameter, Spinners (COT/BCT/ITC) - Dispense Parameter - Sha - Resist# Supply System [Tool Specific] - Table 1	EUV TCT : 25wafres EUV BCT :50wafers EUV COT :100wafers	EUV COT/ITC : 100wafres
				6. System Config Parameter, Ovens - Block IFB Block, [ICPL] Interface Chill Plate - Oven Control Parameter - Up Position / Heat Position	NA	Module Specific
				10. BST Control Parameter - Block 30 IF Block, BST* / BST+** - BST Motor Para - Spin Motor Info. - BST+ related parameter	Without "*" and comment	Add *Only BST+ module present
				13. EC Display Overview - Screen Tree - LOG - Linked Litho comm. log*	NA	Add
				13. EC Display Overview - Screen Tree - LOG - CameraControl&Viewer communica	NA	Add
				13. EC Display Overview - Screen Tree - MAINTENANCE - CameraControl&Viewer channel parameter	NA	Add
				13. EC Display Overview - Screen Tree - ONLINE SETTING - Linked Litho Channe	NA	Add
				14. EC MAINTENANCE Setting - CameraControl&Viwer channel parameter	NA	Add
				15. EC ON-LINE Setting - Linked Litho Chanel Parameter*	NA	Add
				16. EC SYSTEM Setting - Item Level Settings - LOG - Linked Litho comm. log**	NA	User service
				16. EC SYSTEM Setting - Item Level Settings - LOG - CameraControl&Vviewer co	NA	User service
				16. EC SYSTEM Setting - Item Level Settings - MAINTENANCE - CameraControl&Viewer channel parameter	NA	User service
				16. EC SYSTEM Setting - Item Level Settings - ONLINE SETTING - Linked Litho Channel Parameter**	NA	User service

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11/08/2021	1.16	K. Procto	Red	Cover - Software/Sub Operation Panel version/Teaching Version/Temperature/Tempe	All tools expect PBR Software version : 500.0.63 Teaching Version : 1.41.0 Temperature Version : 1.40.0	All tools expect PBR Software version : 500.0.65 / 500.1.9* *Apply to New UI tools Teaching Version : 1.43.0 Temperature Version : 1.45.0
				4. System Configuration Parameter, Arm - Block 1 CS Block - 1-0 / 1-20 HCSB Arm - Position Data - Auto Flow Adjustment Z-axis Offset*	19550pulse	19143pulse
				5.1. System Config Parameter, Spinners (COT/BCT/ITC) - Local Nozzle - E.B.R.1 - - Dispense Monitoring Control Data - Flow Rate during Dispense Process* - Invalidated Flow Rate Monitoring Times during Dispense Process	NA	2 Times
				5.1. System Config Parameter, Spinners (COT/BCT/ITC) - Local Nozzle - E.B.R.1 - - Dispense Monitoring Control Data - Flow Rate during Dispense Process* - Upper Limit Error Level for Flow Rate during Dispense Process	NA	40.00%
				5.1. System Config Parameter, Spinners (COT/BCT/ITC) - Local Nozzle - E.B.R.1 - - Dispense Monitoring Control Data - Flow Rate during Dispense Process* - Lower Limit Error Level for Flow Rate during Dispense Process	NA	30.00%
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) - - Block 11.12.13 PR Block for IMM tool / Blcok 12.13 PR Block for EUV tool - Dispense Parameter - Shared Nozzle - RESIST NOZZLE# - Pump18 - Filter Vent	300	300 for BARC,EUV 600 for Immersion
				8. System Parameter - Others - Automatic ESD Collection	Invalid	Valid
				8. System Parameter - Others - Option Switch container number of Chemical usage m	NA	Valid
				8. System Parameter - Wafer Collection - Real-time Save Recovery Info	Invalid	Valid
				8. System Parameter - Monitoring - Ramp down delay detect*	NA	99 sec
				8. System Parameter - Special Transfer Control - Number of Waiting Cycles for Transfer of Transition Between PRA**	NA	1 cycle
				8. System Parameter - Special Transfer Control - Option Mutual Exclusion of RIA and PJ which Use Same Module	NA	Valid(Nozzle Purge)
				13. Unified UI app screen (New UI)*	NA	Add
				14. Unified UI app Maintenance Setting(New UI)*	NA	Add
				15. Unified UI app Online Setting(New UI)*	NA	Add
				16. EC SYSTEM Setting - Equipment mode change 2 - Transfer Stop Monitoring	BARC Tools: Valid/300sec Imm and EUV tools: Inalid	Valid/1200sec
				16. EC SYSTEM Setting - IP address - Ingenio TL	172.17.206.116	10.10.10.14
				16. Unified UI app SYSTEM Setting(New UI)*	NA	Add
12/17/2021	1.17	K. Procto	Red	5.1. System Config Parameter, Spinners (ANTD) - Dispense Parameter - Local Nozzl - DEV6(Local Arm) / DEV6 Sub Local / RINSE1 / BACK RINSE - Interval for Circ	Invalid	Valid
				5.1. System Config Parameter, Spinners (ANTD) - Dispense Parameter - Local Nozzl - DEV6(Local Arm) / DEV6 Sub Local / RINSE1 / BACK RINSE - CRF Setting	60	0
				5.1. System Config Parameter, Spinners (ANTD) - Dispense Parameter - Local Nozzl - NTD FILTDRAIN1* /3* /5* - Interval for Circulation	Invalid	Valid
				5.1. System Config Parameter, Spinners (ANTD) - Dispense Parameter - Local Nozzl - NTD-R FILTDRAIN1* /2*/ 3* - Interval for Circulation	Invalid	Valid
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) - Block 13.14.15.16 PR Block for BARC tool / Block 11.12.13 PR Block for IMM / Blcok 12.13 PR Block for EUV tool - Dispense Parameter - Shared Nozzle - Pump - Filter Vent Interval	300 for BARC,EUV 600 for Immersion	600
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) - RRC NOZZLE1 / DRN C / NZL/BATH CLN R# / NZL/BATH CLN CMN / NZL/BATH CLN ALL - Interval for Circulation	COT/BCT: Invalid	COT/BCT: Valid
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) - Dispense Monitoring Con / NZL/BATH CLN R# / NZL/BATH CLN CMN / NZL/BATH CLN ALL - CRF Setting - Guarantee Time of Continuous Circulation	BCT: 60 COT/ITC: 0	BCT: 0 COT/ITC: 0
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) - RRC NOZZLE1 / DRN C - RRC FILTDRAIN1/2 - Interval for Circulation	RRC FILTDRAIN1: Invalid	RRC FILTDRAIN1: Valid
				8.System Parameter - Others - Option Advanced Wafer Level Monitor	Invalid	Valid* Does not exist on PBR
				8.System Parameter - Exposure Interface - Exposure APR Setting	***Valid for ASML immersion links, Invalid for others	***Valid for all ASML links, Invalid for others
				8.System Parameter - FOUP Exchanger - Option Carrier to transfer to sender from receiver in High speed CSB	Invalid	Valid
				21.FD Manager Setting	NA	Add
				22.PM Reminder	NA	Add

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02/10/2022	1.18	K. Procto	Red	Cover - Software/Sub Operation Panel version/Teaching Version/Temperature/Tempe	All tools expect PBR Software version : 500.0.65 / 500.1.9* *Apply to New UI tools Sub Ope Version : 5.32.14 Teaching Version : 1.43.0 Temperature Version : 1.45.0	All tools expect PBR Software Version : 500.1.10.100 Sub Operation Panel Version : 5.32.17 Teaching Version : 1.46.0 Temperature Version : 1.44.0
				5.1. System Config Parameter, Spinners (ADEV) - Block 14,15,16 PR Block, Developers [14-1/2/3] - [16-1/2/3] for 9x9 PTD - Dispe - Local Nozzle - DEV6(Local Arm) = MGP Nozzle, DEV6(Local Arm), DEV6 Sub - DEV.SOLU.1 Supply System - Supply Valve Close Delay Time	NA	0.10 sec
				5.1. System Config Parameter, Spinners (ANTD) - Dispense Parameter - Local Nozzle - DEV6(Local Arm) / DEV6 Sub Local / RINSE1 / BACK RINSE - N.T.DEV SOLUTION1 Supply System - Supply Valve Close Delay Time	NA	0.10 sec
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) - RRC NOZZLE1 / DRN CASE CLEAN / NZL/BATH CLN R# / NZL/BATH CLN / NZL/BATH CLN ALL - Solvent 1 Supply System - Supply Valve Close Delay Ti	NA	0.10 sec
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) - E.B.R.1 / BACK RINSE1 / BEVEL RINSE V2 / EXH DUCT CLEAN - Solvent 1 Supply System - Supply Valve Close Delay Time	NA	0.10 sec
				8.System Parameter - Others - Option Upper Limit of Spin Speed When Dispensing with IE NOZZLE	2000 rpm	0 rpm
				8.System Parameter - Others - Option Process Suspension when PCS Refilling is Impossible	NA	Valid
				8.System Parameter - Others - Option Continuation of PCS Process during Source Trouble	NA	Valid
04/26/2022	1.19	K. Procto	John V Red	4. System Configuration Parameter, Arm - 1-10 FT Atm - Transfer Arm Control Para - X1 Normal Speed (No Carrier) - Sentence	NA	*Normal speed(No Carrier) setting value x1.8 in internal parameter.(actually working 180%).
				6. System Config Parameter, Ovens - Block 11.12.13.14.15.16 PR Block, [CVV] Chilling Very High Temperature Hot Plate with VE Chamber Process Station Controller Analogue sensor Stop Range Lower Limit / Upper Limit (Outer EXH)	500	10
				6. System Config Parameter, Ovens - Block 11.12.13.14.15.16 PR Block, [CVV] Chilling Very High Temperature Hot Plate with VE Chamber Process Station Controller Analogue sensor Stop Range Lower / Upper Limit (Center EXH OPEN)	500	8
				6. System Config Parameter, Ovens - Block 11.12.13.14.15.16 PR Block, [CVV] Chilling Very High Temperature Hot Plate with VE Chamber Process Station Controller Analogue sensor Stop Range Lower / Upper Limit (Center EXH CLOSED	NA	Add for center exhaust damper CLOSED
				6. System Config Parameter, Ovens - Block 11.12.13.14.15.16 PR Block, [SCPL] Slim Chill Plate Process Station - Table for Temperature Control Method Configuration / Module / Plate temp. / Plate Chilly water flow rate	NA	Add for PBR tool
				6. System Config Parameter, Ovens - Block 11.12.13.14.15.16 PR Block, [SCPL] Slim Chill Plate Process Station - Table for Channel No. / Monitor Type / U Initial Data / Source Value Monitoring Valid / Source Value Monitoring Band / Line	NA	Add for PBR tool
				6. System Config Parameter, Ovens - Block IFB Block, [ICPL] Interface Chill Plate - Monitoring Parameter - Plate Chilly water flow rate - Controller TM206-CHILLE	100.00	6.20
				6. System Config Parameter, Ovens - Block IFB Block, Block IFB Block, [EIF] Exp	NA	Add
				16. Unified UI app SYSTEM Setting(New UI)* - Local Secutity - Item Level Setting	NA	Vendor Service has access to all items and menus.
				16. Unified UI app SYSTEM Setting(New UI)* - Local Secutity - Item Level Setting - Table for item level(Content tab)	System - Version Maintainer: Admit Operator: Admit System - Shoutdown Run - initialize Maintainer: Deny Run - Process Start (MNT) Maintainer: Deny Run - Process Start (MNT) Maintainer: Deny Maintenance - Exclude Module From Wafer Transfer Maintainer: Admit Maintenance - Wafer Count Adjustment Maintainer: Deny	System - Version Maintainer: Deny Operator: Deny System - Shutdown Run - initialize Maintainer: Admit Run - Process Start (MNT) Maintainer: Admit Run - Process Start (MNT) Maintainer: Admit Maintenance - Exclude Module From Wafer Transfer Maintainer: Deny Maintenance - Wafer Count Adjustment Maintainer: Admit

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06/03/2022	2.0	K. Procto	Sato Terry	Cover - Software/Sub Operation Panel version/Teaching Version/Temperature/Tempe	ProZ System & ProZ Immersion System & ProZ EUV System All tools expect PBR Software Version : 500.1.10.100 Sub Operation Panel Version : 5.32.17 Teaching Version : 1.46.0 Temperature Version : 1.44.0	ProZ System & ProZ Immersion System & ProZ EUV System & ProZ KrF System All tools expect PBR Software Version : 500.1.12.201 Sub Operation Panel Version : 5.32.17 Teaching Version : 1.46.0 Temperature Version : 1.44.0
				5.1. System Config Parameter, Spinners (ADEV) - Dispense Parameter - Local Nozzle - BACK RINSE - Dispense Monitoring Control Data - Dummy Dispense Flow Rate Monitoring Valid	Valid	Invalid
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) - Block Arm - Left / Module Arm - Left/Right	NA	Block Arm - Right Rail No. : Lower Rail Arm Presence : Exist Middle Wait : Valid Auto Bath Cleaning : Valid Waiting time after dispense stop during DFT : 0.0 sec Nozzle Type : Resist Nozzle Y-axis Driver Type : Motor Drive Z-axis Driver Type : 0.004000000 Z-axis Pulse Rate : 0.003000000 IN, OUT Speed : 115000 IN, OUT Acceleation : 187500 IN, OUT Deceleration : 187500 In, OUT Speed(Outside the Cup) : 0 In, OUT Acceleration(Outside the Cup) : 0 In, OUT Deceleration(Outside the Cup) : 0 UP, DOWN Speed : 40000 UP,DOWN Acceleation : 200000 UP,DOWN Deceleration : 200000 Maintenance Speed : 50% Starting point search position from limit : 103875, *90000 NMA Adjustment Offset : 3.00
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) - RESIST NOZZLE# - Nozzle information - Light Setting - Liquid Column Area Setting - Liquid Level Area Setting** - Dispense Inspection Settings - Liquid Level Inspection Settings** - PSB - Liquid Level Inspection Settings** - DFT - Nozzle Inspection Settings - Inspection at Dispensing - Dispense Inspection Alarms (Valid/Invalid) - Liquid Level Inspection Alarms (Valid/Invalid) - Nozzle Inspection Alarms (Valid/Invalid)** - Consecutive Occurrence Alarms (Valid/Invalid)** - Inspection after DFT Formation - Liquid Level Inspection Alarms (Valid/Invalid) - Nozzle Inspection Alarms (Valid/Invalid) - Inspection after Pre-PJ Dummy Dispensing - Liquid Level Inspection Alarms (Valid/Invalid)** - Liquid Level Inspection Alarms (Valid/Invalid)**	N/A	Add NMA2.0
				6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block, [CGCH] Chilling General-Purpose Hot Plate Proces - Monitoring Parameter - Controller Analogue sensor - Warning Range Lower Limit	3.00	2.70
				6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block, [CGCH] Chilling General-Purpose Hot Plate Proces - Monitoring Parameter -Controller Analogue sensor - Warning Range Upper Limit	3.00	2.70
				6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block, [CGCH] Chilling General-Purpose Hot Plate Proces - Monitoring Parameter - Controller Analogue sensor - Stop Range Lower Limit	500.00	3.00
				6. System Config Parameter, Ovens - Block 13.14.15.16 PR Block, [CGCH] Chilling General-Purpose Hot Plate Proces - Monitoring Parameter - Controller Analogue sensor - Stop Range Upper Limit	500.00	3.00
				8. System Parameter - Basic Transfer Control - Cascade Process for High Speed Temperature Change	Valid	Valid(Wait Just Before Spin)
				20.2 CCV Setting(NMA2.0)	NA	Add
				6. System Config Parameter, Ovens - Block 11,12,13,14,15,16 PR Block, [CPHP] Chilling High Precision Hot Plate Pr - Monitoring Parameter - Controller Analogue sensor - Warning Range Lower Limit	3.00	2.50
				6. System Config Parameter, Ovens - Block 11,12,13,14,15,16 PR Block, [CPHP] Chilling High Precision Hot Plate Pr - Monitoring Parameter -Controller Analogue sensor - Warning Range Upper Limit	3.00	2.50
				6. System Config Parameter, Ovens - Block 11,12,13,14,15,16 PR Block, [CPHP] Chilling High Precision Hot Plate Pr - Monitoring Parameter - Controller Analogue sensor - Stop Range Lower Limit	500.00	3.00
				6. System Config Parameter, Ovens - Block 11,12,13,14,15,16 PR Block, [CPHP] Chilling High Precision Hot Plate Pr - Monitoring Parameter - Controller Analogue sensor - Stop Range Upper Limit	500.00	3.00
				6. System Config Parameter, Ovens Block 11,12,13,14,15,16 PR Block, [CPHP] Chilling High Precision Hot Plate Proc Block 13,14,15,16 PR Block, [CPHP] Chilling High Precision Hot Plate Process Sta Controller Analogue sensor - Set Value	9.0	9.35
				Add KrF item	---	---

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07/12/2022	2.01	K. Procto	SATO Terry	16. Unified UI app SYSTEM Setting(New UI)*	N/A	dded Table for Global Security settin
				13. Unified UI app screen (New UI)* 14. Unified UI app Maintenance Setting(New UI)* 15. Unified UI app Online Setting(New UI) 16. Unified UI app SYSTEM Setting(New UI)*	creen picture background color is blac	creen picture background color is whi
				8.System Parameter Others Option FIMS Door Interference Detection for High Throughput CSB	N/A	Invalid
				8.System Parameter Others Option Default Value of Recipe Comparison Detailed Condition Setting Function	N/A	Valid
				8.System Parameter Maintenance Option RIA without Arm Blocking Function	N/A	Valid
				5.5.Spinner Parameter Spinner Information Parameter Vent Skip function at RIA	N/A	Valid
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) Block 13.14.15.16 PR Block for BARC tool Block 11.12.13 PR Block for IMM tool / Blcok 12.13 PR Block for EUV tool / Blc Resist# Supply System [Tool Specific] Refill Monitoring Time	30	40
				6. System Config Parameter, Ovens Block 13.14.15.16 PR Block, [CADH] Chilling Adhesion Process Station for BARC Block 11.12.13 PR Block, [CADH] Chilling Adhesion Process Station for Imm tool Block 13.14 PR Block, [CADH] Chilling Adhesion Process Station for KrF tool HMDS Supply System *Dispense Count Upper Limit	N/A	Invalid
				8.System Parameter Others Verification for Dispense Time in Pump Recipe**	N/A	Invalid
				5.1. System Config Parameter, Spinners (ADEV)/5.1. System Config Parameter, Spir CUP EXH Spinner Exhaust Monitoring Control Data High Pressure	40.00	40.00/*39.00 *High altitude setting
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) CUP EXH Spinner Exhaust Monitoring Control Data	High Pressure :'65.00 Low Pressure : '23.00	High Pressure :'65.00/*63.00 Low Pressure : '23.00/*22.00 *High altitude setting
				6. System Config Parameter, Ovens Block 11,12,13,14,15,16 PR Block, [CPHP] Chilling High Precision Hot Plate Proc Block 13,14,15,16 PR Block, [CPHP] Chilling High Precision Hot Plate Process Sta Chamber Exhaust Pres Controller Analogue sensor Set Value	9.35	9.35/*9.10 *High altitude setting
				6. System Config Parameter, Ovens Block 13.14.15.16 PR Block, [CGCH] Chilling General-Purpose Hot Plate Process S Chamber Exhaust Pres Controller Analogue sensor Set Value	16.00	16.00/*15.50 *High altitude setting
				6. System Config Parameter, Ovens Block 12.13.14.15 PR Block, [CVVP] Chilling Very High Temperature Hot Plate w Outer Chamber Exhaust Pres / Chamber Exhaust Pres Controller Analogue sensor Set Value	26.00	26.00/*25.1 *High altitude setting
				6. System Config Parameter, Ovens Block 13.14.15.16 PR Block, [CADH] Chilling Adhesion Process Station for BARC Block 11.12.13 PR Block, [CADH] Chilling Adhesion Process Station for Imm tool Block 13.14 PR Block, [CADH] Chilling Adhesion Process Station for KrF tool Chamber High Exhaust Pres Controller Analogue sensor Set Value	4.70	4.70/*4.50 *High altitude setting
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) CUP EXH Spinner Exhaust Monitoring Control Data	High Pressure(Error Lower Limit) : 45 Low Pressure(Error Upper Limit) : 45	High Pressure(Error Lower Limit) : 45.00/*43.00 Low Pressure(Error Upper Limit) : 45.00/*43.00 *High altitude setting

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07/12/2022	2.01	K. Procto	SATO Terry	5.2. System Config Parameter, Spinners (COT/BCT/ITC) CUP EXH(KrF tool) Spinner Exhaust Monitoring Control Data	High Pressure :65.00 High Pressure(Error Lower Limit) : 45 Low Pressure : 13.00 Low Pressure(Error Upper Limit) : 45	High Pressure :65.00/*63.00 Low Pressure : 13.00/*13.00 High Pressure(Error Lower Limit) : 45.00/*43.00 Low Pressure(Error Upper Limit) : 45.00/*43.00 *High altitude setting
08/24/2022	2.02	K. Procto	John V Terry	6. System Config Parameter, Ovens Block 12.13.14.15 PR Block, [CVIP] Chilling Very High Temperature Hot Plate wit	CVVP	CVIP
				6. System Config Parameter, Ovens Block 12.13.14.15 PR Block, [CVIP] Chilling Very High Temperature Hot Plate wit Control Table Data List [Set Value Lower Limit 350]	Accumulated Threshold = No Input Accumulated Time = No Input	Accumulated Threshold = 150 Accumulated Time = 15
				6. System Config Parameter, Ovens Block 12.13.14.15 PR Block, [CVIP] Chilling Very High Temperature Hot Plate wit Control Table Data List [Set Value Lower Limit 380]	Accumulated Threshold = No Input Accumulated Time = No Input	Accumulated Threshold = 300 Accumulated Time = 15
				6. System Config Parameter, Ovens Block 12.13.14.15 PR Block, [CVIP] Chilling Very High Temperature Hot Plate wit Control Table Data List [Set Value Lower Limit 400]	Accumulated Threshold = No Input Accumulated Time = No Input	Accumulated Threshold = 500 Accumulated Time = 15
				6. System Config Parameter, Ovens Block 12.13.14.15 PR Block, [CVIP] Chilling Very High Temperature Hot Plate wit Control Table Data (Temperature Range 380 - Not Imput)	NA	Added
				6. System Config Parameter, Ovens Block 12.13.14.15 PR Block, [CVIP] Chilling Very High Temperature Hot Plate wit Control Table Data (Temperature Range 450 - Not Input)	Offset = No Input	Offset = Tool Specific
				4. System Configuration Parameter, ARM Block 1 CS Block Position data 1-0 HCRA Z-Axis Maintenance Position	277935	328749
				4. System Configuration Parameter, ARM Block 1 CS Block Position data 1-20 HCRA Z-Axis Maintenance Position	273211	322086
				6. System Config Parameter, Ovens Block IFB Block, [ICPL] Interface Chill Plate Process Station Controller Analogue sensor Set Value	22.2	24.0
				8.System Parameter Exposure Interface	NA	Added Option Linked Litho Advance Function : Invalid
12/21/2022	2.04	K. Procto	Terry	5.2. System Config Parameter, Spinners (COT/BCT/ITC) RRC NOZZLE1 / DRN CASE CLEAN / NZL/BATH CLN R# / NZL/BATH CLN C Solvent1 Supply System/Chemical Installation/Sequence*/Step*	NA	Add
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) RRC NOZZLE1 / DRN CASE CLEAN / NZL/BATH CLN R# / NZL/BATH CLN C Solvent2 Supply System/Chemical Installation/Sequence*/Step*	NA	Add
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) Report of Divided Flow Rate Report of Divided Flow Rate, Valid/Invalid	NA	Valid
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) Report of Divided Flow Rate Chemical Usage Monitoring Report	NA	Valid
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) Local Nozzle Solvent2 Supply System/Chemical Installation/Sequence*/Step*	NA	Add
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) Table for TM206-CHILLER / THC(EUV Tool) 12-1 (COT) - Resist temp - Source Value Monitoring Valid	NA	Invalid
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) Table for TM206-CHILLER / THC(EUV Tool) 12-3 (ITC) - Resist temp - Source Value Monitoring Valid	NA	Invalid
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) Table for TM206-CHILLER / THC(KrF Tool) 13-1 (COT) - Resist temp - Source Value Monitoring Valid	NA	Invalid
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) Table for TM206-CHILLER / THC(KrF Tool) 13-1 (COT) - CUP temp - Source Value Monitoring Valid	NA	Invalid

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12/21/2022	2.04	K. Procto	Terry	5.2. System Config Parameter, Spinners (COT/BCT/ITC) Table for TM206-CHILLER / THC(KrF Tool) 13-1 (COT) - CUP humidity - Source Value Monitoring Valid	NA	Invalid
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) Table for TM206-CHILLER / THC(KrF Tool) 13-3 (COT) - Resist temp - Source Value Monitoring Valid	NA	Invalid
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) Inspection after DFT Formation Liquid Level Height Judgment (Valid/Invalid)	NMA1.0 : Valid NMA2.0 : -	Delete
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) Inspection after DFT Formation Judgment for Nozzle Scratch & Stain (Valid/Invalid)	NMA1.0 : Set Each NMA2.0 : -	Delete
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) Inspection after DFT Formation Inspection after DFT Formation (Valid/Invalid)	NMA1.0 : - NMA2.0 : Valid	NMA1.0 : Valid NMA2.0 : Valid
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) Inspection after DFT Formation Inspection Alarms after DFT Formation (All Inv/Set Each)	NMA1.0 : - NMA2.0 : -	NMA1.0 : Set Each NMA2.0 : Set Each
				8.System Parameter Others Button to Switch Step Data Valid/Invalid on Recipe Edit Screen	NA	Invalid
				8.System Parameter Others Option Chemical Install Assist Function(Main Screen) limited number of concurrent	NA	1
2/3/2023	2.05	K. Procto	Terry	5.2. System Config Parameter, Spinners (COT/BCT/ITC) Resist Interval Return Setting Excessive-Return Preventive Amount	33	999
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) RRC NOZZLE1 / DRN CASE CLEAN / NZL/BATH CLN R# / NZL/BATH CLN C / NZL/BATH CLN ALL Regular Retrieval of Flow Rate LL Mode	NA	Invalid
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) Regular Retrieval of Flow Rate LL Mode	NA	Invalid
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) Regular Retrieval of Flow Rate *KrF LL Mode	NA	Invalid
				5.1. System Config Parameter, Spinners (COT/BCT/ITC) Local Nozzle Regular Retrieval of Flow Rate *KrF LL Mode	NA	Invalid
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) Controller EPCA P Contant	45	30
				6. System Config Parameter, Ovens -CPHP Control Table Data List Set Value Upper Limit	81	82
				6. System Config Parameter, Ovens -CPHP Control Table Data List for KrF Set Value Lower Limit	55.10, 60.10, 90.10, 100.10, 105.10, 110.10, 115.10, 120.10, 130.10,	Delete
				6. System Config Parameter, Ovens -CPHP Control Table Data List for KrF Set Value Upper Limit	81	82
				6. System Config Parameter, Ovens -CPHP Monitoring Parameter Table for Controller TM206-CHILLER Imm/EUV*-set Value	7.2	8.4
				6. System Config Parameter, Ovens -CPHP Monitoring Parameter Table for Controller TM206-CHILLER TBN	NA	Add

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		Intel	TEL			
02/03/2023	2.05	K. Procto	Terry	6. System Config Parameter, Ovens -CGCH Monitoring Parameter Table for Controller TM206-CHILLER Set Value* 9.6	NA	Add
				6. System Config Parameter, Ovens -SCPL Table for Temperature Control Method TBN only	NA	Add
				6. System Config Parameter, Ovens -SCPL Table for Channel No. / Monitoring Type / Use Point Offset / Initial Data / Source Value Monitoring Valid/ Source Value Monitoring Band / Line No. / Set Va Configuration TBN only	NA	Add
				6. System Config Parameter, Ovens -CADH Table for Temperature Control Method Configuration-TBN	NA	Add
				6. System Config Parameter, Ovens -CADH Table for Temperature Control Method Table for 13-11 CADH HMDS Bubbler Tank temp.	NA	Add
				8.System Parameter Others Button to Switch Step Data Valid/Invalid on Recipe Edit Screen	NA	Invalid
				8.System Parameter Others Option-Chemical Install Assist Function(Main Screen) limited number of concurrent execution	NA	1
				8.System Parameter Cup Wash Option-Improvement of Automatic CWH Specification Method for Manual Cup Was	NA	Valid
				8.System Parameter Special Transfer Control Option-Wafer Transfer during Interval dummy when Shared Arm is not used	NA	Valid
				8.System Parameter Cup Wash Option-CarrierID Re-reading at FOUP Exchanger Initialization	NA	Valid

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		Intel	TEL			
04/03/2023	2.06	K. Procto	Matt B / John V	3. Sys Config(Sys) Table for Chanel No. / Line No. / Set Value	NA	Addition of TBN table
				3. Sys Config(Sys) Table for Band Monitoring Refernce Value / Warning Range Lower Limit / Warning Range Upper Limit	NA	Addition of TBN table
				4. Sys Config(Arm) 4. System Configuration Parameter, Arm Block 11, 12, 13, 14, 15, 16 PR Block Fork1 / Fork2 Z-axis Multistep Movement Z-axis Multistep Movement (Receive) Z-axis Multistep Movement (Send) Z-axis Multistep Movement (Long Receive) Y,Z and Theta axis Offset	CVVP	CVIP
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) DFS Process Suckback Position Setup1 Position Setup2 Position Process Suckback Position Suckback1 Position Suckback2 Position Suckback3 Position	NA	BARC 48 ± 3 0 0 0 22 ± 3 22 ± 3 5 ± 3
				5.2. System Config Parameter, Spinners (COT) *TBN	N/A	TBN Table for Reload Initial Pressure and Pump Return Vent Initial Pressure Settings Added
				5.2. System Config Parameter, Spinners (COT/BCT/ITC) Block Arm - Left / Module Arm - Left/Right Home Position	Home Position Table Nozzle Specific	Home Position Table Addition: *Refer to Nozzle Height Home Position
				6. System Config Parameter, Ovens Block 11, 12, 13, 14, 15, 16 PR Block, [CVIP] Chilling Very High Temperature Hot Plate with VE Chamber Process Station	Block 12, 13, 14, 15 PR Block, [CVIP] Chilling Very High Temperature Hot Plate with VE Chamber Process Station	Block 11, 12, 13, 14, 15, 16 PR Block, [CVIP] Chilling Very High Temperature Hot Plate with VE Chamber Process Station
				6. System Config Parameter, Ovens Block 11, 12, 13, 14, 15, 16 PR Block, [CVIP] Chilling Very High Temperature Hot Plate with VE Chamber Process Station Control Table Data (Temperature Range 350 - No Input) Control Table Data (Temperature Range 380 - No Input) Control Table Data (Temperature Range 400 - No Input) Control Table Data (Temperature Range 450 - No Input)	NA	Table Data No. 7 Tool Specific No Input No Input No Input
				8. System Parameter Other	N/A	Addition: Option Excution of Auto Bath Wash Only at the End of Last Shot in each Step of Nozzle Purge Recipe - Valid
					Option Execution of Auto Bath...	Spelling fix: Excution --> Execution
					Button to Switch Step Data...	F --> Invalid
				8. System Parameter Basic Transfer Control	*PBR = Valid	Invalid PBR Only = Valid
					*PBR = Invalid	Valid (Wait just before Spin) PBR Only = Invalid
				8. System Parameter Specail Transfer Control	N/A	Addition: Option Access Fork Fixation for 2nd Spinner function - Valid
07/14/2023	2.07	K. Procto	Matt B	4. Sys Config(Arm) Fork1 / Fork2	Z-axis Receive Stroke - 3350/3370 Z-axis Send Stroke	Addition of ** COT = 3350, ADEV/AND = 3770
				5.2 Sys Config(BCT,COT,ITC) Table of Temperature Control Method (Imm tool) Table of Temperature Control Method (KrF tool)	12-3 (ITC) BCT/COT/ITC Temp. Control flow rate - Temp ctl ON N/A 13-1 (COT) Resist temp. Temp ctl ON 13-1 (COT) Cup temp. Temp ctl ON 3-1 (COT) Cup humidity Temp ctl ON 13-1 (COT) BCT/COT/ITC Temp. Control flow rate Temp ctl ON 13-3 (COT) Resist temp. Temp ctl ON **13-3 (COT) BCT/COT/ITC Temp. Control flow rate Temp ctl ON**	Temp ctl OFF 12-1,2,3,4 (COT) 13-1 (COT) Resist temp. Temp ctl OFF** 13-1 (COT) Cup temp. Temp ctl OFF** 13-1 (COT) Cup humidity Temp ctl OFF* 13-1 (COT) BCT/COT/ITC Temp. Control flow rate Temp ctl OFF** 13-3 (COT) Resist temp. Temp ctl OFF** **13-1 (COT) BCT/COT/ITC Temp. Control flow rate Temp ctl OFF****
				13. Unified UI App Screen (New UI)	13. EC Display Overview	13. Unified UI App Screen (New UI) Tab and Header Change
				14. Unified UI App Maintenance Setting (New UI)	14. EC MAINTENANCE Setting	14. Unified UI App Maintenance Setting (New UI) Tab and Header Change
				15. Unified UI App Online Setting (New UI)	15. EC ON-LINE Setting	15. Unified UI App Online Setting (New UI) Tab and Header Change
				16. Unified UI App System Setting (New UI) Network Setings Subnet Mask Router	16.EC SYSTEM Setting IP Address: 10.10.10.10 255.255.255.0 N/A	16. Unified UI App System Setting (New UI) Tab and Header Change Tool Specific 255.255.255.0 or 255.255.244.0 Site Specific
				20.1 CCV Setting	20. CCV Setting	20.1 CCV Setting Header Change

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07/25/2023	2.07	K. Proctor	Matt B	4. Sys Config(Arm) Block 11, 12, 13, 14, 15, 16 PR Block Fork1 / Fork2	** COT = 3350, ADEV/AND = 3770	*COT Deck or PBR = 3350, DEV Deck = 3770 **Link Tool = 4750, Standalone Tool = 3550
				Y, Z and Theta Axis Offset	N/A	TRS 0 Pulse * 0 Pulse
						*COT Deck or PBR = 3350, DEV Deck = 3770
					*	***Link Tool = 4750, Standalone Tool = 3550
				Block 30 IFB Block Transfer Arm Control Parameter	Auto Temp Adj Speed - X1 = 50, X2 = 50, Y = 50, Z = 50, Th = 50	Auto Temp Adj Speed - IRAM X1 = NA, X2 = NA, Y = NA, Z = NA, Th = NA
					Auto Temperature Adjustment Speed	Auto Temperature Adjustment Speed - IRAI
					N/A	Auto Flow Adjustment Move Module Speed X1 = 100, X2 = 100, Y = 100, Z = 100, Th = 100
					N/A	Auto Flow Adjustment Wafer In/Out Speed X1 = 100, X2 = 100, Y = 100, Z = NA, Th = 100
				5.2 Sys Config(BCT,COT, ITC) Monitoring ParameterTable for Temperature Control Method [KrF tool]	12-1 (COT)* Cup Tmp On	12-1 (COT)* Cup Tmp OFF
					12-1 (COT)* Humidity On	12-1 (COT)* Humidity OFF
					13-1 (COT)* Cup Tmp On	13-1 (COT)* Cup Tmp OFF
					13-1 (COT)* Humidity On	13-1 (COT)* Humidity OFF
					*TBN Only	*Not present on TBZ
08/11/2023	2.07	K. Proctor	Matt B.	5.2.Sys Config(BCT,COT,ITC) Table for DRN CASE CLEAN	NA	Addition of TBN table
				Monitoring Parameter Table for Temperature Control Method [KrF tool]	"Tmp ctl ON**	Tmp ctl ON